CALIBRATION AND SERVICING HANDBOOK



INSTRUMENTS

AUTOCAL STANDARD

CALIBRATION AND SERVICING HANDBOOK

for

THE DATRON 4000 & 4000A AUTOCAL STANDARD

(for operating procedures refer to the User's Handbook)

850055

Issue 3 (JAN 1988)

For any assistance contact your nearest Datron Sales and Service Centre.

Addresses can be found at the back of this handbook.

Due to our policy of continuously updating our products, this handbook may contain minor differences in specification, components and circuit design to the instrument actually supplied. Amendment sheets precisely matched to your instrument serial number are available on request.



DANGER HIGH VOLTAGE



THIS INSTRUMENT IS CAPABLE OF DELIVERING A LETHAL ELECTRIC SHOCK!



FRONT or REAR terminals carry the Full Output Voltage.

THIS CAN KILL!



Guard terminal is sensitive to over-voltage

It can damage your instrument!

it is safe to do so,

DO NOT TOUCH the

I+ I- Hi or Lo leads

and terminals

DANGER

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SECTION 1

CALIBRATION

1.1 INTRODUCTION

1.1.1 Manufacturer's Initial Calibration

The 4000 is fully calibrated before leaving the factory, and remains within the appropriate specification for the time periods detailed in Section 6 of the User's Handbook.

1.1.2 Need to Recalibrate

Sections 1.2 to 1.5 detail the procedures necessary to recalibrate instrument functions to known specifications. The occasions for re-calibration are as follows:

- (1) PERIODIC ROUTINE AUTOCALIBRATION
 The specifications for the 4000 are based on
 standard intervals of up to 24 hours, 90 days
 or 1 year from calibration. User's may wish
 to choose alternative schemes, accounting for:
 - (a) The accuracy required when in use,
 - (b) The scheduled calibration intervals normally adopted by the user's organisation, and
 - (c) The instrument specifications (User's Handbook Section 6)
- (2) RE-STANDARDISATION

Occasions may arise when it is necessary to trim the instrument internal Master Reference.

For example, when the 4000 is to be made traceable to a different National Standard.

after transportation from one country to another.

The procedure for "STD" autocalibration is detailed in Section 1.2.8 (Refer to Section 1.28 para 3 note C).

(3) BATTERY CHANGE

The Lithium battery which powers the non-volatile calibration memory should be replaced after 5 years (Refer to Section 5.3).

After replacement, a full Pre-calibration (Precal – Section 1.4) followed by a Routine Autocalibration (Section 1.2) is required.

(4) CRITICAL PARTS

Recalibration will be required after replacement of a critical pcb assembly or critical component. These are listed in Table 1.1, indicating the extent of recalibration necessary.

1.1.3 Recalibration Procedures in this Section

Routine Autocalibration (Section 1.2)

The Routine Calibration procedures are sufficient for all normal recalibration purposes, except when "Pre-cal" is called for (Refer to Table 1.1).

Remote Calibration over the IEEE 488 Bus (Section 1.3)

Section 1.3 describes the device-dependent commands necessary for routine calibration of the 4000 over the IEEE 488 bus, as a supplement to Section 5 of the User's Handbook. A guideline example is given, but this needs to be adapted for the bus controller in use.

Pre-calibration Procedures (Section 1.4)

In an initial internal calibration process at manufacture, certain "Pre-cal" parameters are established in a special calibration memory. Under certain conditions (detailed in Table 1.1) these parameters need to be reestablished by the "Pre-cal" procedure in Section 1.4, before the Routine Autocalibration of Section 1.2.

Ω Option Internal Adjustment (Section 1.5)

If a standard resistor value has been changed by subjecting to undue stress, it may be possible to recalibrate by internal adjustment. Refer to Section 5.4 for further information.

Table 1,1

PCB Assembly	Components Replaced	Precal (Sect. 1.4)	Routine Autocalibration (Sect. 1.2)
Digital (400442)	Complete Assembly	Full	Full
(400442)	Lithium Battery (Sect. 5.3) Non-volatile RAM (M10/26/27) Non-volatile RAM Supply Commutator components	Full Full Full	Full Full Full
Reference Divider (400444)	Complete Assembly Reference PCB Assembly (400452) Any set of main, guard or LSD switch FETs	Full Full Full	Full Full Full
	Reference Buffer Switch Driver Flip Flops or their preselected resistors	Full Full	Full Full
	R79	Full	Full
DC (400445)	Complete Assembly 1V attenuator R73/R74	<u>-</u>	DC (All Ranges) only. DC (1V, 100mV, 10mV, 1mV, 100μV Ranges) only
	100mV attenuator R69/70/71 } 72/75/76	_	DC (100mV, 10mV, 1m\ 100μV Ranges) only.
·	100V/1000V Attenuator R8/9/25/26/46/47/64/65 88/95/98	_	DC (100V, 1000V Range only
I/Ω (400448)	Complete Assembly (N.B. Internal Adjustment required — refer to Section 5.5)	_	I and Ω (AII Ranges) only
	÷ 10 attenuator (R43/44) (I Function)	-	I (All Ranges) only
	Current shunts R8/9/10/79/80 (I Function)	_	I (All Ranges) only
	Standard resistors, associated pre-selected or variable trimmer resistors (Ω Function)	Ω Option internal adjustment (Sect. 1.5)	Ω (Replaced Values) only

Table 1.1 List of Critical pcbs and components

1,2 ROUTINE AUTOCALIBRATION

1.2.1 Introduction

The 4000 possesses excellent short and long term stability. Some users will wish to maintain the highest accuracy by recalibrating at short intervals (e.g. every 24 Hours). In these cases, recalibration of the 4000 becomes a routine task. For this reason, Routine Autocalibration procedures are repeated in section 8 of the User's Handbook. It is emphasised that the 4000 can be used immediately after recalibration.

1.2.2 The 4000 Autocal Feature

Full or part calibration may be carried out for all routine purposes from the front panel. Removal of covers is unnecessary, therefore avoiding thermal disturbance. Calibration corrections are stored in an internal memory which remains energised by a battery even when the instrument power supply is switched off. The life of the battery is estimated at 10 years, and it is normally changed at 5-year intervals. On power-up, the 4000 performs a self-test which includes a check of the contents of the calibration memory.

1.2.3 Equipment Requirements

DC Voltage — A Standard DC Voltage source of suitable accuracy

Example: Series bank of 10 standard cells and Datron 4904 Standard Cell buffer.

A Precision Divider:
 Example: Datron 4902 High
 Voltage divider and
 Datron 4903 DC
 Switching Unit

 A battery-operated null detector with variable sensitivity, able to withstand 1200V across its input terminals
 Example: Keithley Instruments Model 155

Resistance — a set of standard resistors covering 1Ω to $10\mathrm{M}\Omega$. The 1Ω to $10\mathrm{k}\Omega$

should be 4-wire type.

 an accurate resistance bridge, or other ratiometric device for measuring resistance to the required accuracy.

 a Datron 1071 used as a transfermeasurement device. DC Current — A DC Voltage source, calibrated to suitable accuracy at approximately 1V and 100mV

Example: The standard voltage source used for DC Voltage, with the Datron 4903 DC Switching Unit.

- The battery-operated null detector used for DC Voltage.
- A set of calibrated current shunts of suitable accuracy.

N.B.

To allow the same value to be set on the DC Voltage source for each range, the shunts may be of five decade values. Then the same Null Detector sensitivity can be used on each range.

CAUTION

When choosing a set of current shunts ensure that their power dissipation ratings are sufficient to avoid permanent degradation from the self-heating effects of the current being checked. This applies particularly to the 1 Amp shunt.

 alternatively, a dmm of sufficient accuracy may be used to measure the voltage across the set of calibrated current shunts.
 Example: Datron 1071 using "compute" mode.

1,2,3,1 Notes on the Use of the Null Detector

The null detector is connected to the Hi lead between the DC Voltage Source and the 4000. A high-impedance-input device should be chosen to reduce off-null currents due to differences in the outputs of the DC voltage source and the 4000. A battery-operated instrument is preferred to ensure adequate isolation. Some null detectors possess high input impedance only when their readings are on-scale, so care should be taken to ensure that drain currents from the DC Voltage source do not become excessive. This applies particularly if the DC source is a standard cell or a bank of cells. Five points are important:

- The null detector should be connected to the 4000 (or 4000 load resistor) only when the 4000 OUTPUT OFF LED is lit. (With Output OFF, the I+, I-, Hi and Lo terminals are at high impedance).
- Always set the null detector to its lowest sensitivity before connecting up, and increase sensitivity only when the voltages output by the DC Voltage source and the 4000 are close in value.
- Do not change polarity of the 4000 or DC Voltage source without first switching the 4000 OUTPUT OFF. Care must be taken to ensure that the correct-polarity ON key

is pressed, to avoid excessive voltages being connected across the null detector, particularly when checking the 4000 directly against a standard cell.

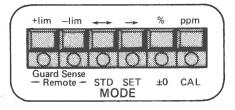
- 4. WARNING During Performance checks and calibration a common mode voltage equal to the full range voltage is present at the Null Detector input terminals. On ± 1000V checks this voltage is potentially lethal, so EXTREME CAUTION must be observed when making adjustments to the null detector sensitivity.
- 5. CAUTION The Null Detector used must be able to withstand voltages up to 1200V between its input terminals. Such voltages will be present during the time that the 4000 is ramping from zero to 1000V Full Range after setting OUTPUT ON. Inadvertent disconnection of the Precision Divider terminals can transfer full output across the Null detector.

1.2.4 Interconnections

Interconnection instructions in this section are necessarily simple and basic, and are mainly intended to show connections to the 4000. It is recognised that they may need to be adapted to meet an individual user's require-

ments. It is assumed that users will possess knowledge of the operation and use of standards equipment such as that mentioned above.

1.2.5 Calibration Modes



Four of the Mode Keys have 'Autocal' functions:

STD, SET, ±0 and CAL

These are printed in red below the keys and are activated only when the cal legend is present on the MODE display. The normal key modes, (Spec, Error, Offset and Test) are disabled by the selection of CALIBRATION ENABLE on the rear-panel keyswitch. The STD, SET and ±0 keys have toggle action (e,g, when a mode is set it may be deselected by a second key-press).

1.2.5.1 General Procedure

The OUTPUT display is set to the Calibration Standard value, the 4000 output is switched ON, and one of the calibration mode preselector keys (SET, STD or ± 0) is pressed. The 4000 output is adjusted to obtain a null at the Calibration Standard value, and the CAL key is pressed to execute the calibration.

1.2.5.2 Autocal Facilities

SET

The SET key allows calibration to any value in the selected Range (e.g. at a standard cell voltage). If the value initially set on the OUTPUT display is below 2% of Full Range value, the 4000 assumes that an offset calibration is requested, and if at 2% or above, a gain calibration is assumed.

±0

The ±0 key is used to align the ON+ and ON- zeros of all voltage and current ranges, by a two-part calibration on the 10V range. It is only necessary when the ON+ and ON- zeros on the 10V range do not coincide at the same null.

STD

The STD key allows a user to trim the value of the internal Master Reference voltage. The facility can be used to correct for any long-term drift, or to avoid a full recalibration of the 4000 when Laboratory References have been re-standardised. STD calibration effectively changes the gain of all voltage and current ranges in the same ratio, by a simple procedure available either on 1V or 10V range.

CAL only The CAL key executes the preselected AUTOCAL mode. If the CAL key is pressed without first pressing SET, ±0 or STD, the 4000 assumes that a calibration at either Zero or Full Range is required. It uses the value set on the OUTPUT display to distinguish between Zero (Offset calibration) and Full Range (Gain calibration) as for SET mode.

1.2.5.3 Autocal Availability

As the Autocal keys perform specific tasks, they are available only as defined by Table 1.2. The message "Error 3" appears on the MODE display for any attempt to select an inappropriate mode.

AUTO	CAL Mode	DC Voltage	DC Current	Resist	ance (Ω)
		(DC)	(1)	Local Sense (2-wire)	Remote Sense
SET	Zero offset for range at User's selected value	100mV-1000V	All		
and CAL	Gain for range at User's standard value	Ranges only	Ranges		
+0 and CAL	Alignment of internal ON+ and ON- zeros	10V Range only			
STD and CAL	Internal Reference gain at User's Standard value	1V and 10V Range only			
CAL	Zero offset for range	AII Ranges	All	1Ω $-1ΜΩ$	
ONLY	Gain for range at Full Range Value	10mV-1000V Ranges only	Ranges	Ranges only	All Ranges

Table 1.2 Autocal availability

1,2,6 **Zero Calibration**

It is common practice to accept a small offset in the output of a voltage calibration standard, providing that the same offset is present at all output values, including zero.

The output of the 4000 is fully floating, so its output may be referred to any common mode voltage within the range specified on page 6.1 of the User's Handbook. In particular, its zero may be aligned to absolute zero in Local Sense by calibration to a null across its Hi and Lo (Sense) terminals. But if it is then gain-calibrated against an offset standard without re-zeroing to that standard's offset zero, normal mode gain errors will result.

It is therefore essential that each voltage and current range zero is first calibrated to a standard's zero before using that standard to calibrate the range gain.

If the 4000 zero output is to be regarded as absolute Laboratory Reference Zero, then AFTER range gain calibration its range zero output may be recalibrated to a null across the Hi and Lo (Sense) terminals.

1.2.7 Calibration Sequence

The sequence of operations for full calibration of a 4000 Autocal Standard is given below:

Preparation	Section 1.2.7.1
DC Voltage	1.2.8
DC Current	1.2.9
Resistance	1.2.10
Return to Use	1.2.7.2

WARNING During performance checks and calibration a common mode voltage equal to the full range voltage may be present at the Null Detector input terminals. On ±1000V checks this voltage is potentially lethal, so EXTREME CAUTION must be observed when making adjustments to the null detector sensitivity.

If only a partial recalibration is to be done, step 1 of the DC Voltage sequence should be carried out immediately after the preparation.

The Null Detector used must be able to CAUTION withstand voltages up to 1200V between its input terminals. Such voltages will be present during the time that the 4000 is ramping from zero to 1000V. Full Range after setting OUTPUT ON. Inadvertent disconnection of the Precision Divider terminals can transfer full output across the Null detector.

1.2.7.1 Preparation

Before any calibration from the front panel is carried out, prepare the 4000 as follows:

- allow minimum of 4 hours to warm-up in the specified environment.
- 1. Turn on the instrument to be checked and

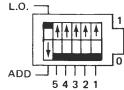


1.2.7.2 Return to Use

When any calibration is completed, return the 4000 to use as follows:

1. Ensure that OUTPUT OFF LED is lit.

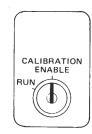
IEEE 488 Address switch: Set to ADD 11111 as shown (Address 31)



2. CALIBRATION ENABLE kev switch: Turn to RUN and withdraw calibration key.



CALIBRATION ENABLE key switch: Insert Calibration Key and turn to ENABLE.



3. IEEE 488 Address switch: Restore to correct address if the 4000 is to be used in an IEEE 488 system.

These actions activate the four calibration modes (labelled in red) and present the cal legend on the MODE display.

4. Ensure that OUTPUT OFF LED is lit.



DANGER HIGH VOLTAGE



THIS INSTRUMENT IS CAPABLE OF DELIVERING A LETHAL ELECTRIC SHOCK!





Guard terminal is sensitive to over-voltage

It can damage your instrument!

it is **safe** to do so, **DO NOT TOUCH** the **I+ I- Hi** or **Lo leads**and **terminals**

DANGER

CAUTION

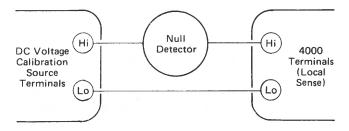
First read the Notes on the use of the Null Detector in Section 1.2.3.1.

1. Ensure that the 4000 OUTPUT OFF LED is lit.

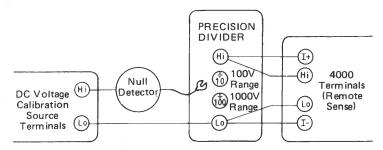
Select DC and connect the DC Voltage Calibration source and Null Detector to the 4000 terminals as shown in Fig. 1.1. Use short leads and ensure that Null Detector is set to Low Sensitivity.

Fig. 1.1 4000 connections for DC Voltage Calibration

(a) Low Voltage: $100\mu V - 10V$ Ranges



(b) High Voltage: 100V and 1000V Ranges



Ensure that the interconnecting circuit has thermally stabilised before carrying out each "Autocal" operation

- 2. Calibrate the DC Voltage Ranges in the step sequence of Table 1.3 using the Calibration Routine at each step (except steps 2 and 3).
- Calibration Routine: Calibration of DC Voitage to a Standard voltage calibration

For calibration at any value, this routine may NOTES: A be used as printed.

- For calibration at zero or positive nominal Full Range only, operation (g) may be
- To trim internal Master Reference Voltage on 1v or 10V Range, substitute "STD" for "SET" at operation (g). (Refer to earlier description of "STD").
- In Table 1.3(a), use interconnections as Fig. 1.1(a) (Low Voltage), obtaining the correct calibration voltage from the source. In Table 1.3(b), use interconnections as Fig. 1.1(b) (High Voltage) selecting \div 10 at steps 10 and 11, ÷ 100 at steps 12 and

CAUTION

Below 2% of Range, the 4000 corrects for an assumed offset error; at 2% of Range and above the correction is for an assumed gain error.

a) Null Detector

b) 4000

e) 4000

Set to Low sensitivity **Ensure OUTPUT OFF**

c) DC Source

d) 4000

Set to the required polarity and value Select correct FUNCTION and RANGE Use full Range, Zero or OUTPUT ↑/↓

keys to set the required polarity and

value on OUTPUT display.

N.B. Operation (f) must be carried out before operation (g)

f) 4000

Press the correct-polarity ON key

Omit Operation (g) if calibrating at zero or Full Range value

g) 4000

Press SET Key:

SET LED lights green

OUTPUT display reading also appears

on MODE display

h) Null Detector

Increase sensitivity to give an off-null reading and use 4000 OUTPUT 1/4 keys to back off to null. Repeat until null lies between two values of the OUTPUT display least-significant digit.

j) Null Detector

Set to LOW sensitivity

k) 4000

Press CAL key CAL LED flashes once

Not applicable if operation (g) omitted

MODE display value is transferred to OUTPUT display

MODE display is cleared SET LED goes OFF

The 4000 is now calibrated at this value.

4. ±0 Alignment Routine: Alignment of 10V Range positive and negative zeros if necessary at step 3 of Table 1.3.

a) Null Detector

Set to low sensitivity

b) 4000

d) 4000

Ensure OUTPUT OFF on DC 10V

Ensure set to zero and thermally stable.

Range.

c) Calibration Source

Press OUTPUT Zero Key

Press ON+ Key

Press ±0 Key:

±0 LED lights, OUTPUT display at

Increase sensitivity to give an off-null reading and use 4000 OUTPUT 1/1 keys to back off to null. Repeat until null lies between two values of the OUTPUT display least-significant digit.

Press CAL key:

CAL LED lights

No change to OUTPUT display.

g) 4000

f) 4000

Press ON - key

h) Null Detector

e) Null Detector

Obtain accurate null as in (e) above

i) 4000

Press CAL key: CAL LED goes OFF ±0 LED goes OFF

OUTPUT display falls to zero

The 4000 positive and negative zeros are now both aligned to the Calibration Source zero.

Table 1.3 DC Voltage Calibration

(a) Low Voltage - connect as Fig. 1.1(a)

Step	Calibration Operation	4000 Range	Calibration Source Voltage (Nominal value) [1]	4000 Output Setting (Nominal value) [1]	AUTOCAL Key Used [2]
1	10V Range ON+ zero	10	0.00000V	(ON+) 0.000000V	-
2	10V Range ON- zero check only – do not calibrate	10	0.000000V	(ON-) 0.000000V	Check only 0.000000V
3	±0 Alignment	10	0.000000V	Refer to ±0 Alignment Routine	'±0'
4	100mV Range zero	100m	0.00000mV	0.00000mV	_
5	100mV Range gain	100m	+100.0000mV	(ON+) 100.00000mV	'SET' for non-nominal
6	1V Range zero	1	.0000000V	(ON+) .0000000V	_
7 ^[3]	1V Range Gain	1	+1.000000V	(ON+) 1.000000V	'SET' for → C
8	10V Range zero	10	0.000000V	(ON+) 0.000000V	-
9[3]	10V Range gain	10	+10.000000V	(ON+) 10.000000V	'SET' for -> C

(b) High Voltage - connect as Fig. 1.1(b)

Step	Calibration Operation	4000 Range	Calibration Source Voltage	Precision Divider Select	4000 Output Setting (Nominal value) [1]	AUTOCAL Key Used [2]
10	100V Range zero	100	0.00000∨	÷ 10	(ON+) 0.00000V	
11	100V Range gain	100	+10.000000V	÷ 10	(ON+) 100.00000V	'SET' for non-nominal
12	1000V Range zero	1000	0.0000∨	÷ 100	(ON+) 0.0000V	_
13	1000V Range Gain LETHAL VOLTAGE	1000	+10.000000V	÷ 100	(ON+) 1000.0000V* *Enter High Voltage state using interlock procedure (User's Handbook Sect. 4)	'SET' for non-nominal

NOTES [1] it is expected that many users will wish to calibrate Range gains at values other than the nominals shown. In these cases set the Calibration Source voltage and 4000 OUTPUT display to in-house standard values near nominal.

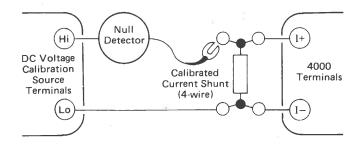
[2] Except for Step 2, use CAL key as trigger (Refer to Calibration Routine).

^[3] To trim the internal Master Reference voltage, substitute 'STD' for 'SET' for 1V or 10V Range (Refer to Calibration Routine and description of 'STD').

DC CURRENT CALIBRATION

Ensure that the 4000 OUTPUT OFF LED is lit. Select I and connect the DC Voltage calibration source, null detector and calibrated current shunt to the 4000 OUTPUT terminals as shown below. Do not connect null detector to shunt until the voltage across the shunt and the source voltage are close in value.

Fig. 1.2 4000 connections for DC Current Calibration



Preferred shunt values are as follows:

Calibration Source Output Voltage for Full Range

100μA range	_	10k Ω 1mW min	1V
1mA range	_	$1 k\Omega$ 10mW min	1V
10mA range		100Ω 100 mW min	1V
100mA range	_	10 Ω 1 Watt min	1V
1A range	-	0.1Ω 1 Watt min	100mV

Ensure that the calibration source voltage is set to zero and that the interconnecting circuit has thermally stabilized.

- 2. Calibrate the DC Current ranges in the step sequence of Table 1.4, using the Calibration Routine at each step.
- Calibration Routine: Calibration of DC Current using a DC Voltage Calibration Source and a series of calibrated current shunts.

NOTES:

- For calibration at any value, the routine may be used as printed.
- For calibration at zero or positive nominal Full Range only, operation (g) may be omitted.

CAUTION:

Below 2% of Range, the 4000 corrects for an assumed offset error; at 2% of Range and above the correction is for an assumed gain error.

a) Null Detector

Set to Low sensitivity

b) 4000

Ensure OUTPUT OFF

c) DC Source

Set to the required polarity and value

d) 4000

Select correct FUNCTION and RANGE

e) 4000

Use Full Range, Zero or OUTPUT ↑/↓ keys to set the required polarity and

value on OUTPUT display

N.B. Operation (f) must be carried out before operation (g)

f) 4000

Press the correct polarity ON key

CAUTION: Pressing the wrong ON key will result in twice the OUTPUT being connected across the null detector.

Omit operation (g) if calibrating at Zero or Full Range value

a) 4000

Press SET key:

SET LED lights green

OUTPUT display reading also appears

on MODE display

h) Null Detector

Increase sensitivity to give an off-null reading and use 4000 OUTPUT ↑/↓ keys to back off to null. Repeat until null lies between two values of the OUTPUT display least-significant digit.

i) Null Detector

Set to LOW sensitivity

k) 4000

Press

CAL key

Not applicable if operation (g) omitted

CAL LED flashes once MODE display value is transferred to OUTPUT display MODE display is cleared SET LED goes OFF

Table 1.4 DC Current Calibration

Step	Calibration	Shunt	Calibration	4000	4000 OUTPUT Current	
	Operation	Value	Source [1]	Range	OUTPUT Setting [1]	Key _[2]
1	100μΑ Range zero	10kΩ	.0000000V	100μ	0.0000μΑ	-
2	100μΑ Range gain	10kΩ	+ 1.0000000V	100μ	+100.0000μΑ	'SET' for non-nominal
3	1mA Range zero	1kΩ	.0000000V	1m	.000000mA	_
4	1mA Range gain	1kΩ	+ 1.000000V	1m	+ 1.000000mA	'SET' for non-nominal
5	10mA Range zero	100Ω	.0000000V	10m	0.00000mA	_
6	10mA Range gain	100Ω	+ 1.000000V	10m	+ 10.00000mA	'SET' for non-nominal
7	100mA Range zero	10Ω	.0000000V	100m	0.0000mA	_
8	100mA Range gain	10Ω	+ 1.0000000V	100m	+100.0000mA	'SET' for non-nominal
9	1A Range zero	0.1Ω	0.0000mV	1	A000000	_
10	1A Range gain	0.1Ω	+100.00000mV	1	+ 1.000000A	'SET' for non-nomina

NOTES

^[1] It is expected that many users will wish to calibrate Range gains at values other than the nominals shown. In these cases set the Calibration Source voltage and the 4000 OUTPUT display to in-house standard values near nominal.

^[2] At each step, use CAL key as a trigger (Refer to Calibration Routine).

1.2.10 RESISTANCE CALIBRATION

1. **Calibration Memory**

In Ω function, each RANGE key selects a nominalvalue standard resistor. Routine adjustment of the resistor is not necessary. During calibration the actual value is measured and stored in the calibration memory to be displayed whenever that range is selected. Separate memory stores exist for Remote Sense (4-wire), Local Sense (2-wire) and Local Sense zero.

2. 4-Wire Calibration Limits

The value measured in 4-wire Remote Sense does not include the resistance of internal or external wiring. The 4000 accepts any value within ±200 ppm of nominal as a valid calibration.

2-Wire Calibration Limits 3.

The value measured in 2-wire Local Sense is greater than for 4-wire Remote Sense, as it includes the resistance of internal wiring and relay contacts. The 4000 will not accept any 2-wire value less than the stored value for 4-wire, so the 4-wire Remote Sense calibration must be carried out before attempting 2-wire Local Sense. The extra internal resistance varies between Ranges, so the 4000 accepts the following values (x) as valid 2-wire calibrations:

> Zero calibration. $1\Omega - 1M\Omega$ Ranges: 0<0.900Ω

Value calibrations 1Ω Range:

4-wire value $\leq x \leq (4$ -wire value + 0.999 Ω)

 $10\Omega - 1M\Omega$ Ranges: 4-wire value $\leq x \leq$ (4-wire value + 1.999 Ω)

4. "Error 6" message

"Error 6" appears on the MODE display for any attempt to enter a value outside the 4-wire or 2-wire limits quoted above.

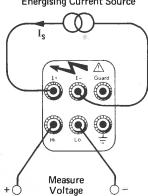
NOTE: When resistance is calibrated in Remote Sense. the 4000 overwrites the Local Sense calibration memory with the new 4-wire value.

5. 4-wire and 2-wire Connections

Fig. 1.3 (a) 4-wire calibration

Fig. 1.3 (b) 2-wire calibration (using 4-wire method externally)

Remote Sense Energising Current Source



Energising Current Source

Local Sense

Measure Voltage

Calibration sequence

Press Ω key and calibrate the resistors in the step sequence of Table 1.5 (a and b), using the Calibration Routine at para 7 (a or b). Refer to para 5 for connections to the measuring equipment. For 4-wire connections in Remote Sense, only the value of the internal Standard Resistor is measured. In Local Sense, a 4-wire method is used to exclude the resistance of the external leads from the measured value.

- Calibration Routine: Measurement and Storage of the values of an internal resistor.
 - Remote Sense (Internal 4-wire, connected as Fig. 1.3(a).)

Full Range values - Routine for Table 1.5(a)

4000 Select OUTPUT OFF and Ω i) Select Remote Sense

ii) 4000 Press required resistor (RANGE) key: The previously calibrated value appears on the OUT-**PUT** display

Press OUTPUT ON+ and 4000 and measure the value of the resistanceinternal resistor measuring equipment

4000 Set the measured value on **OUTPUT** the OUTPUT display 1/↓ Keys

4000 Press to store OUTPUT CAL Key display value

4000 Set OUTPUT OFF vi)

- Repeat operations (ii) to (vi) for each vii) step of Table 1.5(a)
- b) Local Sense (Internal 2-wire, connected as Fig. 1.3(b).), Remote Sense OFF) Full Range and Zero values - Routine for table 1.5(b)

i) 4000 Select OUTPUT OFF and Ω Deselect Remote Sense

4000 Press required resistor ii) (RANGE) Key: The previously-calibrated value appears on the OUT-PUT display.

4000 and Press OUTPUT ON+ and resistancemeasure the value of the measuring internal resistance equipment

4000 iv) Set the measured value **OUTPUT** on the OUTPUT display 1/↓ Keys

4000 Press to store OUTPUT CAL Key display value

4000 Press and repeat operations Zero Key (iii) to (v) for this RANGE selection.

4000 Set OUTPUT OFF vii)

viii) Repeat operations (ii) to (vii) for each step of Table 1.5(b).

Resistance Calibration

Table 1.5 Internal Resistor value measurement and storage

a) Remote Sense (Internal 4-wire, connect as Fig. 1.3(a).)
Calibration at Full Range. Resolution 7½ digits, Tolerance ±199.9ppm (±1999 digits).

Step	Range	Measured resist	ance v	alue, Calibration	Limits
1	10ΜΩ	9.998,001	to	10.001,999	MΩ
2	1ΜΩ	.999,800,1	to	1.000,199,9	$M\Omega$
3	100kΩ	99.980,01	to	100.019,99	kΩ
4	10kΩ	9.998,001	to	10.001,999	kΩ
5	1kΩ	.999,800,1	to	1.000,199,9	kΩ
6	100Ω	99.980,01	to	100.019,99	Ω
7	10Ω	9.998,001	to	10.001,999	Ω
8	1Ω	.999,800,1	to	1.000,199,9	Ω

b) Local Sense (Internal 2-wire, connect as Fig. 1.3(b), Remote Sense OFF) Calibration at Full Range and Zero. Resolution as listed in table. Tolerances $-0\Omega+0.999\Omega$ on 1 Ω Range, $0\Omega+1.999\Omega$ on $10\Omega-1M\Omega$ Ranges, $-0\Omega+0.900\Omega$ for zero on $1\Omega-1M\Omega$ Ranges.

Ste	ep Range	Resolution (digits)	Resistance value Limits	Zero Limits			
9	1ΜΩ	7½	Step 2 value, —0 +19 digits	.000,000,0	to	.000,000,9	Ω M
10	100kΩ	7½	Step 3 value, —0 +199 digits	0.000,00	to	0.000,90	kΩ
11	10kΩ	7½	Step 4 value, -0+1999 digits	0.000,000	to	0.000,900	kΩ
12	1kΩ	6½	Step 5 value, -0+1999 digits	.000,000	to	0.000,900	kΩ
13	100kΩ	5½	Step 6 value, -0+1999 digits	0.000	to	0.900	Ω
14	10Ω	41/2	Step 7 value, -0+1999 digits	0.000	to	0.900	Ω
	1						

Step 8 value, -0 +999 digits

.000

.900

to

Ω



15

 1Ω

31/2

1.3.1 Introduction

The operation of the 4000 in systems applications via the IEEE 488 Interface, is described in Section 5 of the User's Handbook.

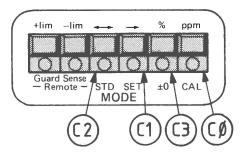
In addition to its capability as a programming calibrator, the 4000 can itself be calibrated under remote control. Full autocalibration of the instrument over the bus implies availability of programmable standards, a programmable null-detector and a suitably-programmed controller.

The Datron 4900 Series DC Voltage Calibration System is designed to be programmable, requiring only the addition of a bank of ten standard cells and a null detector.

1.3.2 Calibration Commands

Table 1.6 lists the device-dependent commands used in the 4000. The relevant calibration codes are described in Fig. 1.4 and Table 1.6.

Fig. 1.4 Transfer of front-panel calibration controls to System Operation



These commands can only be activated when two conditions have been fulfilled:

The CALIBRATION ENABLE Keyswitch on the 4000 Rear Panel must be set to ENABLE, and the IEEE Interface command-code W1 must have been received and activated.

When the 4000 is under remote control over the bus, the command-code $W\phi$ disables the 'C' codes, regardless of the keyswitch setting.

Table 1.6 Availability of Command Codes

Command	AU'	TOCAL Mode	DC Voltage	DC Current	Resis	stance (Ω)
Codes			(DC)	(1)	Local Sense (2-wire)	Remote Sense (4-wire)
C1	SET	Zero offset for range at User's selected value	100mV-1000V	All		
Сф	CAL	Gain for range at User's standard value	Ranges only	Ranges		
C3 and C ϕ	±0 and CAL	Alignment of internal ON+ and ON- zeros	10V Range only			
C2 and Cφ	STD and CAL	Internal Reference gain at user's Standard value	1V and 10V Range Only			
Сф	CAL	Zero offset for range	All Ranges	All	1Ω – 1MΩ	
Only	Only	Gain for range at Full Range Value	100mV-1000V Ranges Only	Ranges	Ranges Only	All Ranges

1.3.2.1 General Procedure

The Main Register is set to the Calibration Standard value (M***...), the 4000 Output is switched ON (O1), and one of the calibration mode command

codes (C1, C2, C3) may be transmitted. The 'M' Code is adjusted to obtain a null at the Calibration Standard value, and $C\phi$ is transmitted to execute the calibration.

1.3.2.2 Command Code Facilities

C1 (SET) C1 allows calibration to any value in the selected Range (e.g. at a standard cell voltage). If the value initially input by 'M' Code is less than ±2% of Full Range value, the 4000 assumes that an offset calibration is requested, and if at ±2% or greater, a gain calibration is assumed.

C2 (STD) C2 allows a user to trim the value of the internal Master Reference voltage. The facility can be used to correct for any long-term drift, or to avoid a full recalibration of the 4000 when Laboratory References have been restandardised. C2 (STD) calibration effectively changes the gain of all voltage and current ranges in the same ratio, by a simple procedure available either on 1V or 10V range.

C3(±0)

C3 is used to align the ON+ and ON-zeros of all voltage and current ranges, by a two-part calibration on the 10V range. It is only necessary when the ON+ and ON- zeros on the 10V range do not coincide at the same null.

Cφ (CAL only)

 $C\phi$ executes the preselected AUTO-CAL mode. If it is sent without first sending SET, ± 0 or STD, the 4000 assumes that a calibration at either Zero or Full Range is required. It uses the value input by 'M' Code to distinguish between Zero (Offset calibration) and Full Range (gain calibration) as for C1 (SET) mode.

M****...

1.3.3. Guidelines — An Example

(a)

The following sequence suggests a method of calibrating the 4000 IV Range Gain against a standard cell value of +1.018057V. It is assumed that the 4000 is correctly addressed with its Calibration Keyswitch set to ENABLE, that the 4000 Output is OFF; and that a Null Detector set to Low Sensitivity is connected between Standard Cell buffer and 4000 Hi/Lo terminals as in Fig. 1.1 (a) of Section 1.2.8.

4000 Codes

Command the 4000:	4000 00acs
DC Volts	$F\phi$
1V Range	R5
Local Guard and Sense	$G\phi S\phi$
Calibration Enable	W1
Output Value to calibration point	M+1.018057
Select "SET" Calibration mode	C1
Output ON	01

- (b) Establish null tolerance limits
- (c) Command the null detector:

 Recall Sensitivity Range and Reading
 Increase Sensitivity Range and repeat
 recall until reading exceeds half-scale
- (d) Calculate 4000 setting for null Set 4000 output to calculate value
- (e) Repeat (c) and (d) until null is within limits
- (f) Command the 4000 to execute "CAL"C ϕ The example suggests only the broad outline of one of many sequences which could be used to perform 4000 calibration.

1.4 PRECALIBRATION

For all normal purposes, the routine procedures detailed in Section 1.2 (and repeated in User's Handbook Section 8) are sufficient to maintain 4000 calibration.

In an initial internal calibration process at manufacture, certain 'pre-cal' parameters are established in a special calibration memory to define the overall linearity of the 4000, and to allow maximum routine calibration memory span for adjustments. Thus all routine calibrations may be performed from the front panel or over the IEEE Interface without removing any covers.

The stored parameters are invalidated by replacement of certain critical parts of the instrument:

 The Lithium battery which powers the whole calibration memory when the instrument supply is switched off. This should be replaced at five-year intervals (refer to Section 5.3). 2) The Digital Assembly

The Reference Divider Assembly

 Critical components in the Digital or Reference Divider assemblies Normally replaced only on failure. A full list is

given in Section 1.1 Table 1.1

After replacement of any of these parts, new parameters are generated and stored in the "pre-cal" memory by the procedures detailed in this section.

Pre-calibration must be followed by a full Routine Calibration of the whole instrument (Section 1.2).

1.4.1 Pre-calibration Procedure

1.4.1.1 Validity

The adjustments detailed in the following sequences include intentionally clearing the instrument's calibration memory, which loses all previous calibration information. Therefore, before proceeding make certain that the reasons for carrying out a complete recalibration are valid. (If in any doubt, consult your Datron Service Centre)

1.4.1.2 Calibration Standards Equipment Required

- A DC Voltage Calibration source of 10V ±20ppm
- A ÷2 precision divider, capable of dividing 20.000,000V to 10.000,000V ± 0.1ppm, D.C.
- A battery-operated null detector with variable sensitivity.

Example:

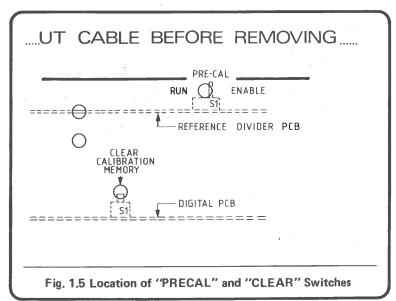
Keithley Instruments Model 155 Read the "Notes on the Use of the Null Detector" at Section 1.2.3.1.

1.4.1.3 Identification of Access Holes (Fig. 1.5)

- a) Release 6 screws retaining the top cover
- b) Lift the top cover at the front of the instrument and locate two holes giving access to the two-position "pre-cal Enable" switch and the press-button "Clear Calibration Memory" switch.

DO NOT OPERATE EITHER SWITCH YET

c) Replace the top cover, do not secure



1.4.1.4 Preparation

Before any calibration is carried out, prepare the 4000 as follows:

- 1. Turn on the instrument to be checked and allow minimum of 4 hours to warm-up in the specified environment
- L.O. 2. IEEE 488 Address switch: Set to ADD 11111 as shown (Address 31) ADD . 54321
- 3. CALIBRATION ENABLE key switch: Insert Calibration Key and turn to ENABLE.



1.4.1.5 Interconnections

CAUTION: First read the Notes on the use of the Null Detector in Section 1.2.3.1.

- (a) Ensure that the 4000 OUTPUT OFF LED
- (b) Select DC and connect the DC Voltage Calibration source, Precision Divider and Null Detector to the 4000 terminals as shown. Use short leads.

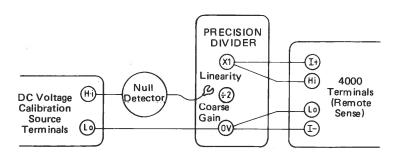


Fig. 1.6 Interconnections for Pre-calibration (Coarse Gain and Linearity)

(c) Ensure that the calibration source voltage is set to zero and that the interconnecting circuit has thermally stabilized. Do not connect the Null Detector yet.

1.4.1.6 "Pre-cal Enable" and Calibration Memory "Clear" Switches

(a) 4000 Lift the top cover at the front. Locate the hole which gives access to the pre-cal enable switch.

(b) "Enable" Insert an insulated tool in the hole and move the precal switch to the right (Enable).

> The legend Cal appears on the OUTPUT display also.

(c) Locate the hole which gives access to the Calibration Memory "Clear" button.

> Insert an insulated tool in the hole and press the button to clear the calibration memory. Refit the top cover but do not secure.

1.4.1.7 ±0

(d) "Clear"

(a) Null Detector Set to Low sensitivity.

(b) 4000 Ensure OUTPUT OFF in 10V DC range. Ensure Remote Sense LED is unlit.

Press OUTPUT Zero Key (c) 4000 Connect the Null Detector between Hi and Lo terminals Press ON+ Kev

> Press ±0 Key: ±0 LED lights, OUTPUT display at zero.

(d) Null Detector Increase sensitivity to give an off-null reading (approx. -20mV) and use 4000 OUT-PUT ↑/↓ keys to back-off to null. Repeat until null lies between two values of the output display least-signifi-

cant digit.

(e) 4000 Press CAL key: CAL LED lights

No change to OUTPUT

display

(f) 4000 Press ON- key

(g) Null Detector Obtain accurate null as in (d) above.

(h) 4000 Press CAL key:

> CAL LED goes OFF ±0 LED goes OFF OUTPUT display falls to

(i) Null Detector Set to Low sensitivity

The 4000 positive and negative zeros are now both aligned to zero.

> (k) 4000 Disconnect the Null Detector

1.4.1.8 Coarse Gain (a) Null Detector Set to Low sensitivity (b) 4000 **Ensure OUTPUT OFF** (c) 4000 Select Remote Sense and (h) Null Detector Increase sensitivity to give ensure LED is lit an off-null reading and use 4000 ↑/↓ keys to back-off (d) 4000 Press the SET Key: to null. Repeat until null SET LED lights green lies between two values of **OUTPUT** display reading the OUTPUT display leastgoes to zero. significant digit. (e) 4000 Use OUTPUT ↑/\$ keys to (j) 4000 Press CAL Key: set the OUTPUT display to CAL LED flashes once. +19.999,999V **OUTPUT** display changes (f) 4000 Press the ON+ Key to +19.999,999V. (g) Null Detector Connect between Calibra-SET LED goes OFF tion Source Hi and Precision (k) Null Detector Set to Low Sensitivity. Divider ÷2 terminal (Fig. (1) 4000 Set OUTPUT OFF 1.6) 1.4.1.9 Linearity

(a) Null Detector	Disconnect from Precision Divider	(g)	Null Detector	Increase sensitivity to give
(b) 4000	Ensure set to OUTPUT OFF Select Remote Sense and ensure LED is lit.	197	Null Beteetor	an off-null reading and use 4000 ↑/↓ keys to back-off to null. Repeat until null
(c) 4000	Press the STD Key: STD LED lights green OUTPUT display reading			lies between two values of the OUTPUT display least- significant digit.
	goes to zero.	(h)	4000	Press CAL Key:
(d) 4000	Use OUTPUT \uparrow/\downarrow keys to set the OUTPUT display to $+10.000,000V$			CAL LED flashes once OUTPUT display changes to +10.000,000V
(e) 4000	Press the ON+ Key			STD LED goes OFF.
(f) Null Detector	Connect between Calibra- tion Source Hi and Precision	(j)	Null Detector	Set to Low sensitivity. Disconnect.
	Divider X1 terminal.	(k)	4000	Set OUTPUT OFF.

1.4.1.10 Pre-cal Enable Switch (See CAUTION below)

(a)	4000	Lift the front.				
		Locate thaccess to switch.				,

Insert an insulated tool in the hole and move the pre-cal switch to the left (RUN). The legend "cal" on the OUTPUT display disappears, but the same legend remains on the MODE display.

CAUTION: DO NOT re-press the calibration memory "clear" button. If this is done, the micro-zero, coarse gain and linearity adjustments will have to be repeated.

(b) 4000

Refit and secure the top cover.

1.4.1.11 Routine Calibration

The 4000 is now ready for full Routine Calibration as detailed in Section 1.2.

The Autocal procedure for routine calibration of the 4000 Resistance Function is described in Section 1.2.10.

The method of calibration is to measure the value of each standard resistor, and store the measured value in non-volatile calibration memory. Subsequently, each time a resistance RANGE is selected, the previously calibrated value is displayed.

If a standard resistor has been subjected to undue stress, its value may have moved outside its tolerance (signalled by an Error 6 message during Routine Autocalibration). If the value is less than approx. 50ppm outside tolerance, it can be adjusted internally using a variable trimmer. For values out of tolerance in excess of 50ppm it is likely that the resistor has been over-stressed — consult your Datron Service Centre.

1.5.1 Manual Trimming Procedure

The following procedure is a supplement to Routine Autocalibration. It is necessary only when the 4-wire calibration of Section 1.2.10 has resulted in an "Error 6" message.

It can also be used when, for operational reasons, it is necessary to calibrate a resistor at its nominal value. For this purpose a continuously-reading method of measurement is convenient.

- (a) Release eight screws retaining the top cover.
- (b) Lift the top cover at the front of the instrument and locate the 8 holes giving access for " Ω OPTION ADJUSTMENT"
- (c) Insert an insulated screw driver tool in the hole for the range selected, and adjust the preset resistor (rotating clockwise increases the resistance value)
- (d) Re-measure the 4-wire value and repeat operation (c) until the desired value is obtained
- (e) Re-calibrate the range for 4-wire and 2-wire connections as detailed in section 1.2.10.
- (f) Repeat the manual trimming procedure above for all ranges as required.
- (g) Finally refit and secure the top cover using the eight screws removed in (a), above.

SECTION 2

FAULT DIAGNOSIS

WARNING HAZARDOUS ELECTRICAL POTENTIALS

ARE EXPOSED WHEN THE INSTRUMENT

COVERS ARE REMOVED.

ELECTRIC SHOCK CAN KILL!

CAUTION

The instrument warranty can be invalidated if damage is caused by unauthorised repairs or modifications. Check the warranty detailed in the "Terms and Conditions of Sale". It appears on the invoice for your instrument.

2.1 INTRODUCTION

2.1.1 Use of diagnostic guides

The diagnostic guides given in Section 2.2 are intended to aid the user in locating a failed printed circuit board or other assembly. The self-diagnostic capabilities of the 4000 provide the first step in fault analysis by displaying a FAIL message on the mode display. Initial actions to be taken after the occurrence of a FAIL message are given, where applicable, in the diagnostic guides (section 2.2). The FAIL message localizes the failure into a distinct functional area and the "Fault Condition" summary in each guide relates the function failure into a probable hardware boundary. The identities of the assemblies involved in the failure are given beneath the fault condition summary, but it is unlikely that all assemblies listed will prove to be faulty.

For successful failure analysis, it is advisable to be familiar with the electronic functioning of the instrument and with the physical location of the assemblies. To assist in these aspects,, the diagnostic guides include references to relevant parts of this publication.

2.1.2.2. FAIL 5 as default state

Faults which result in display messages FAIL 2, 3 or 4 can pose a safety hazard to the operator, and apply excessive voltage to external circuitry. To protect against this, the instrument is programmed to default to FAIL 5 state as rapidly as possible after its initial response to the failure symptoms. The CPU switches Output OFF, trips the safety monitor (Watchdog) and changes the display to FAIL 5.

In normal use, an operator will probably notice only FAIL 5, and miss the original failure message. In FAIL 5 state, front panel control is inhibited until Safety Reset is pressed. This returns the instrument to the state for which the original fault conditions and failure message were produced, but with Output OFF.

2.1.2 Effects of protective measures on diagnosis

2.1.2.1 Protective suppression of fault conditions

The 4000 incorporates built-in protection in hard-ware and software. To minimise damage, protective circuitry acts immediately, backed up by a pre-programmed CPU response to detected failure symptoms. The CPU informs the user by presenting a failure message on the MODE display.

When investigating a failure, it should therefore be anticipated that protective measures will have suppressed the original fault conditions. A useful starting-point is to identify the origin of the failure message to localise the area of search.

2.1.2.3 To observe the original failure message

Two procedures can be used:

- (a) Carry out the self-test routine (section 2.3) The failure message may recur during this test.
- (b) Reset the instrument to reproduce the fault, carefully watching the MODE display. The original failure message should reappear momentarily, prior to defaulting into FAIL 5.

Then select the appropriate diagnostic guide in section 2.2.

2.2 DIAGNOSTIC GUIDES

2.2.1 FAIL 1 display message

DISPLAY: FAIL 1

Excessive internal temperature

INITIAL ACTION

- 1. Switch Power OFF
- 2. Allow to cool for 15 minutes
- 3. Switch Power ON If FAIL 1 persists, repeat 1 & 2
- 4. Select operating mode when FAIL 1 clears
- No failure display no further action
 FAIL 1 recurs fault persists

FAULT CONDITION

High temperature sensed in:

- 1. Positive Heatsink Assembly
- or 2. Negative Heatsink Assembly

Fault indication signal TEMP ST active

POSSIBLE FAULT LOCATION

1.	Positive Heatsink Assembly	400454
2.	Negative Heatsink Assembly	400461
3.	Power Amplifier (dc) Assembly	400449

FURTHER INFORMATION IN THIS HANDBOOK

Circuit diagram number: 430449 Layout drawing numbers: 400449 400454

400461

Technical descriptions: Section 4.8

2,2,2 FAIL 2 display message

DISPLAY: FAIL 2

Over-voltage

INITIAL ACTION

- NB. This failure can be caused by injection of an external voltage exceeding 130V across the 4000 terminals.
- Ensure that OUTPUT is OFF (4000 should have tripped to FAIL 5).
- 2. Disconnect external leads from 4000 terminals.
- 3. Press Safety Reset.
- 4. Carry out self-test sequence.
- 5. FAIL 2 recurs fault persists.
- No failure display Reproduce original conditions in Local Sense with no external connections.
- 7. No failure display check external circuit and proceed with careful use.
- 8. FAIL 2 recurs fault persists.

FAULT CONDITION

- Over voltage circuit on DC pcb has detected a voltage in excess of 130V between PHi and PLo lines, and has activated HV ST signal to the CPU. AND
- The CPU has recognised that the instrument is not in High Voltage State, so has generated FAIL 2 display. THEN
- The CPU has switched output OFF, tripped the watchdog and generated FAIL 5 display.

POSSIBLE FAULT LOCATION

- 1. Injection of external voltage
- 2. DC pcb assembly

400445

3. Power Amplifier (dc) pcb assembly

400449

FURTHER INFORMATION IN THIS HANDBOOK

Circuit diagram numbers: 430449, 430445 Layout drawing numbers: 400449, 400445

Self-test procedure: Section 2.3 Technical descriptions: Section 4.7, 4.8

2.2.3 FAIL 3 display message

DISPLAY: FAIL 3

Control data corrupted

INITIAL ACTION

No immediate action required

FAULT CONDITION

- 1. Control data corrupted
- CPU has detected errors in serial transfer of data between out-guard and in-guard circuits, and generated FAIL 3 display. THEN
- 3. The CPU has switched Output OFF, tripped the watchdog and generated FAIL 5 display.

POSSIBLE FAULT LOCATION

- 1. Reference Divider PCB Assembly
- 400444
- 2. Analogue Interface PCB Assembly

400443

FURTHER INFORMATION IN THIS HANDBOOK

Circuit diagram numbers: 430443; 430444 Layout drawing numbers: 400443; 400444

Technical descriptions: Section 4.5

2.2.4 FAIL 4 display message

DISPLAY:

FAIL 4

Precision divider fault

INITIAL ACTION

No immediate action required

FAULT CONDITION

- 1. Precision divider fault
- CPU has detected errors in the most-significant data bits set in the precision divider input data latches, and generated FAIL 4 display. THEN
- The CPU has switched Output OFF, tripped the watchdog and generated FAIL 5 display.

POSSIBLE FAULT LOCATION

Analogue Interface PCB Assembly 400443

FURTHER INFORMATION IN THIS HANDBOOK

Circuit diagram number: 430443 Layout drawing number: 400443 Technical description: Section 4.6

2.2,5 FAIL 5 display message

DISPLAY: FAIL 5

Safety Monitor (Watchdog) tripped

INITIAL ACTION

Use the checking sequence below, watching the MODE display carefully at each stage to detect any FAIL number appearing momentarily before FAIL 5. If no failure message occurs, carry on to the next stage.

Stage 1: Press Safety Reset

Stage 2: Carry out Self-test sequence (Section 2.3)

Stage 3: Set Output ON

Stage 4: Proceed with careful use.

If FAIL 2 occurs at stage 3, ensure that it is not due to injection of an external voltage in excess of 130V by disconnecting the 4000 terminals and repeating the checks. If FAIL 5 alone occurs, proceed to "Fault Condition" below. For any FAIL other than FAIL 5, transfer to the diagnostic guide for that message.

FAULT CONDITION

18mS monostable (M10 in reference divider) has been deprived of at least two trigger pulses and has timed out, activating "BARK" and "BARK DELAYED" (BARK + 47mS) signals from M13 in the reference divider pcb.

Summary of "BARK" effects:

- 1. 16KHz drive to PA is inhibited
- PA output disconnected from HV transformer
- 3. HV transformer primaries shorted
- 4. Standard resistors in I/Ω pcb isolated
- 5. Current output OFF 100μA range selected
- 6. BARK status message sent to CPU
- 7. CPU starts controlled shut-down

Summary of "BARK DELAYED" effects:

- 1. DC pcb RL 13 and 14 de-energised (Output OFF)
- Outputs from control latches in reference divider pcb are disabled by setting into "Tristate". Each output line has a pull-up or pull-down resistor which sets the analogue circuitry into a safe condition.

POSSIBLE FAULT LOCATION

Digital PCB Assembly (No gated WRT STRB pulses at J2/J3—29)	400442
Analog Interface PCB Assembly (No SSDA strobe pulses; or Watchdog disabled)	400443
Reference Divider PCB Assembly (Incorrect functioning of Watchdog	
setup circuitry)	400444

NB The Watchdog is designed primarily to ensure that CPU malfunctions do not set up dangerous conditions in the analogue circuitry.

FURTHER INFORMATION IN THIS HANDBOOK

Circuit diagram numbers:	430442
	430443
	430444
Layout drawing numbers:	400442
,	400443
	400444
Technical description: Section 4.5	

2.2.6 FAIL 6 display message

DISPLAY: FAIL 6

Calibration memory fault

INITIAL ACTION

- 1. Select Output OFF, Spec OFF, Error OFF
- 2. Perform self-test sequence (Section 2.3)
- 3. No failure display no further action
- 4. FAIL 6 recurs recalibration required
- 5. Select Cal.
- 6. Recalibrate

Refer to Section 1

7. Calibration failure – fault persists

FAULT CONDITION

Calibration memory fault on Digital pcb assembly

POSSIBLE FAULT LOCATION Digital PCB Assembly 400442

FURTHER INFORMATION IN THIS HANDBOOK

Circuit diagram number: 430442 Layout drawing number: 400442 Self-test procedures: Section 2.3 Calibration procedures: Section 1 Technical descriptions: Section 4.2

2.2.7 FAIL 7 display message

DISPLAY: FAIL 7

P.A. 15V/50V power failure or 50V Regulator over temperature

INITIAL ACTION

- 1. Switch power OFF
- 2. Allow to cool for 15 minutes
- Check line supply is correct for input voltage setting
- Switch power on If FAIL 7 persists, repeat 1 & 2
- 5. Select operating mode when FAIL 7 clears
- 6. No failure display no further action
- 7. FAIL 1 recurs fault persists

FAULT CONDITION

- 1. ± 15V common 2 power supply failure;
- 2. ± 50V power supply failure;
- 3. Power Supply/I Heatsink overtemperature;
- 4. Fault indication signals PS ST or DC ST active;
- 5. Line input voltage too high?

POSSIBLE FAULT LOCATIONS

- 1. Power Amplifier (dc) PCB Assembly 400449
- 2. In-guard power supply PCB assembly 400451
- 3. Power Supply/I Heatsink Assembly 400455
- . Interconnection PCB Assembly 400439

FURTHER INFORMATION IN THIS HANDBOOK

Circuit diagram numbers: 430439; 430449; 430451;

430455 Layout drawing numbers: 400439; 400449; 400451;

Layout drawing numbers: 400439; 400449; 400451; 400455

Technical descriptions: Section 4.8

2.2.8 Error OL display message

DISPLAY: ERROR OL

DC Volts: Output current limited at 25mA

: Output voltage compliance limited at 3V

INITIAL ACTION

- If DC Voltage range selected:
 - Set Output OFF (Automatic if 100 or 1000V range selected)
 - Disconnect external circuit (b)
 - (c) Set Ouput ON - If no Error OL or FAIL message. check external circuit for low resistance, drawing output current in excess of 25mA limit.
 - If Error OL recurs, internal fault persists.
- 2. If I range selected:
 - Set Output OFF (a)
 - (b) Short Output terminals I+ to I-
 - Set Output ON (c) - If no Error OL or FAIL message, check external circuit for high resistance. developing output voltage in excess of 3V compliance limit

- If Error OL recurs, internal fault persists

FAULT CONDITION

- If Low DC Voltage range ($100\mu V 10V$): Overcurrent sense circuit (M9/M8 in DC pcb) has detected a current in the I- line of approx 28mA or more, and has activated LIM ST 1 signal to the CPU.
- 2. If High Voltage range (100V or 1000V): Either (a) Opto-isolator detector (M11 in the Power Amp (DC) pcb) has detected a current in the I+ line of approx 35mA or more,

(b) Over Voltage detector (M9 in the or Power Amp (DC) pcb) has detected an output voltage in excess of 1440V.

In either condition (a) or (b), M10 in the power amplifier removes the 16KHz drive from the input to the PA, and generates HIIST signal to the CPU; which responds by setting Output OFF, and DC Reference voltage to zero.

3. If I range selected:

Overvoltage detector circuit (M15 in I/Ω pcb) has detected a terminal voltage of 4.4V or more and has activated LIM ST1 signal to the CPU. If 100mA or 1A range selected, the CPU switches Output OFF and reduces DC Reference voltage to zero

POSSIBLE FAULT LOCATIONS

1.	External circuit	
2.	DC PCB Assembly	400445
3.	Power Amp (DC) Assembly	400449
4.	I/Ω PCB Assembly	400448

FURTHER INFORMATION IN THIS HANDBOOK

1.	Circuit diagram numbers:	430445 430449 430448
2.	Layout drawing numbers:	400445
		400449
		400448

Technical descriptions:

Low DC Voltage ranges: Section 4.7 100 or 1000V ranges: Section 4.8

I ranges: Section 4.9

2.3 SELF-TEST SEQUENCE

2.3.1 General

The self-test sequence is performed in two stages:

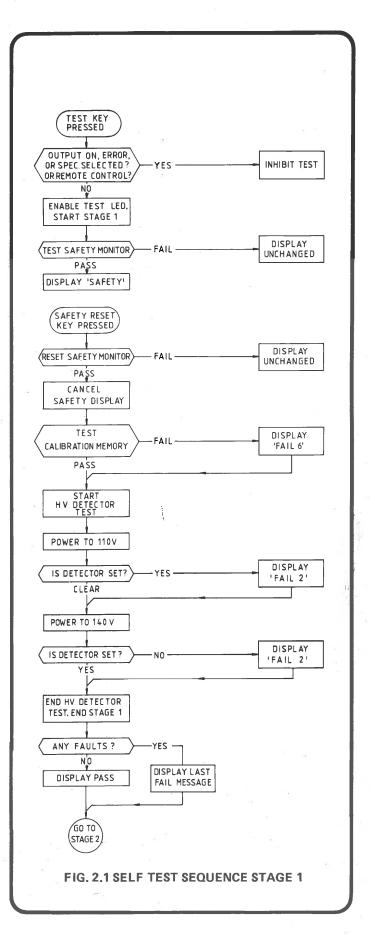
Stage 1 is a fully automated test of safety monitoring and high-voltage safety interlocks;

Stage 2 is a semi-automatic test of keyboard and display functions and requires operator-involvement.

2.3.2 Stage 1 (Fig. 2.1)

Entry into Stage 1 is selected automatically whenever the TEST key is pressed for the first time (the test is not allowed if OUTPUT ON, ERROR or SPEC are selected or when in remote control). Indication of test mode is given by the LED in the TEST key being lit. The full sequence of Stage 1 must be completed before exit from the test mode can be made. The tests performed in Stage 1 are as follows:

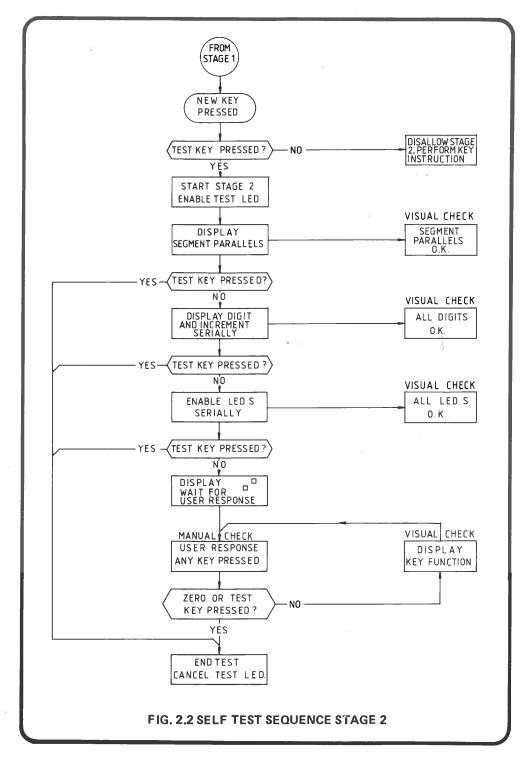
- Safety Monitor Watchdog Test. In this, the safety monitor is tripped causing the word SAFETY to appear in the Mode display. It is necessary for the operator to reset the safety monitor by pressing the SAFETY RESET key, after which, the SAFETY display is cancelled and the test sequence continues.
- Calibration Memory Test. The contents of the nonvolatile calibration RAM are checked for validity. Failure results in the message FAIL 6 appearing on the Mode display.
- High-voltage Protection. This test ensures that a voltage demand made to the power amplifier does not trip the software voltage detector when immediately below the detector threshold level, but when raised to a level above the detector threshold the detector is tripped. Incorrect detect action is shown by the message FAIL 2 on the Mode display. No voltages appear at the output terminals during this test. Fail messages are updated as the test sequence progresses through the calibration memory and high-voltage tests. After completion of the high-voltage test, the test mode ends and the test LED is cancelled. If faults were encountered the last FAIL message will remain on the display. Fault diagnosis can now be performed. If no faults are encountered during Stage 1, the message PASS is displayed. The calibrator may now be returned to normal operation, or Stage 2 of the self-test sequence can be selected.



2.3.3. Stage 2 (Fig. 2.2)

Entry into Stage 2 of the self-test sequence is made when the TEST key is pressed AFTER the completion of Stage 1. The test proceeds by sequentially displaying all segments and legends. The test continues, showing segment-by-segment, all seven-segment digits, legends and commas. After all digits have been displayed, the keyboard LED indicators are lit in a sequence which proceeds from left to right. (TEST LED remains lit).

The next test in the sequence requires operator participation in order to check key functions. Two half-digit symbols are shown on the mode display to indicate that the keys are ready to be checked. Operation of Up, Down and Output Selection keys are shown by a symbol on the display immediately above the key; operation of Mode, Range, Function and Output keys are shown by the key's LED. In these tests the display or LED remains lit until another key is pressed. At any part of Stage 2, pressing TEST or ZERO key will end the test and cancel the TEST LED.



2.4 Fuse Protection

In addition to the electronic protection devices used in the 4000, fuses are provided to protect against catastrophic component failure.

2.4.1 Fuse Replacement

A blown fuse is merely a symptom of failure, in the large majority of cases the cause lies elsewhere.

CAUTION Every occurrence of a blown fuse should be investigated to find the cause. Only when satisfied that the cause is known, and has been removed, should a user replace a fused link by a serviceable item.

2.4.2 Reasons for fusing

The fuses in the 4000 fall into two main groups:

- Clip-in anti-surge fuses in the Power Supplies and Power Amplifier protect the power source from extreme loading.
- (ii) Solder-in fuses on the DC and I/Ω assemblies protect the low voltage, current and resistance circuits from the application of high voltages in the event of relay failure.

Table 2.1 lists their locations.

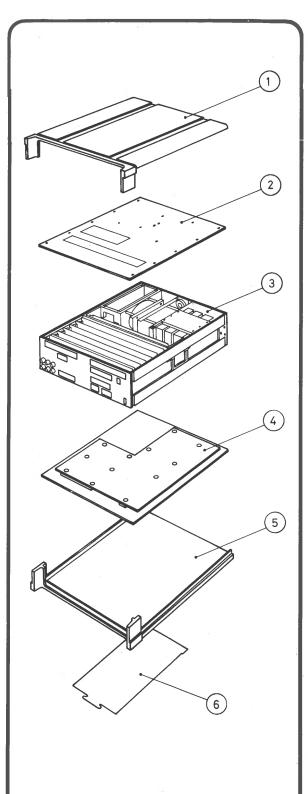
2.4.3 Locating a Blown Fuse

The ultimate causes of blown fuses are so extensive that it is impractical to list them. In many cases the underlying cause, or the blown fuse itself, will activate an electronic protective process which can conceal some of the symptoms.

Fault location in the 4000 should proceed from the primary indications of fault condition (eg failure messages described in section 2.2). These will lead to particular areas of investigation, and at this point the relevant circuit fuses should be checked first. Whether fuses are blown or not, the checks will add to the information available for further diagnosis. Table 2.1 is indexed in PCB Circuit Diagram number order, giving fuse values. The types of fuses to be used can be found in the component lists of Section 6.

Location and Circuit Diagram	Designator/Value	Protected Circuits (Power Input fuse)		
Power Input Module 430439	F1 (3A/230V) (6.25A/115V)			
DC PCB 430445 Sheet 1 Sheet 1	F1 1A F2 1A	Error Amp and 1V Buffer Sense Inputs (10V and 1V Buffer outputs (1V and 100mV Attenuators		
Sheet 1 Sheet 3	F3 1A F4 1A)	100mV Attenuator		
Sheet 3 Sheet 3	F5 1A) F6 1A)	DC Voltage Circuitry (from excess external voltages)		
I/Ω PCB 430448 Sheet 1 Sheet 3 Sheet 3 Sheet 3 Sheet 1	F1 375mA F2 375mA) F4 375mA) F3 1A F5 2.5A	Not used unless Ext I Option fitted. Standard resistors (I+ and I- terminal lines) Standard resistors (Hi terminal line) Current Source (I+ terminal line)		
Power Amp (dc) PCB 430449 Sheet 2 Sheet 2 Sheet 1	F1 4A) F2 4A) F3 4A	Line transformer (50V Secondaries) Power Amp. Output Stages		
Power Supply (In Guard) PCB 430451 Sheet 1 Sheet 1	F1 4A) F2 4A)	Current Option Supply diode bridge and Line transformer secondaries.		
Sheet 1 Sheet 1	F3 2A) F4 2A)	Common - 2 Supply diode bridge and Line transformer secondaries.		
Power Supply (Out Guard) PCB 430470 Sheet 1	F1 4A	Main Digital Supply Full-wave rectifier and Transformer Secondary.		

Table 2.1 Fuse Locations and Purpose



- 1. TOP COVER
- 2. TOP GROUND/GUARD ASSEMBLY
- 3. CHASSIS ASSEMBLY
- 4. BOTTOM GROUND/GUARD ASSEMBLY
- BOTTOM COVER
- 6. INSTRUCTION CARD

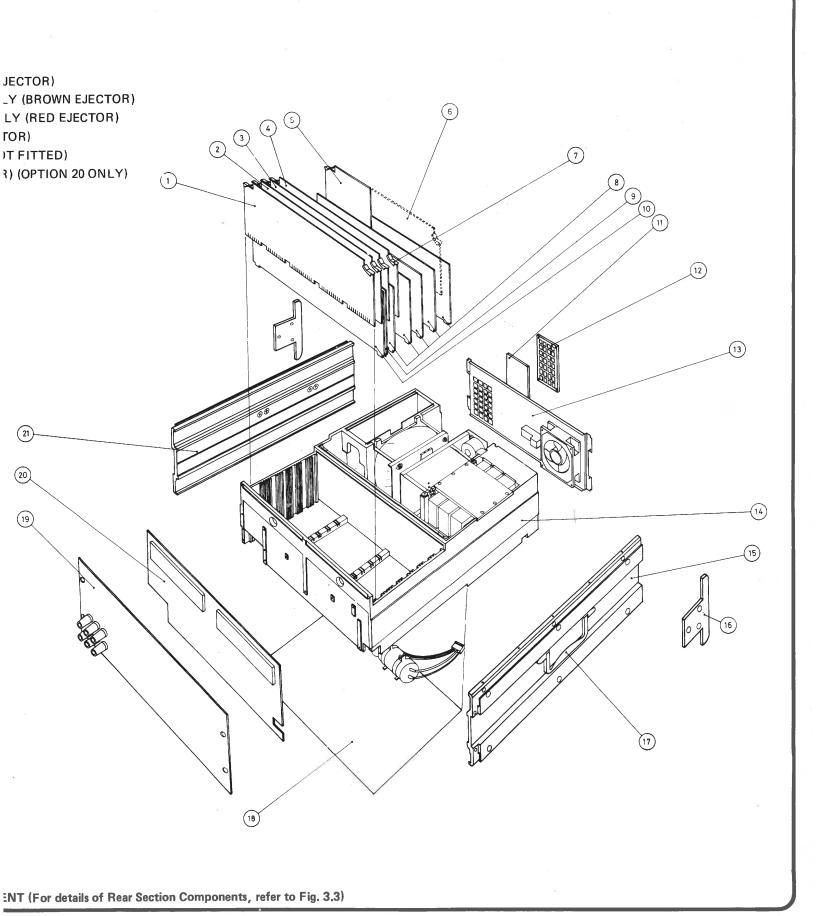
FIG. 3.1 OPEN VIEW OF INSTRUMENT

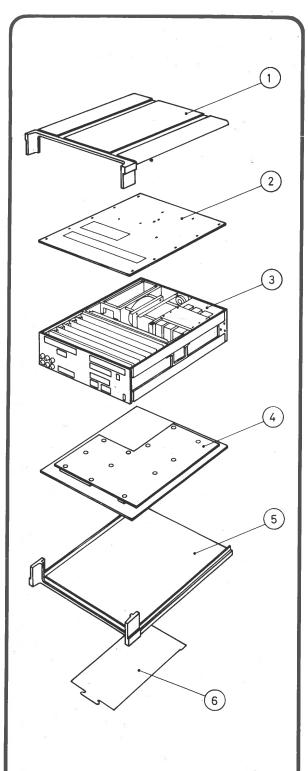
- 1. DIGITAL PCB ASSEMBLY (BLACK EJECTOR)
- 2. ANALOG INTERFACE PCB ASSEMBLY (BROWN E
- 3. REFERENCE DIVIDER PCB ASSEMBLY (RED EJE
- 4. DC PCB ASSEMBLY (ORANGE EJECTOR)
- 5. I/Ω LINK PCB (WHEN OPTION 20 NOT FITTED)
- 6. I/Ω PCB ASSEMBLY (BLUE EJECTOR) (OPTION 2
- 7. PCB EJECTOR
- 8. COMMON 2 SCREEN
- 9. GUARD SHIELD
- 10. GROUND SHIELD
- 11. FILTER
- 12. FILTER GRILLE
- 13. REAR PANEL ASSEMBLY
- 14. CHASSIS ASSEMBLY
- 15. RH EXTRUSION
- 16. REAR SPACER
- 17. HANDLE
- 18. MOTHER PCB ASSEMBLY
- 19. FRONT PANEL ASSEMBLY
- 20. FRONT PCB ASSEMBLY
- 21. LH EXTRUSION





FIG. 3.2 EXPLODED VIEW OF INSTRUMENT (For detail





- 1. TOP COVER
- 2. TOP GROUND/GUARD ASSEMBLY
- 3. CHASSIS ASSEMBLY
- 4. BOTTOM GROUND/GUARD ASSEMBLY
- 5. BOTTOM COVER
- 6. INSTRUCTION CARD

FIG. 3.1 OPEN VIEW OF INSTRUMENT

- 1. DIGITAL PCB ASSEMBLY (BLACK EJECTOR)
- 2. ANALOG INTERFACE PCB ASSEMBLY (BROWN EJE
- 3. REFERENCE DIVIDER PCB ASSEMBLY (RED EJECT
- 4. DC PCB ASSEMBLY (ORANGE EJECTOR)
- 5. I/Ω LINK PCB (WHEN OPTION 20 NOT FITTED)
- 6. I/Ω PCB ASSEMBLY (BLUE EJECTOR) (OPTION 20 O
- 7. PCB EJECTOR
- 8. COMMON 2 SCREEN
- 9. GUARD SHIELD
- 10. GROUND SHIELD
- 11. FILTER
- 12. FILTER GRILLE
- 13. REAR PANEL ASSEMBLY
- 14. CHASSIS ASSEMBLY
- 15. RH EXTRUSION
- 16. REAR SPACER
- 17. HANDLE
- 18. MOTHER PCB ASSEMBLY
- 19. FRONT PANEL ASSEMBLY
- 20. FRONT PCB ASSEMBLY
- 21. LH EXTRUSION



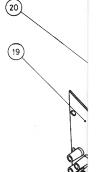
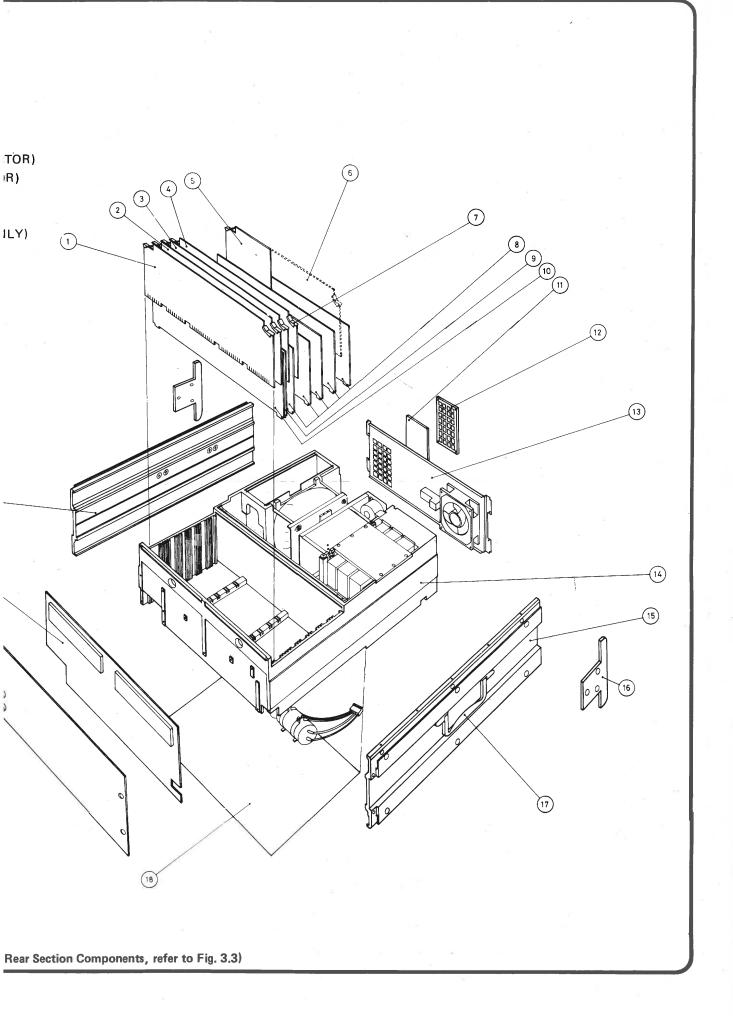


FIG. 3.2 EXPLODED VIEW OF INSTRUMENT (For details of



SECTION 3

DISMANTLING AND REASSEMBLY

WARNING

- 1) ISOLATE FROM POWER SUPPLIES BEFORE DISMANTLING AND REASSEMBLING.
- 2) REMOVING TOP AND BOTTOM COVERS AND GROUND/GUARD ASSEMBLIES AND THE REAR PANEL ASSEMBLY LEAVES THE MOULDED INTERNAL CHASSIS UNSUPPORTED. THIS CAN CONSTITUTE A SAFETY HAZARD TO BOTH PERSONNEL AND EQUIPMENT.

CAUTION

- Do not touch the pcb edge connectors with the hands.
- Ensure no wires are trapped when fitting ground/ guard assemblies.

3.1 GENERAL MECHANICAL DESCRIPTION

The 4000 AUTOCAL STANDARD can be used as a bench-top instrument or may be rack mounted in a standard 19" rack. All circuits are housed within a single unit on printed circuit boards, the seven major pcb's being plugged into a "mother" pcb. An open view of the instrument is shown in Fig. 3.1; exploded views are shown in Fig. 3.2 and Fig. 3.3.

3.1.1 Front Panel

Six output terminals with captive, insulated caps are provided; this facility can be fitted to the rear panel at manufacture (Option 41). A printed overlay on the front panel labels all the controls, and retains polarizing filters for the displays.

3.1.2 Rear Panel

The recessed Power Input plug, Power Fuses and Line Voltage Selector are contained in an integral filtered module at the centre of the rear panel.

The Calibration Enable switch (with removable key), and the External reset socket (J53) are mounted directly on the panel between the Power Input module and the cooling-air intake filter. The filter is retained by a grille but is removable for cleaning. At the extreme left of the panel an extractor fan draws the cooling air through the intake filter and internal heat exchangers, finally discharging to atmosphere.

The IEEE488 standard connector socket (J27) and instrument address switch, the Calibration Interval Switch and switch S53 (not used on the 4000); are all mounted on an interconnection pcb assembly. This is fitted on spacers to the inside face of the panel with external components protruding to the rear.

3.1.3 External Construction

Rigid side extrusions together with the front and rear panel assemblies form the basic chassis of the instrument. The side extrusions have handles and rear spacers fitted for bench-top use or are fitted with 'ears' and slides for rack mounting (see User's Handbook, Section 2). The top cover locates into the side extrusions and is secured by screws. The bottom cover is attached in the same way, and includes six domed feet. An operator's instruction card pulls forward from below.

3.1.4 Internal Construction

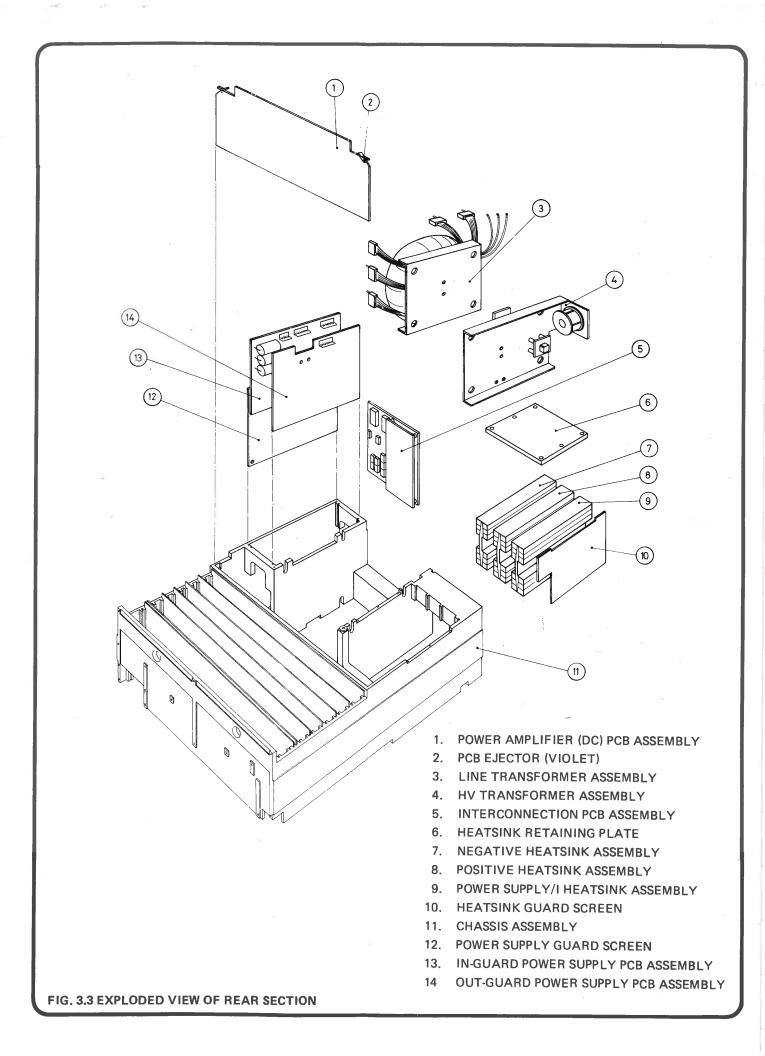
The chassis is enclosed top and bottom by ground and guard assemblies. The upper ground and guard screens allow internal adjustments to be performed without removal. Locations of adjustable components, instructions and warnings are printed on the outer surface.

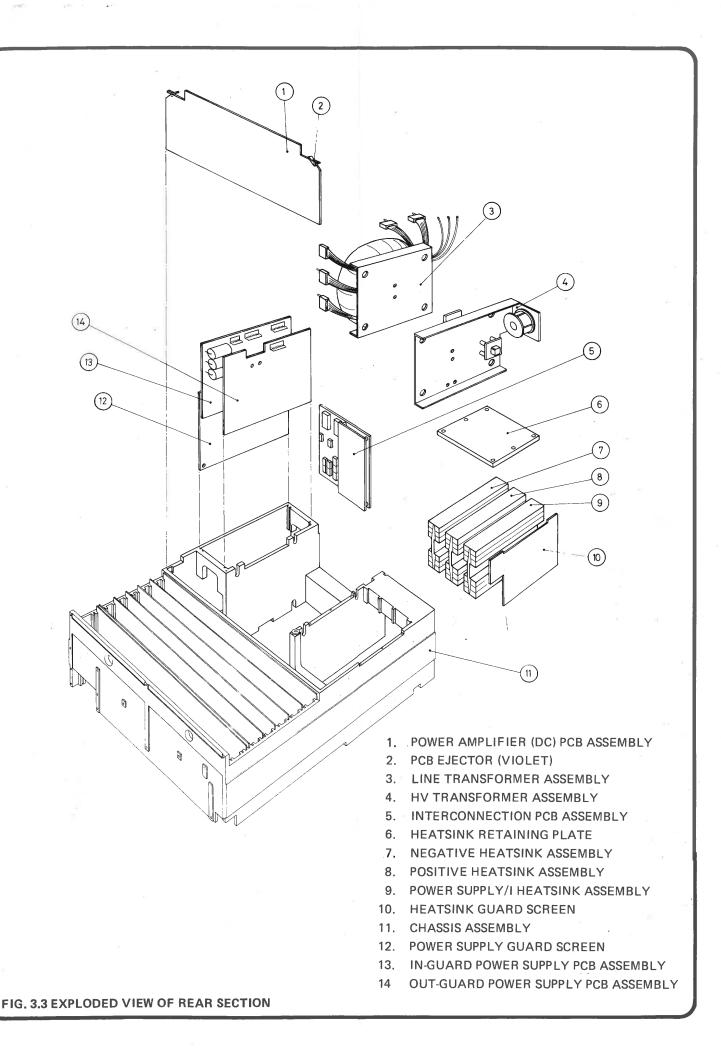
The interior of the chassis is thermally divided into two compartments. One compartment occupies the forward half of the chassis and is used to house the low power, precision printed circuit boards (pcb's). The rear compartment contains high power components and is air cooled.

The rear compartment is further sub-divided: one houses two power supply pcb's and provides anchorage for the line transformer assembly, these are positioned across the grille of the air intake filter; the other houses three heatsink assemblies, provides anchorage for the HV transformer assembly and ducts the cooling air into the extractor fan. Filtered air is drawn over the power supplies and line transformer, over the power amplifier pcb (which is situated at the front wall of the rear compartment) and through the heatsink assemblies, to be expelled from the instrument by the extractor fan. Guard screens are provided against the outer walls of the power supply sub-compartment and the heatsink compartment.

Interconnections between the power amplifier, all forward compartment printed circuit boards and the front pcb assembly are made via a mother pcb. The latter is fitted across the bottom of the forward compartment and out to the front pcb. Four moulded stiffeners keep the mother pcb rigid and provide lateral locating slots for the front compartment printed circuit boards and guard screens. The main printed circuit boards in the forward compartment, the guard screens and the power amplifier pcb fit across the full width of the instrument chassis and slide into vertical slots cut into the moulded chassis. Each pcb edge-connector make electrical contacts with sockets on the mother pcb. The power amplifier also has discrete connectors for high power lines. The front pcb, which carries the display components, connects into the front end of the mother pcb outside the thermally-insulated compartment.

Each printed circuit board has a unique edge connector configuration which prevents incorrect fitting. The printed circuit boards are identified by colour coding of the circuit board ejector levers as shown in Fig. 3.2 and Fig. 3.3.





TOP COVER (FIG. 3.1)

3,2,1 Removal

- a. Remove the eight M4 x 12mm Socket head countersunk screws from cover.
- b. Remove cover by lifting at the front.

3.2.2 Fitting

Reverse procedure of para 3.2.1 (locate cover at rear first, then lower the front).

a. Pull the instruction card forward to its fullest

3.3 BOTTOM COVER (FIG. 3.1)

3.3.1 Removal

- a. Invert the instrument.
- b. Remove the eight M4 x 12mm Socket head countersunk screws from cover,
- c. Remover cover by lifting at the front.

3.3.2 Fitting

Reverse procedure of para 3.3.1 (locate cover at rear first, then lower the front)

3.3.3. Replacing Instruction Card

- extent.
- b. Bow the card and release the rear lugs from the slots.
- c. Refit in reverse procedure.

3.4 TOP GROUND/GUARD ASSEMBLY (FIG. 3.1)

3.4.1 Removal

- a. Remove top cover (para. 3.2.1).
- b. Refer to Fig. 3.4 and remove:
 - 1) from position 'a', ten M4 x 8mm pozicountersunk screws;
 - from position 'b', six M3 x 6mm pozi-pan screw and M3 shakeproof washers;
 - from position 'c', one M3 x 12mm pozipan screw and M3 shakeproof washer.
- c. Remove top ground/guard assembly.

3.4.2 Fitting

Reverse procedure of para, 3.4.1.

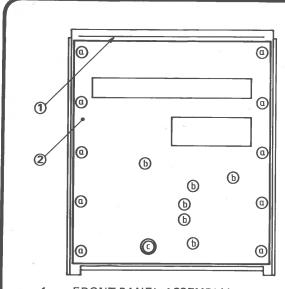
3.5 BOTTOM GROUND/GUARD ASSEMBLY (FIG. 3.1)

3.5.1 Removal

- a. Remove bottom cover (para. 3.3.1).
- b. Refer to Fig. 3.5 and remove:
 - 1) from positions 'a', ten M4 x 8mm pozi-countersunk screws;
 - 2) from positions 'b', four M3 x 6mm pozipan screws and M3 shakeproof washers;
 - 3) from position 'c', one M3 x 12mm pozi-pan screw and M3 shakeproof washer.
- c. Remove bottom ground/guard assembly.

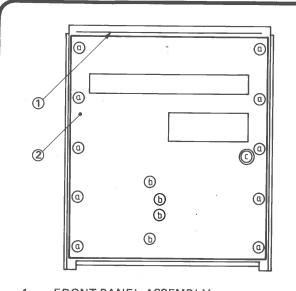
3.5.2 Fitting

Reverse procedure of para 3.5.1.



- 1. FRONT PANEL ASSEMBLY
- 2. TOP GROUND/GUARD ASSEMBLY

FIG. 3.4 FITTING TOP GROUND/GUARD



- FRONT PANEL ASSEMBLY 1.
- BOTTOM GROUND/GUARD ASSEMBLY

FIG. 3.5 FITTING BOTTOM GROUND/GUARD

NOTE In the procedures 3.6 to 3.20, numbers in parenthesis indicate the call-out number of the referenced diagram.

N.B. Remove top cover (para 3.2) and top ground/guard assembly (para. 3.4) before performing procedures 3.6 to 3.12.

3.6 PCB ASSEMBLIES (FIG. 3.2)

DIGITAL (1)

DC (4)

ANALOG INTERFACE (2)

 I/Ω LINK (5) (when option 20 not fitted)

REFERENCE DIVIDER (3)

 I/Ω (6) (option 20 only)

3.6.1 Removal

- a. Ensure instrument power is OFF.
- b. Identify the pcb assembly to be removed (see table 3.1).
- c. Place the thumb of each hand under the lip of the two pcb ejectors (7) on the pcb assembly to be removed.
- d. Gently pull the pcb ejectors upwards and outwards to release the pcb edge connectors.

NOTE The I/Ω Link pcb has only one pcb ejector. To remove this pcb, grip the top edge of the pcb and pull gently while moving the pcb ejector lever upwards.

e. Remove the pcb.

3.6,2 Fitting

- a. Ensure instrument power is OFF.
- b. Identify the chassis location of the pcb assembly to be fitted (see table 3.1).

NOTE The single ejector of the I/Ω link pcb locates to the 'BLU' identifier of the chassis.

- c. Ensure the pcb ejectors are in the 'down' position.
- d. Insert the pcb sides into the respective slots in the side walls of the chassis.
- Allow the pcb to slide down to the mother pcb, then press home by gently pushing down on the ejectors.

PCB ASSEMBLY	EJECTOR COLOUR	MAIN CHASSIS PCB IDENTIFIER	COMPONENT SIDE TO FACE:
Digital	black	BLK	rear
Analog Interface	brown	BRN	front
Reference Divider	red	RED	rear
DC	orange	ORG	rear
Not fitted	_	YEL	_
Not fitted	_ a	GRN	, .
I/Ω Link	blue	BLU	_
Ι/Ω	blue	BLU	rear
Power Amplifier	violet	VLT	rear

TABLE 3.1 LOCATION AND ORIENTATION OF PCB ASSEMBLIES

3.7 COMMON-2 SCREENS, GUARD SHIELD AND GROUND SCREEN

NOTE These items are interchangeable, designation is according to location as shown at (8), (9) & (10), Fig. 3.2.

3.7.1 Removal

Grip the plate and slide out from chassis.

3.7.2 Fitting

- NOTE Each plate mates with a miniature connector on the mother pcb adjacent to the side wall of the chassis. Do not touch the connecting edge of the plate.
 - a. Insert the plate into the respective slots in the side walls of the chassis (orientation is not important).
 - b. Allow the plate to slide down to the mother pcb, then gently press home.

3.8 POWER AMPLIFIER (DC) PCB ASSEMBLY (FIG. 3.6)

3.8.1 Removal

CAUTION. Do not pull on the connector wires.

a. Disconnect the six connectors (1), (2), (4), (5), (6) and (7) from the pcb (8).

NOTE Some resistance to movement will be felt from the locking clips of the connector bases.

- Fold back the connectors and wires clear of the pcb (8).
- c. Place the thumb of each hand under the lip of the two pcb ejectors (3).
- d. Gently pull the pcb ejectors upwards and outwards to release the pcb edge connectors.
- e. Remove the pcb.

3.8.2 Fitting

- Ensure all wires and connectors are clear of the pcb area.
- b. Insert the pcb sides into the respective plots in the side walls of the chassis; pcb component side facing the rear of the instrument.
- c. Allow the pcb to slide down to the mother pcb taking care not to trap any wires.
- d. Ensure the pcb ejectors (3) are in the 'down' position then press the pcb home by gently pushing down on the ejectors.
- e. Identify and fit the six connectors (1), (2), (4), (5), (6) and (7) as shown in Fig. 3.6, with reference to the legend.

3.9 IN-GUARD POWER SUPPLY PCB ASSEMBLY (FIG. 3.6)

3.9.1 Removal

CAUTION. Do not pull on the connector wires.

a. Disconnect the three connectors (10), (11) and 13 from the pcb (9).

NOTE. Some resistance to movement will be felt from the locking clips of the connector bases.

- b. Fold back the connectors and wires clear of the pcb (9).
- c. Grip the top edge of the pcb and pull gently from the chassis.
- d. Remove the pcb.

3.9.2 Fitting

- Ensure all wires and connectors are clear of the pcb area.
- Insert the pcb sides into the respective slots in the chassis sub-compartment.
- Allow the pcb to slide down to the miniature connectors on the chassis, taking care not to trap any wires.
- d. Press the pcb home by gently pushing the top edge of the pcb.
- e. Identify and fit the three connectors (10), (11) and (13) as shown in Fig. 3.6, with reference to the legend.

3.10 OUT-GUARD POWER SUPPLY PCB ASSEMBLY (FIG. 3.6)

3.10,1 Removal

CAUTION. Do not pull on the connector wires.

 Disconnect the three connectors (10), (11) and (13) from pcb (9), and connector (17) from pcb (15).

NOTE. Some resistance to movement will be felt from the locking clips of the connector bases.

- Fold back the connectors and wires clear of the pcb (15).
- c. Grip the top edge of the pcb and pull gently from the chassis.

3.10.2 Fitting

- Ensure all wires and connectors are clear of the pcb area.
- b. Insert the pcb sides into the respective slots in the chassis sub-compartment.
- c. Allow the pcb to slide down to the miniature connectors on the chassis, taking care not to trap any wires.
- d. Press the pcb home by gently pushing the top edge of the pcb.
- e. Identify and fit the three connectors (10), (11) and (13) to pcb (9) and connector (17) to pcb (15) as shown in Fig. 3.6, with reference to the legend.

3.11 HEATSINK ASSEMBLIES (FIG. 3.6)

3.11.1 Removal

- a. Remove the six M3 x 12mm pozi-countersunk screws from the heatsink retaining plate (21).
- b. Remove the heatsink retaining plate (21).

NOTE. Although the heatsink assemblies are discrete items, removal is simplified when performed in the following order.

- 1. Negative heatsink assembly (25);
- 2. Positive heatsink assembly (24);
- 3. Power supply/I heatsink assembly (23);

when disconnecting connectors, some resistance to movement will be felt from the locking clips of the connector bases.

CAUTION. Do not pull on the connector wires.

- c. 1) Disconnect connector (6) from the power amplifier (dc) pcb assembly (8).
 - 2) Remove negative heatsink assembly (25).

- d. 1) Disconnect connector (5) from the power amplifier (dc) pcb assembly (8).
 - 2) Remove positive heatsink assembly (24).
- e. 1) Disconnect connector (4) from the power amplifier (dc) pcb assembly (8).
 - Disconnect connector (22) from the mother pcb.
 - 3) Disconnect connector (10) from the in-guard power supply pcb assembly (9).
 - 4) Remove power supply/I heatsink assembly (23).

3.11.2 Fitting

Reverse procedure of para. 3.11.1.

WARNING. Ensure rear panel assembly is fitted before removing top and bottom covers and ground/guard assemblies. Refer to warning 2 at start of Section 3.

3,12 HV TRANSFORMER ASSEMBLY (FIG. 3.6)

N.B. Remove top cover (para. 3.2), top ground/guard assembly (para. 3.4), bottom cover (para. 3.3) and bottom ground/guard assembly (para. 3.5) before performing para. 3.12 and para. 3.13.

3.12.1 Removal

- a. Remove positive heatsink assembly (24) and negative heatsink assembly (25) (see para. 3.11.1).
- b. Disconnect connector (7) from the power amplifier (dc) pcb assembly (8).

- c. Turn the instrument to stand on its right hand side (on R.H. extrusion (15), Fig. 3.2).
- d. Remove the HV transformer assembly (19).

3.12.2 Fitting

Reverse procedure of para. 3.12.1 and refer to Fig. 3.7 for reassembly of items to the M8 transformer bolts

3.13 LINE TRANSFORMER ASSEMBLY (FIG. 3.6)

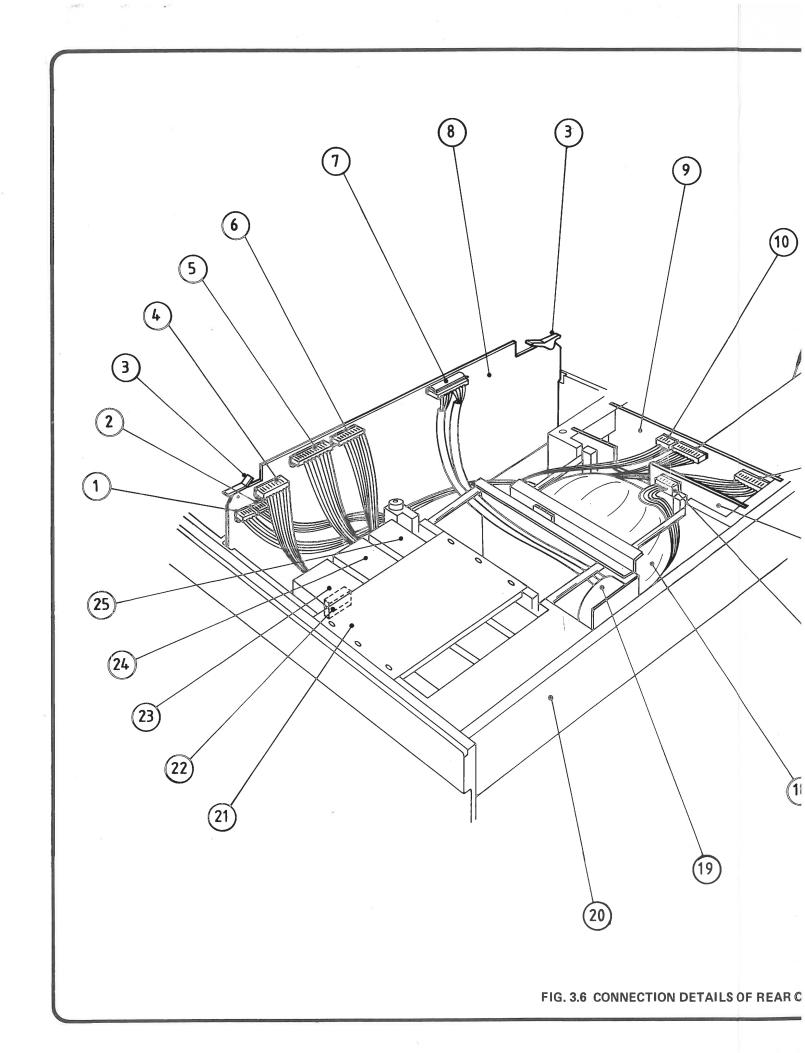
3.13.1 Removal

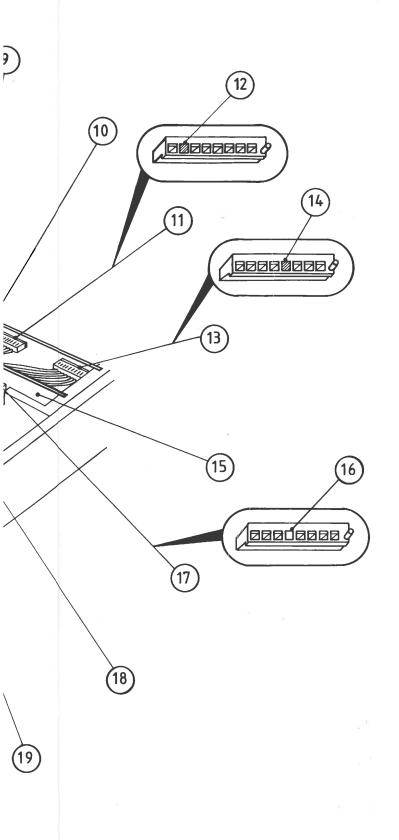
- a. Remove the in guard and out-guard power supply pcb assemblies (9) and (15) (see paras 3.9 and 3.10).
- b. Turn the instrument to stand on its left side (on L.H. extrusion (21), Fig. 3.2).
- c. Disconnect connector (1) from the power amplifier (dc) pcb assembly (8).
- d. Disconnect the line transformer 4-way connector from the interconnection pcb assembly (5), Fig. 3.3) fixed on the rear panel.

- e. Release the four M8 x 110mm bolts, washers and nylock nuts.
- f. Remove the M3 x 8mm pozi-countersunk screw, M3 steel nut and shakeproof washer which secure the solder tag terminals of four ground wires. Fold back the wire which is fitted to the rear panel assembly.
- g. Remove the line transformer assembly.

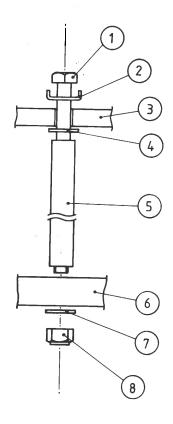
3.13.2 Fitting

Reverse procedure of para. 3.13.1, and refer to Fig. 3.7 for reassembly of items to the M8 transformer bolts.

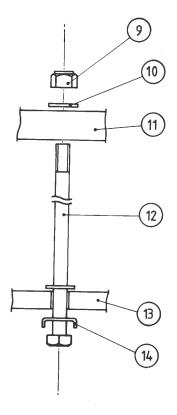




- CONNECTOR J5, 4-WAY WITH LOCATING PIN, CARRIES FOUR WIRES FROM LINE TRANS-FORMER ASSEMBLY.
- CONNECTOR J4, 4-WAY, NO LOCATING PIN-CARRIES FOUR WIRES FROM CAPACITORS ON MOTHER PCB.
- 3. PCB EJECTOR (VIOLET)
- CONNECTOR J3, 8-WAY WITH LOCATING PIN. CARRIES EIGHT WIRES FROM POWER SUPPLY/I HEATSINK ASSEMBLY (20)
- CONNECTOR J1, 12-WAY WITH LOCATING PIN. CARRIES EIGHT WIRES FROM POSITIVE HEAT-SINK ASSEMBLY (21)
- CONNECTOR J2, 8-WAY WITH LOCATING PIN. CARRIES SEVEN WIRES FROM NEGATIVE HEATSINK ASSEMBLY (22)
- CONNECTOR J6, 12-WAY WITH LOCATING PIN. CARRIES WIRES OF TWO CABLES FROM HV TRANSFORMER ASSEMBLY (16)
- POWER AMPLIFIER (DC) PCB ASSEMBLY
- 9. IN-GUARD POWER SUPPLY PCB ASSEMBLY
- IO. CONNECTOR J1, 4-WAY WITH LOCATING PIN. CARRIES TWO WIRES FROM POWER SUPPLY/ I HEATSINK ASSEMBLY (20).
- 11. CONNECTOR J2, 8-WAY WITH SIX-BLANK-ONE PIN GROUPING FROM LOCATING PIN. CARRIES SEVEN WIRES FROM LINE TRANSFORMER ASSEMBLY (15)
- 12. PLASTIC BLANKING PLUG
- 13. CONNECTOR J3, 8-WAY WITH THREE-BLANK-FOUR PIN GROUPING FROM LOCATING PIN. CARRIES SEVEN WIRES FROM LINE TRANS-FORMER ASSEMBLY (15)
- 14. PLASTIC BLANKING PLUG
- 15. OUT-GUARD POWER SUPPLY PCB ASSEMBLY
- SPACE (NO SOCKET TERMINAL FITTED)
- 17. CONNECTOR J3, 8-WAY WITH FOUR-SPACE-THREE PIN GROUPING FROM LOCATING PIN. CARRIES SEVEN WIRES FROM LINE TRANS-FORMER ASSEMBLY (15)
- 18. LINE TRANSFORMER ASSEMBLY
- 19. HV TRANSFORMER ASSEMBLY
- 20. REAR PANEL ASSEMBLY
- 21. HEATSINK RETAINING PLATE
- 22. CONNECTOR J19 (MOTHER PCB), 7-WAY CARRIES WIRES FROM POWER SUPPLY/I HEAT-SINK ASSEMBLY
- 23. POWER SUPPLY/I HEATSINK ASSEMBLY 400455
- 24. POSITIVE HEATSINK ASSEMBLY 400454
- 25. NEGATIVE HEATSINK ASSEMBLY 400461



- a. HV TRANSFORMER BOLT
 - 1. M8 x 100mm BOLT
 - TRANSFORMER BOLT PLATE
 - 3. MOULDED CHASSIS (PART)
 - 4. M8 FLAT STEEL WASHER
 - 5. CLEAR SPACER
 - 6. HV TRANSFORMER ASSY (PART)
 - 7. M8 FLAT STEEL WASHER
 - 8. M8 NYLOCK NUT



- b. LINE TRANSFORMER BOLT
 - 9. M8 NYLOCK NUT
 - 10. M8 FLAT STEEL WASHER
 - 11. LINE TRANSFORMER ASSY (PART)
 - 12. M8 x 110mm BOLT
- 13. MOULDED CHASSIS (PART)
- 14. TRANSFORMER BOLT PLATE

FIG. 3.7 RE-ASSEMBLY OF TRANSFORMER BOLTS

3.14 REAR PANEL ASSEMBLY (FIG. 3.8)

3.14.1 Removal

WARNING. DO NOT REMOVE THE REAR PANEL ASSEMBLY WHEN TOP AND BOTTOM COVERS AND GROUND/GUARD ASSEMBLIES ARE REMOVED. REFER TO WARNING 2 AT START OF SECTION 3.

N.B. Rear panel-mounted components are accessed by releasing the rear panel assembly and moving it away from the chassis to the extent allowed by internal wiring connections. Perform this operation (para. 3.14) with top and bottom covers and ground/guard assemblies fitted, or with AT LEAST the top OR bottom ground/guard assembly fitted. This procedure provides access to rear panel-mounted

components; it does not provide for complete removal of the rear panel assembly.

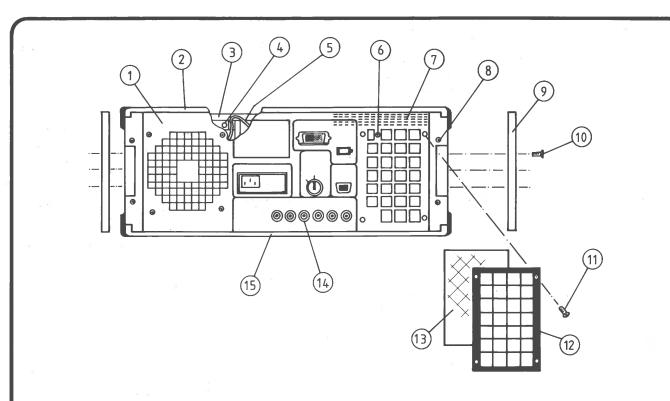
- a. Remove the six screws (10).
- b. Remove the two rear spacers (9).
- c. Remove the four screws (11).
- d. Remove filter grille (12) and filter (13).
- e. Remove screw (6) and the screw from position (4).
- f. Remove the four screws (8).

CAUTION. Do not stress the wires.

g. Gently pull away the rear panel assembly (1) away from the chassis (3) to the extent allowed by the wiring.

3,14,2 Fitting

- a. Press the rear panel assembly (1) to the chassis (3) whilst ensuring that:
 - The wires (5) lay in the cut-out in the moulded internal chassis;
 - The ribbon cables (7) fit in the recess in the moulded internal chassis;
- 3) All other wires are free and not trapped by the rear panel assembly.
- b. Fit screws, filter, filter grille and rear spacers, reversing the procedure of para. 3.14.1.



- 1. REAR PANEL ASSEMBLY
- 2. TOP COVER
- 3. MOULDED INTERNAL CHASSIS
- POSITION FOR M3 x 6mm POZI-PAN SCREW AND M3 SHAKEPROOF WASHER
- 5. WIRES FROM FAN PASSING THROUGH CUT-OUT IN MOULDED INTERNAL CHASSIS
- 6. M3 x 6mm POZI-PAN SCREW AND M3 SHAKE-PROOF WASHER
- 7. RIBBON CABLES FIT IN RECESS IN MOULDED INTERNAL CHASSIS

- 8. M4 x 8mm TAPTITE SCREW IN FOUR POSITIONS
- 9. REAR SPACER
- 10. M4 x 12mm SOCKET HEAD COUNTERSUNK SCREW IN SIX POSITIONS
- 11. M3 x 10mm POZI-COUNTERSUNK SCREW IN FOUR POSITIONS
- 12. FILTER GRILLE
- 13. FILTER
- OUTPUT TERMINALS (WHEN REAR-PANEL MOUNTED)
- 15. BOTTOM COVER

FIG. 3.8 REMOVAL OF REAR PANEL ASSEMBLY

3.15 FRONT PANEL ASSEMBLY

- RED, BLACK, WHITE, BLUE AND BROWN CODED TERMINALS
- 2. TERMINAL COLOUR CODE
- 3. WRAP SOLDER JOINT FOR RED, WHITE AND BLUE WIRES
- 4.
- 5. METHOD NOT USED ON 4000
- 6. SPECIAL SOLDER TAG
- 7. SPACER
- 8. WASHER
- 9. NUT
- 10. NUT
- 11. SOLDER TAG
- 12. GREEN/YELLOW WIRE
- 13. GREEN CODED TERMINAL
- 14. METHOD NOT USED ON 4000
- 15. SECTION OF PANEL

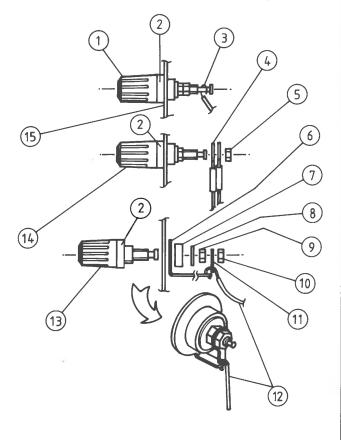


FIG. 3.9 DISMANTLING/REASSEMBLY OF TERMINALS

- 1. BRACKET
- 2. MOTHER PCB
- 3. RED WIRE TO BROWN-CODED 1 + TERMINAL
- 4. BLUE WIRE TO BLUE-CODED I TERMINAL
- 5. RED WIRE TO BROWN-CODED I + TERMINAL
- 6. BLUE WIRE TO BLACK-CODED LO TERMINAL
- 7.
- 8. WHITE WIRES TO WHITE-CODED TERMINAL
- 9. GREEN/YELLOW WIRE TO GREEN-CODED TERMINAL

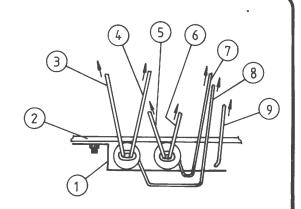


FIG. 3.10 FRONT PANEL ASSEMBLY TERMINAL WIRING

3.15.1 Removal

- N.B. Remove top cover (para. 3.2) and bottom cover (3.3) before performing the following procedure.
 - a. Remove the four M4 x 8mm taptite screws from the front panel assembly.
 - CAUTION. Do not stress the wires.

- NOTE. Steps b. and c. do not apply when output terminals are rear panel-mounted.
- b. Move the front panel assembly away from the chassis to the extent allowed by the wires to the output terminals.

c. Referring to Fig. 3.9

- 1) Unsolder the wrap joints (3) and remove the red, black, white, blue and brown-coded terminals (1).
- Remove nut (10) from green-coded terminal (13); ease soldertag (11) from the terminal taking care not to strain the connection with wire (12) and special solder tag (6); remove nut (9) washer (8) and spacer (7); removal special solder tag (6), together with solder tag (11)

and green/yellow wire (12); reassemble items (7), (8), (9) and (10) to the terminal.

d. Remove the front panel assembly.

3.15.2 Fitting

Reverse the procedure of para. 3.15, referring to Fig. 3.10 for terminal wiring identities, and to Fig. 3.9 for terminal connection methods.

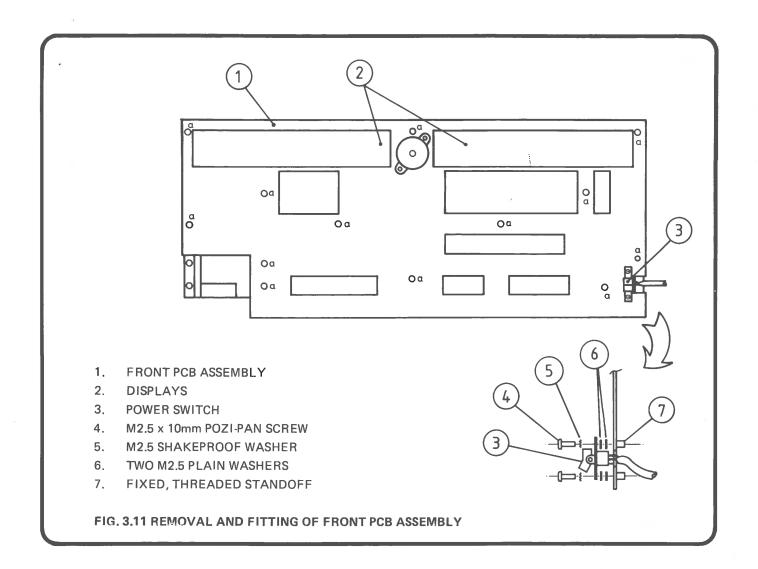
3.16 FRONT PCB ASSEMBLY (FIG. 3.11)

3.16.1 Removal

- a. Remove front panel assembly (para. 3.15.1)
- b. Remove two screws (4), together with two shakeproof washers (5) and four plain washers (6).
- c. Fold the power switch (3) and its cable clear of the pcb (1).
- d. Remove the M3 x 6mm pozi-pan screws from 13 positions on the circuit board (1), marked 'a' on Fig. 3.11.
- e. Ease the lower edge away of pcb (1) away from the mother pcb to disengage the mating connectors.
- f. Remove the pcb.

3.16.2 Fitting

Reverse the procedure of para. 3.16.1. Ensure all mating connectors are fully engaged and that the surfaces of displays (2) are clean.



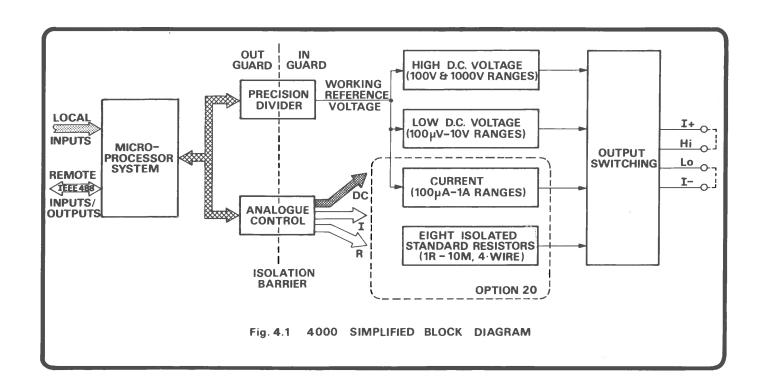
SECTION 4

TECHNICAL DESCRIPTION

4.1 PRINCIPLES OF OPERATION (FIG. 4.1)

SIMPLIFIED FUNCTIONAL DIAGRAM

FIG. 4.1 illustrates the general circuit division and signal flow within the 4000.



4000 BLOCK DIAGRAM

FIG. 4.2 (overleaf) breaks the main functional division down into smaller blocks. It can be thrown clear of the handbook to provide a functional overview and index to other subsections of section 4.

4.1.1 Inputs

The microprocessor system accepts inputs from two main sources:

- (i) The front panel keyboard provides local control inputs.
- (ii) The IEEE 488 bus system provides remote control inputs.

The microprocessor system outputs digital information to two main areas:

- (i) The precision divider which is used in setting the terminal output.
- (ii) Various decoding circuitry which controls function and range selection.

4.1.2 Precision Divider

The circuit produces a DC voltage, called the "Working Reference", which can be accurately set between 0 and \pm 20V. It is divided into two main areas:

- (i) The period division comparator, outside guard, consists of a comparator and a binary counter, both 25 bits. The comparator is set by data from the microprocessor system and the counter is driven by a crystal-controlled clock. When the binary count matches the data set in the comparator, a switching pulse (reset) is produced. The binary counter continues to overflow point when a second switching pulse (set) is produced. In this way, accurately variable mark-space timing is generated.
- (ii) The switching integrator receives the pulses across guard. They are used to drive a solid state switch which chops the output from a very stable 20V DC Master Reference. This in turn produces a square wave which is very accurately defined both in period and amplitude. This resultant square wave is integrated by an active low-pass filter with high rejection at the chopping frequency, to finally produce the 0 - ± 20V Working Reference.

4.1.3 Analogue Control

The analogue circuitry is controlled by data held in a 48 bit in-guard latch. The microprocessor regularly updates the latch contents, using a serial link to pass the data (through opto-isolators) across the isolation barrier.

4.1.4 Low Voltage Output

The basic range of the 4000 is \pm 10V (\pm 19.999,999 FS). This is a buffered output derived directly from the Working Reference. All lower voltage outputs are produced by additional buffers and precision attenuators.

4.1.5 High Voltage Output

Outputs on the 100V and 1kV ranges are produced using an AC Voltage Amplifier/Rectifier system.

The Working Reference is used to control the amplitude of a sine wave output from a voltage controlled amplifier. This drives an AC step-up transformer via a Power Amplifier, which after rectification and filtering produces the high voltage DC outputs.

4.1.6 Current Ouput (Option 20)

For Current outputs the Working Reference is switched to drive a voltage-to-current convertor. The various ranges are selected by digital control signals from the microprocessor system.

4.1.7 Resistance Output (Option 20)

For resistance outputs a range of eight fixed-value precision resistors are fitted. They are fully floating and selected by relays under control of digital signals from the microprocessor system.

4.1.8 Model 4000A - Features Additional to Model 4000

The following features extend the 4000A DC Voltage and Current specifications to 23° C \pm 5° C.

- (1) Buffer M2 on the Reference PCB (400452) is temperature-compensated. Refer to Section 4.6.4.1.
- (2) On the DC PCB Assembly (400445), the 100mV, 1V and 100V/1000V range precision attenuators are uprated. Refer to Sections 4.7.8.1 and 4.8.10.1.

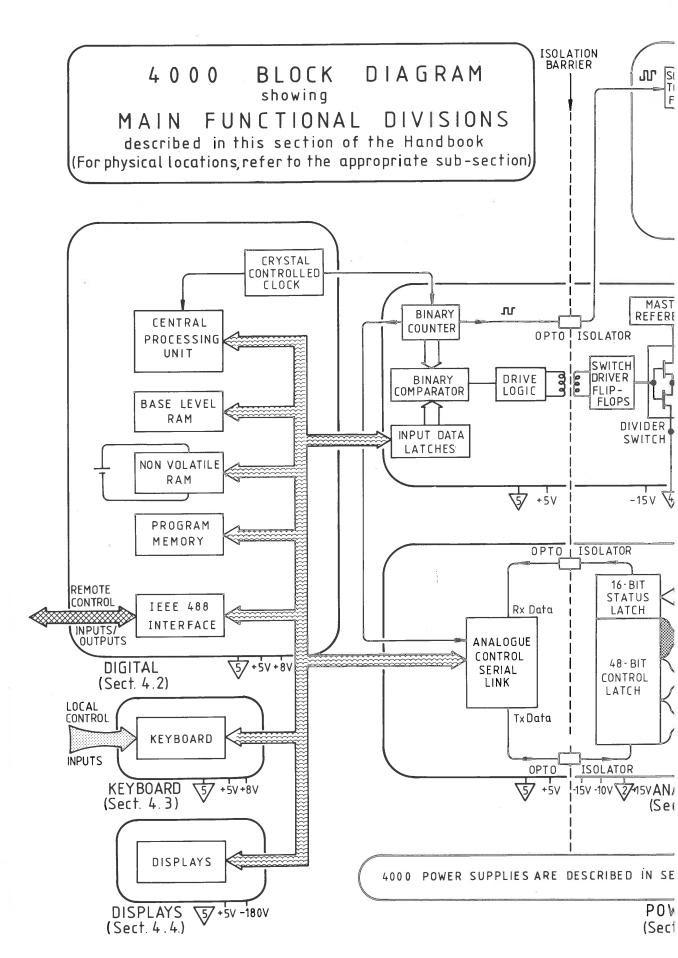


Fig. 4.2

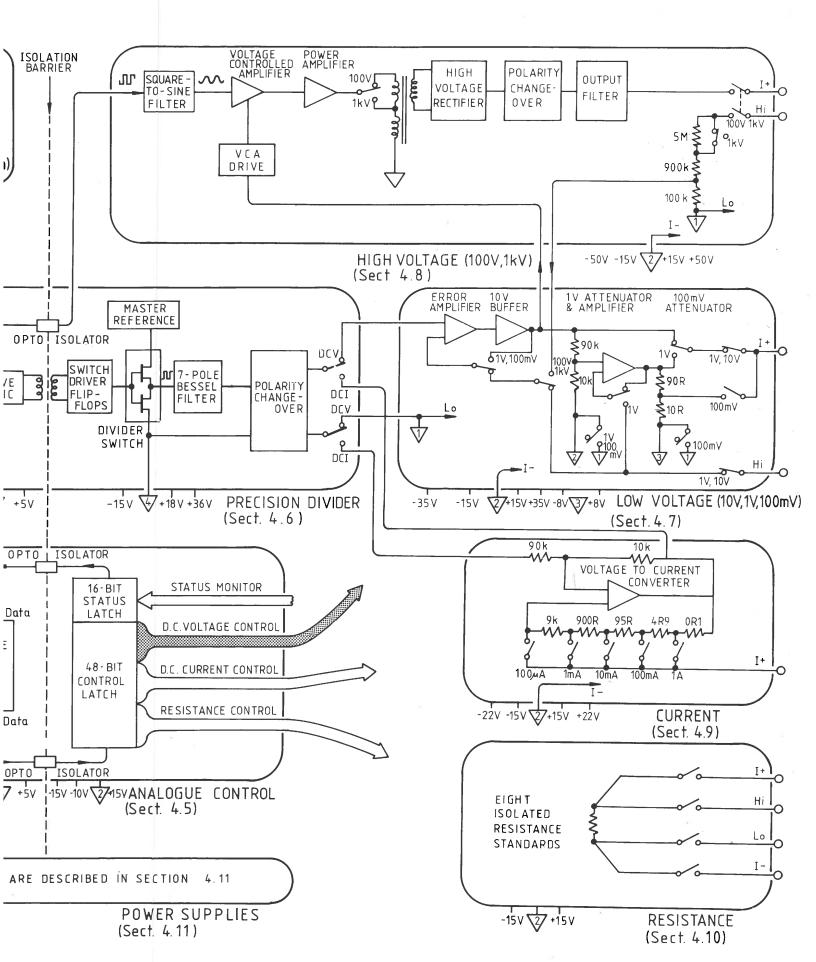


Fig. 4.2 4000 BLOCK DIAGRAM

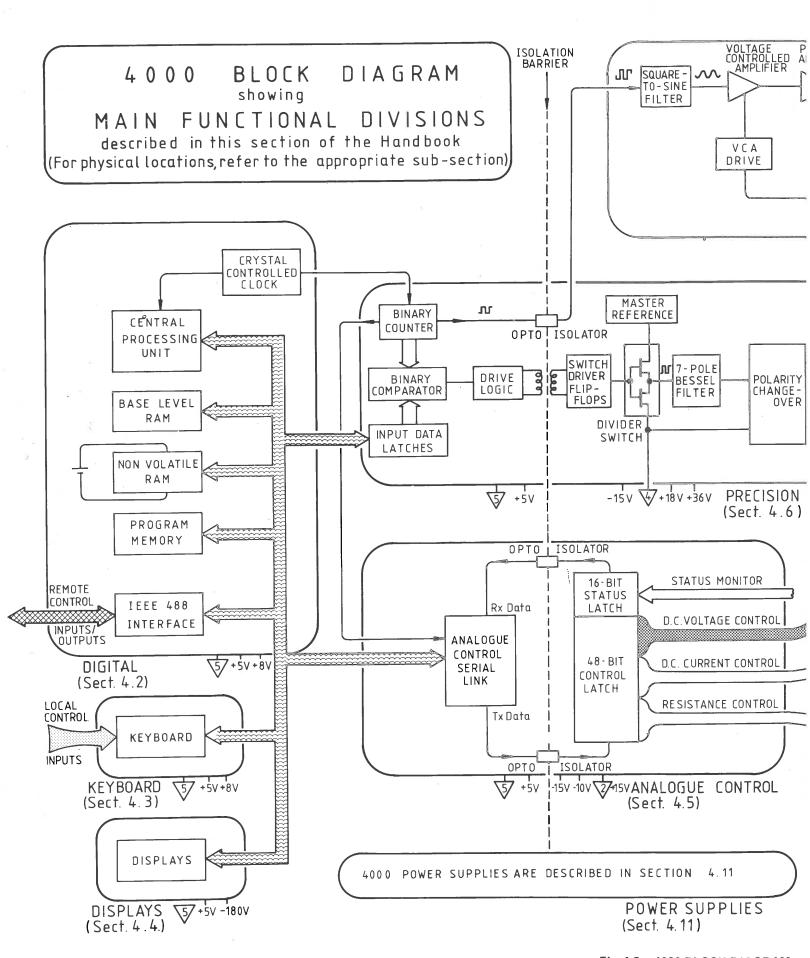
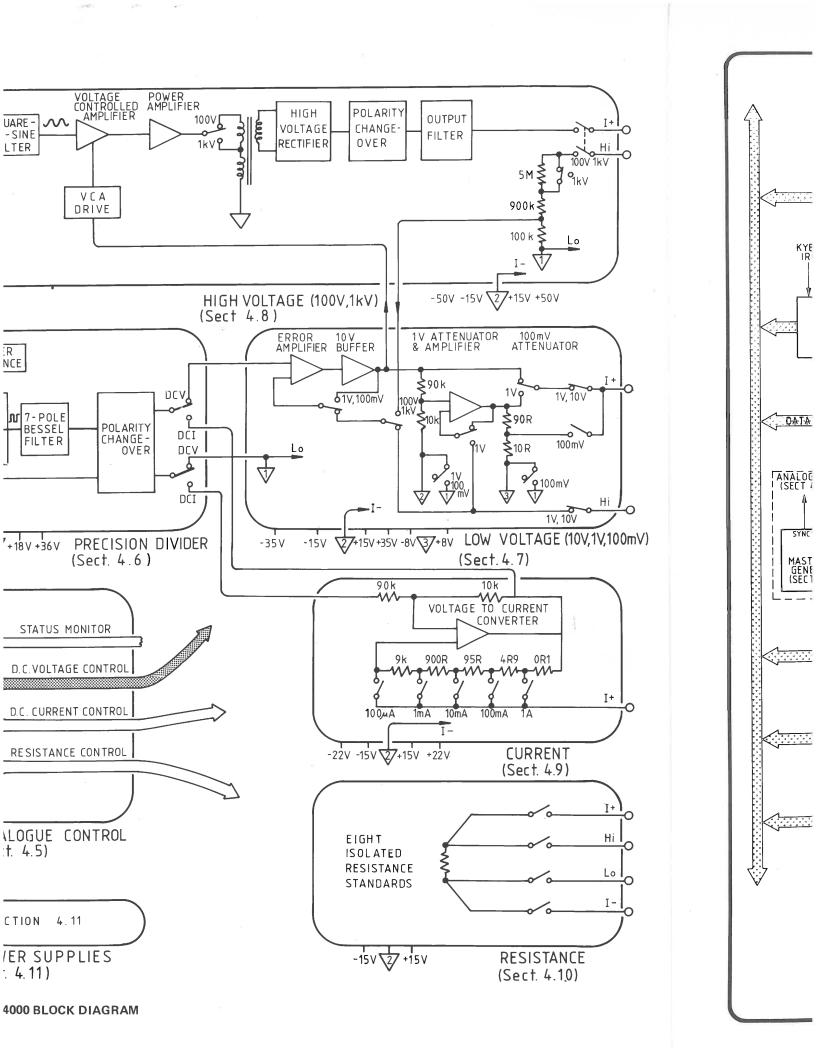
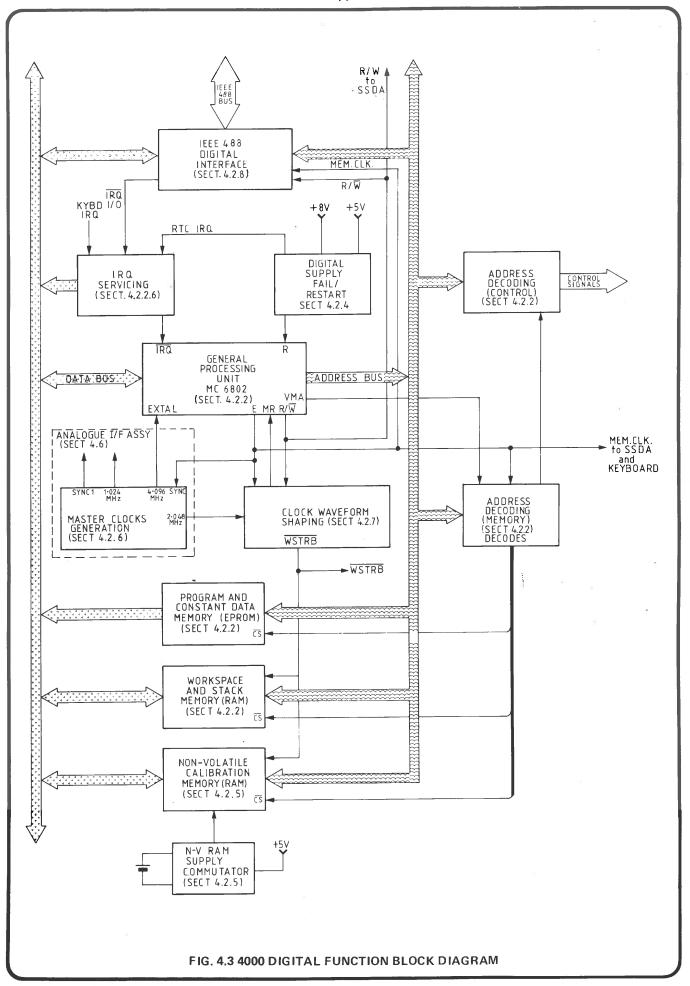


Fig. 4.2 4000 BLOCK DIAGRAM





4.2 DIGITAL

The circuits described in this section perform the following functions:

- Central processing, with supporting memory, for management of instrument operation.
- (2) Storage of calibration constants in non-volatile memory.
- Generation of Master clocks, with clockwaveform shaping.
- (4) Address decoding to generate control signals.
- (5) Controlled power-up and power-down of digital circuits.

- (6) Servicing IRQs from asynchronous sources.
- (7) Interfacing the 4000 to the IEEE 488 bus.

The functions are performed by circuits located mainly on the Digital PCB Assembly (400442). Master Clock generation, synchronisation and division is carried out by circuits on the Analogue Interface PCB Assembly (400443).

Fig. 4.3 shows the arrangement and main interconnections of the central digital circuits.

4.2.1 General

The 4000 is managed by a 6802-series micro-processor system, under the control of an operating program held in 20k bytes of EPROM. All front and rear panel controls provide direct inputs to the system, except for the Power ON/OFF switch and Safety Reset Key. The system ensures that the processor reverts to a safe state on power-up and power-down.

1k bytes of random-access memory (RAM) are used for work space and stack. A further 256 bytes of CMOS RAM act as a non-volatile memory to hold calibration constants, powered by a back-up Lithium battery when the instrument is turned off.

amended task schedule to complete the initial operation synchronously. Three sources of interrupt are used:

Remote Command

Keyboard Command

Real-time Clock Pulses (8mS intervals)

These are identified by polling the data bus each time the 6802 receives an IRQ interrupt.

4.2.1.1 Synchronous Operation

The operating program manipulates the internal circuitry by activating control signals. These result from providing peripheral decoders with specific address combinations. The program is run at 680kHz cycling frequency derived from a 4.096 MHz external oscillator.

4.2.1.3 Output Generation

Having stored user inputs for output value, offset, error and calibration constants, the processor uses them to compute a binary value to a resolution of 25 bits. This is used to adjust the mark/period ratio of the Reference Divider switch which ultimately controls the Working Reference Voltage for the output analogue circuitry.

4.2.1.2 Asynchronous Operation

Any Key operation (other than Safety Reset) generates an asynchronous interrupt to the processor, which suspends its current task to receive data and schedule new tasks associated with this data. The processor then continues with the interrupted task and returns to the

4.2.1.4 Display Refresh

The gas discharge display is continuously refreshed by cycling through character data stored in a separate display-image RAM. To alter the display the processor merely alters the contents of the RAM.

4.2.2 Central Processor and Memory (Circuit Diagram No. 430442 Sheets 2 and 3)

A 6802 microprocessor [M34] together with its memory, controls communication throughout the whole instrument

4.2.2.1 Memory

The memory can be split into five main areas:

- (M18, 19, 20, 21 and 22)
- (1) Program Memory defines and controls the operational functions of the whole instrument system.
- (2) Constant Data Memory (held in EPROM with the Program Memory).
- eq Instrument specification for use in 'Spec' mode, key mapping tables and other fixed factors.
- (3) Non-volatile Calibration Memory (M26 and 27)
- stores all the calibration constants determined during 'Auto-cal' cycle which are used for each output value.
- (4) Volatile Memory (M24, 25)
- used for volatile data storage, eg display images, computational stores, present output value.
- (5) Operating Memory used for scratch pad (M24, 25) operations and storage

The 6802 microprocessor internal RAM is not used.

Separate memory is used for special purposes, such as the Display Image RAM (M16) which is synchronously loaded but asynchronously read, the storage areas in the IEEE 488 GPIA (M29) and the keyboard interface (M6 on Front Assembly), and the Memory Address decoder PROM (M3). These are described in later sections.

4.2.2.2 Central Processing Unit [Circuit Diagram 430442 Sheet 2

The MC6802 [M34] is a monolithic 8-bit microprocessor with Interrupt and Clock-stretching facilities. It is driven by a single phase 4.096 MHz square wave generated by the Master Clock circuit in the Analogue Interface Assembly. (This clock synchronises the reference divider switch with the processor cycle).

4.2.2.3 Address and Data Lines

Address lines A₁₅ _ 11 are decoded as chipselect signals for the RAM/ROM circuit, and lines $A_{1\,2}\,=\,0$ are connected to the instrument address bus. Data lines D7 _ 0 are linked via programming plug JL1 to the instrument data bus.

4.2.2.4 E, MR and MEMCLK

The 4.096 MHz clock input at M34-39 (EXTAL) is divided by four and used as output at M34-37(E). Although the natural frequency of E is 1.024 MHz, the action of the waveform shaping input to MR reduces it to approx. 680 kHz as MEMCLK for the Front and Analogue-Interface assemblies.

4.2.2.5 NMI

The internal switch S1 provides a non-maskable hardware interrupt which has two functions:

- (1) With the external CALIBRATION switch set to RUN, NMI initialises the processor system
- (2) With the CALIBRATION switch set to ENABLE, NMI clears the non-volatile calibration memory (M26/27) before initialising the processor system.

4.2.2.6 IRQ

Any one of three asynchronous Interrupt Request signals are able to activate the maskable IRQ input at M344:

- (1) RTC IRQ is a real-time clock which occurs every 8mS to provide timing information for the processor's monitoring facility.
- (2) KB IRQ occurs each time a key is pressed on the front panel. (Not Safety Reset)
- (3) IRQ IO occurs when the IEEE 488 Interface has a transaction to communicate to the processor.

D1, D2 and Q1 constitute a DTL OR-gate to isolate the IRQ inputs from one another. On receipt of Logic-O on pin 4, M34 stores its register contents in stack RAM, and vectors to IRQ service addresses FFF8 and FFF9, saving the current processor environment. The IRQ service routine addresses M51 and M52, generating logic-0 at M52-9 which enables the tristate buffers M36 and M37 at M36-1 and 15, M37-15, This sets IRQ data bits D5, D6 and D7 on the data bus so that the processor can identify the source of the IRQ and select the appropriate sub-routine to service the interrupt request. The IRQ inputs are released as part of the service sub-routine, and after its completion, the processor recovers its environment from stack RAM and proceeds with the interrupted operation.

4.2.2.7 Software IRO

The 6802 will also recognise Opcode 3F on the data bus as an interrupt request ('Implied' addressing mode). In the 4000 this code is hard-wired via R9, R10 and AN3 onto the data bus so that if the processor tries to access a non-available address, the floating bus will be pulled to 3F, initiating the software IRQ. The processor vectors to FFFA and FFFB, whose contents cause the 6802 to re-initialise the whole system.

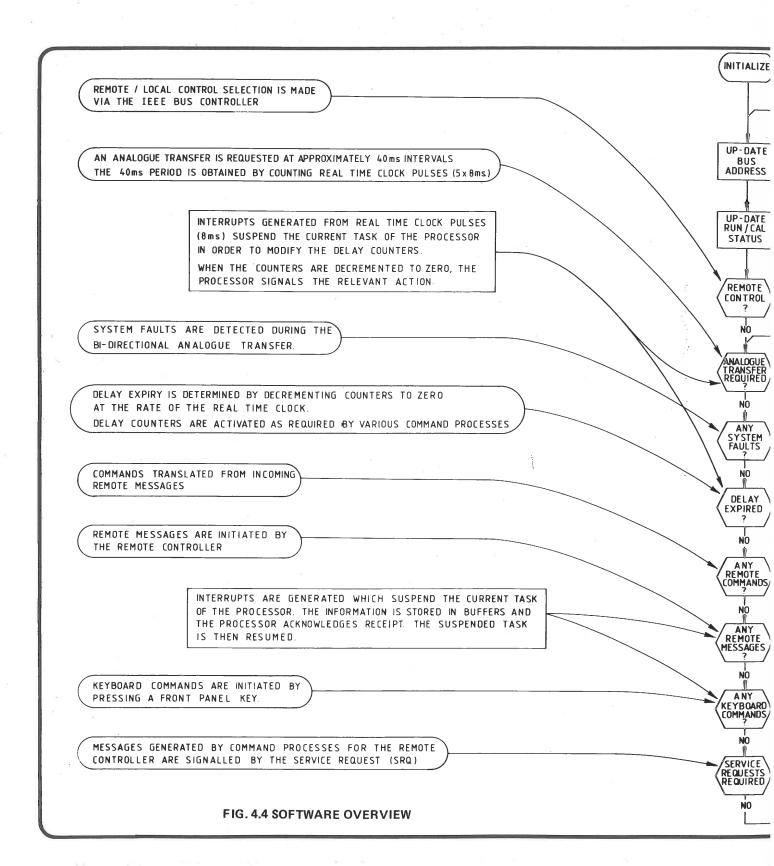
4.2.2.8 Read-write line R/W

The processor sets the R/W line to logic 1 when it is in Read state, and logic-0 when it has data to write into the addressed device. The R/W signal is passed only to the SSDA on the Analogue Interface assembly, and to the IEEE 488 GPIA (M29). All other devices which require read-write control, operate from RSTRB and WSTRB signals generated from R/\overline{W} by M49/50.

4.2.3 Software Overview

The software management organization is shown in Figure 4.4. The machine cycle, which progresses through the task schedule shown, is modified by the requirements of real time-conscious activities and by those dedicated to

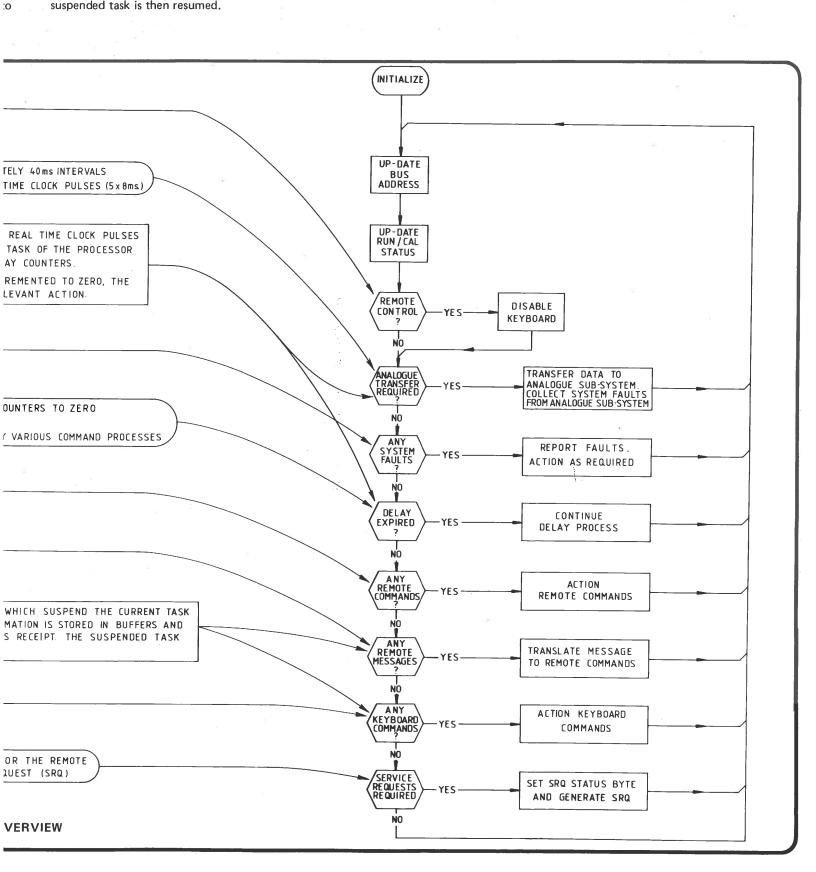
remote commands. Real time and remote command interrupts suspend the current activity of the processor in order to service the immediate task requirement; the suspended task is then resumed.



jh

ts

remote commands. Real time and remote command interrupts suspend the current activity of the processor in order to service the immediate task requirement; the suspended task is then resumed.



4.2.4 Digital Supply Fail/Restart Circuitry

Power-up, restart and shut-down of the digital circuitry are performed in a controlled sequence to safeguard against hardware failures or a software crash. A continuous surveillance of the software management is

performed by the safety monitor (watchdog — refer to Section 4.5). This will shut-down the instrument in the event of a failure in the digital control circuits or in software management.

4.2.4.1 Power-up Sequence (Circuit Diagram No. 430442)

Power-on is first sensed by the Supply Fail Detector circuit. This draws its supplies from the +8V dc unregulated supply, which is the first of the power supplies to rise to a working level. The comparator circuit of M28 has a nominal threshold of 7.1V dc, above which a good working level of the + 5V dc supply is assured. M28 will give a logic-0 output below the 7.1V threshold level which will prevent the start-up sequence progressing.

As power supplies rise towards a working level, flip flop M8 is held in RESET state with its \overline{Q} output at M8-2 at logic-1. This will initiate the following actions:

- PWR ON RST active/ fed to the front panel assembly, this logic -1 level holds keyboard encoder M6 in Reset and disables the LED cathode driver decoder M4.
- 2) PWR ON RST active (via inverter M6-4). In the digital pcb assembly, this logic -0 level holds the microprocessor M34 and the IEEE 488 GPIA M29 in Reset. It is also fed to the analogue interface pcb assembly where it holds SSDA M44 in Reset.

PWR ON RST and PWR ON RESET are held active until flip flop M8 is clocked from counter M9. This is a 14-bit binary counter clocked at 2.048 MHz, thus giving a delay of 8mS from start of count to output from M9-3. The counter is enabled by a logic-0 at its Reset input; the conditions which allow this at power-on reset are as follows:

- 1) Comparator M28 output at logic-1 (High)
- 2) Microprocessor M34-5 VMA output at logic 0; this is forced by logic-0 at its reset input, thus inhibiting address decoder M3 and setting all M3 address outputs to logic-1. This combination gives logic-1 at M5-13, but M6-2 at logic-0 gives logic-1 at M5-11 and subsequently logic-1 at M7-2.

At full count, M9-3 output clocks flip flop M8, taking M8-1 to logic-1 and M8-2 to logic-0.

This initiates the following actions:

- PWR ON RST at logic-0. Enables keyboard encoder M6 and LED cathode driver decoder M4 on the front pcb assembly.
- (2) PWR ON RST at logic-1:
 - (a) Lifts reset level to microprocessor M34 allowing software initialization to commence, and enables IEEE bus controller M29 on the digital pcb assembly. (Part of the instrument initialisation procedure is a software reset for M29).
 - (b) Lifts reset level to the SSDA M44 on the analogue interface pcb assembly.
- (3) M8-1 at logic-1.
 - (a) Enables RTC IRQ. The action of M9, M8 and M51 generates a "Real-time clock IRQ" at 8mS intervals. M51-5 is normally at logic-1; but after a RTC IRQ has been serviced, the CPU addresses M51, pulsing M51-5 (M7-12) to logic-0 (RTC RST). M7-12 is pulsed to logic-1, resetting M8-13 (RTC IRQ) to logic-0. At the next full count of M9; M8-13 is clocked to logic-1, initiating the next RTC IRQ.
 - (b) Provides an enabling input to M10-1 (See Non-volatile RAM Supplies Section 4.2.5).
 - (c) Triggers monostable M53-4. This monostable has a relaxation period of 470 mS; during which time it holds the FP RST output at logic-0 which allows the watchdog circuits to reset on the reference divider pcb (see Safety Monitor Section 4.5).

M9-3 pulses also regularly clock the binary state of M8-5 through to M8-1, monitoring the supply status. When running normally, M8-5 and M8-1 are both logic-1, but if the supply fails a fast reset is provided by M7-1 logic-0 to M8-4 logic-1, rather than waiting for the next clock pulse. M7-3 also resets the 8mS counter at M9-11.

4.2.4.2 CPU Re-start (Circuit Diagram No. 430442)

Memory addressing by the CPU is monitored by the NAND logic of M4, M5 (four elements) and M7-3. In the correct addressing sequence there are two basic conditions:

- (1) CPU VMA = logic-0 M3-D1 to D8 = logic-1
- (2) Valid memory address CPU VMA = logic-1 CPU E = Logic-1 M3-D1 to D8 = One address line logic-0

Conditions (1) and (2) both result in a logic-0 From M7-3, allowing clock M9 and flip flop M8 to function normally. The possibility of a glitch occurring at the change-over between conditions (1) and (2) is gated from the control line by switching at M5-5. Incorrect addressing sequence in the CPU would be shown by:

CPU VMA = Logic-1 - The CPU indicates
CPU E = Logic-1 that it has selected a
valid external address

M3-D1 to D8 = Logic-1 — No address is selected.

This situation is most likely with a software failure. The logic control line M4, M5 now gives a logic-0 at M7-2 and thus a logic-1 at M7-3 which:

- (1) Resets counter M9 to zero;
- (2) Forces M8-1 to Logic-0. This forces RTC RST at M7-11 and removes an enable from M10-1 (see Non-volatile RAM supplies – Section 4.2.5).
- (3) Forces M8-2 to logic-1. This change:
 - a. Resets the CPU by M34-40 to logic-0. VMA is forced to logic-0 which in its turn removes the reset from M9-11 and M8-4 via M6-2 at logic-0.
 - b. Makes PWR ON RST and PWR ON RST signals active, thus resetting the other software controlled areas.

After 8mS from CPU reset, flip flop M8-3 is triggered from clock M9. M8-1 and M8-2 change state and the start-up sequence commences.

4.2.5 Non-volatile RAM Supply Commutation

4.2.5.1 Non-volatile RAM Inhibit (NV INHIBIT)

Chip-select to the two non-volatile memories, M26 and M27, is inhibited during power-up, re-start and power-down operations. Memory access to the two non-volatile RAMs is enabled during normal running by the chip-select input NV INHIBIT being held at logic-1. The NAND logic gates M10, used to control the inhibit, remain powered from the RAM standby supply after power-down.

Conditions for normal running are as follows:

- (1) Supply fail detector circuit provides a logic-1 (supplies valid) output to opto-coupler M11. This causes the coupled transistor of M11 to conduct and hold M10-2 at logic-1.
- (2) M10-3 is held at logic-1 (to +5V via R6);
- (3) M10-1 is held at logic-1 by flip flop M8-1.

The above conditions ensure a logic-1 output from M10-10 (NV INHIBIT not active).

During power-up, NV INHIBIT is held active (logic-0) until the power supplies have settled and the CPU has been reset. The input to M10-3 is delayed on the +5V supply by the time-constant C8, R6. Also, the input to M10-1 is held at logic-0 by flip flop M8-1 until the CPU has been reset. At power-down, or in the event of a supply failure, the NV INHIBIT becomes active (logic-0) before the +5V supply fails. The first indication of supply failure is made by supply fail detector M28 output going to logic-0. This cuts-off the opto-coupler M11 which takes M10-2 to logic-0. M10-3 is held at logic-1 by the +5V supply, thus M10-9 is taken to logic-1 and M10-10 to logic-0 (NV INHIBIT active).

In the event of a CPU reset, the $\overline{\text{NV INHIBIT}}$ is made active for the period of reset by the switching action of M8-1 and M10-9.

4.2.5.2 Supply Commutator

This circuit provides the non-volatile RAMs M26 and M27 with a battery-driven standby supply when the instrument is in the power-down condition. It ensures continuity of supply in the change-over between main and standby, and minimizes battery current leakage. In the power-down condition, the battery circuit is to M10, M26 and M27, with the return from battery common 5B via D7 and R60. The battery common 5B is isolated from the general common 5A by transistor Q2, which is cut-off.

During power-up, operational amplifier M28 is powered from the +8V supply before the +5V supply voltage is established. As long as the +5V supply voltage is less than the battery voltage, Q3-4 is biased negatively, and Q3 is unbalanced in favour of heavy conduction through Q3-6. M28-5 is held low, so M28-7 remains at Common-5A potential, and opto-coupler M39 is not energised. Q2 remains cut off, maintaining isolation of Common-5B and the battery supply. M10, M26 and M27 remain powered from the battery.

As the +5V supply voltage increases, D7 cathode potential rises, reducing Q3-4 bias, reaching zero when its

voltage is equal to the battery voltage (less than 10mV is developed across R60).

When the +5V supply voltage exceeds the battery voltage, Q3 becomes biassed in favour of heavy conduction through M3-2, pulling M28-6 low and reversing the differential input to M28. M28-7 rises to the +8V rail and energises the opto-coupler M39, which switches Q2 on, connecting common-5B to common-5A. M10, M26 and M27 are now powered from the +5V supply and the standby battery is isolated by reverse-biased diode D7.

During power down, Q3 compares the +5V supply against the battery, switching Q2 off via M28 and M39 when the supply voltage falls below the battery voltage, and the non-volatile RAM supply commutates to standby battery. Alternatively, Q2 is switched off by failure of the +8V supply to M28 if this occurs before the +5V supply voltage falls below the battery voltage.

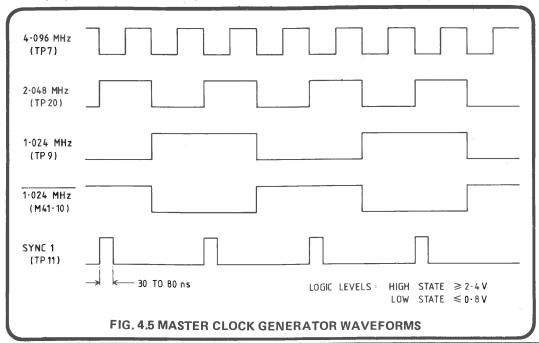
Eventually the +5V and +8V supplies both fall to zero, the battery supplies the non-volatile RAM, and common-5B is isolated from common-5A by Q2.

4.2.6 Master Clock Generation (Circuit Diagram No. 430443 Sh. 3) (refer to Fig. 4.5 for waveforms)

The master clock generator is based on crystal X1 which, with positive feedback buffers M1-2/M1-4, provides a precision 4.096 MHz squarewave reference frequency output.

The primary frequency of 4.096 MHz is divided by JK flip flop stages M41, both of which are connected to toggle when clocked. The first division stage is synchronized at its reset input, M41-3, to the memory clock via

flip flop M42. This ensures correct phasing of the 2.048 MHz squarewave output from M41-14 (for description of synchronising action, refer to section 4.2.7.3). M41-11 and M41-10 outputs provide complementary 1.024 and 1.024 MHz squarewaves respectively. Monostable M40, triggered at 2.048 MHz from M41-15 provides the positive-going 2.048 MHz synchronizing pulses, SYNC 1.



4.2.7 Clock Waveform Shaping (Circuit Diagrams Nos. 430442 Sheet 2 and 430443 sheet 3)

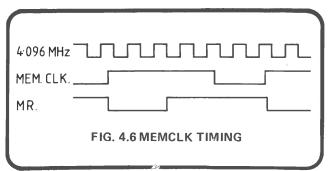
NB As the locations of the circuits in fig. 4.7 are clearly marked, and as there are no duplicate designators in the circuits, this description does not refer to a component's location except where necessary.

NOTE To avoid confusion, the terms "high" and "low" are used to replace "logic-1" and "logic-0" respectively in this description.

The crystal oscillator on the Analogue interface assembly provides a 4.096 MHz Master Clock signal (M1-4) for the whole instrument. This signal drives the 6802 microprocessor at M34-39 (EXTAL) so M34-38 is not connected. M41 divides the 4.096 MHz to generate a 2.048MHz clock for the Memory Clock Stretching Circuit (M35/M49).

M34 divides the EXTAL input internally by 4 and outputs the result as E (Enable) at M34-37, to act as a "\u03c42" Memory Clock for the SSDA on the analogue interface assembly and the keyboard controller on the front assembly.

If M34-3 (MR — Memory Ready) were permanently held at +5V, the E signal would be 1.024 MHz. But in the 4000, a "stretching" circuit (M35/M49) doubles the Logic High (+5V) time of E by switching MR to Logic Low (0V) for part of the cycle. This is shown on Fig. 4.6.



As a result, the frequency of E is reduced to approximately 680kHz. With $1\mu S$ available for access to the SSDA, Keyboard Controller, IEEE GPIA and memory.

4.2.7.1 Memory Clock Stretching Circuit (Fig. 4.7)

The action of M35 and M49 is dependent upon the finite propagation time between clocks at M35-1/M35-6 and Ω output at M35-15.

When M34-3 (MR) is +5V; M34-37 (E) is toggled by alternate positive-going edges of the 4.096 MHz clock, with a propagation delay of approximately 80nS.

Also, the 4.096MHz signal is divided by 2 in M41, resulting in 2.048MHz signal whose negative-going edges clock M35.

M35 cascade action is controlled by the condition of the Memory Clock (E) and affected by its own propagation times.

4.2.7.2 Shaping Action (Figs. 4.7 and 4.8)

The 4.096MHz clock edge at T1 causes E to rise from low to high at T2. As M35-10 is also high, MR changes from high to low at T2, holding E high. M35 pin state is 4 and 10 high, 9, 12 and 16 low.

At T3 the 2.048MHz falling edge clocks M35, and M35-9 rises to high awaiting the next clock edge (not until T5). M35-10 remains high, so MR is held low and E stays high.

At T4, MR is still low, so the 4.096MHz clock has no effect on E, and E is stretched.

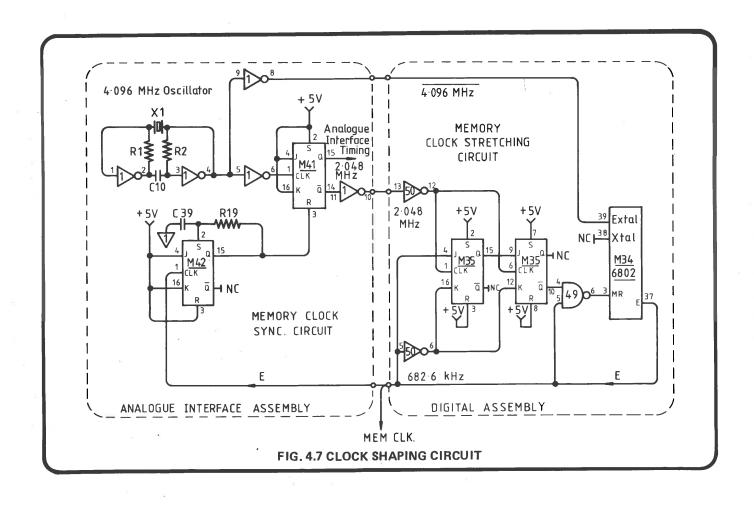
At T5, MR is returned to high when the logic-1 on M35-9 is clocked as a logic-0 to M49-4. This allows the 6802 to toggle E at the next effective clock edge.

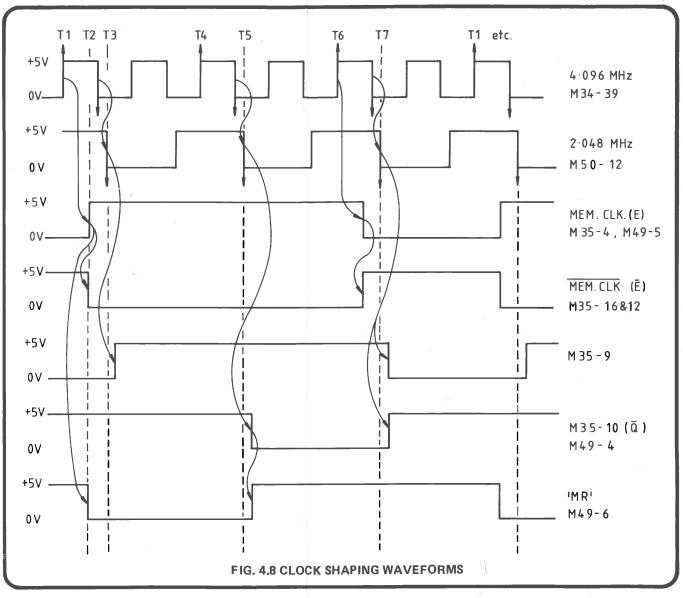
At T6 the rising edge of the 4.096MHz clock causes E to fall to low, setting up M35-4 to low, M35-12 and 16 to high, M35-9 is already high.

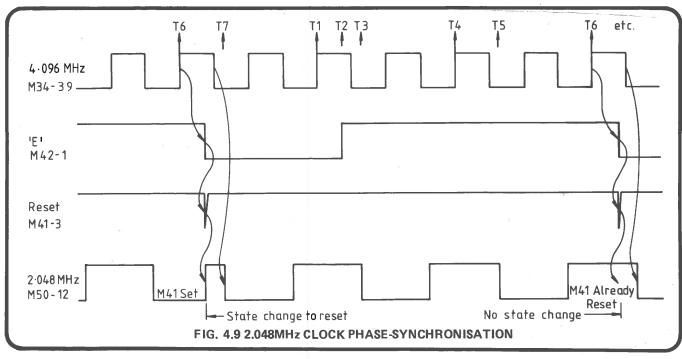
At T7, M35-10 is toggled to high, but as M49-5 is now low, MR remains high to allow E to be toggled at the next effective processor clock edge (not until the next T1). Also at T7, M35-15 is clocked to low to set M35-9 ready for the next (T3) clock edge. The circuit is now set up to its initial (pre-T1) condition so the action repeats.

4.2.7.3 2.048MHz Clock Synchronisation (Figs. 4.7 and 4.9)

Unless M41 is synchronised, it could toggle in reverse phase, upsetting the timing of the stretching circuit. In Figs. 4.7 and 4.9, M42 acts as a monostable to provide a negative reset pulse into M41-3, coincident with the negative-going edge of E. If M41 starts up in the wrong phase, its state is corrected just prior to T7. Once established in the correct phase, M41 will already be in reset when the pulse appears, and is not affected.







4.2.8 IEEE 488 Digital Interface (Circuit Diagram No. 430442 Sheet 4)

The IEEE Interface circuitry is located on the bottom right-hand corner of the Digital PCB (viewed from the front of the instrument). M29, M40, M47 and M48 execute and decode interface functions, and perform data input/output transfers.

The General Purpose Interface Adaptor (GPIA) M29, is software-driven by the 6802 CPU, as part of its normal function. M29 is addressed at $\overline{\text{CS}}$ by $\overline{\text{XIOBBD}}$ from M51, and its internal registers are accessed by A₀, A₁ and A₂ from the address bus.

The GPIA is clocked by Memory Clock E, with read or write control direct from the processor R/W signal at M29-5, and at 4000 power-on M29 is initialised at M29-19 by the PWR ON RST signal from the Restart Generator circuit (M6-4).

Information is passed between M29 and the CPU (M34), via the data bus D_0-D_7 . The address switch data is linked to D_0-D_6 by tristate buffers M47. During initialisation, and periodically thereafter, the state of M29-4 (ASE) changes from +5V to 0V, enabling M47. The status of the address switches on the 4000 rear panel are transferred into M29 via M47 and the data bus for comparison with the received address.

M40 and M48 are bidirectional bus driver arrays. The drivers for bus management lines: IFC, ATN and REN are permanently held in Receive state, and the SRQ driver in Transmit state. The EOI line driver is switched from Receive to Transmit by M29-28 (T/R1) changing from 0V to +5V as required by M29. M29-7 (T/R2) is normally held at 0V for reception of system data via DIO 1 - 8 bus lines, and set to +5V for 4000 data to be sent over the bus.

Some system controllers output excessive noise along the $\overline{\text{REN}}$ line. To avoid spurious switching of M29 between Local and Remote control states, R58 and C31 act as a filter for this noise.

M29-40 $\overline{(IRQ)}$ is used to inform the CPU when certain states occur. In particular, \overline{IRQ} is generated at each byte-transfer over the bus, whether the type is sent or received. Additionally, \overline{IRQ} is activated whenever certain specific commands are received, e.g. DCA, SPA and Remote/Local Change. When the CPU receives \overline{IRQ} , it addresses M39's Interrupt Status Register to identify the reason via the instrument data bus.

For further information refer to "Getting Aboard the 488 bus" published by Motorola, or the appropriate device data sheets.

4.3 KEYBOARD

The circuitry described in this section performs the following functions:

- (1) Provides front-panel operator control of 4000 Output, Function, Range and Mode circuitry, by push-button keys. Key operation is detected internally and transferred to the CPU via the instrument data bus.
- (2) Indicates the current instrument state by means of LEDs fitted in the Keys.
- (3) Generates audible warning of high voltage at the Output Terminals.

In addition a rocker switch sets instrument Power ON and OFF (refer to Section 4.11) and a "Safety Reset" Key provides a hardware reset for the safety monitor (Watchdog) circuits (Refer to Section 4.5). The circuitry is located on the Front PCB Assembly (400441), linked to the CPU by control signals and the data bus.

Circuit Diagram No. 430441 sheet 1 shows the arrangement and interconnections of the Keyboard circuits.

4.3.1 Key and LED Matrices (Circuit Diagram No. 430441 sheet 1)

The keys are electrically arranged in a 7×8 matrix as shown in the diagram. The 7 columns are scanned by M5; any key contact is memorised by M6 and signal KBIRQ is passed to the microprocessor, which responds by interrogating M6 Keyboard memory and acting on the specific key command.

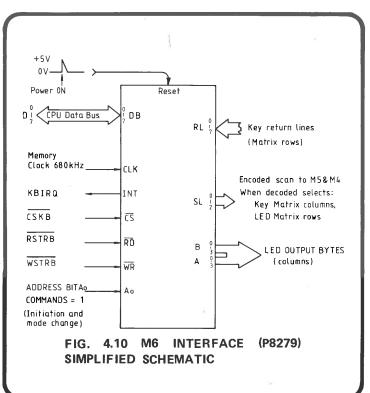
The key LEDs are electrically arranged in an 8×3 matrix. The three rows are scanned by M4, and the 8 columns receive the appropriate bit patterns from M6 display memory. This memory is up-dated as required from the microprocessor data bus $D_0 - D_7$.

4.3.2 Programmable Interface M6 (Fig. 4.10)

M6 interfaces the keyboard and LEDs to the instrument data bus. It is addressed by \overline{CSKB} from the digital assembly, to chip-select \overline{CS} which enables commands or data to flow via the data bus at DB_{0-7} . For data flow, the processor address Ao = logic-0 and for programming the interface during initialisation or for mode change, A0 = logic-1.

4.3.2.1 Read/Write Control

The \overline{WSTRB} signal from the digital assembly is applied to M6 \overline{WR} . Data or Command is input to M6 from the processor data bus during \overline{WR} low and \overline{CS} low, and is latched on the \overline{WR} positive-going edge. The \overline{RSTRB} signal from the digital assembly is applied to M6 \overline{RD} . Data is output from M6 on to the data bus during \overline{RD} low and \overline{CS} low.



4.3.2.2 M6 Initialisation

When the 4000 is switched on, M6 is cleared by the PWR ON RESET pulse from the digital assembly. The interface is then programmed during initialisation as follows:

to ÷8

Clock divider set — The memory clock (E) at approx. 680 kHz is divided by 8 to give internal clock frequency of 85kHz, inherent division by reduces the scan clock to 5kHz giving a scan cycling frequency of 333Hz.

Encoded Kevboard Scan

The scan output from SL₃₋₀ is a 4-bit binary count. SL_3 is not used; SL_{2-1}

scans M4, and SL2-0 scans

Keyboard Mode - The internal keyboard RAM is programmed as FIFO, input via RL₇₋₀ return lines. Twokey lockout is employed with debounce.

Display Mode

 8 Character left entry for the LED display.

 Inter-digit blanking: all 1's on B_{0-3} , A_{0-3} between digits.

4.3.2.3 M6 Reprogramming

The 13 dual ↑/↓ keys and the zero key (below the two displays) have a reprogramming function. When one of these keys is pressed, the P8279 is reprogrammed into Scanned Sensor Mode. When released, the P8279 reverts to Encoded Keyboard Scan Mode,

4.3.3 Scan Decoding

The encoded scan output from M6 (approximately 333Hz cycle frequency at SL2-0) is decoded by M5 to energise each key-matrix column line once every scan

cycle. SL_{2-1} scan outputs are also decoded by M4 to energise each LED-matrix cathode driver once in every scan cycle for a period of two digits.

4.3.4 **Key Selection**

The keys are electrically grouped within a matrix of 8 rows of 7 (some positions vacant). This does not conform to their physical grouping on the front panel. The eight return lines RL₀₋₇ each define a row in the matrix whose columns are scanned by M5 (Low active). In M6, the internally-synchronised keyboard memory stores the state of each of the 48 keys. The use of 2-key lockout rejects two or more simultaneous contacts. Any single key depression is debounced, initiating the interrupt KBIRQ to the processor which interrogates the keyboard RAM. The next action is dependent upon the Key's function:

> 'Zero' or 1/↓ key pressed

- a) M6 is reprogrammed into Scanned-Sensor mode for as long as the key is pressed, as the processor acts on the key informa
 - b) If an appropriate 1 key is pressed whilst 'Zero' is held down, the resolution of the Output display is changed.

- c) If a single ↑ or ↓ key is held down longer than approximately 1/2 second the display enters "auto increment/decrement" mode, running at approximately 6 digits/second.
- d) When the key is released, M6 is returned to Encoded Keyboard Scan mode.

Any other key pressed (not Safety Reset)

- a) M6 remains in Encoded Keyboard Scan mode; the scan continues as the processor acts on the key information.
 - b) KBIRQ interrupts are generated only by the lowgoing edges of the key contact pulses, so M6 remains sensitive to other key depressions.

4.3.5 **Key LED Operation**

After performing the change requested by the key depression, the processor changes the bit-patterns stored in M6 internal display RAM. As this is scanned internally in synchronism with the decoded outputs of M4, each output byte of B₀₋₃ A₀₋₃ drives the row of LEDs accessed by M4 output lines.

The bit-pattern of the byte selects the LEDs to be lit in that row (B_{0-3}, A_{0-3}) bits high = unlit, low = lit). As B_{0-3} A₀₋₃ lines change from one byte to the next, they are all set high to avoid spurious LED flashes. Q25-32 drive the LED anodes from a +5V supply regulated by M2, and Q21-23 Darlingtons drive the LED cathodes.

4.3.6 Audible Warning Buzzer

M4B and M1 act as a control latch for the quartz warning buzzer. With \overline{ALARM} at logic-1 (+5V) M1 remains unchanged; but with \overline{ALARM} at logic-0 (0V) the state of M1 depends on the condition of Ao:

Ao at logic-1 the alarm sounds a 4kHz tone.

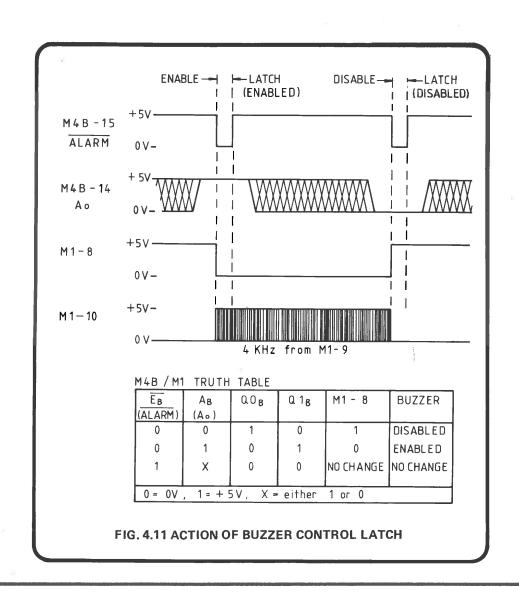
Ao at logic-0, the alarm is silent

The latch is operated at processor speed. Two ALARM pulses are used for each burst of sound. The first, with Ao at logic-1, starts the burst; and the second, with Ao at logic-0, ends it. The waveforms and truth table in Figure

4.11 illustrate the action of the latch. Note that Ao may be used for other purposes when ALARM is at logic-1, but this will not affect the buzzer state.

During Power ON initialisation the combination: $\overline{ALARM} = 0$, Ao = 0 are applied to M48 to ensure that the latch powers up in the Disabled condition.

The 4kHz tone signal at M1-9 originates in the precision-divider counter on the Analogue Interface pcb (Circuit Diagram No. 430443 sheet 1).



4.4 DIGITAL DISPLAYS

The circuits described in this section perform the following functions:

- Storage of display data in a Display Image RAM, updated under CPU control.
- (2) Generation of a multiplex count which selects segment data from the RAM, and energises the appropriate digital blocks in synchronism.
- (3) Distribution of high voltage supplies to energise the plasma displays.

Part of the Digital PCB Assembly (400442) houses the display multiplexer, which includes the display image RAM, the interdigit and multiplex counters, and control circuitry.

The two plasma displays, the block multiplex decoder, segment drivers and high voltage circuits are located on the Front PCB Assembly (400441). Figure 4.12 shows the arrangement and main interconnections of the display circuitry.

4.4.1 General (Fig. 4.12)

Basically, the Display Image RAM stores the current display data, which is read out to drive the display segments. A Display Block Counter generates a 4-bit count at 2kHz which scans the 11 digit-blocks of both displays in parallel. The same count scans the RAM, selecting segment information for each block in turn. As there are two displays, and therefore two RAM bytes to read for each block, the Mode display data is first entered into a holding latch during the inter-digit blanking period before its block is selected.

To update the displayed characters, the CPU writes into the RAM at high speed (680 kHz), using signal XDDSP to connect the Address bus through the Address Source

Switch to the RAM. XDDSP also connects the Data Bus to the RAM through the Data Bus Buffers, writing the new segment data into the selected RAM Address. The high transfer speeds avoids spurious effects on the displays.

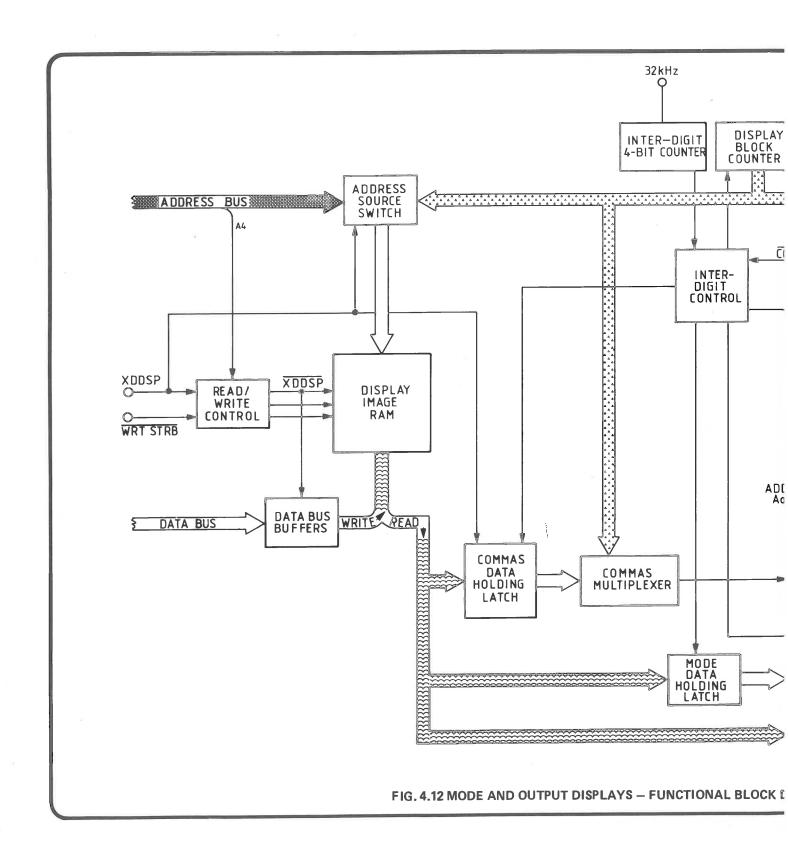
Each RAM address contains only 8 bits, but there are nine segments in each display block. Comma-segment information is therefore not written into its normal block address in the RAM, but stored as a bit in a separate "Comma" byte, which holds the data for all eight blocks which have a comma. The byte is read out into a Commas Data Holding Latch, once every block scan cycle, and then selected for display by a Commas Multiplexer 8-into-1 switch.

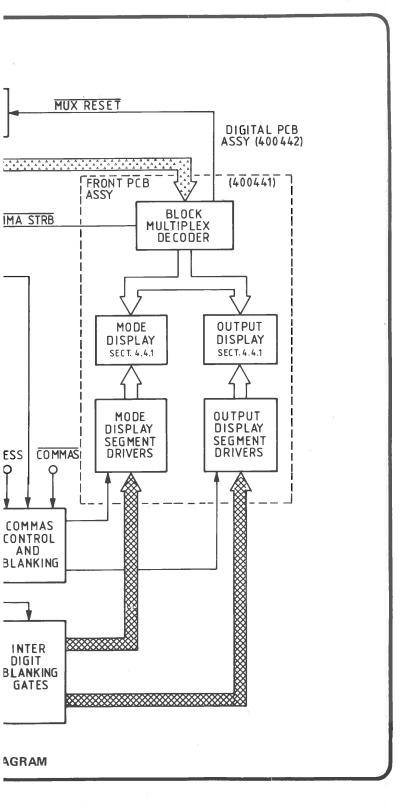
4.4.2 Static Conditions (Circuit Diagram 430441 sheet 2)

The plasma displays are driven from +5V (anode supply and -175V (cathode supply). The supplies are connected by conduction of anode driver transistors (Q10 - Q20), and cathode driver transistors (Q2 - Q9 and Q41 -Mode display, and Q33 - Q40 and Q42 - OUTPUT display).

When not selected, all anodes and cathodes are held at -70V by the action of 75V zener D17. When

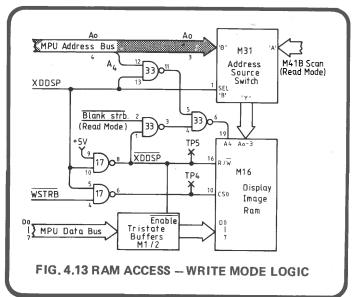
selected, a block anode driver conducts and lifts its two anodes to +5V. At the same time the segment cathodes selected for display are pulled to -175V by their cathode drivers, striking the discharge. Four keep-alive electrodes in each digit block (2 anodes and 2 cathodes) are maintained at +5V and -175V respectively. This ensures a rapid strike when a digit is energised, and helps to prevent inter-block "streaming".





4.4.3 Write Mode (Fig. 4.13)

Whenever the CPU has cause to update a display (e.g. Range, Function, Mode or Value change) it sets address decode XDDSP to logic-1 with each byte of data to be transferred. This causes M31 and M33 to select the



CPU address lines A_{4-0} which are mapped directly to the RAM address input lines A_{4-0} . The RAM is placed into its write mode by signal XDDSP at logic-0 (M17-8, TP5, M16-16)

The address line A_4 is used to differentiate between Output and Mode display images. If the CPU is loading the RAM with Output display data, it sets $A_4 = 1$, but for Mode or Comma display data, $A_4 = 0$ (M33-4 and 13 at Logic-1 in write mode).

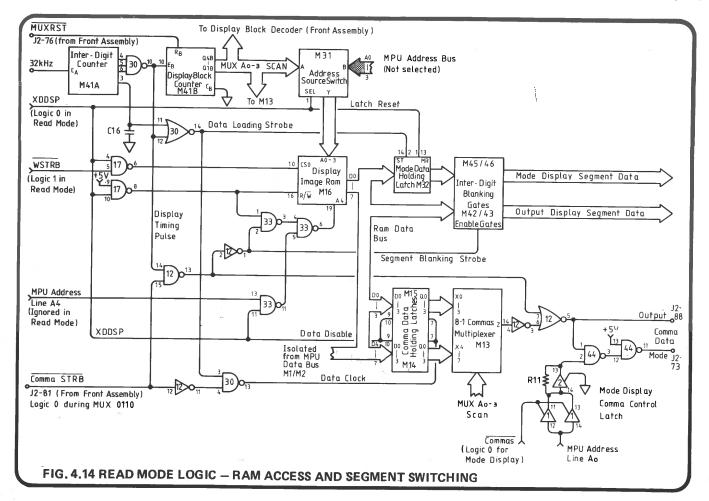
The two images are written into separate sections of M16 memory. (In read mode the A_4 input (M16-19) is again used to differentiate between the two image sections)

The signal XDDSP (M17-8) enables the tri-state buffers M1 and M2, connecting the CPU data bus to M16 data input/output lines D₀₋₇. The CPU also generates the write strobe signal WSTRB with each byte of display data. This is combined with XDDSP (M17-6, M16-10, TP4) to enable M16 internal Input/Ouput tristate buffers to accept the data byte (chip select CSO). Once the display data has been loaded into the RAM, XDDSP remains at logic-0, and the RAM reverts to read mode.

4.4.4 Read Mode (Fig. 4.14)

Unless the CPU has data to update, the signal XDDSP remains at logic-0, to hold the display multiplexer

circuitry in read mode. The RAM data bus is isolated from the CPU data bus by tristate buffers M1/M2 and M16 is chip-selected in read mode by M17-6 and 17-8 at logic-1.



4.4.4.1 Display Scan Address Interlacing (Fig. 4.15)

M31-1 (SEL) at logic-0 addresses the RAM from the display block scan, mapping M41B outputs: Q4B, Q3B, Q2B, Q1B to RAM address input lines: A_0 , A_3 , A_2 , A_1 respectively. This provides interlacing of the extracted data to synchronize with alternate block selection by the Front Assembly Scan decoder.

4.4.4.2 Block Multiplex Decoding (Circuit Diagram 430441 Sheet 2)

The 4-bit Block scan output MUX A_{3-0} from the multiplex scan counter M41B (dig) is used at DATA₄₋₁ input to M3, which decodes it into a low-active 16-line scan $S_{1.5-0}$.

 ${\color{red} {\rm M3~output~S_6~generates~the~comma~strobe~signal~} \over {\color{red} {\rm COMMA~STRB},~S_{13}~terminates~each~scan~by~resetting~} \over {\color{red} {\rm M41~B~(dig)~(MUX~RESET)},~and~S_{7},~S_{14}~and~S_{15}~are~not~used.} }$

The other eleven outputs from M3 switch Q10 — Q20 on sequentially, to drive the anodes of both plasma displays in synchronism. The anodes of both displays are activated alternately to prevent inter-block "streaming". Figure 4.15 details the interlacing sequence.

MUX	(A3-0 SCAN			M3 (Front Assy.)	
A ₃	A ₂	A 1	A ₀	M 3 Output (Low Active)	Energised Line
M ₃ DATA ₄₋₁ Input			nput	(LOW METTIC)	(Both displays' Anodes
D4	D3	D ₂	D1		and Signals)
M ₁₆ (Dig.Assy)A3-0 Input (Display Image RAM)					
A ₀	А3	A ₂	A1		
0	0	0	0	S ₀	A1
0	0	0	1	S ₁	A3
0	0	1	0	S ₂	A5
0	0	1	1	S ₃	A7
0	1	0	0	S ₄	Α9
0	1	0	1	S ₅	A11
0	1	1	0	S6	COMMA STRB
0	1	1	1	S ₇	Not used
1	0	0	0	S ₈	A ₂
1	0	0	1	S9	A4
1	0	1	0	S ₁₀	A6
1	0	1	1	S ₁₁	AB
1	1	0	. 0	S ₁₂	A ₁₀
1	1	0	1	S13	MUX RESET
1	1	1	0	S14	Not included in cycle
1	1	1	1	S ₁₅	(MUX RESET at S ₁₃)

FIG. 4.15 DISPLAY SCAN ENERGISING SEQUENCE

4.4.4.3 Output and Mode Display Data Selection

When the processor writes display data into the Display Image RAM, the A_4 input is used to select the "Mode" or "Output" data storage area. In read mode, A_4 is set to logic-1 for the "Output" data memory and to logic-0 for "Mode" or "Comma" data. At any instant, 18 bits of data are required for the display:

One byte for the Output display block segments One byte for the Mode Display block segments Two bits for commas The problem of transferring two bytes of data along the single-byte RAM data bus is overcome by strobing each Mode display segment byte into a holding latch (M32), during the first $30\mu S$ of its block selection period. The mode display section of the RAM is selected by setting its A₄ input to Logic-0 for this 'Inter-digit' period, during which the inter-digit blanking gates (M2/43, M45/46) set all segment lines to the Front Assembly at logic-0 (segments OFF). Commas are stored as a separate byte as described in section 4.4.4.6.

4.4.4.4 Display Timing (Fig. 4.16)

Read mode is driven by a 32kHz square wave (Waveform 'A', generated from the 13-bit counter in the Analog Interface Assembly M15-16), used as clock for a 4-bit counter (M41A). The three most-significant bits are combined at M30-10 to produce Waveform B, the display master-timing pulse, used also for Inter-digit blanking.

The following example explains how the display data is set up for the next display block in sequence, during the $62.5\mu Sec$ of the display timing pulse.

Example: M41B count has already reached 1001, and the block 4 anodes of both displays are energised (Fig. 4.15). The Output display data for block 4 is selected in the display image RAM (M16) to drive the segment cathodes for a figure "6", which appears on the output display. Block 4 of the mode display is showing a figure "3", and the data for this is being output from the Mode display holding latch (M32). The data held

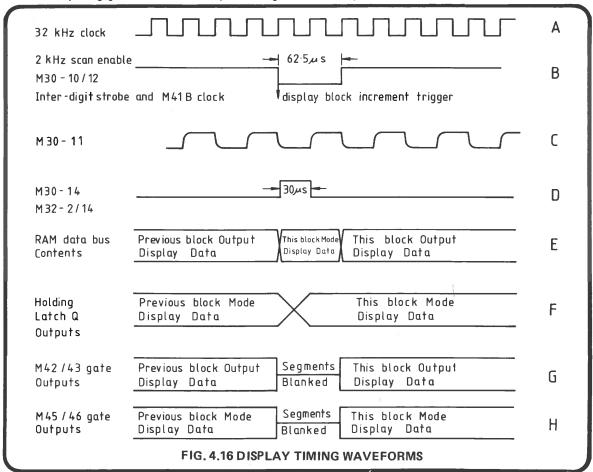
in M16 for the next byte (Block 6 of both displays) is: Figure "8" (output display) and figure "7" (mode display). The changeover to the next block occurs during the display master timing pulse (Fig. 4.16, Waveform B).

- (a) The negative-going leading edge triggers the scan counter (M41B) whose output advances to 1010 (block 6). On the Front Assembly, M3 de-energises A₄ anodes and energises A₆ anodes.
- (b) For the duration of the display master timing pulse (Logic-0 at M12-14), the A_4 input to M16 is set to logic-0 as A_{3-0} inputs are advanced to 0101. Mode display data for figure "7" is loaded onto the RAM data bus as follows:
 - (i) M17-6 at logic-1 chip-selects M16 at M16-10,

- (ii) M17-8 at logic-1 holds M16 in Read mode,
- (iii) RAM address A₄₋₀ = 00101 loads block 6 Mode display data byte onto the RAM data bus (M1/M2 isolates from the CPU data bus),
- (iv) M30-14 at logic-1 strobes the byte into M32 during the $30\mu S$ of waveform D, then returns to logic-0 leaving figure "7" data latched at M32 output
- (v) M12-1 at logic-0 blanks the two displays by setting M45/M46/M42/M43 outputs at logic-0, regardless of their inputs from M32 and the RAM data bus.
- (c) The positive-going edge of waveform B lifts the RAM A_4 input (M16-19) to logic-1, addressing the Output display section of memory. A_{3-0} is still at 0101, selecting

block 6 display data (in our example a figure "8"), which it loades on to the RAM data bus. The end of the master timing pulse also releases the blanking by enabling M42/43 and M45/46, so the display data for both Mode and Output displays are now delivered to the correct cathode drivers on the Front Assembly, to strike the gas discharge in the two blocks A₆. This condition persists for 437.5µS until the next master timing pulse, when waveform B repeats the process for the next block of stored display data.

At any time during the cycle, the CPU can re-activate write mode. This does not disturb the scan from M41B, but XDDSP resets M32 outputs to logic-0 (M32 - 1/13). The speed of byte transfer from the CPU ensures that spurious information is not visible on the Output display, but each display will follow its new stored data.



4.4.4.5 Display Segment Drive

The strobed segment signals from the Digital assembly are input to the Front Assembly on J1 - 67 to J1 - 75 (MODE display) and J1 - 82 to J1 - 90 (OUT-PUT display). These are already synchronised to their blocks by the 4-bit block scan MUX $\rm A_{3-0}$ within the Digital assembly.

For each block in sequence, the appropriate segment bit-pattern is set at the input to the segment drivers. For bits at logic-1, the rise is passed through line capacitors to reverse-bias DC restoration diodes and forward bias their driver — transistor bases. The resultant collector currents pull the segment cathodes from their quiescent

-70V, to -170V. The correct block anode is simultaneously lifted from -70V to +5V by its anode driver transistors, striking the gas discharge and displaying its digit. For bits at logic-0 the cathode drivers remain cut off.

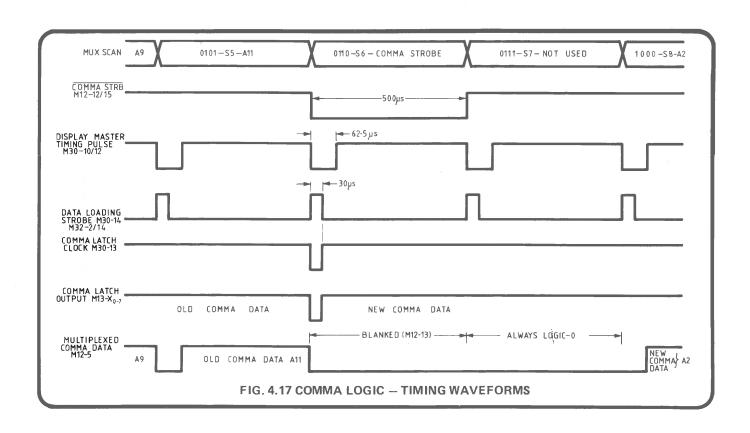
The driver emitter resistors control the segment cathode currents for uniform brilliance.

During changeover between blocks, all segment inputs at logic-1 are returned to logic-0 by the inter-digit blanking strobes M42, 43, 45 and 46 (dig). This turns off the drive transistors and blanks the display. As the scan frequency is high enough, the blanking is not observed on the display.

4.4.4.6 Comma Logic (Fig. 4.17 and Circuit Diagram No. 430442 Sheet 1)

The comma is the ninth segment (i) in each of the numerical display blocks. It cannot fit into a block's byte in memory, as there are only eight bits per byte. Although there are nine numerical blocks, the ninth block does not require a comma, and segment i in blocks A_{10} and A_{11} are not connected. So the full comma information (8 bits) can therefore be stored in a single byte of memory in the RAM. (RAM address 01100). This is updated by the CPU in write mode, and is read out (as though it were

another display block) by M41B scan 0110 during the master display pulse (waveform B sets RAM A_4 input to logic-0). The same MUX combination 0110 selects S_6 output from M3 decoder on the Front Assembly, which sets the signal COMMA STRB to logic-0. Thus for the duration of $S_6=0$ (500 μS), the common data is on the RAM data bus but the blanking gates prevent it reaching the display segments a-h.



4.4.4.7 Comma Drive Multiplexing

Signal COMMA STRB is also inverted and combined with the Data Loading Strobe at M30-13 as a logic-0 pulse, whose positive-going edge clocks the comma data into latches M14/15, approx. $30\mu\text{Sec}$ after it has been loaded on to the RAM data bus. The permanently-enabled outputs from these latches are input as X_{0-7} into the 8-into-1 multiplexer M13 for a complete MUX scan until the next $\overline{\text{COMMA STRB}}$ signal. The block-multiplex scan from M41B selects the correct X input to synchronise with activation of its display block anode. This is output from M13-14 (Z), into blanking gates M12. Comma information is blanked during $\overline{\text{COMMA STRB}}$ and by inter-digit blanking during display-block changeover (M12-7). The comma drive line, from M12-5 to the front panel via J2-88, controls segment "i" cathode driver for the Output display. If

commas are required on the Mode display (e.g. in "Offset" Mode) they are always in the same display blocks as the Output display. The CPU pulses the COMMAS line to logic-0 at the same time as Address line A₀ goes to logic-1. Tristate buffer outputs M1-11 and 13 go to +5V, setting M2-13 output to +5V (logic-1). Outputs M1-13 and 11 go tristate when the COMMAS line returns to logic-1, leaving M2-13 latched to +5V by the positive feedback action of R11. So M44-2 enables the comma data to the Mode display segment driver via J2-73 to copy the Output display commas on to the Mode display. When mode display commas are not required, A₀ is set to logic-0 (0V) with COMMAS signal at logic-0. In this case M2-13 is latched to logic-0 and M44-2 disables the flow of comma data to the Mode display.

4.5 ANALOG CONTROL INTERFACE

The circuitry described in this section performs the following functions:

(1) Provides a two-way interface via a serial data link between out-guard digital processing and in-guard analogue control circuitry on the reference divider pcb. (See Fig. 4.18)

(2) Monitors the CPU operation, serial transfer, digital supply failure and restart operations (watchdog), imposing a controlled safety default condition if there is a danger of losing digital control of the analogue functions.

A manual reset of the safety monitor is provided on the front panel. (See Fig. 4.21)

4.5.1 General

Safety and Control information is input from Digital (400442) and Front (440441) Assemblies to outguard circuits located on the Analogue Interface Assembly (400443), processed and transferred across the "Guard" isolation barrier to in-guard circuits in the Reference Divider Assembly (400444). After further processing in the Reference Divider Assembly, safety and control information

is output to the DC Assembly (400445), I/Ω Assembly (400448) and PA (DC) Assembly (400449).

Certain selected "Status" signals, originating in the analogue assemblies, are returned to the CPU during the data transfer. Thus, the data link forms a forward and return loop, as illustrated by Fig. 4.18.

4.5.2 Serial Data Transfer (Fig. 4.18 and Circuit Diagrams Nos. 430442 Sheet 2, 430443 Sheet 3, 430444 Sheets 4 and 5)

A bi-directional serial data link passes information across the guard isolation screen; conveying instructions from the CPU to control the in-guard analogue circuitry, and transferring critical status signals from the guarded circuits back to the CPU. The link is managed by a synchronous serial data adapter (SSDA) which, having first been loaded with three bytes of control instructions by

the microprocessor; transmits the resultant 24-bit word across guard one bit at a time, via its Tx DATA channel. The 48 bits necessary to control the analogue circuitry thus require two successive 24-bit transmissions. Simultaneously with each 24-bit transmission, the SSDA receives a 24-bit word via its Rx DATA channel, enabling the CPU to obtain the status of the analogue functions.

4.5.2.1 The Transfer Cycle (Fig. 4.18)

The CPU uses an address-code signal AN I/F STRT to initiate each 24-bit shift, by triggering a separate clock generator (M2, M3, M4) which produces a burst of 24 clocks per shift. Data is clocked in a serial string through the 48-bit, serial in/parallel out, analogue control shift register; through the 16-bit, parallel in/serial out, status shift register; and back to the SSDA receiver interface in a continuous loop. The serial data string is correctly located after two 24-bit shifts, so then the SSDA generates a strobe pulse which:

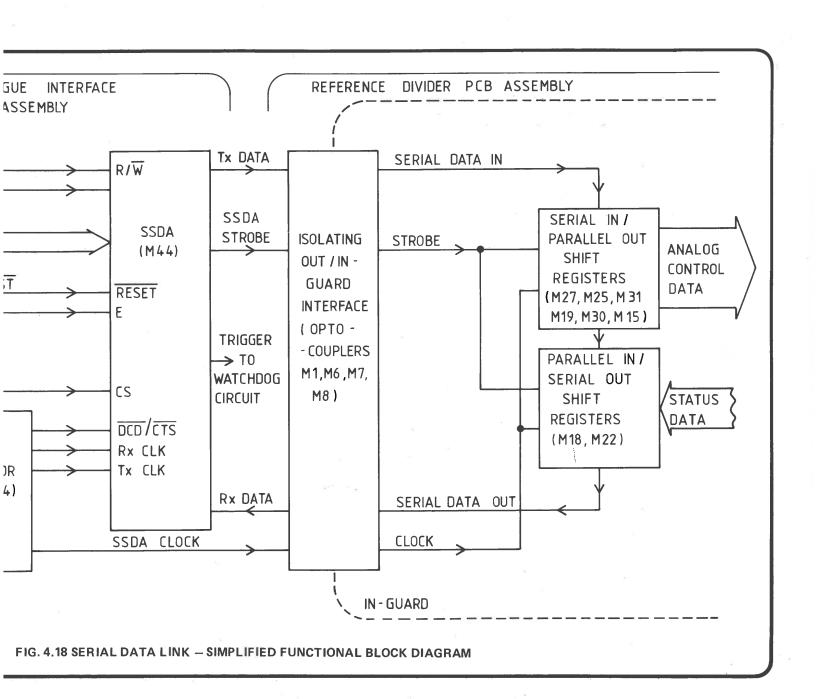
- (1) Latches the data present in the serial data string of the six 8-bit analogue-control shift registers (M27, M25, M31, M19, M30, M15) into their enabled parallel output registers and onto the analogue control bus.
- (2) Injects the status data at each of the parallel inputs of the two 8-bit status shift registers (M18, M22) into corresponding locations in

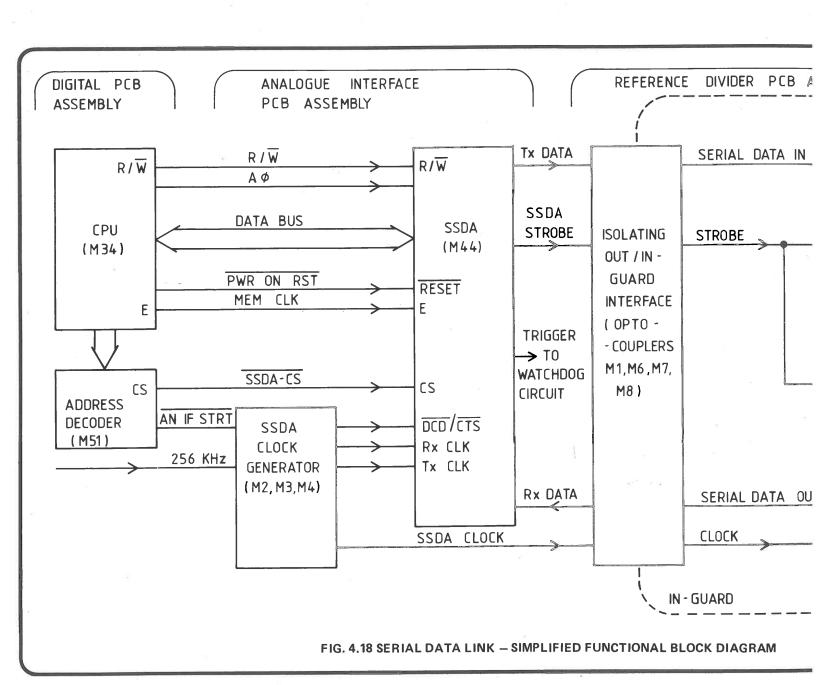
the serial data string. When the strobe ends, the parallel inputs to the status registers are disabled.

After the strobe pulse, the CPU initiates a further circulation of serial data (including the status data); in order to confirm that the data latched onto the analogue control bus was without error, and to obtain the status data. This requires three more 24-bit shifts, so a complete data transfer consists of five shifts if no error is detected.

If an error is detected on the first transfer, the CPU activates a second, and then a third transfer if an error is detected on the second. If the error persists after the third transfer, the instrument will shut-down under the control of the watchdog safety monitor. With no error, the SSDA provides a trigger-enable to allow updates to the watchdog circuits.

All interfacing between out-guard and in-guard circuits is achieved using electrically-isolating opto-couplers.





4.5.2.2 Data Transfer Organization (Fig. 4.19)

Data is transferred serially via the SSDA, control registers and status registers under the control of the CPU. The exchange of data between the CPU and SSDA is made on the 8-bit instrument data bus, each exchange comprising three bytes (24 bits) of data. The serial shifts of data are synchronized by clocks which are controlled from the CPU, and the SSDA receiver registers are cleared when read by the CPU. Transfer of the serial data to the parallel outputs of the control registers, and transfer of status data

from the parallel inputs of the status registers to the serial data string; is enabled only when a strobe is generated by the SSDA. The transfer operation requires five serial data shifts, each of three bytes, through the registers. During this operation: the control registers are loaded with bytes of new data (ND); the status registers are loaded with new status data (NS); and the whole of the ND and NS data is returned to the CPU. The CPU verifies that the data transfer has been made with no error and acts upon the status data received.

4.5.2.3 Transfer Sequence

The sequence of events in the transfer operation is as follows, refer to Fig. 4.19:

- (A) Three bytes of new data, ND1, 2 and 3 are loaded into the SSDA transmitter registers; this data is destined for control registers D1, 2 and 3. The SSDA receiver registers were cleared when last read by the CPU.
- (B) A burst of 24 clock pulses, initiated by the CPU, shifts all data three bytes to the right. After the shift is completed, the transmitter registers are loaded with new data bytes ND4, 5 and 6 (destined for control registers D4, 5 and 6). During this period, no transfers are made between the serial data string and the parallel control or status registers.
- (C) A second burst of 24 clock pulses again shifts all data three bytes to the right. New data bytes ND1 to 6 are now correctly positioned in control registers D1 – D6. After completion of the shift, three dummy bytes are loaded into the transmitter registers. Old data (OD) in the receiver register is ignored.
- (D) With new data bytes ND1 to 6 correctly located, the SSDA generates a strobe pulse. This pulse:
 - latches the 48 bits of bytes ND1 to 6 at the parallel outputs of control registers D1 to 6;

- (2) enables the parallel inputs of status registers S1 and 2, loading two new status bytes NS1 and 2 and clearing old data OD5 and 6 from the registers.
- (E) A third burst of 24 clocks again shifts all data three bytes to the right. The CPU reads bytes NS1, NS2 and ND1 from the SSDA receiver registers (the CPU may take immediate action on NS returns). After the shift is complete, new data bytes ND1, 2 and 3 are re-loaded into the transmitter registers.
- (F) A fourth burst of 24 clocks again shifts all data three bytes to the right. The CPU reads bytes ND2, 3 and 4 from the receiver registers. After the shift is complete, new data bytes ND4, 5 and 6 are re-loaded into the transmitter registers.
- (G) A fifth burst of 24 clocks again shifts all data three bytes to the right. Bytes ND5 and 6 are read from the receiver registers. The CPU has now read all new data and status bytes and the transfer sequence ends. If an error is detected between new data transmitted and new data received, the transfer process is repeated; three attempts are allowed before a fault condition is declared.

4.5.3 Synchronous Serial Data Adaptor (Circuit Diagram 430443, Sheet 3)

4.5.3.1 SSDA Initialization

When power supplies are first switched-on or an external reset EXT RST is applied, the signal PWR ON RST is held at logic-0 for approximately 8mS. During this period, the SSDA is latched in a reset condition to prevent erroneous output transitions at its Tx and Rx interfaces; the internal transmit registers are inhibited to prevent the loading of data from the data bus and the SSDA strobe output is held at logic-1. After PWR ON RST returns to logic-1; the latches, registers and SSDA strobe are cleared in software, during the initialisation routine.

4.5.3.2 Parallel Data Input from CPU

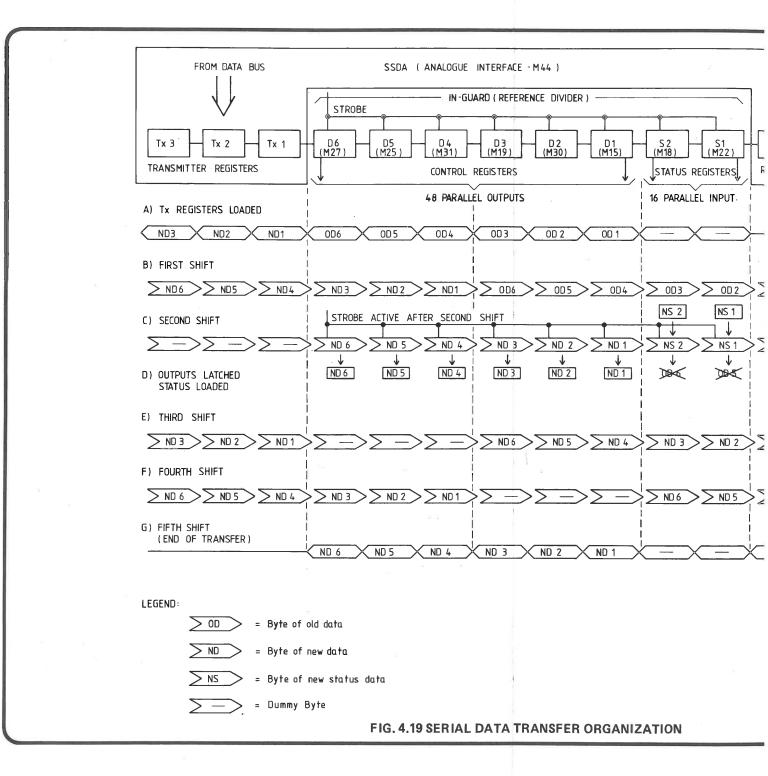
The conditions for parallel data on the data bus to be accepted by the SSDA are as follows:

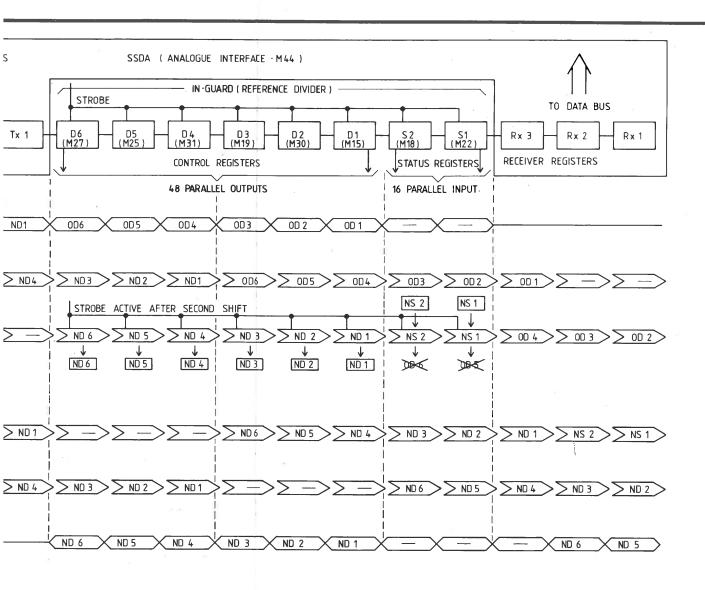
- (1) Chip-select SSDA CS at logic-0.
- (2) Read/Write command R/W at logic-0. This

- controls the direction of data flow via the Data Bus through the SSDA input/output port. When R/W is at logic-0, data on the Data Bus is written into a selected register within the SSDA.
- (3) The memory clock "MEMCLK" 682.6 kHz square wave is present to synchronise the SSDA operating cycle to that of the CPU.

With input conditions present as above and register address bit $A\phi$ at logic-1, the SSDA accepts data from the data bus into an internal 3-byte FIFO register. The data is entered over several MEMCLK cycles and stored in the FIFO register in readiness for serial transmission from the SSDA.

Software programming of the SSDA is performed when the address bit $A\phi$ is at logic-0. For details of "Control Byte" operation, refer to Motorola 6852 data sheet.





Byte of old data

Byte of new data

Byte of new status data

Dummy Byte

FIG. 4.19 SERIAL DATA TRANSFER ORGANIZATION

4.5.3.3 Parallel Data Output to CPU

The conditions for data to be read from the SSDA on to the data bus are as follows:

- (1) Chip select SSDA CS at logic-0.
- (2) Memory clock, MEM CLK, present.
- (3) Read/Write command R/W at Logic-1.

The data read from the SSDA may be from one of two sources, selection being made by the address bit $A\phi$. With $A\phi$ at logic-1, received data from the serial data input FIFO is transferred to the data bus; with $A\phi$ at logic-0, an internal status register is read.

4.5.3.4 Serial Data Transmission

Serial data transmission is controlled by the CTS (clear to send) input to the SSDA. Transmission is inhibited by CTS at logic-1, and enabled when CTS is set to logic-0 by the CPU address-code signal AN I/F STRT. The first serial bit is transmitted by the negative transmission of the first full positive Tx clock pulse (256 kHz) after CTS has been set to logic-0. CTS is held at logic-0 by the AN I/F STRT latch for the duration of 24 full Tx clock pulses, thus enabling the serial shift transmission of the 24 data bits from the Tx Data FIFO in the SSDA.

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4.5.4

SSDA Clock Generation

Serial data is transmitted and received in bursts of 24 data bits. Three clocks are used to time the flow of bits, ensuring that:

- Data has time to settle before being clocked along the shift registers.
- (2) The first Rx data sample is taken before it is lost by the first bit-shift.
- (3) Subsequent Rx data has time to settle before being sampled by the SSDA.
- (4) Exactly 24 bits are shifted in each burst.

4.5.4.1 SSDA, Tx and Rx Clock Action (Fig. 4.20)

The three clocks are derived from the 256 kHz square wave output from the 13-bit counter (Circuit drawing No. 430443 sheet 2): The 256 kHz squarewave is used directly as "Tx clock" into the SSDA. The negative transition of the first full positive pulse after $\overline{\text{CTS}}$ is set to logic-0; triggers the first serial Tx data bit setup (Refer to Fig. 4.20 waveforms G and H).

"Rx clock" is an inverted version of the 256 kHz squarewave. The positive transition of the first full Rx clock cycle, after DCD is set to logic-0; triggers the SSDA to sample the first Rx data bit before the first SSDA clock has triggered the shift registers. (Refer to Fig. 4.20 waveforms K and J)

"SSDA clock" is also an inverted version of the 256 kHz squarewave. The inversion allows approx. 2mS of data setup time for all serial data bits prior to clocking the data along the shift registers. SSDA clock is gated at M2-3 by the action of M3-12 to ensure that the first Rx data is sampled before it is lost by the first bit-shift. 24 SSDA clock pulses are counted by M4, allowing 24 bits to be shifted before resetting AN I/F start latch M2-11 (TP3) to logic-1. (Refer to Fig. 4.20 waveform I).

4.5.3.5 Serial Data Reception

Serial data is received by the SSDA, controlled by the \overline{DCD} (data carrier detect) level and clocked by Rx CLOCK. \overline{DCD} is common to the transmit control \overline{CTS} so that transmission to, and reception from the serial/parallel shift registers is synchronous. Both Rx CLOCK and Tx CLOCK have the same frequency but Rx CLOCK is inverted with respect to the latter. The first bit arriving at its Rx DATA input is clocked into the SSDA Receive FIFO register on the positive transition of the first full Rx clock after \overline{DCD} is set to logic-0.

4.5.4.2 SSDA Clock Circuitry (Circuit Diagram 430443 Sheet 3)

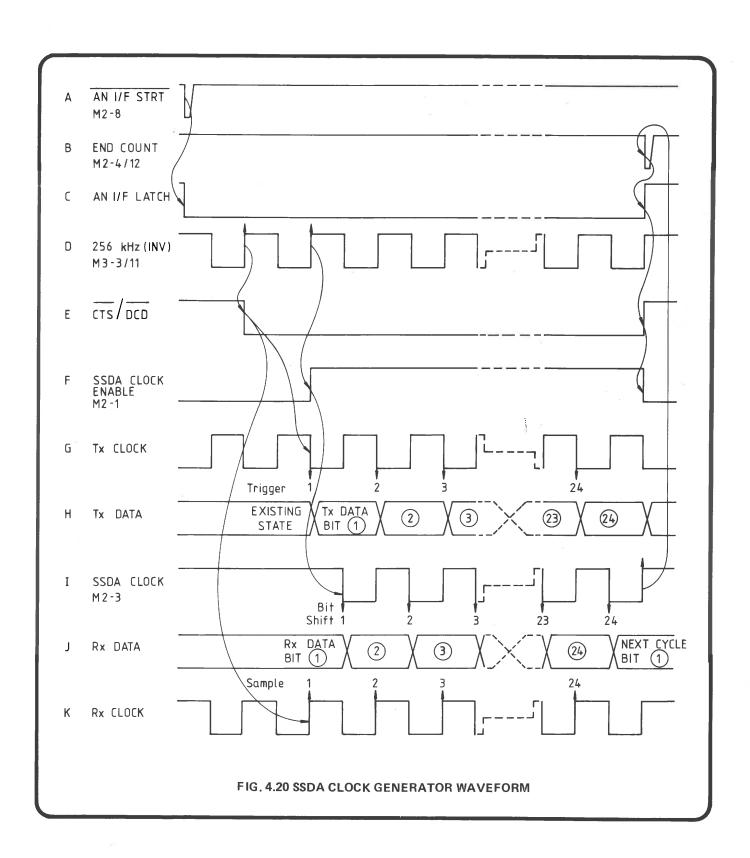
The following paragraphs describe the action of the SSDA clock generator circuitry.

The action of the SSDA clock generator is initiated by the command AN I/F STRT from the CPU. This occurs after the parallel data has been loaded into the SSDA transmit registers from the data bus. The logic-0 pulse of AN I/F STRT sets flip-flop M2-10/11 to give a logic-0 at TP3 which then:

- (1) Sets the D input level of flip flop M3-5;
- (2) Removes 'set' to enable flip-flops M3 at M3-6 and M3-8:
- (3) Removes 'reset' to enable counters M4 at M4-7 and M4-15. (Refer to Fig. 4.20 Waveforms And C)

At the next rising edge of the inverted 256 kHz (Rx clock) from M43-8 after AN I/F STRT, the two flip-flops M3 are clocked but only M3-1 "Q" output changes state to logic-0. This is applied to the SSDA CTS and DCD inputs, thus releasing the inhibits on the SSDA transmit and receive registers, (Refer to Fig. 4.20 Waveforms D and E). At the next (second) rising edge of the clock to flip-flop M3, M3-12 changes to logic-1. This allows NAND M2-3 to pass 256 kHz clock pulses via buffer M5-12 to the reference divider pcb for the analogue-control and status shift registers. (Refer to Fig. 4.20 Waveforms D, F and I). The 256 kHz clock at NAND M2-3 is applied to the 4-bit up-counter clock input at M4-1, each rising edge causing the counter to increment by 1. The divide-by-16 output M4-6 is applied to the enable input at M4-10; the falling edge of this output occurs at count-16 and increments the second counter to give, at M4-11, a logic-1 output. At count-24, M4-6 changes again to logic-1, and together with M4-11 output, gives a logic-0 from NAND M2-4, causing the following actions:

- (1) Flip-flop M2-12 is reset to give logic-1 at TP3.
- (2) The logic-1 at TP3 sets flip flops M3 to give: logic-1 at M3-1, thus inhibiting DCD and CTS; and logic-0 at M3-12, stopping NAND M2-3 passing any further SSDA clocks.
- (3) The logic-1 at TP3 resets the up-counters M4 causing: the counter outputs to fall to logic-0, inhibiting further counting; and NAND M2-5 to logic-1, pre-setting flip-flop M2-12 to prepare for the next AN I/F STRT input. (Refer to Fig. 4.20 Waveforms I, B, C, E and F).



4.5.5 Serial/Parallel Data Converter (Circuit Diagram No. 430444 Sheet 4 and Sheet 5)

Serial control data transmitted from the SSDA (Analogue Interface Assembly), together with its control signals (SSDA strobe and SSDA clock), enters the Reference Divider Assembly via the Mother pcb.

The data and signals cross the isolation barrier through opto-isolators M6, M7 and M8 into guard.

Serial control and status data is returned out of guard to the SSDA receiver via opto-isolator M1.

4.5.5.1 Logic Levels

The nominal logic levels used in the out-guard SSDA circuits (logic-1 = +5V, logic-0 = 0V) are offset at the opto-isolator outputs to logic-1 = 10V, logic-0 = 15V; and level-shifted to logic-1 = 0V, logic-0 = 15V for the in-guard circuitry.

4.5.5.2 Serial-in/Parallel-out Control-Data Converters

Six 8-bit serial shift registers M27, M25, M31, M19, M30 and M15 each have latchable parallel outputs. Their serial "D" inputs and "Q's" outputs are cascaded to form a single 48-bit serial shift register. M27 receives "serial data in" from M8 via level-shifting buffer M36-4, and M15 passes serial data on to the Parallel-in/Serial-out Status-Data converters.

4.5.5.3 Parallel-in/Serial-out Status-Data converters

Two 8-bit serial shift registers M18 and M22 each have parallel inputs. M18 serial "Ds" input accepts serial data from M15; M18 "Q8" output is cascaded to M22 "Ds" input; and M22 "Q8" output delivers "serial data out" to buffer M11-11 and back to the SSDA via M1 opto-isolator.

M18 and M22 thus form a 16-bit serial shift register whose 16 parallel inputs states can be inserted into the serial data string.

4.5.6 Safety Monitor (Watchdog) (Fig. 4.21)

The watchdog circuits provide a continuous monitor of the CPU/SSDA functional process. Detection of a processor malfunction by the watchdog results in the following actions:

BARK. This removes the 16 kHz power amplifier drive signal.

BARK. This is returned as a status bit to the CPU via the SSDA to signal a failure.

BARK DELAYED. This occurs 47mS after BARK and is used to switch the power amplifier into the low voltage condition.

BARK DELAYED. This disables the registers of the serial/parallel data converters.

The watchdog outputs are manipulated by the power-on reset circuits as follows:

- (1) BARK DELAYED and BARK DELAYED are held active for 80mS from power-on and then are allowed to the inactive state only after two SSDA strobes have been detected.
- (2) BARK is forced active until CPU/SSDA gunctioning has been verified; the latter must occur within 470mS of power-on.
- (3) BARK is held inactive for 470mS from power-

4.5.5.4 Serial Data Cycling

The serial data, organised in five blocks of three bytes (Refer to Section 4.5.2.2) is accompanied by synchronized bursts of 24 clock pulses. The latter are buffered from opto-coupler M7 via level-shifter M36-2 and then inverted at M14-6, to ensure that all bits of serial data distributed throughout the shift registers have had time to stabilise before being clocked on. Subsequent bursts of data and clock pulses continue under the control of the CPU until the six control registers M27, M25, M31, M19, M30 and M15 are filled with their correct data. A strobe from the SSDA now latches the data in the registers' parallel outputs and at the same time, enables the parallel inputs of status registers M18 and M22, allowing these two registers to fill with status bits. At the end of the strobe period, the parallel-serial status data transfer and serialparallel control data transfer are disabled.

The control and status bits in the registers are then circulated by further bursts of clock pulses, until the CPU has read the returned status bits and all the control bits that were latched at the control register outputs. Verification that the control data received was the same as the data sent ends the transfer.

If after three attempts the returned data does not match the transmitted data the CPU omits to retrigger monostable M10 on the reference divider pcb, which times out and allows BARK DEL to go to logic-0. This isolates the 48 parallel data outputs by "tri-stating" the registers M27, M25, M31, M19, M30 and M15.

4.5.5.5 Parallel Control-Data Outputs and Status-Data Inputs

The operation of these control lines is described in the sub-sections relevant to their destinations.

As this is a multi-purpose converter, designed for use in more than one model of instrument, some of the control lines are not used.

on, after which it provides a FAIL message to the CPU.

Operation of the Safety Reset control on the front panel provides a further 100 mS period for the CPU/SSDA functional process to settle, during which time the watchdog circuits must verify correct functioning before its outputs are reset.

The watchdog is tripped if a failure to transmit analogue-control updates to the analogue circuitry occurs. The updates are of two types:

Transfer of "Output value" data via the Analogue Interface comparators,

Transfer of analogue switching data via the SSDA every 40 mS.

The CPU generates pulses at 8 mS intervals to verify that the correct output value has been latched into the Analogue Interface comparators. These pulses are allowed to pass into guard only if the SSDA verifies that the analogue switching data is being transferred normally at 40 mS intervals. Once in guard, the pulses prevent the watchdog flip-flops from generating their four BARK and BARK DELAYED output signals; by re-triggering a monostable (M10-4:18 mS).

If two or more pulses are missing, M10 releases the hold, and the watchdog flip flops "Bark", activating the safety circuitry. They will be missing if the output value comparators are incorrectly updated, or if the SSDA fails to generate "Transmit" IRQ pulses for a period exceeding 220 mS, or if the CPU crashes.

The in-guard watchdog circuits are located on the Reference Divider pcb; the out-guard control signals originate in the Digital pcb and are processed in the Analogue Interface pcb.

4.5.6.1 Out-guard Watchdog (Circuit Diagram No. 430443 and 430444)

Each time the CPU verifies that an exchange of data performed via the serial link is valid, the CPU instructs the SSDA to generate a watchdog enable trigger. This pulse termed W.DOG ENBL SET, is used to trigger monstable M29-11 (circuit drawing No. 430443 Sheets 1 and 3). The relaxation period of this monostable is 220 mS but is extended by re-triggering to give a logic-0 W.DOG ENABLE output at M29-9. Absence of W.DOG ENBL SET triggers for a period exceeding 220 mS will allow M29-9 to return to logic-1 level. The W.DOG ENABLE level is inverted at M43-3 and applied to NAND M46-12.

During each processor cycle, the CPU decoded address at M51-9 (circuit drawing No. 430442 sheet 2) is gated with WRT STRB to give, at M49-11, the active-low output. W. DOG. The latter is fed via the mother pcb to the analogue interface, to be gated at NAND M46 with W. DOG ENABLE. The resulting output at M46-13, W. DOG, comprises positive-going pulses at 8 mS intervals when the CPU/SSDA system is working normally, or a logic-1 level if the SSDA has failed. The signal W. DOG is fed, via the mother pcb, to the in-guard circuits on the reference pcb.

4.5.6.2 In-guard Watchdog (Circuit Diagram No. 430444 sheet 5)

NOTE. The operating levels of the in-guard CMOS circuits are negatively displaced as follows (nominal voltages):

Opto-coupler output circuits

logic-1: -10V dc logic-0: -15V dc

Digital CMOS circuits

logic-1:0V logic-0:-15V

Interfacing between levels is performed by level-shifter M36.

The signal, W.DOG, is opto-coupled into guard via M9. During normal operation these positive-going 8 mS pulses trigger, and successively re-trigger the monstable M10-4 to give a continuing logic-0 at M10-7. The 18 mS relaxation time of the monostable allows for the absence of one pulse, but the absence of two or more pulses allows the monostable to reset, taking M10-7 to logic-1.

The logic level from M10-7 is applied to the set input of flip-flop M13-6. With reset M13-4 at logic-0 during normal operation, the output conditions of M13-1 and M13-2 are as follows:

- (1) Set input M13-6 = logic-0 (no fault); M13-1 (Q) = logic-0 - BARK not active M13-2 (Q) = logic-1 - BARK not active
- (2) Set input M13-6 = logic-1 (malfunction); M13-1 (Q) = logic-1 — <u>BARK</u> active M13-2 (Q) = logic-0 — <u>BARK</u> active.

The action of M13-2 changing to logic-0 triggers monstable M10-11, which has a relaxation time of 47 mS. After 47 mS, M10-9 output clocks flip-flop M13-11 to give the command BARK DEL from M13-13 and BARK DEL from inverter M14-12.

4.5.6.3 Power-on Reset (Circuit Diagram No. 430444 Sheet 5)

When power is first applied, the flip-flop latch circuit of M37 is forced to give a logic-0 output at M37-2 by R122/C7 holding the Reset inputs at logic-1 for approximately 80 mS, the Set input being at logic-0. M37-1 holds M10 inactive at M10-3, thus preventing random triggering at M10-4 from erratic W.DOG inputs whilst the SSDA/CPU function starts up. M37-2 imposes logic-1 at the Set input M13-8 of flip-flop M13. The Reset inputs M13-4 and M13-10 are held at logic-1 for a period of 470 mS from power-on by the action of the signal FP RST from the digital pcb. Therefore, the Set/Reset inputs M13-8/M13-10, initially both at logic-1, force M13-13 output to logic-1 to give active BARK DELAYED and BARK DELAYED outputs.

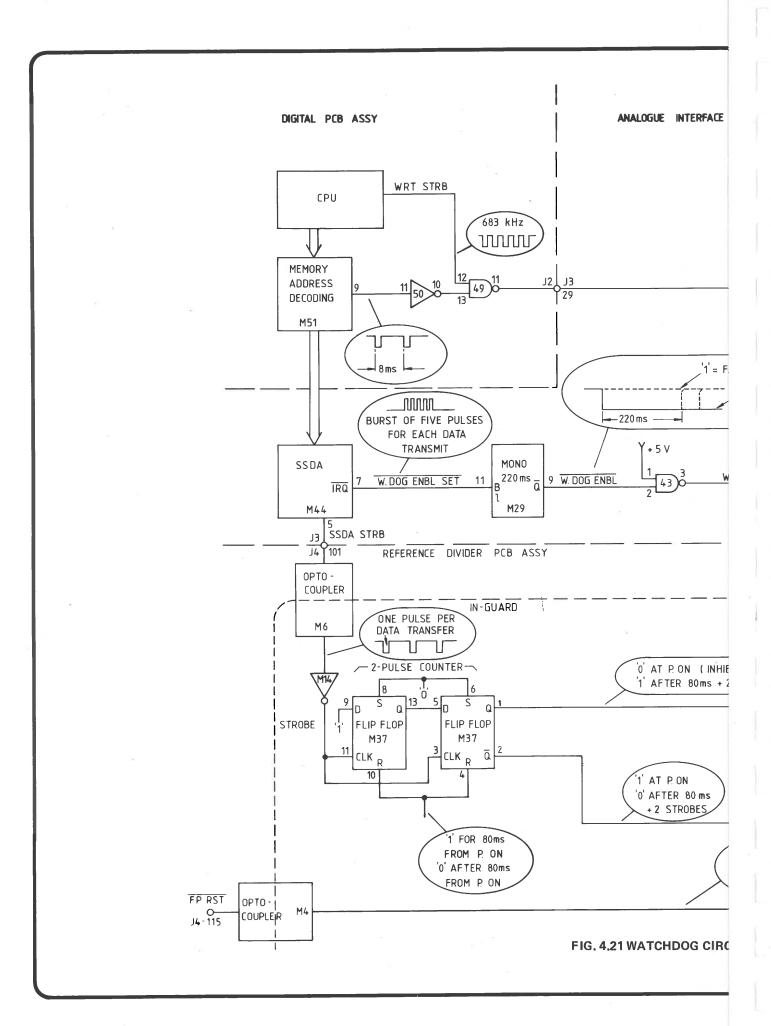
The Set/Reset inputs M13-6 and M13-4, also initially both at logic-1, force: M13-1 to logic-1 to give an active BARK output which inhibits the 16 kHz drive at M24-3; and M13-2 to logic-1 which makes the BARK output inactive.

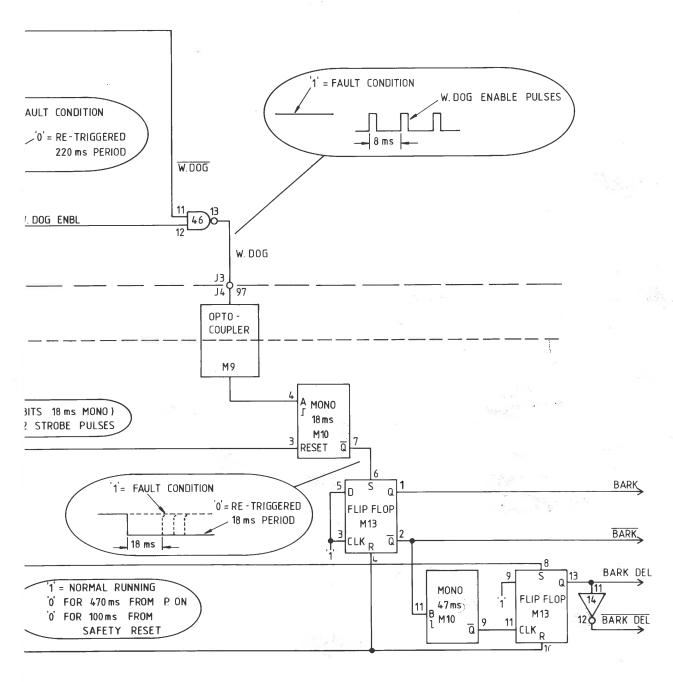
The output conditions of M37 (M37-1 = logic-0, M37-2 = logic-1) remain unchanged after the 80mS time constant at M37 Reset inputs, but then M37-11 is free to be triggered from the SSDA strobe input. Two strobe inputs must occur before M37-1 clocks to logic-1 and M37-2 to logic-0. M13-13 now changes to logic-0, making BARK DELAYED and BARK DELAYED inactive, and the inhibit is removed from M10-3.

The outputs M13-1 and M13-2 remain unchanged until M10-7 falls to logic-0 by the clocking action of pulses on the W. DOG input. This must occur before M13-4 returns to logic-0 (at 470 mS from power-on) for BARK to be made inactive, otherwise BARK remains active and BARK is set to logic-0, giving a fail status bit to the CPU.

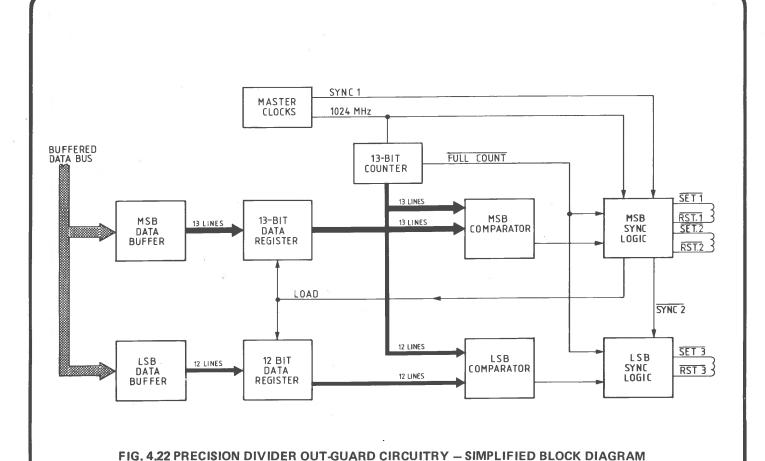
4.5.6.4 Safety Reset

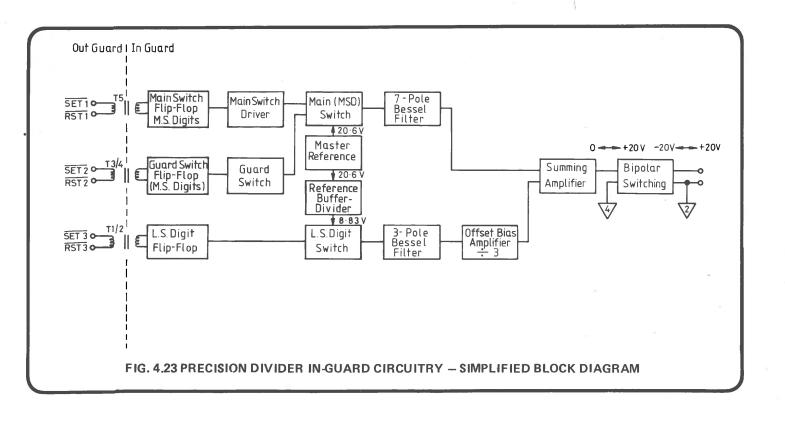
Detection of a failure by the watchdog circuits results in permanent activation of BARK, BARK, BARK DELAYED and BARK DELAYED. The watchdog can be reset, if the malfunction has cleared, by the operation of the Safety Reset control on the front panel. The safety reset input to the watchdog circuit, FP RST, is active for 100 mS from Safety Reset. (M53-9 on Digital Assembly — Circuit Diagram 430442 Sheet 2) During this period, the Reset inputs to M13-4 and M13-10 are held at logic-1 thus allowing correct pulse inputs from the processor and SSDA to hold M13-6 at logic-0, and to reset M13-13 to logic-0. The watchdog will not reset if the malfunction persists.





CUITRY - SIMPLIFIED BLOCK DIAGRAM





The out-guard circuitry described in this section performs the following functions:

- Receives the demanded output value from the CPU in the form of a 25-bit data word.
- (2) Generates a continuous 13-bit count from the 1.024 MHz Master clock (cycling frequency 125 Hz)
- (3) Compares the 13-bit count with the 13 mostsignificant bits of the 25-bit word, generating "Set" and "Reset" pulses, which are transferred into guard to trigger the Reference Divider Main and Guard JFET switches
- (4) Compares the 12 most-significant bits of the count with the 12 least-significant bits of the 25-bit word, generating "Set" and "Reset" pulses, which are transferred into guard to trigger the Reference Divider "Least-Significant" JFET switch.

The out-guard circuitry is located on the Analogue Interface PCB Assembly.

The in-guard circuitry performs the following functions:

- (5) Generates a Master Reference Voltage (20.6V) which is chopped by the Main and Guard JFET switches; to provide a square-wave whose Mark/Period ratio is controlled by the 13 most-significant bits of the 25-bit word. The square-wave is smoothed by a 7-pole Bessel filter to provide a D.C. voltage whose value varies directly as the Mark/Period ratio of the square-wave
- (6) Generates a Buffered Reference Voltage (8.83V) which is chopped by the Least-Significant JFET switch; to provide a squarewave whose Mark/Period ratio is controlled by the 12 least-significant bits of the 25-bit word. The square-wave is smoothed by a 3-pole Bessel filter to provide a DC voltage whose value varies directly as the Mark/ Period ratio of the square-wave.
- (7) Sums the two DC voltages produced by the 7-pole and 3-pole filters, to generate a "Working Reference Voltage" between 0V and +20V; whose value is accurately proportional to the value demanded by the CPU's 25-bit word
- (8) Switches the polarity of the Working Reference Voltage to output a reference voltage between -20V and +20V DC. This is used as reference on "DC" and "I" Functions of the instrument.

The in-guard circuitry is located on the Reference Divider PCB Assembly.

4.6.1 Precision Divider Comparators (Circuit Diagram No. 430443)

4.6.1.1 General

The precision divider comparators translate information from the central processing unit into time-related pulses which control the mark/period switching of the reference divider. Two comparators are used; one to translate the 13 most-significant bits of MPU data; the other, the 12 least-significant bits. The comparators perform concurrently, cycling continuously at 125Hz, taking 8mS per full count. During the initial stages of each counting period, the comparators generate SET pulses to start the reference divider mark period. After precisely-measured delay times, reset pulses are generated to terminate the mark period.

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4.6.1.2 Comparator Function (Fig. 4.22)

Binary data is entered into the MSB and LSB buffered data latches under the control of the CPU. The contents of the buffered data registers are up-dated to the working data latches at the end of each comparator counting cycle by the LOAD command. This is derived from the 13-bit counter FULL COUNT output, which is also used by the MSB and LSB synclogic circuits to initiate generation of the set pulses SET 1, SET 2 and SET 3.

Translation of the binary data into reset pulses (whose time relationship to the set pulses is established by the demanded output value) is obtained in the MSB and LSB comparators.

4.6.1.3 13-Bit (MSB) Comparator (Circuit Diagram No. 430443 Sheet 2)

The 13 Exclusive-OR elements of the MSB Comparator are scanned in ascending sequence by the outputs of the 13-bit counter. The least-significant bit has a frequency of 512 kHz, and the most-significant a frequency of 125 Hz thus giving a natural division of 8192 time slots of 977 nS over the counting period of 8mS. Each time slot has a unique binary code; when this coincides with the bit-pattern set in the data register, the comparator provides an output pulse to the MSB sync logic. The latter initiates generation of reset pulses RST 1 and RST 2 and synchronizes them to SYNC 1 (2,048 MHz).

4.6.1.4 12-Bit (LSB) Comparator (Circuit Diagram 430443 Sheet 1)

This functions in the same manner as the MSB comparator but with 12 bits over the same 8mS counting period. This accommodates 4096 time slots and gives a 1954 nS period for each binary increment. Synchronizing of the RST3 output from the LSB sync logic is performed by SYNC 2 pulses which are half the rate of the SYNC 1 pulses.

4.6.2 Comparator Circuit Action

4.6.2.1 Input Data Latches (Circuit Diagram No. 430443 Sheets 1 and 2)

The input buffered data latches M31 to M34 and M37 to M39 receive 27 data bits in four bytes from the buffered data bus. Latches are selected by signals REF DIV 1, 2, 3 or 4 from the memory address decoding on the digital pcb. Data is clocked to the "Q" outputs of the latches on the positive-going edge of WRT STRB.

Data from the input latches is used as follows:

25 bits form a data word to the comparator registers M47, M48, M49 (part), M51 and M52. One bit triggers monostable M29 (part), the Q output of which is inverted and buffered to provide the control UPD (OG) used in the relay drive logic for analogue switching. One bit, EXT FREQ ÷ 10, is not used in the 4000.

4.6.2.2 13-Bit Counter (Circuit Diagram No. 430443 Sheet 2) (refer to Fig. 4.24 for Waveforms)

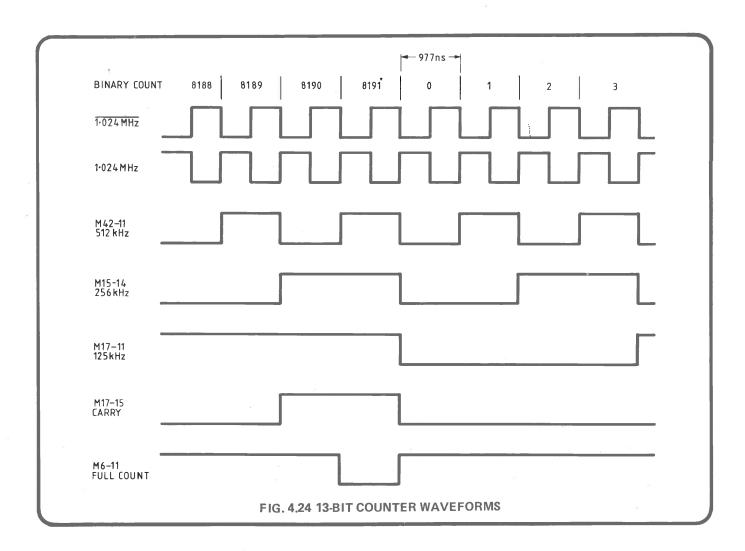
The counter comprises three 4-bit binary counters M15, M16, M17 and J-K flip flop M42 (half dual package). The outputs required from the counter are 13 binary-coded lines, the first (least significant) being a 512 kHz squarewave, the others successively divided in frequency to the most significant output of 125 Hz.

Bit 1 is provided by J-K flip flop M42, which toggles on each falling edge of the 1.024 MHz clock to give 512 kHz Q and $\bar{\rm Q}$ outputs. These outputs are used as follows:

- (1) Q and \overline{Q} complementary outputs together provide the least-significant input to the 13-bit comparator;
- (2) The Q output controls the counting rate of M15, synchronizes M16 and M17, and is used in the gating of FULL COUNT.

Counters M15, M16 and M17 are cascaded as a 12-bit counter and synchronously clocked by the 1.024 MHz. M15 counting is enabled only when M42 Q output is logic-1 at the count-enable input M15-7. As M42 output is at 512 kHz, clocking of M15 occurs on the rising edge of alternate 1.024 MHz clocks, thus giving outputs of 256, 128, 64 and 32 kHz squarewaves from M15. Counter M16 is enabled by the carry output from M15 together with 512 kHz from M42 at the count-enable pins M16-10 and 7 respectively, thus giving outputs of 16, 8, 4 and 2 kHz squarewaves from M16. Counter M17 functions in a similar manner to give outputs of 1 kHz, 500, 250 and 125 Hz squarewaves.

The 2 μ S-long carry output from M17 occurs at the end of the 125 Hz output when all counter outputs are at logic-1. The carry output is NAND gated with M42 Q output to give the 1 μ S-long logic command FULL COUNT. The counting cycle continues, starting from bit 1.



4.6.2.3 13-Bit Comparator Action (Circuit Diagram No. 430443 Sheet 2)

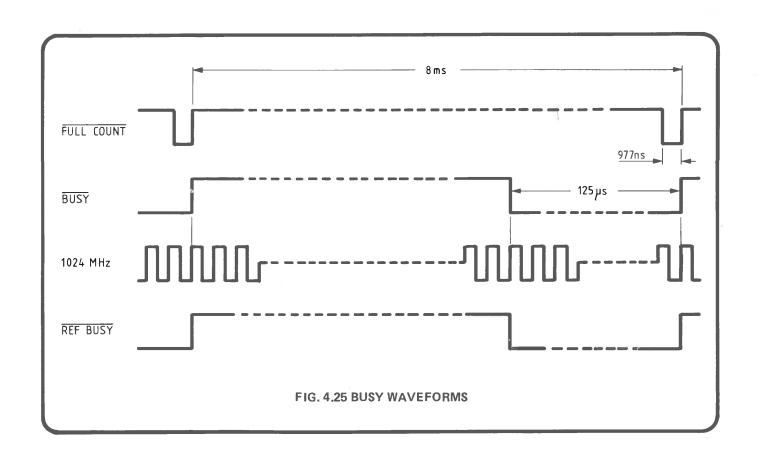
The 13-bit comparator provides a logic-1 output at TP12 whenever a coincidence occurs between the following two sets of data:

- (1) Data set in registers M47, M48 and M49-1;
- (2) Data from the 13-bit counter M42, M15, M16 and M17.

Twelve exclusive-OR elements M25, M26, M27 and three NOR gates of M12 are used to detect a coincidence. The data in the registers is preset by the CPU, while that presented by the 13-bit counter cycles through every binary combination possible on 13 lines. Two coincident inputs to an exclusive-OR gate provide a logic-0 to the 12-input NOR gates M24/M23; full coincidence in bits 2 to 13 is shown by a logic-0 at NAND M13-6. Coincidence at bit 1 is shown by logic-0 at M12-13 and M12-4 as follows:

M12	INPUT	PINS	M12 OUTPUT PINS		
6	11	9/12	4	13	
0	1	0	0	0	
0	1	1	1	0	
1	0	0	0	1	
1	0	1	0	0	

only 4 input combinations available A BUSY signal is generated by the comparator at NAND M50-13 (TP2) when the 13-bit counter approaches full count. Bits 8 to 13 are at logic-1 for the period of 125µS preceding the end of the counter cycle (see Fig. 4.25). The BUSY level is applied to the D input at M49-9 and is clocked through as REF BUSY to buffer M45.2 by 1.024 MHz. When the CPU has data to load into the input data latches, it first interrogates the comparator by enabling buffers M45 through REV DIV RD. A logic-1 on REF BUSY at M45-3 indicates to the CPU that sufficient time is available for the latch-loading process to take place (at least 125µS before LOAD pulse). The remaining elements of M45 buffer the five most significant data bits back to the CPU so that data parity can be confirmed.



4.6.2.4 MSB Sync Logic (Circuit Diagram No. 430443 Sheet 2) (refer to Fig. 4.26 for waveforms)

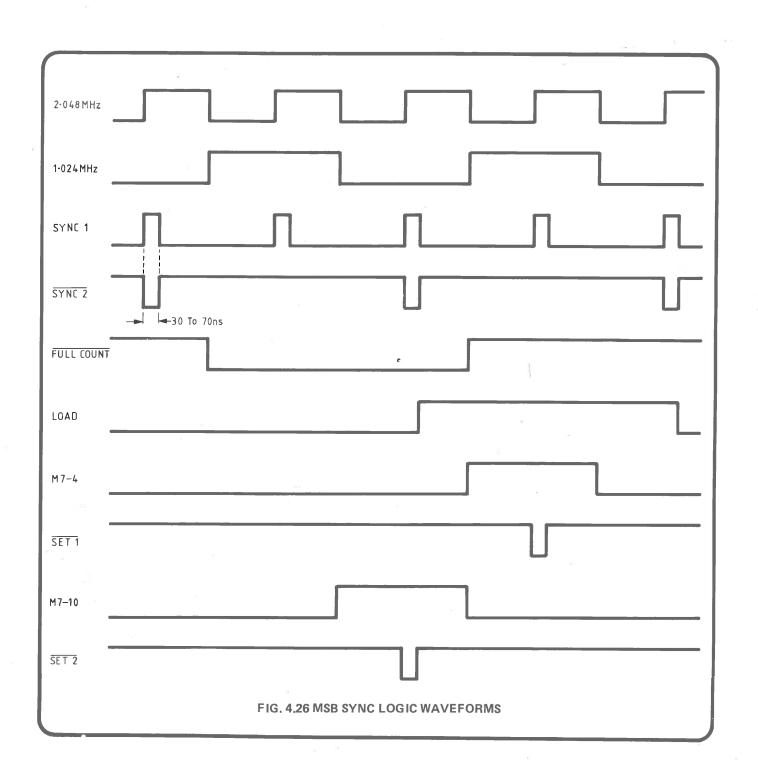
This circuit, M14, M6, M7 and M8, provides the following signals: \overline{SYNC} 2, LOAD, \overline{SET} 1, \overline{SET} 2, \overline{RST} 1 and \overline{RST} 2.

SYNC 2 is obtained by NAND gating 1.024 MHz and SYNC 1 to give a synchronizing pulse at half the rate of SYNC 1. (See Fig. 4.26)

The LOAD pulse, which enables the 13-bit counter registers, is generated at M14-6 towards the end of the counter's full-count output. FULL COUNT sets the D input

M14-2 and the level is clocked, inverted, from M14-6 by the next two $\overline{\text{SYNC 2}}$ pulses that occur.

The inverse of LOAD is used to time the pulse SET 1 by NOR gating at M7-4 with 1.024 MHz. The pulse at M7-4 is then NAND gated with SYNC 1 to provide SET 1 from M8-1. The pulse SET 2, which occurs 977 nS before SET 1, is obtained by gating FULL COUNT with 1.024 MHz at NOR M7-10 and then NAND gating at M8-10 with SYNC 1.



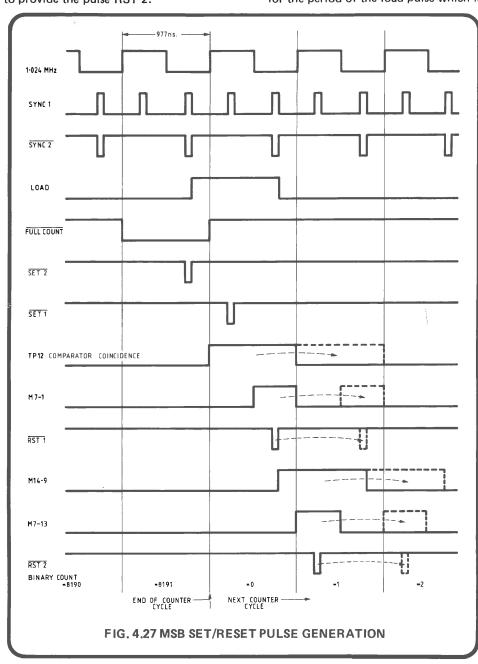
Reset pulse generation (see Fig. 4.27) is indicated by a logic-1 level at TP12. This can occur at any one of the 8192 binary counts of the 13-bit counter, the actual time slot in which it appears depends on the binary count at which the coincidence occurs.

The coincidence level at TP12 is NAND gated at M6-8; M6-10 being at logic-1 for all binary counts except 8191. The logic-0 at M6-8 is NOR-gated at M7-1 with 1.024 MHz, this is then used to select the next SYNC 1 pulse via NAND M8-4 to provide the pulse RST 1.

The coincidence level at TP12 is used to set the D input at flip flop M14-12. This level is clocked to NAND M6-5 by the next SYNC 2 pulse. NAND input M6-4 is at logic-1 except when LOAD is active, thus M14-9 output is inserted at M6-6 to be NOR-gated with 1.024 MHz at M7-13. This is then used to select the next SYNC 1 pulse via NAND M8-10 to provide the pulse RST 2.

The pulse-timing example given in Fig. 4.27 shows the generation of RST 1 and RST 2 when coincidence occurs in the comparator at binary count = 0 (waveforms in unbroken lines). Coincidence occuring at binary count 1 causes RST 1 and RST 2 to increment in time by 977 nS with respect to the SET 1 and SET 2 pulses (waveforms in broken lines). RST 1 and RST 2 will be generated with the same relationship in time to the comparator coincidence when the latter occurs in any binary count time slot from 0 to 8190 (inclusive); note that SET 1 and SET 2 remain staionary with respect to FULL COUNT and LOAD and that RST 1 and RST 2 increment, in time, away from these.

RST1 and RST 2 are inhibited when coincidence occurs at binary count 8191 to allow for the re-loading of the input registers at the end of the counter cycle. The inhibit is performed by the FULL COUNT level going to logic-0 at NAND M6-10 which prevents RST 1 being generated, and by flip flop M14-5 output going to logic-0 for the period of the load pulse which inhibits RST 2.

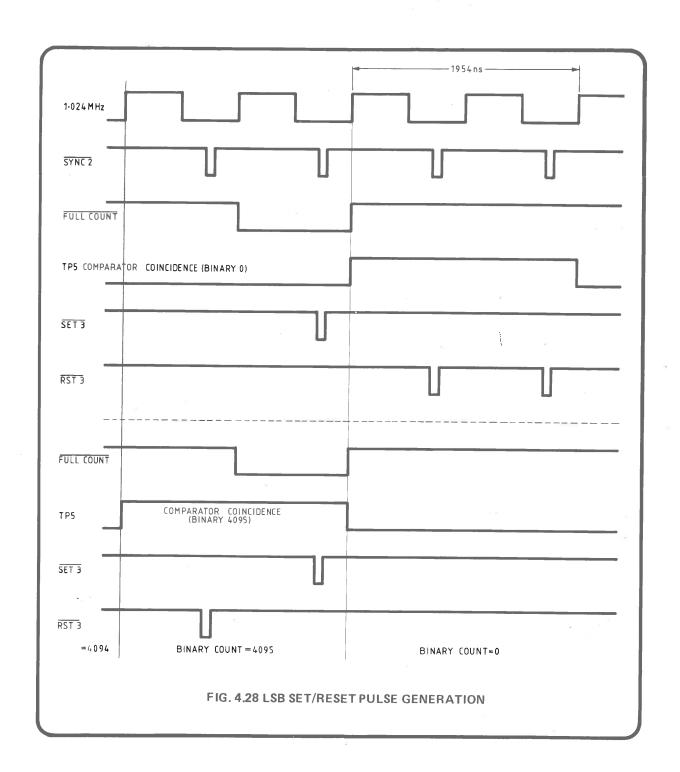


4.6.2.5 12-Bit Comparator Action (Circuit Diagram No. 430443 Sheet 1)

This functions in an identical manner to the 13-bit comparator previously described. Twelve exclusive OR gates, M19, M20 and M21, receive 12-bit binary output from the common counter and compare these bits with the data in the data registers. The least significant bit changes at a rate of 256 kHz, and the most significant bit at 125 Hz. Coincidence occurring in any of the 4096 binary count time slots available in the comparator cycle is shown as a logic-0 at TP5 for a period of 1954 nS.

4.6.2.6 LSB Sync Logic (Circuit Diagram 430443 Sheet 1) (refer to Fig. 4.28 for waveforms)

The timing of SET 3 is controlled by the FULL COUNT pulse from the 13-bit counter. The inverted FULL COUNT at M43-6 is gated with the inverted SYNC 2 from M43-11 to give, at M46-1, SET 3. The comparator coincidence logic level is inverted to logic-0 at M12-1; M12-2 being at logic-0 except when FULL COUNT is low. The waveform at M12-1 is of 1954nS duration and therefore allows two consecutive SYNC 2 pulses to be gated to M46-4 (RST 3). This condition exists for all RST 3 timings except at the binary count of 4095; in this instance, the FULL COUNT pulse occurs after the gating of the first SYNC 2 pulse, sets M12-2 to logic-1 and so prevents the second pulse appearing at RST 3. In practice, the second pulse of RST 3 has no operational significance.



4.6.3 References and Reference Divider (Circuit Diagram No. 430444 and Fig. 4.23)

The set and reset pulses from the prevision divider comparators control the timing of FET-switches which chop Master Reference voltages. The chopped references are filtered to generate voltages whose level is proportional to

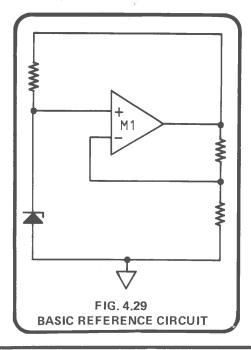
the mark:period ratio (duty cycle). MSD and LSD voltages are added in the summation amplifier to generate a variable $0 \leftrightarrow 20V$ at high resolution (0.03ppm, $\stackrel{\triangle}{=} 0.5\mu V$ increments).

Bipolar switching inverts the working reference for negative output selections.

4.6.4 Master Reference (Circuit Diagram No. 430452 and Fig. 4.29)

The Master Reference determines the fundamental long and short-term stability of the 4000. It is a separate pcb mounted on the Reference Divider assembly (Refer to Layout Drawings Nos. 400444 and 400452).

The basic circuit shown in Fig. 4.29 acts as a constant-current generator for a zener reference.



The random character of zener drift in the short-to-medium term may in the long term be regarded as averaging to zero. The averaging action of the eight zener diodes in Drawing 430452 reduces the short and medium term variations (due to drift and noise) by a factor of $\sqrt{8}$, effectively 3 times more stable than a single zener diode.

The diodes and resistors are selected and matched for near-zero temperature coefficient; the overall instrument values are shown together with the stability and accuracy specifications in Section 6 of the User's Handbook.

Test links TLA1-6 and TLB1-5 are selectively removed during manufacture as a fine adjustment of zener operating current for zero temperature coefficient. The zener voltages of +24.5V at TP3 and TP1 wrt common-R1 are reduced by the star-point buffer M2 to approximately +20.6V at the Main Switch in the Reference Divider. This voltage is delivered to the Reference Divider by a full 4-wire sensed connection.

4.6.4.1 Buffer M2 — Temperature Compensation (Circuit Diagram 430452 Sheet 1)

In the 4000A instrument, the temperature compensation applied to M2 is adjusted at manufacture by R29 (set TC slope). This adjustment requires specialised test equipment and should not be attempted by users.

If a fault is suspected on the Reference PCB Assembly (400452), contact your Datron Service Centre.

4.6.5 Reference Buffer-Divider (Circuit Diagram No. 430444 Sheet 2)

R80/81 drop the 20.6V Master Reference voltage (V Ref) to +8.83V. M23/Q40 is a voltage-follower providing

+8.83V wrt common-4 at the star-point TP14 to supply the least-significant digit switch.

4.6.6 Least-Significant-Digits Switching (Fig. 4.30)

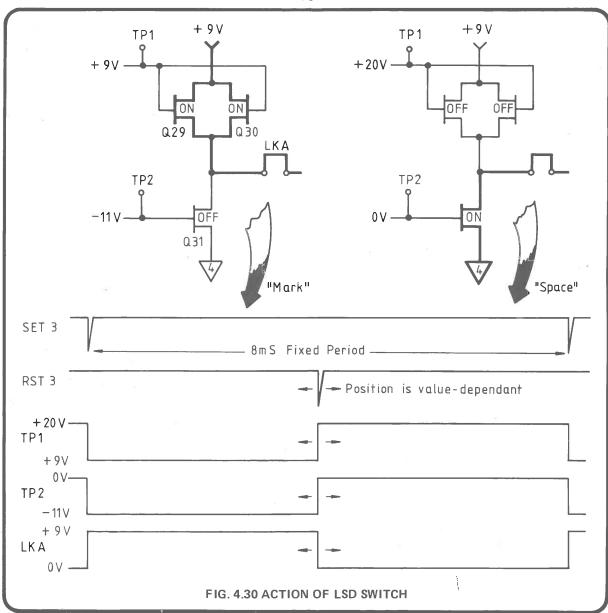
4.6.6.1 Switch Driver

SET 3 and RST 3 pulses from the LSD Comparator in the Analogue Interface Assembly are transferred into guard via pulse transformers T1 and T2, whose centretapped secondaries are balanced about 0V (T1) and +9V (T2). Q5-Q7 form a fast bistable using emitter-coupled logic, to switch TP1 between +9V (mark) and +20V (space). During the "Mark" time after SET 3 pulse, Q29 and Q30 are switched ON, connecting LKA to +9V Ref. During the "Space" time after RST 3 pulse, Q29 and Q30 disconnect LKA from +9V Ref. Q1 — Q4 have the same fast bistable action, Switching Q31 off during the "Mark" period by -11V at TP2, disconnecting LKA from common-4 (0V); and on during the "Space" period, connecting LKA to common-4 (0V). Fig. 4.30 demonstrates this action.

4.6.6.2 FET Switch and 3-pole Filter

The combined action of the switch FETs alternately provides charging current for the 3-pole filter (during "mark") and discharging current (during "space"). Two FETs in parallel (Q29 and Q30) are necessary to equalise the charging and discharging time constants by matching the "ON" resistances. This preserves linearity of the filter output voltage over the full range of mark/period ratios applied via the set and reset pulses.

The 3-pole filter has the advantage of not being in series with the DC output signal. The 125Hz ripple content is reduced to an acceptable level for the overall instrument specification. The filter output is buffered by voltage-follower M16.



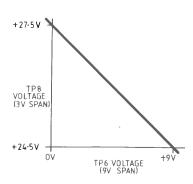
4.6.6.3 Offset Bias Amplifier

M20 performs a dual role:

- (1) Its gain is set to $-\frac{1}{3}$ by R64/65
- (2) Its output is level-shifted to provide an offset bias for the summing amplifier (This allows the summing amplifier output to have a negative zero offset).

Also a small thermal coefficient zero correction is factory-preset (D10/R85).

M20 transfer function is approximately as follows:



The actual values are as set digitally in software, affecting the mark:period ratio of the FET switches, using stored calibration constants.

4.6.7 Most-Significant-Digits Switching (Circuit Diagram No. 430444 Sheet 1)

The large reference voltage (20.6V) and the need for higher resolution makes the MSD Switching circuitry more complex than for LSD; but the principle is the same: the set and reset pulse-timing adjusts the mark:period ratio of the square wave fed to the filter.

The arrangement used for the MSD switching satisfies two essential requirements:

(1) The charge and discharge path resistances for the 7-pole filter must be closely matched.

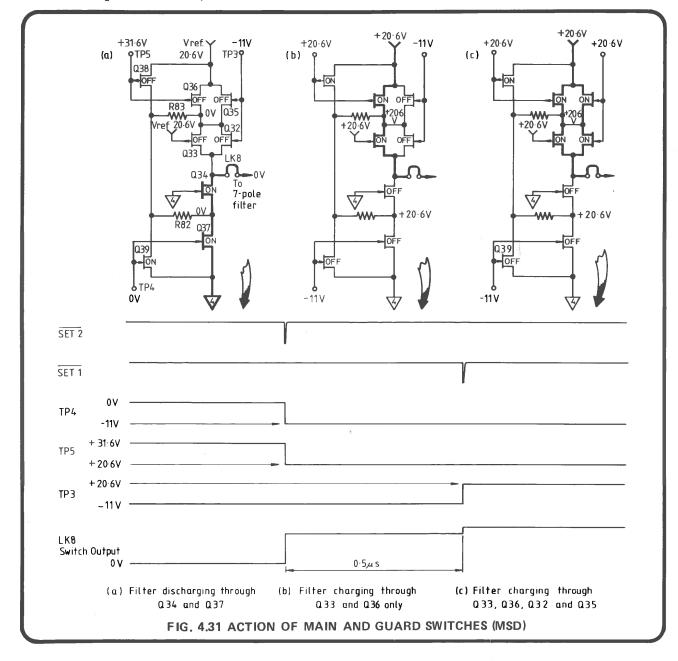
(2) The leakage current of the path switched off must be minimal.

Requirement (1) demands that the matched devices used in both paths are of the same type (P-channel JFETs have approximately 10 times the "on" resistance of N-channel types). But without the voltage standoff and leakage-current shunt created by the guard switch, the pinch-off gate voltage for one of the paths would be high enough to generate gate-leakage current in excess of requirement (2).

4.6.8 Main and Guard Switches (Fig. 4.31 and Circuit Diagram No. 430444 Sheet 1)

Refer to Fig. 4.31, in which only the Space \rightarrow Mark state-transfer a-b-c is shown. (The Mark \rightarrow Space transfer is symmetrical c-b-a). The switch driver flip flops establish the voltage shown at TP3, 4 and 5 as controlled

by the set and reset pulses. The drivers are ECL fast bistables, but note that Q19 and Q20 are included in the main switch driver as a level-shifter for Q32/Q35.



4.6.8.1 Switch Timing

SET 1 pulse is delayed by 0.5µSec after SET 2 pulse, and RST 2 is delayed by 0.5µSec after RST 1.

SET 2 and RST 2 pulses control the timing of the guard switch Q38 and Q39, and Q36, Q33, Q34 and Q37 in the main switch (TP4 and 5).

SET 1 and RST 1 pulses turn Q35 and Q32 on and off (TP3). Because of the 0.5µSec delays, Q35 and Q32 conduct only during the time that Q36 and Q33 are also conducting.

4.6.8.2 Filter Discharge Path

In Fig. 4.31(a) the switches are in "space" state. Any leakage current due to the high voltage of Q36/Q35/Q38 gates is shunted via Q39/R83, eliminating Q33/Q32 leakage by zero source-drain voltage. During "space" state the 7-pole filter capacitors have a discharge time constant which includes Q34 and Q37 'On' resistance (3-5 ohms each).

4.6.9 7-pole Filter

M26, M28, M32, Q41 and Q42, together with associated capacitors and resistors, form a 7-pole Bessel Function filter in three active elements; providing approximately 135dB of attenuation at the 125Hz switching frequency and increasing at 140dB/decade. This allows sufficient bandwidth to avoid execessive settling time whilst reducing the output ripple to within instrument specification. Q41 and Q42 source-followers provide

4.6.10 Summing Amplifier (Circuit Diagram No. 430444 Sheet 3)

M33, M34 and Q44 sum together the MSD and LSD voltages. M35, D14, D15, Q48 and Q49 provide bootstrapped supplies to preserve full dynamic-range linearity. Q46 and Q47 establish 3mA constant-current drives for D14 and D15, over the range of BS-common voltage variation.

M33 is a high-gain, chopper stabilised integrator with a bandwidth of approx. 10Hz, and Q44 provides additional bandwidth for rejection of HF common-mode noise.

M34/Q45 provide the output and feedback drive, buffering the summed outputs of M33 and Q44. The summing amplifier acts as a voltage-follower to the MSD input, but divides and inverts the LSD input. The LSD gain ratio is set by R100 \div R99 = 475 \div 555,410 \cong 8,552 x 10⁻⁴. The span of LSD inputs of approximately 3V (+27.5V at zero LSD filter output to +24.5V at LSD filter output of +9V) leads to a span of approximately 2.5mV subtracted from the MSD voltage at the emitter of Q45.

The reference voltages and reference division circuitry are chosen to allow for software calibration adjustments, so the span of the summing amplifier overlaps the required Full Scale of 0 to 19.999999V at both extremes:

Zero:

At zero count the MSD input voltage is approx. 3.2mV. Zero count on the LSD comparator produces an

4.6.8.3 Filter Charge Path

To preserve linearity over the full range of Mark: Period ratios, the filter charging path must also have the same time constant, so Q35 and Q32 form a matched set with Q34 and Q37, all N-channel J-FETs (The "on" resistance of P-channel FETs is much higher: 30 — 40 ohms). But to avoid high voltages being developed across Q35/Q32 when changing between states (causing excessive leakage), P-channel FETs Q36/Q33 are switched on before (and switched off after) Q35/Q32.

Fig. 4.31(b) shows this intermediate state after SET 2 and before SET 1, and Fig. 4.31(c) shows the fully-conducting state after SET 1. Note that the second step on LK8 waveform is heavily exaggerated for descriptive purposes, and is not readily viewed on an oscilloscope. The longer charging time-constant during this half-microsecond is not sufficient to disturb the linearity of the filter in excess of specification.

To minimise leakage during "mark" state, Q34 source-drain voltage is maintained at zero by R82 connection. Thus Q34, Q33 and Q32 act as isolators in their "OFF" state, giving rise to the name "Guard Switch" for Q38/39.

input bias currents for M26 and M28 from the 15V supplies, and buffer the line from bias-current effects.

The filter output at TP11 is fed to the summing amplifier to be added to the output from the Least-significant digits offset-bias amplifier. R101 and C51 prevent spikes from the chopper-stabilised summing amplifier being fed back into the filter.

output at TP6 of approx. 1.1mV, which translates into an output voltage to the summing Amplifier of approx. +27.5V. The combined output at Q45 emitter is found by

$$Vo = V_{msd} - (V_{lsd} - V_{msd}) \times \frac{R100}{R99}$$

=
$$0.0032V - (27.5V - 0.0032V) \times \frac{475}{555410} = -20.3mV$$

This overlap of approx. -20.3mV allows a zero offset to be stored in the digital calibration memory to align the zero output to a defined external zero.

Full Scale:

A full count of 8191 on the MSD Comparator would produce a +20.6V input to the summing amplifier. Similarly a full count of 4095 on the LSD Comparator would produce +8.83V at TP6, and +24.5V at TP8 at the input to the summing amplifier. The combined output is again found by $V_o = V_{msd} - (V_{lso} - V_{msd}) \times \frac{R100}{R00}$

The maximum value is

20.6V - (24.5V - 20.6V)
$$\times \frac{475}{555410} = + 20.597V$$

This value cannot be achieved in practice as the software modifies all digital demands by a factor of approx 0.97. Use of 20.6V Master Reference and this gain factor gives a margin for accurate calibration, from digital gain factors held in the non-volatile calibration memory.

4.6.11 Bipolar Reference Switching

The polarity-reversal relay RL1 is driven from M31 pin 4, M14 and M29 (Circuit Diagram 430444 Sheet 4). For positive outputs RL1 is energised; and for negative outputs, de-energised.

For positive DC Voltage outputs, common 4 is connected via RL1-8 as DC Ref Lo which is tied to the DC Assembly common 1 and the front panel Lo terminal. The summing amplifier output star-point connects via RL1-5 to become positive DC Ref Hi for the Error Amplifier on the DC Assembly.

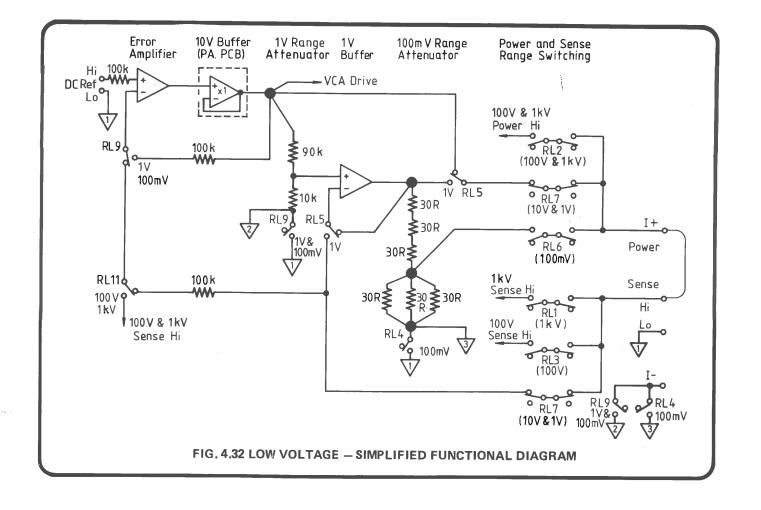
For negative DC Voltage outputs. RL1-10 connects the summing amplifier output star-point to Common-1 as DC Ref Lo, and Common-4 becomes negative DC ref Hi via RL1-7.

When option 20 is fitted, RL2 can be energised for current outputs by selection of I function (M19 pin 7 on sheet 4).

In this case the summing amplifier output is used as positive or negative DCI Ref, to drive the voltage-to-current converter on the I/Ω pcb.

4.6.12 Power Supplies

To avoid the effects of common-mode transients on the lines from the in-guard common-4 power supply at the rear of the instrument, the +36V, +18V and -15V supplies entering Reference Divider pcb are heavily filtered. The +18V supply is regulated after filtering to generate +15V supply.



4.7 LOW VOLTAGE

The circuits described in this section perform the following functions:

- Buffer the DC REF voltage (-20V to +20V) and provide output voltages to the instrument terminals, on 10V DC Range.
- (2) Attenuate the 10V Range voltages and provide output voltages (-2V to +2V) on 1V DC Range.
- (3) Further attenuate the 1V Range voltages and provide output voltages:

-200mV to +200mV	on	100mV Range
-20mV to +20mV	on	10mV Range
-2mV to +2mV	on	1mV Range
-200µV to +200µV	on	100µV Range

(4) Sense the voltages at the output terminals (or at the load in Remote Sense) in closed negative-feedback loops which compare the output voltage with the DC REF (or attenuated DC REF) voltages from the Precision Divider.

- generating analogue control signals to correct the output voltage on 10V and 1V ranges.
- (5) Provide switching of DC Voltage Ouput, Range, Guard and Sense, under the control of signals from the Analogue Control Interface.
- (6) Sense excess currents in the output circuit, providing a LIM ST 1 status signal to the CPU via the Analogue Control Interface.
- (7) Sense excess voltages (>130V) on the PHi (I+) output line, providing a HVST status signal to the CPU via the Analogue Control Interface. The low voltage generation circuitry and Range switching are illustrated in fig. 4.32.

All the circuits described in this section are located on the DC PCB Assembly, except the 10V Buffer, which is placed on the PA (DC) Assembly.

4.7.1 General

When DC Function is selected, RL2 on the Reference Divider pcb feeds the output of the summing amplifier into the DC pcb Assembly as DC REF (Hi and Lo), the value of which represents the demanded output voltage and polarity.

The DC Voltage circuitry selects the required range, from switching data transmitted into guard via the Serial Data Link. The appropriate range circuit generates the demanded voltage at the output terminals. Output switching and protection is provided.

4.7.2 10V Range (Fig. 4.32 and Circuit Diagram No. 430445)

In Fig. 4.32 the relay contacts are shown in positions set for the 10V Range. The 1V buffer and attenuators have no effect.

DC Ref is variable between -20V and +20V with respect to common-1 (Instrument Lo terminal). The Error Amplifier and 10V Buffer are connected as a voltage-follower when I+ is connected to Hi (either local or remote sense).

The output from the 10V Buffer is connected directly to I+ via RL5 and RL7 power contacts, and the sense feedback connects via RL7 sense contacts, RL11 and RL9 back to the Error Amplifier inverting input. The Output voltage at the Hi line is adjusted by the feedback until it equals the DC Ref Value, i.e. for zero differential input to the Error Amplifier.

4.7.3 1V Range

Relays RL5 and RL9 change over to provide the 1V Range Switching. (Four positions on Fig. 4.32). RL9 transfers the sense point of the Error Amplifier and 10V Buffer to the star-point at the top of the 1V Range attenuator, and also connects the lower end of the attenuator to Common-1.

The DC Ref Voltage now appears across the 1V Attenuator, which applies one tenth of its value to the 1V Buffer. RL5 connects the 1V Buffer output to the I+ terminal, and its Feedback point is the Hi terminal.

The output voltage at the terminals is adjusted by the feedback until it equals one tenth of the DC Ref Voltage.

4.7.4 100mV Range

Relay RL5 switches the 1V Buffer feedback to its own output, which drives the 100mV Range Attenuator. RL4 connects the lower star-point of the attenuator to common-1 (I- and Lo terminals).

All RL7 contacts are disconnected and RL6 connects the attenuated output to the I+ terminal.

(Note that on 100mV Range, the Hi and Lo terminals are permanently connected to the I+ and I-terminals, i.e. Remote Sense is not available).

On the 100mV Range the DC Ref Voltage is divided by 10 in the 1V Range Attenuator, and again by 10 in the 100mV Attenuator. Full Range voltage of 100mV is thus derived from 10V DC Ref, and the same full span of the Reference Divider output is employed.

4.7.5 $100\mu V - 10mV$ Ranges

These ranges use the same relay settings as 100mV Range, so the output voltages remain at 1/100 of the DC Ref voltages. The differences lie in the spans of DC Ref voltages used.

To achieve the correct DC Ref span, the appropriate scaling is computed digitally and the 4-byte binary words set in the 13- and 12-bit comparator latches of the Analogue Interface. The DC Ref spans are scaled as follows:

10mV Range - -2V ↔ +2V (÷ 10)

1mV Range - ~200mV ↔ +200mV (÷ 100)

100 μ V Range − -20mV \leftrightarrow +20mV (\div 1000)

Because of this scaling, the resolution available on these ranges is reduced in proportion to the scaling ratio. The displayed output resolution is automatically adjusted according to range selection:

10V, 1V and 100mV Ranges 7½ digits 10mV Range 6½ digits 1mV Range 5½ digits 100μV Range 4½ digits

4.7.6 Error Amplifier (Circuit Diagram No. 430445 Sheet 1)

The DC Ref Voltage from the Reference Divider is applied to two amplifiers: M20 is a high-gain chopper-stabilised integrator of approximately 10Hz bandwidth, Q11 provides additional bandwidth for rejection of HF common-mode noise. M19 provides additional gain and the output drive to the 10V Buffer through a diode clamp

circuit for transient suppression. The whole amplifier is bootstrapped by M18, D44, D45, Q7 and Q10. Q8 and Q9 provide 1.4mA constant-current drives for D44 and D45 over the range of BS-common variation (-20 to +20V). Extensive screening and filtering is employed to eliminate the effects of the chopping spikes at inputs and output of M20.

4.7.7 10V Buffer (Circuit Diagram No. 430449 Sheet 5)

The discrete, complementary, 10V Range bufferamplifier is located on the PA pcb. Its power stage provides the full output current, so the heat from its power stage is developed outside the Chassis Assembly (Thermal shield) and dissipated by forced-air cooling from the fan. Its output is fed back on to the DC pcb for range and output switching.

4.7.8 1V Buffer (Circuit Diagram No. 430445 Sheet 2)

The output from the 10V buffer (10V O/P A) is divided by 10 in the 1V Attenuator (R73/R74) and applied to dual source-follower Q6 and chopper-stabilised integrator M16. This is a simplified version of the Error Amplifier, but with one tenth of its dynamic range. M17 drive to output buffer is clamped to suppress transients. On 10V range the 1V amplifier is isolated from the instrument output circuit by relays RL5 and RL9. On 1V Range it acts as a voltage follower, feeding the instrument I+terminal, and receiving its sense feedback from the instrument Hi terminal. On $100\text{mV} - 100\mu\text{V}$ Ranges its sense is directly fed back from the star-point at TP12. On these lower ranges one tenth of its output at the TP9 star-point feeds the instrument I+ terminal, so there is no remote sensing.

The 1V amplifier is bootstrapped by M13, D25, Q3 and dual op-amp M14. M15 (1V Output buffer) is not bootstrapped, Q4, Q5, D28 and D29 provide current limiting.

4.7.8.1 Model 4000A — 1V and 100mV Precision Attenuators (Layout Drawing 400445 Sheet 1 and Circuit Diagram 430445 Sheet 2)

In the Model 4000A, the DC PCB is fitted with uprated 1V and 100mV attenuators, to hold the specification over a wider temperature range than the 4000:

(1) R73 and R74 are combined in one 90k/10k unit (part no. 090058/A).

(2) R69, R70, R71, R72, R75, R76 are combined with changed values in one 1k/111.11R unit (part no. 090059/A).

4.7.9 Output Switching (Circuit Diagram No. 430445 Sheet 3)

The PHI and SHI outputs from the Range relays (sheet 1) are passed to the instrument output terminals via relay contacts which provide switching for Remote/Local Sense and Guard, and Output On/Off; for DC Voltage Ranges. The terminal lines are switched for function

changes on the I/ Ω PCB Assembly if option 20 is fitted. When option 20 is not fitted, the I/ Ω Link pcb (Part No. 410182-3) is fitted in place of the I/ Ω PCB Assembly, providing direct connections to the instrument terminals.

4.7.9.1 Remote Sense Switching

Relays RL10 and RL12 connect PHI to SHI and PLO to SLO when Remote Sense is not selected. In Remote Sense the contacts are opened, for full 4-wire sensing at the load external to the instrument. For DC Voltage Ranges with Output On, the Lo terminal is connected to common-1 by RL8-14, completing the circuit to the 100mV and 1V attenuators' low-impedance points, and to DC Ref Lo. At the same time, the I+ terminal is connected through R32 to common 2A or 3A, by RL8 and RL9, or RL8 and RL4.

The current passing through the load is monitored as a voltage across R32 by M9.

4.7.9.2 Remote Guard Switching

The internal guard shields are connected directly to the Instrument Guard terminal (J5 - 15 to J5 - 11). When Remote Guard is not selected, RL15 - 8 connects the guards to I- (PLO) at the junction of F5 and F6. In Remote Guard the contact is opened to isolate the guards from I-.

4,7,9,3 Output On/Off

With Output selected On in DC Voltage Function RL14 connects PHi to I+, and SHi to Hi terminals. RL13 connects PLo to I-, and SLo to Lo terminals.

4.7.10 Over Current and Over Voltage Sensing (Circuit Diagram No. 430445 Sheet 3)

The circuit shown on sheet 3 may be divided into two separate functions providing two separate outputs, which are passed to the CPU via the serial data link:

LIM ST 1 (Limit status 1) is normally logic-1 (pulled to 0V by AN 2 on the Reference Divider pcb), and logic-0 (-15V) when the 4000 Output current exceeds 25mA (at approximately 28.5mA).

HV ST

(High Voltage Status) is logic-1 (pulled to 0V by AN 2 on the Reference Divider pcb) when the output voltage is below 110V, and logic-0 (-15V) when the output voltage exceeds 110V (at approximately 130V).

4.7.10.1 Over Current Sense

The current taken by the instrument load is diverted from common-1 (used as reference common only) and returned through R32 to common-2 (common-3 on 1V range for 1V buffer).

The voltage developed across R32 is buffered by M9 op-amps. M9 pin 1 output voltage is level-shifted by D11 and D7, divided by R12, R11 and R18, R17 and applied to M8 pin 5 (M9 pin 1 voltage + approx. 650mV) and M8 pin 1 voltage - approx. 650mV).

 $\,$ M8 pins 6 and 10 are referred to common by M9 pin 7.

Under normal operation, when the output current is less than 25mA, both M8 outputs at pins 7 and 8 are at +15V, reverse-biassing D9 and D8, so that the LIM ST 1 is at 0V (logic-1).

If the output current through R32 exceeds approximately \pm 28.5mA, the voltage across it exceeds \pm 650mV. Either D8 or D9 is forward-biassed by -15V at its cathode as its M8 op-amp input polarity reverses. R14 and R15 ensure rapid switching action in case of a short-circuited output.

D9 or D8 conduction sets LIM ST 1 to logic-0 (-15V). The CPU responds by presenting "Error OL" on the MODE display. If 100V or 1000V is selected, the output is switched off.

The 10V and 1V buffers are protected by current limiters which operate between 30-40mA. The $100\text{mV}-100\mu\text{V}$ ranges are not protected by current limiters, and on these ranges the over current sense circuit is disabled by RL4 and RL9.

4.7.10.2 Over Voltage Sense

M9 pin 1 is referred to Common-1 (Sense Lo) either through RL12 (Local Sense) or via the external load circuit (Remote Sense). R29 and R22 divide the output voltage by 54 at TP 17, buffered by M10. M8 forms the comparator, using D11 as 2.45V reference for positive, and D7 for negative, output voltages.

For output voltages between -110V and +110V, TP7 is between -2.1V and +2.1V so both D5 and D6 are reverse-biassed by +15V on their cathodes, and \overline{HVST} is at logic-1. For output voltages greater than approximately \pm 130V, TP17 voltage is greater than \pm 2.45V. Either D6 (positive voltages) or D5 (negative voltages) is forward-biassed by -15V at its cathode, as its M8 op-amp input polarity reverses.

D5 or D6 conduction sets \overline{HV} \overline{ST} to logic-0 (-15V). The CPU is now aware that the 4000 output voltage exceeds \pm 110V. If High Voltage state has not been commanded, a fault is assumed and FAIL 2 message is presented on the MODE display.

4.7.11 DC PCB Switching Logic (Circuit Diagram 430445 Sheet 4)

The analogue control signals are transferred into guard on the Reference Divider pcb, and latched as 'Q' outputs in the Serial/Parallel Data Converter. Offset positive logic is employed (0 = -15V, 1 = 0V) for the signals entering the DC pcb via J5 from the Mother pcb.

M1 and M2 are Darlington open-collector Inverter/ Drivers. The Relay Drive Logic places a logic-1 (0V) on the input of selected drivers, and logic-0 (-15V) on those not required. A selected driver operates its relay(s) by pulling its output Voltage to -14V. Whenever a switching command has been received, the CPU performs a control data transfer and the UPD (IG) line from J 5-104 is pulsed to -15V for 50mS.

Q1 is turned on, applying +15V to the relays connected to its collector (Relays RI 1, 2, 3 and 15 are permanently connected to +15V). The selected relays are thus energised by 30V, but after the UPD (IG) pulse has finished they are held on by 10.5V between -3.5V at the anode of D2 and -14V at the selected driver output. This method reduces the local heat generated by energised relay coils, in the relay contacts.

4.7.11.1 Range Switching Logic

Range control data is input as a 3-bit code on DC R ϕ , DC R1 and DC R2 lines. The bit-pattern is decoded by M4 to energise the correct relays for the selected range. As the $100\mu V$, 1mV, 10mV and 100mV ranges all use the same analogue circuitry, only one bit-combination is required for these four ranges. The resulting five combina-

tion variations are listed in Table 4.1 against the range selections, showing the states of M4 'Q' output pins and the relays energised for each range.

Note that deselection of DC function de-energises all range relays except RL4, RL5 and RL9, regardless of the range code being transferred.

Range	Bit DC	Patt	ern	M4	0ι	ıtpu	t pin	S		Ran	ge I	Rela	ys E	ner	jise	d	
	R2	Ř1	RØ	7	9	10	11	12	RL4	RL6	RL9	RL 5	RL7	RL3	RL2	RL11	RL1
100mV	1	0	0						/	/	/						
1٧	0	1	1	1	1						1	/	/				
10 ∨	0	1	0		:	1							/				
100∨	0	0	1				1							V	/	/	
1000∨	0	0	0					1							/	/	✓

Notes. 1. 1 = 0V. 0 = -15V

- 2. All M4 Output pins at 0 unless shown at 1.
- 3. Unless shown energised on the table, all relays are de-energised.

 (Relay contacts on Circuit Drawing 430445 shown in de-energised state.)

TABLE 4.1 RANGE SWITCHING VARIATIONS

4.7.11.2 Function and Output Switching Logic

The DC output voltages are passed through the DC pcb on all ranges. RL13 and RL14 connect the PHi, PLo, SHi and SLo to the I+, I-, Hi and Lo terminals of the instrument. Four signals control these relays:

OFF at logic-0 when Output is selected ON.
BARK DEL at logic-0 unless the watchdog has tripped.

AC FUNCT always at logic-1.

DC FUNCT at logic-1 if DC Function is selected

Under these conditions M5 pins 1, 2 and 8 are set to logic-0, M5 — 9 is at logic-1 so RL13 and RL14 are energised. Any change in one of the three switchable inputs will disconnect the terminals from the output.

Additionally, when Ω or I function is selected, DC FUNCT changes to logic-0, and RL8 is energised (DC). This disconnects SLo from common-1, and PLo from the Over voltage and Over current Sense circuit.

4.8 HIGH VOLTAGE

The circuits described in this section perform the following functions:

- Generate a 16kHz sine wave by band-pass filtering a 16kHz squarewave from the Reference Divider Assembly
- (2) Control the amplitude of the 16kHz sine wave in a voltage-controlled amplifier, followed by power amplification to drive a step-up HV transformer.
- (3) Rectify and filter the HV transformer secondary voltage to provide DC voltages to the I+ terminal:
 - -200V to +200V on 100V Range -1200V to +1200V on 1000V Range
- (4) Sense the voltages at the output terminals (or at the load in Remote Sense)

(5) Attenuate the sensed voltage and compare against the DC Reference Voltage in the Error Amplifier, using the error voltage as drive to the Voltage-Controlled Amplifier.

The circuits together form a negative-feedback loop which refers the output DC voltage to the value of the DC Reference Voltage, using AC drive transformation and DC sense attenuation as means of achieving the required high voltage outputs. This is illustrated in Fig. 4.33, which shows 100V Range selected, positive output in remote sense with output on.

In the main, the circuits are located on the Power Amplifier (DC) Assembly. The Error Amplifier, VCA drive circuitry, sense attenuator, overvoltage and overcurrent detectors and output switching are located on the DC PCB Assembly. Some of these circuits are common to the Low Voltage DC functions.

4.8.1 General (Fig. 4.33)

AC transformation is carried out at 16kHz, derived from M16 in the Analogue Interface 13-bit counter, and transferred into guard as a square wave through optocoupler M3 on the Reference Divider pcb.

The square wave is filtered to provide a 16kHz sine wave. The filter has high selectivity at 16kHz to eliminate harmonic distortion.

The sine wave amplitude is controlled by the DC loop-error drive in a Voltage-Controlled Amplifier (VCA), and power-amplified to drive the step-up transformer primary. Range switching is achieved by changing the step-up ratio, both primary windings being connected in series on the 100V Range.

A constant-current source acts as a shunt to sustain the current drawn from the high-voltage secondary winding through the bridge rectifier, and polarity is switched with respect to common-2 via the LC-filtered \pm 15V common-2 supplies. Positive polarity output is referred to $-15\mathrm{V}$ at zero output, to provide an overlap with Negative polarity output referred to $+15\mathrm{V}$. The overlap allows digital calibration constants to be used to align zero voltage output in both polarities to the same calibrated zero.

The main output filter is placed in the output line. This is a low-pass filter with a high rejection at 16kHz, reducing the ripple voltage to within specification limits.

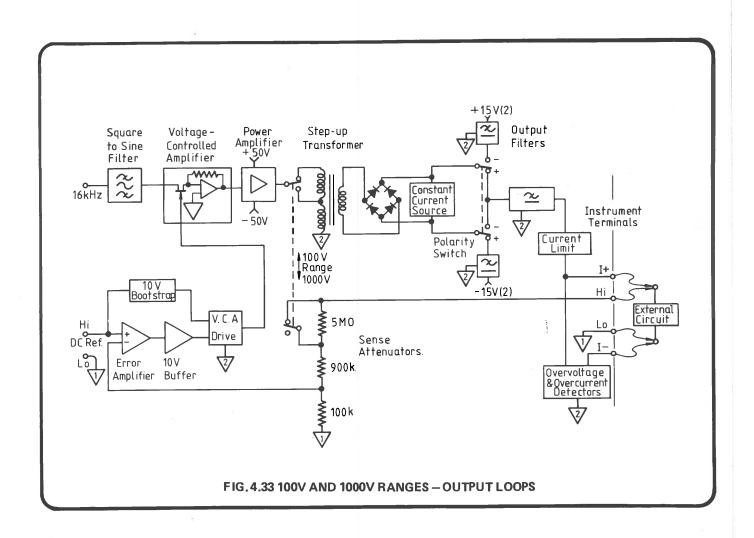
Shutdown of the high voltage power-circuitry occurs when an output current of 30-40mA is detected in the Current Limit circuitry. The output voltage is fed

out through the Range switch on the DC pcb, where it is subject to Remote Sense and Output On/Off switching and over voltage detection, before being passed to the I+terminal by the same route as for low voltage ranges. The external current is sunk into common-2 via the overcurrent detector, which warns the control processor when the output current exceeds approximately 28.5mA. On 100V and 1000V ranges the processor will switch the output off on receipt of the overcurrent signal from either the current limit circuit or the overcurrent detector.

The output voltage is sensed between the Hi and Lo terminals. Lo is referred to Sense attenuator Lo and DC Ref Lo. The Hi sense voltage is divided in the Sense Attenuators by 10 (100V Range) or 60 (1000V Range). The attenuated output is compared against DC Ref Hi in the Error Amplifier, and modifies its output to the 10V Buffer and VCA drive. The 10V Bootstrap, in addition to supplying the Error Amplifier, also buffers DC Ref Hi as reference for the VCA Drive circuit.

The error voltage between the buffered DC Ref Hi and the 10V buffer output is conditioned by the VCA drive to provide a suitable control signal for the VCA itself.

The Sense loop thus stabilises the High Voltage DC output to a value which on 100V range is 10 times the DC Ref voltage and on 1000V range is 60 times the DC Ref voltage. On 1000V range, the DC Ref voltage is scaled digitally so that Full Scale of 20V corresponds to 1200V on the OUTPUT display and at the output terminals.



4.8.2 Square-Sine Filter (Circuit Diagram No. 430449 Sheet 4)

The 13-bit counter in the Analogue Interface generates 16kHz at M16-14 (Circuit Diagram 430443 Sheet 2), which is transferred into guard through optoisolator M3 on the Reference Divider (Circuit Diagram 430444 Sheet 4). The 16kHz square wave, switching between logic-1 = 0V and logic-0 = -15V, enters the Power Amplifier pcb on J9-86.

M8 buffers apply the full 15V p-p squarewave to coupling capacitors C38 and C39. M3 input circuit is a 16kHz series-tuned filter. This, together with M3 active low-pass filter, produces a sine wave at TP15 of 0.6V to 0.8V pk-to-pk amplitude and approx 5% distortion.

4.8.3 Voltage Controlled Amplifier

The DC loop error voltage is applied from the VCA drive to Q26 to control the input resistance to M4. Q26 and R66 are matched to standardise the gain range (mid-range gain of approx 0.5). A manual gain adjustment

(Q28, R68, R65) is provided for test purposes.

M4 output is AC-coupled as drive to the power amplifier.

4.8.4 Output Clamp (Circuit Diagram No. 430449 Sheet 1)

When the CPU switches the Power Amplifier on or off in 100V or 1000V ranges, it controls the 16kHz drive to the high voltage power amplifier. For both ranges, a signal PA OFF is provided at M15 pin 5 on the Reference Divider (Circuit Diagram No. 430444 Sheet 4) which is buffered by M8/Q43 on the Power Amplifier (Circuit Diagram No. 430449 Sheet 4), as PA OFF B signal.

With output off, the Output Clamp circuit is allowed to operate by D47 reverse bias. The \pm 2.5V Reference from the 50V Power Supply is divided by R70/71/73/74 to provide \pm 0.45V bias for M5 on 100V range. Q27 conducts only when the CPU has selected 1000V range, reducing M5 bias to \pm 0.025V.

Example of clamp action

On 100V range, the bias on M5 pin 5 is -0.45V. If the PA output voltage is less negative than -5.95 volts, M5 pin 6 is more positive than pin 5 and D46 is nonconducting due to -15V at TP26. If the PA output is more negative than -5.95V, M5 pin 6 is more negative

than -0.45V, TP26 rises to cause D46 conduction and Q33 starts to conduct. The 16kHz drive to the PA is reduced due to the extra volts drop across R87, which limits the negative half-cycles of the PA output at approx. -6V.

In similar fashion, D49 conducts on positive output half-cycles to start limiting at +6V and on 1000V range, positive and negative half-cycles start limiting at approx. 0.3V.

This limiting action ensures that when the 4000 output is off, the PA output to the step-up transformer is limited to less than 10V peak on 100V range, and less than 3V peak on 1000V range.

As the PA OFF B input is low (-15V) when output is on in 100V or 1000V range, Q33 is pinched off, and the PA output is not clamped.

Q34 in the PA drive line is pinched-off by $\overline{\text{LIM}}$ at -15V when the output Current Limit is activated (see Section 4.8.9).

4.8.5 Power Amplifier (Circuit Diagram No. 430449 Sheet 1)

The Power Amplifier deals with AC and DC separately. The overall purpose is to stabilize the mean output level at zero DC, whilst driving the step-up transformer with a large enough voltage swing to provide DC output voltages at the I+ terminal of 200V (100V range) and 1200V (1kV range). The power delivered to the transformer is sufficient to provide output loading for each range of 25mA, with a little in reserve.

C46 is the only DC blocking capacitor in the whole amplifier, so Q36 and Q35 form the AC preamplifier as one half of an emitter-coupled cascode amplifier with Q38 and Q37. Q40 provides the constant current which reduces common mode disturbances at Q37 collector.

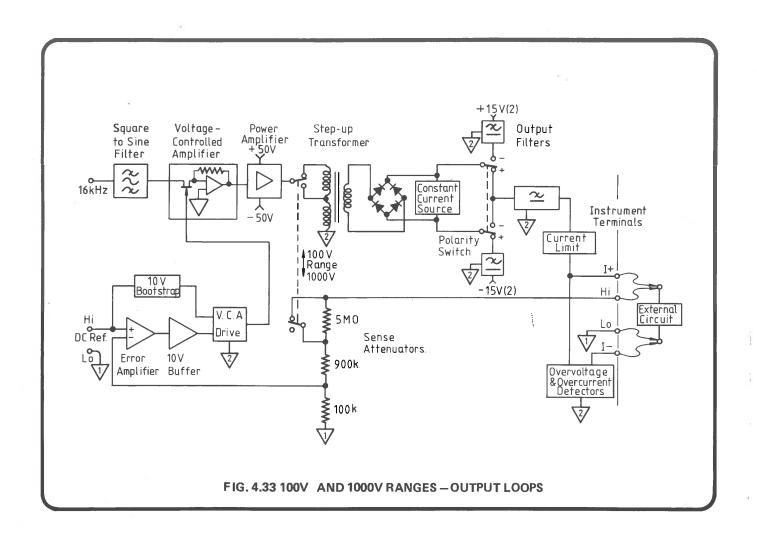
The DC path through the power amplifier passes through M6 and the Q38/Q37 half of the long-tailed pair. The DC loop is self-zeroing at input and output due to its

three inversions in M6, Q38 and Q39. M6 is converted into an integrator by C48, so acts as a low-pass filter with unity gain at around 15Hz. Q32, Q39 and Q42 shift the DC level and provide high driver gain into the output Darlington amplifier. Q5 establishes the correct bias on Q24 to reduce crossover distortion, compensating four output V_{be} variations with temperature by being in thermal contact with the positive heat sink. Q41 provides constant current pull-down for the driver stage.

Q29 and Q30 current limiters prevent damage in the event of an output short circuit.

The d.c. output level is therefore referred to common-2 by R116 at M6 non-inverting input.

The AC loop also includes three inversions, so feedback controls both AC and DC to R96/(R87 + R88).



4.8.6 High Voltage Transformer and Rectifier (Circuit Diagram No. 430449 Sheet 3)

Relay RL2 is energised permanently when the watchdog BARK signal is low (-15V). The 16kHz PA output passes via RL2 pins 7 and 10 to RL1 contacts and to the High Voltage transformer.

When the watchdog BARK signal goes high (0V), the drive is removed and the transformer primary is shorted to common-2 as RL2 is de-energised.

RL1 is only energised on 1000V range with switch S1 ON (indicated by LED D37 lit on the PA (DC) Assembly. On 100V range it is set as shown on the circuit drawing, selecting both primaries in series for a step-up ratio of 9.2. For 1000V range, RL1 connects the PA

output to only one primary winding (J6-1 to J6-4), a step up ratio of 49.2.

These ratios generate secondary voltage outputs sufficiently large to provide DC outputs from the instrument of 200V (100V range) and 1200V (1000V range).

The rectifier bridge uses to series diodes in each arm. Each diode is current-rated at 1A, with a p.i.v. of 1.5kV.

N.B. The transformer secondary, and bridge rectifier are not directly referred to any common. This allows the rectifier output to float so that it may be used for either polarity.

4.8.7 Constant-Current Source and Overvoltage Detector Assembly (400472)

4.8.7.1 Constant-Current Source

Q1-12 form a series Darlington chain, connected across the bridge rectifier output as a constant-current source, having two functions:

- (1) It provides a discharge path which is a "constant" current at all output voltages, of approx 1.2mA above 120V, rising to 7mA at 0V.
- (2) It maintains diode bridge D56-D63 conduction in no-load conditions. At higher voltages, D14-D17 limit Q11 base voltage to +2.4V, limiting the series current in R11 to 1.2mA, with Q13 pinched off. At lower voltages Q13 conducts, shunting R11 with 170-180 Ω (R10 plus Q13 'On' resistance which falls to approx 125 Ω), and increasing the discharge current to approx 7mA.

Note that the minimum voltage applied across the constantcurrent source is 15V. Even at zero output voltage and current, the diode bridge generates 15V to back off the positive or negative 15V connected to RL3.

4.8.7.2 Overvoltage Detection

Zener diodes D1 - D13 form a series chain across the High Voltage supply. When the voltage exceeds 1440V this chain conducts, lifting D13 cathode and driving optoisolator M9. M9 emitter rises, and provides a "Reset" logic-1 (0V) input to M10-10, resulting in a logic-0 (-15V) output from M10 - 13.

The operation of M10 and subsequent action is described in section 4.8.9.

4.8.8 Polarity Switching and Ouput Filter

Double-pole relay RL3 performs the polarity-reversal. With RL3 de-energised as shown the output filter is connected to rectifier negative, and +15V Common-2 supply is connected to rectifier positive. During zero calibration, the +15V is backed off to give a true zero output by an output from the rectifier.

When RL3 is energised by the POSITIVE signal from the serial data-link parallel output registers at logic-1 (0V), the output filter is connected to the rectifier positive rail, referred to -15V common-2 supply. Again, this -15V is backed off to zero when calibrated.

Filtering is accomplished in three stages:

- L8, R128, C58, C59 2-pole filter attenuates 16kHz by approx 30dB and 32kHz by approx 42dB.
- (2) L9, L10 and associated capacitors form a 5-pole filter with elliptic characteristics, attenuating by at least 60dB above 16kHz.
- (3) The final stage is formed by C1 on the Mother PCB (Refer to Circuit Diagram 430440 Sheet 1) and the output resistance (approx 500Ω) of the high voltage circuitry on the Power Amplifier PCB (Circuit Diagram 430449 sheet 3). This gives attenuations of approx. 30dB at 16kHz and 36dB at 32kHz.

4.8.9 High Voltage Output Current Limit Detector

Section 4.7.10 describes over-current sensing circuitry on the DC pcb Assembly, which provides LIM ST 1 signal when the output current exceeds approximately 28.5mA. It also generates HV STATUS signal when the output voltage exceeds 130V.

In addition to these signals; the two high voltage ranges are protected against over-voltage (see Section 4.8.7.2) and over-current on the Power Amplifier pcb itself.

4.8.9.1 Over-Current Detector

An output current of approx. 35mA will cause the output to be shutdown. Opto-isolator M11 is set to respond to a threshold level of approximately 5.25V across R143, causing conduction between pins 6 and 5.

4.8.9.2 Protection Logic

On Power-up, M10 settles into its stable state with Q (pin 2) and Q (pin 13) both at logic-1 (0V). Both sections have set and reset pins at logic-0 (-15V), and PA OFF B signal at logic-1. Q44 is cut off, as also are M9 and M11 output emitter-followers, holding M10 reset (pin 10) at -15V (logic-0).

By selecting Output On in 100 or 1000V range, PA OFF B goes to logic-0. M10 is not clocked by the negative edge, but Q44 is turned on, providing the supply to M11, which remains cut-off unless overcurrent is detected.

When an over-current is detected M11 Output stage conducts, lifting pin 5 from -15V to approximately -1V (logic-1 on M10 pin 10). The Q output of M10 (pin 13) is forced into reset state. HI I ST and I LIM fall to logic-0 (-15V).

The I LIM signal switches off Q34 at the input to the Power Amplifier (sheet 1), removing the 16kHz drive, and reducing the output voltage to zero, thus providing instantaneous shut-down. HIIST signal is returned

via the serial data link to the CPU, which presents "Error OL" on the MODE display and carries out the normal Output OFF routine, disconnecting the external load, reducing R143 current to zero, hence cutting off M11 Output stage. M10 pin 10 reverts to Logic-0, sensitising the flip-flop to any positive clock-edge on pin 11.

At the same time, the PA OFF B signal rises to Logic-1, cutting off Q44, and clocking the logic-1 on M10 pin 5 through to pin 1 (Q) so Q (pin 2) goes to logic-0.

Pin 4 rises on time constant C61 R135, and the monostable times out after 8mS by forcing Reset state. Pin 1 falls to logic-0 and rapidly sets pin 4 to logic-0, sensitising the monostable to any positive clock-edge on pin 3. Meanwhile, pin 2 has reverted to logic-1, clocking the logic-1 on pin 9 through to pin 13, and returning HIIST and ILIM signals to their non-active logic-1 state. The detector remains in this state until output is again switched ON on 100V or 1000V range. The "Error OL" presentation is retained until the user makes a further Front Panel or Remote selection.

If the instrument is operating normally with Output ON in 100V or 1000V range, and Output OFF is selected, M10 monostable pin 2 again delivers its negative 8mS pulse to Pin 11 and the logic-1 at pin 9 is clocked in. But as pin 13 is already at logic-1 this does not disturb the HIIST and ILIM signals.

4.8.10 Output Switching, Sense Attenuator and Guard (Circuit Diagram No. 340445)

The high voltage output is taken from the Power Amplifier to be Range-switched on the DC pcb (RL2 on Circuit Diagram No. 430445 Sheet 1). On 100V or 1000V the selected PHi voltage is Remote/Local and Output ON/OFF switched before passing to the instrument output I+ terminal. Any output current drawn by the external load is returned via the I- terminal and the over-current sensor to common-2 (Refer to section 4.7.10).

The external load Lo is connected directly to the Lo terminal and hence to common-1 in the DC pcb. Load Hi is returned via the Hi terminal to the head of a high-voltage attenuator (R10, R27, R48, R66, R89, R96, R99 of circuit drawing 430445 Sheet 1), which is also referred to common-1.

The attenuator is range-switched by RL3 between 1000V and 100V ranges. On 1000V range the attenuation is 60:1, reducing Full Scale load voltage of 1200V to 20V for comparison against the DC Ref Hi voltage. On 100V range; R89, R96 and R99 divide the voltage by 10. The attenuator and DC Ref Lo are both returned to common-1.

To guard the necessarily high-impedance attenuator each connection between resistors is shielded. The potential divider R8, R9, R25, R26, R46, R47, R64, R65, R88, R95 and R98 connected between the Power Amplifier output voltage and common-2 maintains each screen at the potential of the connection it is shielding, to reduce leakage. RL3 shorts part of the divider on 100V Range to equalise potentials.

4.8.10.1 Model 4000A - 100V/1000V Precision Sense Attenuator (Layout Drawing 400445 Sheet 1 and Circuit Diagram 430445 Sheet 1)

In the Model 4000A, the DC PCB is fitted with an uprated 100V/1000V attenuator, to hold the specification over a wider temperature range than the 4000:

- (1) R10, R27, R46 and R48 (1M25) are replaced by five 1MO resistors.
- (2) R89, R96 and R99 are replaced by one 900k/ 100k unit.

The whole attenuator set is referenced as part no. 090057/A.

4.8.11 VCA Drive and Control

The attenuated sense signal is applied to the inverting input of the Error Amplifier via RL11-10 and RL9-14. This bootstrapped, high-gain amplifier compares the sense signal with DC Ref Hi. When both are equal: the output from the 10V buffer at TP5 star-point, the bootstrap common BS2, DC Ref Hi and the sense signal are all at the same level. Therefore the differential input to M12 (VCA error amplifier) is zero at R42/R43.

The gain from M12-1 to I+ terminal is approx. x2000 on the 1000V Range and approx. x400 on the 100V Range. Components R97, C33 at the Error Amplifier input, and R33, C16 on M11 provide frequency compensation for the overall loop.

The second M12 stage acts as a polarity switch. With OUTPUT ON + LED lit, the POSITIVE control signal is at logic-1 (0V). Q2 conducts setting M12 non-inverting

input (pin 5) to zero volts, so the amplifier inverts the pin 6 input. If OUTPUT ON- LED is lit the POSITIVE signal is at logic-0 (-15V) cutting off Q2, M12 pin 5 follows the pin 1 voltage, so the amplifier acts as a voltage follower.

The polarity switching is necessary to adapt the bi-polar action of the error amplifier to the unipolar sensitivity of the Voltage Controlled Amplifier.

4.8.11.1 VCA Action

If a user increases a positive OUTPUT display value, the positive DC REF Hi voltage will increase, (a demand to increase a positive output voltage). The polarity switch inverts the positive input from M12-1. So M12-7 feeds a negative output to M11. This is inverted and fed, via the Mother pcb, to D36 on the Power Amplifier Assembly as an error signal (Circuit Diagram No. 430449 Sheet 4).

On the Power Amplifier Assembly; as the VCA control signal becomes more positive the gain of M4 between TP15 and TP19 is increased, thus increasing the output at I+. The attenuated sense voltage rises to equallise the differential inputs to the error amplifier, and the I+ voltage stabilises at its new value.

M4 has a maximum gain of x12 when TP24 is at 0V and a minimum gain of x0.01 when TP24 is at -12V or lower.

4.8.12 Decoding Logic (Circuit Diagram 430499 Sheet 4)

4.8.12.1 "PA OFF"

The PA OFF signal is originated by the CPU and latched at M15 Q2 (pin 5) Serial/Parallel data converter on the Reference Divider pcb (Circuit Diagram No. 430444 Sheet 4); as logic-1 (0V) for PA OFF, and logic-0 (-15V) to provide the DC 100V/1kV drive from the Power Amplifier Assembly. Under normal use test link TLJ is made, but for test purposes link TLJ can be unsoldered, and TLH made. PA OFF is buffered by M8 and Q43 as

PA OFF B, which has two functions:

- (1) At logic-1 it allows the output clamp to operate but at logic-0 removes the clamp from the PA input. (Refer to Section 4.8.4).
- (2) A 0-1 transition by PA OFFB clocks the over-voltage and over-current detector M10 to reset. (Refer to Section 4.8.9).

4.8.12.2 "POSITIVE"

The polarity of 100V and 1000V Range outputs is determined by the CPU. In addition to changing the polarity of the DC Ref Hi signal fed from the Reference Divider into the DC Error Amplifier, the POSITIVE signal performs polarity switching in the VCA drive (refer to sections 4.6.11 and 4.8.11). On the Power Amplifier pcb it energises RL3 when at logic-1 (0V), connecting the

positive rectified voltage from the HV transformer to the Output Filter (Refer to Section 4.8.8). At logic-0 (-15V), RL3 is de-energised, and the drive to the output filter is negative.

The POSITIVE signal is latched at M31 Q1 (pin 4) on the Reference Divider pcb serial/parallel data converter. (Refer to Section 4.5.5).

4.8.12.3 "HV ENBL"

On 1000V Range, HV ENBL signal is at logic-1 (0V) to energise RL1, whose contacts apply the P.A. output to the single primary winding (J6-1 to J6-4) of the high voltage transformer. (Refer to Section 4.8.6). The Output Clamp circuit requires reduced reference voltages on this

range, so HV ENBL is buffered as PA 1kV signal and applied to Q27 for this purpose (Refer to Section 4.8.4). Switch S1 on the PA pcb can be set to disable the 1kV Range output by releasing RL1 and shorting the 16kHz drive to the PA. When the switch is in the "Enable" position, LED D37 lights as a visible warning.

4.8.12.4 "DC ST"

The DC ST line returns to the Reference Divider pcb, (Circuit Diagram No. 430444 Sheet 4), and is connected there to M21 pin 5. An identical line from the DC pcb also connects to M21 pin 5. Each line is pulled down to -15V through a $15k\Omega$ resistor. When both lines are correctly connected, M21 pin 7 (TP17) is at logic-0 (-15V), input

to M22-13 Parallel/Serial data converter. The DC status bit is read out of the SSDA "Receive" register by the CPU on each data transfer. If at logic-0, DC function may be selected by a user. If at logic-1, the CPU inhibits selection. The same method is used for AC ST, but as AC is not fitted in the 4000, M22-4 will always be at logic-1.

4.8.12.5 "BARK"

The Safety Monitor (Watchdog) produces the BARK signal when the CPU or SSDA is functioning incorrectly, and the SAFETY message is presented on the MODE display. The BARK signal is normally at logic-0 (-15V) so that RL2 is energised, applying the PA output

to the HV transformer. When a failure trips the watchdog, BARK goes to logic-1, de-energising RL2, which disconnects the PA output and shorts the HV primary to common-2, reducing the 4000 output voltage to zero. (Refer to Section 4.5.6 for information on the Safety Monitor).

4.8.13 50V Power Supply (Circuit Drawing No. 430449 Sheet 2)

The power supply on the PA pcb provides \pm 50 volts regulated power for the Power Amplifier. It incorporates "Foldback" current limiting and "excess input voltage" limiting for both polarities. Overheating of the positive or negative heatsink (PA Output stages) generates a TEMP ST signal to the CPU via the serial data link. Overheating of the PS/I heatsink, failure of the \pm 15V supply or \pm 50V output undervoltage; generates a PS ST signal to the CPU.

In both cases the CPU sets 4000 Output Off and displays a FAIL message:

FAIL 1 — TEMP ST at Logic-0 FAIL 7 — PS ST at Logic-0

When the power supply is operating normally, both signals are at logic-1. The logic levels for these signals at TP3 and TP22 are Logic-0 = -15V, Logic-1 = 0V (common-2).

4.8.13.1 50V Supply Regulation

Power is input from the Line Transformer secondaries, both fused at 4A. R1 provides an adjustment to eliminate line frequency hum on the guard shields, in conjunction with R52/C4 on the Mother pcb. (For adjustment procedure refer to Section 5.7).

The secondaries are referred to common-2, and the rectified outputs are smoothed by reservoir capacitors C2 and C3 at the rear of the Mother pcb.

The series regulation elements Q3 and Q4 are mounted on the PS/I heatsink assembly. These Darlingtons are driven by Q10 and Q9.

NB. The following description refers only to the positive 50 Volt supply. The action in the negative supply is similar.

Q17 generates constant current of 3mA to activate D15 2.45V Zener diode. The +2.45V provides the positive reference supply for the Output Clamp circuit (Refer to Section 4.8.4.). It is also the reference for comparator M2-2. The output voltage is sensed on the +50V rail and divided down to Reference potential at M2-3. M2-1 output drives Q6 whose collector voltage at TP18 controls Q3 (PS/I Heatsink) conduction via Q10. If the +50V rail voltage falls due to loading, TP18 voltage rises, increasing the conduction of Q3 to restore the output rail voltage.

4.8.13.2 50V Current Limit (Positive 50V only described)

R24 is the series current detector, which drops 0.4V at 2.7A. Q19 generates a constant current of approximately 3mA which can be shared between Q12 and Q11. Q12 is saturated, generating approximately 200mV across R39. With little or no load current passing through R24, Q11 is off. When the current through R24 reaches approximately 2.7A, Q11 is switched on.

 $$\rm Q11$$ collector voltage rapidly falls below Q10 base voltage, D25 conducts and pulls Q10 base voltage

down, reducing Q3 conduction. This reduces the current through R24, but with Q11 fully conducting, it is held on by the voltage across R39. As a result, Q3 conduction can fall to approximately 500mA, and with the overload still present, the 50V rail voltage can fall to approximately 12.5V. This is a stable condition which persists until the 4000 is powered-down. As the voltage falls below +43V the under-voltage detector is activated (Refer to Section 4.8.13.3).

4.8.13.3 Under-Voltage Detection

With the Power Supply operating normally, the positive rail voltage lies between +49.5V and +52.2V. M1-3 is held at approximately +2.85V, and as the +2.45V Reference is connected to M1-2, D11 is reverse-biassed by +15V at M1-1. (D11 anode is normally pulled to 0V by AN2 on the Reference Divider pcb — Refer to Circuit Drawing No. 430444 Sheet 4).

When the rail voltage falls below approximately +43V, M1-3 falls below +2.45V, and M1-1 changes polarity to -15V, forward-biassing D11, and setting PS ST to logic-0. This is detected by the CPU, which presents FAIL 7 on the MODE display and sets 4000 Output OFF.

4.8.13.4 50V Power Supply Shutdown

At normal operating temperatures, the PS/I heatsink thermal detector has high resistance (approximately 100k Ω). Q3 base is biassed by approximately +1V from the junction of R13/R9, so Q3 is saturated, holding approximately 150mV across R7 — R6, cutting Q1 off. The same 150mV holds p-channel FET Q4 On, which in turns holds Q2 cut off. D5 is unbiassed so PS ST is at logic-1 (0V).

If either the +15V or -15V supply fails, the voltage at Q3 base falls and cuts Q3 off. The clamp on Q1 base is removed, and it draws collector-current through

R26, turning off the conduction in Q3 (PS/I heatsink). In the negative supply, Q4 is cut off, and Q2 turns off Q4 (PS/I heatsink) conduction. D5 is forward-biassed by -15V from the unregulated supply, clamped by D4, setting PS ST to logic-0 (-15V).

If the PS/I heatsink overheats, the temperature is detected by R3 (NTC thermistor). R3 resistance falls from $100k\Omega$ to 100Ω (approximately) as its temperature rises from 80°C to 90°C , reducing Q3 V_{be} to approximately 200mV. Q3 cut-off initiates the power supply shutdown as for loss of $\pm15\text{V}$ supply.

4.8.13.5 PA Overheating

The Positive and Negative Heat Sink assemblies house the Power Amplifier output transistors. Each assembly is sensed by a NTC thermistor. These are connected in parallel, in series with R35 across the -15V supply. If

either heatsink overheats, the TEMP ST signal changes from logic-1 to logic-0, the CPU presents FAIL 1 on the MODE display, and turns the 4000 Output OFF.

4.9 CURRENT (Option 20)

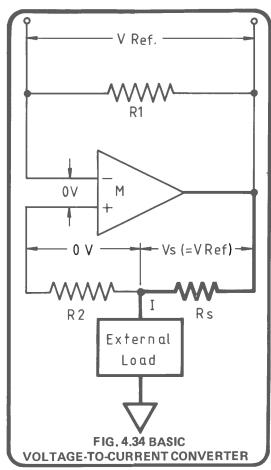
The circuits described in this section perform the following functions:

- Divide the DCI REF voltage (-20V to +20V) by 10 (-2V to +2V)
- (2) Generate output currents whose value varies directly as the value of the DCI REF Voltage.
- (3) Provide switching of DC Current Output and Range, under the control of signals from the Analogue Control Interface.
- (4) Sense excess output voltage, providing a LIM ST 1 status signal to the CPU via the Analogue Control Interface.

The basic arrangement of the voltage-to-current convertor is shown at Fig. 4.34.

The Voltage to Current converter is located on the I/ Ω pcb. It provides five ranges of current output, drawn from the 4000 I+ and I- terminals; the Hi and Lo terminals are not used. The five ranges are 1A, 100mA, 10mA, 1mA and 100 μ A, each extending to 100% overrange.

The output currents are bipolar, controlled within each range by the value of reference voltage (DC 1 Ref) applied from the Reference Divider. The two higher ranges have their reference scaled in software to optimise the choice of circuit components.



4.9.1 Basic Voltage-to-Current Converter

The basic arrangement is shown on Fig. 4.34. A variable reference voltage VREF is developed across R1 between output and inverting input of the high-gain operational amplifier M. The non-inverting input is connected to the output via a resistor network, part or all of which is current-carrying. With both positive and negative feedback, the amplifier will force its differential input voltage to zero. It can only do this by adjusting

the current in the current-carrying path until the full value of VREF is developed across the path. (e.g. in Fig. 4.34 no current flows in R_2 , so all of VREF is developed across Rs). The values of VREF and "shunt" Rs thus determine the value of current flowing in the external circuit. In the 4000, the values of Rs are switched to select the Range in use, and VREF is adjusted to vary the output current within the selected Range.

4.9.2 Range Selection

Fig. 4.35 shows two Range configurations of the voltage-to-current converter. In each case VREF is 0.1 \times DCI Ref. RL1 is a bistable latching relay, in which solenoid current is required only to change state (Two solenoids are incorporated, one for each state).

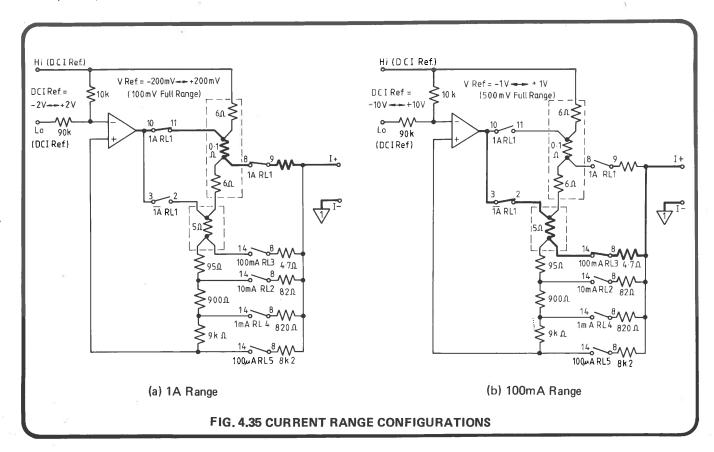
In the 4000, the voltage across the I+ and I-terminals is permitted to rise to 3V with full compliance. Each range incorporates a series resistive element connecting the range selection relay contact to the I+ terminal. These resistors enhance the stability of the circuit, with reactive loads.

4.9.2.1 1A Range (Refer to Fig. 4.35a)

The only current path available is through the 0.1 Ω shunt. As VREF is scaled to 100mV Full Range the current in the 0.1 Ω shunt must be $\frac{100\text{mV}}{0.1\Omega}$ = 1A. The 0.1 Ω shunt is

made up of ten 1Ω precision resistors in parallel, mounted on a separate pcb assembly 400510. As the 0.1Ω shunt is a

composite 4-wire parallel arrangement, each 1Ω precision resistor feeds its voltage to the joint sense lines through two summing networks of ten 61Ω resistors. As they carry no net current except when switching, they are represented on Fig. 4.35 as two 6Ω resistors.



4.9.2.2 100mA, 10mA, 1mA and 100 μ A Ranges (Refer to Fig. 4.35b)

With RL1 contact 2 closed, and contacts 8, 11 open, Relays 3, 2, 4 and 5 select the 100mA, 10mA, 1mA and 100 μ A ranges respectively.

- (1) 100mA Range: Fig. 4.35b is shown with 100mA Range selected. The 5Ω 100mA shunt is located on a heatsink on the I/Ω pcb assembly. DCI Ref is scaled in software for 5V Full Range, so that VREF is 500mV FR. This voltage appears across the 5Ω shunt, to generate 100mA at Full Range in the I+ line.
- (2) 10mA, 1mA and 100µA Ranges: The DCI Ref is scaled in software to 10V for each of these three full ranges, giving VREF of 1V FR.

Each Full Range drive current is set by the resistance between the range relay contact and RL1 pin 2. These currents are listed below against the total shunt value:

4.9.3 Voltage-to-Current Conversion Amplifier (Circuit Diagram No. 430448 Sheet 1) N.B. This amplifier is dual purpose AC/DC. In the 4000 it is used for DC only.

The Conversion Amplifier is driven by the DCI Ref input from the Reference Divider pcb. The value of DCI Ref determines the output current, and is scaled for

range as described in Section 4.9.2. DC Ref I is coupled: Hi to the output, and Lo to the inverting input through the 10:1 divider R43/R44.

4.9.3.1 Voltage Preamplifier

M3, M4 and Q6 form a high-gain, chopper-stabilised voltage amplifier. The input offset of Q6 is trimmed by M3, itself a chopper-stabilised amplifier of high gain and approximately 10Hz bandwidth. Q6 provides additional bandwidth for rejection of HF common-mode noise. M4 contributes additional gain and drives the high current output stage through Q7. Additional frequency

compensation is provided by C43/R81. The whole of the voltage 'pre-amplifier is bootstrapped by M7 and its associated circuitry to increase its input impedance and linearise its dynamic response. Extensive screening and filtering is employed to eliminate the effects of the chopping spikes at inputs and output of M3.

4.9.3.2 High Current Output Stage

The current output stages are located on the PS/I heatsink, current-limited by Q5/Q6. Q7 acts as a thermal detector on the heatsink to derive temperature compensation for the output stages, maintaining the quiescent current through Q1 and Q2.

The quiescent current acts to reduce the output resistance of Q1 and Q2, improving the linearity of the output current. This also suppresses any tendency for the

drive from M4 to fluctuate for output currents around zero; as the drive voltage must slew through approx. 1.3V after switching one output device off, before the other is switched on.

The current shunts complete the feedback and output circuits as described in Sections 4.9.1 and 4.9.2, and the output current is fed to the I+ terminal via protection and output switching.

4.9.4 Output Protection

D14, D15, D18 and D19 are 5V, 5 Watt zeners. D14 and D15 limit the excursion of the power amplifier output voltage in the event of the circuit going "openloop"; D18 and D19 place an absolute limit on the output voltage. The output compliance specification is valid only up to a maximum of 3V across the output terminals (Refer to User's Handbook for maximum load resistance values). Nevertheless, occasions may arise when

a user overloads the circuit by attempting to drive current into an open circuit (e.g. by disconnecting from a load with Output On). In this case the two Zener diodes D18 and D19 protect the Amplifier power stages by limiting the output voltage to 5V. But before the voltage reaches 5V the overvoltage detection circuit generates LIM ST 1 signal.

4.9.4.1 Guard Buffers

M1 guards out the leakage of the four highpower protection zener diodes in normal operation and protects against other leakage, by maintaining the guarding and screens around the output at the output potential. In addition to its bootstrap function, M7 acts as a buffer for guards around the amplifier input, thus preventing any local common-mode disturbances from affecting the performance of the main amplifier.

4.9.4.2 Overvoltage Detection

The output guard buffer drives the overvoltage detection circuit. M15 divides the output voltage by two and acts as an inverting full-wave rectifier, to accommodate both positive and negative voltages. The voltage at M15-4 increases negatively as the terminal voltage increases positively or negatively. M15-6 is biassed to -2.2V, so M15-7 reverse-biasses D10 unless the terminal voltage exceeds \pm 4.4V, when M15-7 will swing to the negative rail and pull the LIM ST1 line to -15V (logic-0).

The CPU receives the LIM ST1 signal via the serial datalink. When at logic-0, the message "Error OL" is presented on the MODE display and if 1A or 100mA range is selected, the 4000 Output is set off and DCI Ref voltage is set to zero, to limit the power developed as heat within the calibrator.

4.9.5 Current Switching Logic (Refer to Circuit Diagram No. 430448 Sheet 2)

The analogue control signals are transferred into guard on the Reference Divider pcb, and latched as 'Q' outputs in the Serial/Parallel Data Converter. Offset positive logic is employed: 0 = 15 V, 1 = 0 V for the signals entering the $1/\Omega$ pcb via J8 from the Mother pcb. The Ohms switching logic is described in Section 4.10.

M12 and M14 are Darlington open-collector Inverter/Drivers. The relay drive logic places a logic-1 (0V) on the input of selected drivers and logic-0 (-15V) on those not required. A selected driver operates its relay (s) by pulling its output voltage to -14V.

Whenever a switching command has been received the CPU performs a control-data transfer and the UPD (IG) line from J8-60 is pulsed to logic-0 for 50mS. Q1 is turned on, applying +15V to the relays connected to its

collector (Current relays RL11, 12 and 1). The selected relays are thus energised by 30V but after the UPD (IG) pulse has ended they are held on by 10.5V between -3.5V at the cathode of D1 and -14V at the selected driver output. This method reduces the local heat generated by energised relay coils, in the relay contacts.

RL1 is a bistable latching relay with two operating solenoids. A logic-0 at pin 6 switches the 1 Amp range on, and at pin 1 switches it off. Normally both pins are floating on an open collector, so the relay remains latched in one bistable state with both solenoids de-energised. During the 50mS UPD (IG) pulse, M16-1 and M16-12 are enabled, allowing the 1 amp range switching-logic state to change RL1 over (if required) before the UPD (IG) pulse ends.

4.9.5.1 Range Switching Logic

Range control data is input as a 3-bit code on IR ϕ , IR1 and IR2 lines. The bit-pattern is decoded to "1 of 8" by M6, to energise the correct relay(s) for the selected range. The resulting variants are listed in Table 4.2 against range selections. Note that RL5 (100 μ A range) is selected whenever the I function is deselected or if the watchdog has tripped and BARK signal is at logic-1.

4.9.5.2 Output Switching

The I FUNCT, BARK and OFF signals are decoded so that RL11 and RL12 are energised only when the 4000 I function has been selected, Output is ON and the watchdog has not barked (i.e. RL11/12 energised if M12-7 = IOFF BARK).

Range	Bit	Patter	n		,			ut pii					Range F	Relays E	nergised		
					(p	in 9	not c	onne	cted)						- · ·		
	IR2	IR1	IRφ	4	5	6	7	10	11	12	RL5	RL4	RL2	RL3	RL1 (6-7)	RL1 (1–12)	RL6
100μΑ	1	1	0					1			\checkmark			-		√.	
1mA	1	0	1						1			\vee				\checkmark	
10mA	1	0	0							1			\checkmark	,		\checkmark	
100mA	0	1	1				1							\vee		\checkmark	
1A	0	1	0			1											
10A	0	0	1		1	}					otion. W , from 1		,		,	√	√
100A	0	0	0	1		J	P	Jul	171	. a. igo	,	o ua	.00/(0			· V	

Notes:

- 1. 1 = 0V, 0 = -15V
- 2. All M6 Output pins at 0 unless shown at 1
- Unless shown energised on the table, all relays de-energised as in 430448 Sheet 1
- 4. One RL1 solenoid energised only during UPD (IG)
- RL5 energised when I function deselected or if watchdog has BARKed

TABLE 4.2 CURRENT RANGE SWITCHING LOGIC SELECTIONS

4.10 RESISTANCE (Option 20) (Circuit Diagram No. 430448 Sheet 3)

Eight standard resistors are mounted on the I/Ω PCB Assembly (400448), each being 4-wire connected to the instrument terminals by range-selection relays.

4.10.1 4-Wire Connection Symmetry

For any given resistor, the connections on the Hi side are made through contacts of the same relays used for the Lo side. The range relays are two-way and their connections ensure that in the sense (Hi-Lo) loop, all thermal contact voltages on the Hi side of any resistor are backed off by those on the Lo side. This symmetrical, 4-wire arrangement transfers the stability and accuracy of each resistor to the front (or rear) panel terminals.

4.10,2 4-wire Junctions and Pre-set Trimming

R63-72 are 4-wire resistors, so for $1\Omega-10 K\Omega$ selections the 4-wire junction is at the standard resistor itself. These resistors are parallel-trimmed.

R62, R74 and R73 are two-wire resistors. For these higher resistance values, $100 \mathrm{K}\Omega$, $1 \mathrm{M}\Omega$ and $10 \mathrm{M}\Omega$, series trimming is employed and the 4-wire junctions enclose the series chain.

Trimming resistors are selected and adjusted in the factory, under carefully-controlled environmental conditions, against traceable standards.

4.10.3 Methods of Calibration

Although each RANGE key is labelled with the nominal value, it is the calibrated value of each standard resistor which is presented on the OUTPUT display when selected. Routine recalibration consists of accurately measuring the resistor value and setting the display to that value without removing the instrument covers (Refer to Section 1.2.10). For many users, the main criterion is that the actual value is known, whereas exact alignment to the nominal is unimportant.

"Error 6" is displayed if the value entered by the user during calibration is outside the resistor's tolerance (Section 1.2) i.e. outside the calibration memory span. Under normal use the resistor drift is well within the tolerance, so "Error 6" appears only if the user enters an erroneous value.

If the resistor has been subjected to undue stress, it is possible that its value may have changed slightly, and be outside its tolerance. If it is less than approx. 50ppm outside tolerance an internal trimmer can be adjusted, and the value can be calibrated.

A stressed resistor may have been damaged if its value is greater than 50ppm outside its tolerance. It is advisable to have such a resistor tested or replaced by an agent of Datron Instruments.

Follow the procedure detailed in Section 1.5 to adjust the resistor value. If this is unsuccessful contact your Datron Instruments Service Centre.

4.10.4 Two-wire Connections

To avoid the intrusion of extra thermal voltages, no switching is employed for selection of 2-wire connections. Users are recommended to connect only to the Hi/Lo terminals, so the 2-wire mode should be recalibrated at these terminals.

4.10.5 4-wire/2-wire Display Values

When the 4000 is in Ω function, selection of Remote Sense mode (Key LED lit) displays the calibrated value for the 4-wire connection, but with the Remote Sense LED unlit, the 2-wire value is displayed.

4.10.6 Ohms Zero

With the 4000 in Ω function, pressing the zero key on the front panel energises relay RL10. This provides a true 4-wire short, the existing range remaining selected.

If Remote Sense LED is lit, the displayed value is zero and cannot be calibrated; but if unlit, the displayed value may be adjusted to the measured value as a calibrated 2-wire zero.

4.10.7 Output Connections-Function switching

The front terminal connections are routed via the I/Ω pcb, and it is there that they are switched between functions. With RL14 and RL19 de-energised as shown in Circuit Diagram No. 430448 Sheet 3, the DC Voltage Power and Sense connections to the DC pcb are routed Out to the I+, I-, Hi and Lo terminals.

NB If Option 20 is not fitted, the I/Ω Link pcb is fitted in its place to make direct connection from the DC Voltage output to the terminals (Refer to Section 3 Fig. 3.2)

4.10.8 Resistance Switching Logic (Refer to Circuit Diagram No. 430448 Sheet 2)

The analogue control signals are transferred into guard on the Reference Divider pcb, and latched as 'Q' outputs in the Serial/Parallel Data Converter. Offset positive logic is employed: 0 = -15V, 1 = 0V for the signals entering the I/Ω pcb via J8 from the Mother pcb. The Current switching logic is described in Section 4.9.

M13 and M14 are Darlington open-collector Inverter/Drivers. The relay drive logic places a logic-1 (0V) on the input of selected drivers and logic-0 (-15V) on those not required. A selected driver operates its relay(s) by pulling its output voltage to -14V.

Whenever a switching command has been received, the CPU performs a control-data transfer and the UPD (IG) line from J8-60 is pulsed to logic-0 for 50mS. Q1 is turned on, applying +15V to the Ω relays, which are connected to its collector. The selected relays are thus energised by 30V but after the UPD (IG) pulse has ended they are held on by 10.5V between -3.5V at DC cathode and -14V at the

selected driver output. This method reduces the local heat generated by energised relay coils, in the relay contacts.

When DC (Voltage) is not selected, the connections from the DC pcb are isolated by open contacts of RL13 and RL14 on the DC pcb. (Circuit Diagram No. 430445 Sheet 3).

The output connections from the Current section of the I/Ω pcb are linked directly to the I+ and I- terminals, but if I is not selected, Relays RL11 and RL12 are deenergised, isolating the Current output Hi and Lo from the common lines to the I+ and I- terminals. (Circuit Diagram No. 430448 Sheet 1).

When Ω is selected, relays RL14 and RL19 are energised, breaking the circuit to DC pcb Power and Sense, and connecting the four lines from the selected standard resistor to the I+, I-, Hi and Lo terminals. (Circuit Diagram No. 430448 Sheet 3).

4.10.8.1 Range Switching Logic

Range control data is input as a 3-bit code on $\Omega R \phi$, $\Omega R 1$ and $\Omega R 2$ lines. The bit-pattern is decoded by M10/M18/M19 to energise the correct relay(s) for the selected range. The resulting variants are listed in Table 4.3 against range selections. Note that unless Ω function

is selected M11 is disabled so that the hardware defaults to the 1Ω range, with no range relays energised. The same default condition occurs when Ω is selected, but the watchdog has BARKed.

Range	Bit	Pattern			Relay I		e Si		19 pi	ns		R	ange Re	elays E	nergise	d		Ω Zero Relay
	Ω R2	Ω R1	Ω R ϕ	2/13	3/6	4	11	3/8	10	11	RL13	RL9	RL15	RL8	RL17	RL18	RL16	RL10
Zero	х	Х	X	х	Х	Х	х	Х	х	Х	х	Х	х	Х	Х	Х	Х	√
1Ω	0	0	0															
10Ω	0	1	0							1							\checkmark	
100Ω	0	1	0					1							√			
1ΚΩ	0	1	1	:				1	1						\checkmark	\checkmark		
10ΚΩ	1	0	0	1														
100ΚΩ	1	0	1	1			1							\checkmark				
1MΩ	1	1	0	1								\checkmark						
10ΜΩ	1	1	1	1	1	1						\checkmark	\checkmark		1			

- Notes: 1. 1 = 0V, 0 = -15V.
 - 2. All Relay Drive Signals at 0 unless shown at 1. X = 0 or 1
 - 3. Unless shown energised on the table, all relays de-energised as in 430448 Sheet 3. X = 0 or 1
 - 1Ω range is Hardware default condition so all range relays de-energised.
 - Range Selections enabled by Ω FUNCT and BARK at the inputs of M11.

TABLE 4.3 RESISTANCE RANGE SWITCHING LOGIC SELECTIONS

4.10.8.2 Ω Output Switching

The Ω FUNCT, BARK and OFF signals are decoded so that RL14 and RL19 are energised only when the 4000 Ω function has been selected, Output is ON and the watchdog has not barked (i.e. RL14/19 energised if M13-7 = $\Omega \bullet OFF \bullet BARK$).

4.10.8.3 Ω Zero

The Ω FUNCT, BARK and Ω ZERO signals are decoded so that RL10 is energised only when the 4000 Ω function has been selected, the Zero Key has been pressed and the watchdog has not barked (i.e. RL10 is energised if M13-2 = $\Omega \cdot ZERO \cdot \overline{BARK}$)

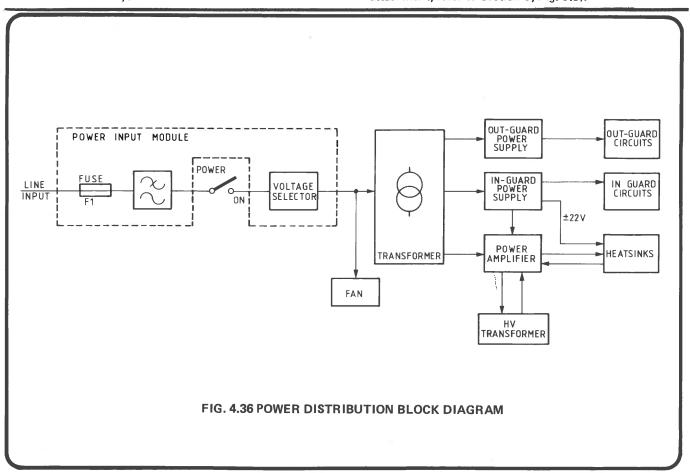
4.11 POWER SUPPLIES

The circuits described in this section perform the following functions:

- Line power switching, fusing, filtering, voltage selection and transformation.
- (2) Main digital supply generation and distribution (Outguard)
- (3) Display high voltage supply generation.
- (4) In-guard stabilized supply generation for Common-2, Common-3 and Common-4 circuitry.

A simplified power distribution block diagram appears at Fig. 4.36.

The power input module is mounted on the rear panel. The line transformer is located in the rear section of the instrument, close to the In-guard and Out-guard Power Supply PCB Assemblies. (For details of location and attachment, refer to Section 3, Fig. 3.3).



4.11.1 Line Power Distribution (Fig. 4.36 and Circuit Diagram No. 430439)

The single phase line supply enters the 4000 via a 3-pole input cable at the rear of the instrument. The cable connector plugs into a power input module (Circuit Diagram No. 430439) which contains a fuse, filter and line voltage selector pcb. (For details of fuse values and operating voltage selection, refer to the User's Handbook, Section 2). Both "line" and "neutral" rails are filtered by a low-pass LC network before being fed through the instrument to the two-pole "Power" switch on the front panel.

The switched supply is fed back to the power input module voltage selector pcb which configures the line transformer primary circuit as determined by the user. Power for the air circulation fan is provided directly from the power input module.

All line transformer secondaries are electrostatically decoupled from the primaries by a ground screen between the windings. The secondaries which supply the Common-2, Common-3 and Common-4 in-guard circuits are decoupled by an additional internal screen which is connected to the instrument guard.

4.11.2 Out-Guard Power Supplies (Circuit Diagram No. 430470)

4.11.2.1 Digital Main Supply

This circuit provides:

- (1) +8V unregulated supply for use in the Front and Digital PCB Assemblies
- (2) +5V regulated supply for out-guard digital circuits

4.11.2.2 +8V Unregulated Supply

This is taken directly from full-wave rectifier D1, D2 via fuse F1 (rated at 4A).

4.11.2.3 +5V Regulated Supply

The output voltage is controlled by series regulator Q5, Q6. Load current is sensed by R1 in the base-emitter circuit of Q1, which increases the conduction of Q5 and Q6 parallel combination for increases of load current. The 2.45 Zener D4 provides the reference voltage for comparators M1 at M1-3. The output voltage is sensed between the +5V and DIG common rails on the Mother PCB Assembly, and divided down to reference potential at M1-2. R8 and R9 ensure that regulation persists even if the sense links are disconnected.

M1 output drives Q2 whose collector voltage controls Q5 and Q6 conduction. If the +5V rail voltage falls due to loading, Q2 collector voltage rises, increasing Q5 and Q6 conduction to restore the rail voltage. Zener D5 prevents the positive excursion of the +5V rail in the

event of regulation breakdown, and Zener D3 provides current limiting by restricting positive excursions of Q2 base voltage, and thus limiting the drive to Q5 and Q6. C9 and C10 provide a controlled fast response to reduce the effects of voltage transients on the +5V rail.

PTC thermistor R7 protects the power supply from high ground-leakage currents, notably in the external circuits of the IEEE 488 bus system. R7 presents a minimum of 80Ω between the digital common line and ground; this resistance increasing with increasing current.

4.11.2.4 - 180V Display Supply

180 Volts are required to operate the plasma digital displays on the Front PCB Assembly. Because the display anode drivers are powered from the Digital Main Supply +5V rail, the 180V positive pole is referred to this rail in the power supply. The display cathode is therefore at a potential of -175V. (Refer to Section 4.4 for further details).

Series regulation is provided by D6, R16 and Q3, and shunt regulation by D7 and Q4. A supplementary +5V supply is fed out to the Front PCB Assembly from J4-21. This is available to power the LEDs in the front panel keys, but is not used on the 4000.

4.11.2.5 Common Mode Null

This circuit provides a line-hum cancelling (bucking) output to the instrument guard network. (For details of adjustment refer to Section 5.7).

4.11.3 In-guard Power Supplies (Circuit Diagram No. 430451)

4.11.3.1 In-guard Common-2 Supplies

Stabilized supplies for the Common-2 circuits are provided by five integrated-circuit regulators as follows:

- +15V from M2, protected at 2A by fuse F3;
- +8V from M4, driven from M2 +15V output;
- -15V from M1, protected at 2A by fuse F4;
- -8V from M3, driven from M1 15V output;
- -10V from M6, driven from M1 -15V output.

Chokes L4, L5 and L6 in the supply lines from the line transformer secondary windings attenuate high frequency transients on the ac input.

4.11.3.2 Current Option Supply

This provides $\pm 22V$ and $\pm 22V$ unregulated power outputs to the Power Supply/I Heatsink assembly. Both supplies are protected at 4A by fuses F1/F2. High frequency filtering of the ac inputs is provided by chokes L1, L2 and L3. The \pm 22V common return is maintained near to the common-2 return by resistor R1.

4.11.3.3 Reference Divider Common-4 Supplies

This circuit provides +36V, +18V and -15V regulated outputs to the reference divider in-guard circuits. The +36V supply is also used to power the +20V Master Reference.

Two secondary windings of the line transformer are used and inter-supply transients are reduced by the special coupling arrangements of common mode choke L10. The rectified output from bridge W4 is series regulated by Q4 with load current sensed by R3, Q2. Stabilization of the +36V output is performed by the feedback loop M5, Q1. A tendency for the output voltage to fall with an increased power demand will cause M5 non-inverting input to fall with-respect-to the 2.45V reference voltage at M5 inverting input. The corresponding fall at M5 output reduces the current flow through Q1 thus taking Q4 base potential more positive and increasing the output power. The output current is limited by the action of Q2 which conducts when R3 current is approximately 180mA. This additional drain from constant current source Q3 reduces the current through Q1 and therefore limits the load current through Q4. Zener diode D5 provides base/emitter bias for Q1.

The 36V output is dropped across Zener D6 to provide 18V (nominal) to the reference divider pcb where further regulation takes place.

The -15V supply is provided via bridge W3 and regulator M7.

4.11.3.4 In-guard Common-3 Supplies

The dc outputs from bridge W2 are regulated by integrated circuits M9 and M8 to produce +8V and -8V outputs respectively for the DC pcb assembly.

SERVICING AND INTERNAL ADJUSTMENTS

WARNING HAZARDOUS ELECTRICAL POTENTIALS

ARE EXPOSED WHEN THE INSTRUMENT COVERS ARE REMOVED.

ELECTRIC SHOCK CAN KILL!

CAUTION

The instrument warranty can be invalidated if damage is caused by unauthorised repairs or modifications. Check the warranty detailed in the "Terms and Conditions of Sale". It appears on the invoice for your instrument.

5.1 INTRODUCTION

This section provides procedures for maintenance operations which require removal of covers or partial dismantling. The operations fall into three categories, as described in Table 5.1 below.

Category A	Servicing Required	Time Interval	Procedure	Calibration Required	Calibration Procedure
Routine	Clean the Air Intake Filter	1 year (or less in adverse conditions)	Section 5.2	No	_
Servicing	Change the Lithium Battery (non-volatile calibration memory)	5 years	Section 5.3	(a) Full pre-ca THEN (b) Full routi recalibration	ne Section 1.2
Category B	Indication	Adjustment Required	Procedure	Calibration Required	Calibration Procedure
Ω Function Standard Resistor value adjustment	"Error 6" during Routine Recalibration	Re-set internal trimmers	Section 5.4	Routine Recalibration 4-wire and 2-v Resistance on	vire
				Calibra	tion required
Category C ^[1]	PCB Assembly	Adjustments	Procedure Section 5	Pre-cal (Sect. 1.4)	Routine Recalibratio (Section 1.2)
Adjustment following replacement of PCBs	Digital Reference Divider DC I/Ω pcb	– – – I Quiescent curre	 ent 5.5	Full Full —	Full Full DC (all ranges) I and Ω (all
	Power Amp (dc) Power Supply	PA Quiescent current bucking null	5.6 5.7	_	ranges) only —
	(Out-guard)	bucking null	5.7	_	_
	Positive Heatsink	P.A. Quiescent current	5.6	_	_
a	Power Supply/I Heatsink	I Quiescent curre	ent 5.5	- a	· _
				l	

Note [1] When an internal assembly is replaced, carry out the relevant adjustments before finally re-assembling the instrument. TABLE 5.1 CATEGORIES OF SERVICING AND INTERNAL ADJUSTMENTS

CAUTION After any maintenance operations which include removal of top or bottom ground/ guard assembly, carry out the Full Self-Test sequence (Section 2.3) before returning to normal use.

5.2 CLEANING THE AIR INTAKE FILTER (REFER TO SECTION 3.14, FIG. 3.8) DATRON PART NO. 450277-1

5.2.1 Servicing Frequency

The filter should be cleaned at intervals no greater than one year. In dusty conditions the frequency should be increased.

5.2.2. Removal (Fig. 3.8)

- (a) Remove the four M3 x 10mm pozi-countersunk screws (11) which retain the filter grille (12)
- (b) Remove the filter grille and reticulated foam filter.

5.2.3 Cleaning

(a) Wash the foam filter in a dilute solution of household detergent (hand-hot). Rinse thoroughly in clean hand-hot water and dry completely, without using excessive heat. (b) Clean the grille, and the grille holes in the rear panel. (Use a vacuum cleaner and soft brush on the rear panel).

5.2.4 Inspection

Examine the foam filter for wear, replacing if links are broken.

5.2.5 Reassembly

Place the filter in the grille housing and secure the grille to the rear panel using the screws removed in 5.2.2 above.

5.3 LITHIUM BATTERY (DATRON PART NO. 920101)

This procedure is to be performed at intervals of 5 years from new.

CAUTION The full Pre-cal and Routine Recalibration Procedures (Section 1.4 and 1.2) must follow the fitting of a new battery, before the instrument specification can be realised, as calibration data will be corrupted. It is therefore recommended that the battery be replaced immediately prior to a scheduled full recalibration.

5.3.1 Procedure

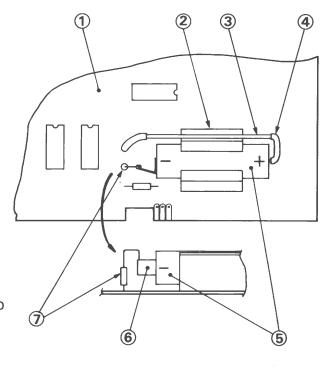
- (a) Ensure that power OFF is selected.
- (b) Remove the top cover (Section 3.2.1) and top ground/guard assembly (Section 3.4.1)
- (c) Remove the digital pcb assembly from the chassis (Section 3.6.1)

CAUTION Do not place the digital pcb on any conducting surface.

- (d) Remove battery as follows (Refer to Fig. 5.1)
 - (1) Push sleeve (4) back along the red wire to expose the solder joint.
 - (2) Unsolder red wire (3) from positive terminal of the battery (5)
 - (3) Unsolder the negative terminal of the battery (5) from resistor R60 at the wrapioint
 - (4) Remove battery (5) from battery clip (2)
- (e) Fit a new battery, reversing the procedure of step (d)
- (f) Refit the digital pcb assembly into the chassis (Section 3.6.2)
- (g) Refit the top ground/guard assembly to the instrument (Section 3.4.2)
- (h) Refit the top cover (Section 3.2.2)

NB The top cover will need to be removed again for Precalibration.

5.3.2 Carry out full Pre-calibration then full Routine Calibration in accordance with Section 1.4 and 1.2 respectively.



- 1. DIGITAL PCB ASSEMBLY
- 2. BATTERY CLIP
- 3. RED WIRE
- 4. SLEEVE
- 5. BATTERY
- 6. NEGATIVE BATTERY TERMINAL WRAPPED AROUND WIRE FROM RESISTOR R60
- 7. RESISTOR R60

FIG. 5.1 DIGITAL PCB BATTERY REPLACEMENT

5.4 Ω FUNCTION — STANDARD RESISTOR ADJUSTMENT

5.4.1 Introduction

Routine adjustment of the standard resistors used in Ω function is not required. A resistor is calibrated by the user entering its measured value into a non-volatile calibration memory. This value is subsequently recalled and displayed to the user each time the resistor is selected.

5.4.2 "Error 6" Message

"Error 6" is displayed if the value entered by the user during calibration is outside the resistor's tolerance (Section 1.2) i.e. outside the calibration memory span. Under normal use the resistor drift is well within the tolerance, so "Error 6" appears only if the user enters an erroneous value.

5.4.3 Undue Resistor Stress

If the resistor has been subjected to undue stress, it is possible that its value may have changed slightly, and be outside its tolerance. If it is less than approx. 50ppm outside tolerance an internal trimmer can be adjusted, and the value can be calibrated.

5.4.4 Possible Damage

A stressed resistor may have been damaged if its value is greater than 50ppm outside its tolerance. It is advisable to have such a resistor tested or replaced by an agent of Datron Instruments.

5.4,5 To Reset Internal Trimmers

Follow the procedure detailed in Section 1.5 to adjust the resistor value. If this is unsuccessful contact your Datron Instruments agent.

5.5 I/Ω PCB — I FUNCTION QUIESCENT CURRENT ADJUSTMENT

Replacement I/Ω assemblies are set up by the manufacturer to ensure correct operation. The final adjustment of the quiescent current in the power stage of the Voltage-to-Current converter is delayed until the pcb is installed in the user's instrument. For this procedure, a 0.1Ω resistor is inserted in series with each 22V supply line to the power stage (Located in the Power Supply/I Heatsink assembly). The quiescent current is set to 10mA by adjusting the voltage across one of the resistors to 1mV using R23 on the I/Ω assembly.

5.5.1 Test Equipment Required

- (1) Digital Voltmeter (Datron Instruments model 1071)
- (2) Two 2.5 watt resistors, 0.1Ω , \pm 10%, Wire Wound. (Welwyn W21 or equivalent),

5.5.2 Initial Conditions

4000 Power OFF

Top cover removed (Section 3.2.1)

Top ground/Guard assembly removed (Section 3.4.1) Replacement I/Ω pcb assembly not yet fitted into J8 (mother pcb)

5.5.3 Procedure (Refer to Layout Drawing No. 400448 and Circuit Diagram No. 430448)

- (a) Before fitting the I/ Ω pcb assembly, ensure that R23 is set fully counter-clockwise.
- (b) Fit the I/Ω pcb assembly (Section 3.6.2)

- (c) Break the 22V supply connections to the Voltage-to-current converter power stage by removing connector J1 from the In-guard power supply pcb.
- (d) Re-make each 22V supply connection from its female pin on the freed J1 connector to its corresponding male pin on the In-guard P.S. pcb, using one 0.1Ω resistor in series with each supply line (Red and Brown wires)
- (e) Connect the digital voltmeter across one of the 0.1Ω resistors fitted in step (d)
- (f) Set 4000 power ON
- (g) Ensure 10V range selected with Output OFF

 CAUTION In the following step (h) use a thin insulated
- **CAUTION** In the following step (h), use a thin insulated screwdriver.
 - (h) Carefully adjust R23 on I/Ω pcb assembly for a digital voltmeter reading of 1mV±50 μ V (equivalent to 10mA through 0.1 Ω resistor).
 - (j) Switch 4000 Power OFF
 - (k) Disconnect and remove both 0.1Ω resistors and the digital voltmeter from J1. Reconnect J1 to the In-guard Power Supply pcb pins.

5.5.4 Return to Use

- (a) Refit top ground/guard assembly (Section 3.4.2) and Top cover (3.2.2)
- (b) Carry out Routine Calibration of current and resistance in accordance with Section 1.2.7.3 and 1.2.7.4.

5.6 POWER AMPLIFIER (DC) PCB — PA QUIESCENT CURRENT ADJUSTMENT

Replacement PA (dc) assemblies are set up by the manufacturer to ensure correct operation. The final adjustment in the PA power stage quiescent current must be carried out when installed in the user's instrument. For this procedure, the quiescent current is set to 20 mA by adjusting the voltage between TP5 and TP13 to 6mV

5.6.1 Test Equipment Required

Digital Voltmeter (Datron Instruments model 1071)

5.6.2 Initial Conditions

4000 Power OFF
Top cover removed (Section 3.2.1)
Top ground/guard assembly removed (Section 3.4.1)
Replacement Power Amplifier assembly already fitted into J9 (Mother pcb), and connectors J1, J2, J3, J4, J5 and J6 already connected (Section 3, Fig. 3.6)

5.6.3 Procedure

- (a) Connect the digital voltmeter between TP5 and TP13 on Power Amplifier (dc) pcb assembly
- (b) Set 4000 power ON. Ensure that Output is OFF and DC selected
- (c) Select 100V Range
- (d) Adjust R82 on Power Amp (dc) Assembly for a reading of $6mV \pm 100 \mu V$
- (e) Set 4000 power OFF and disconnect the digital voltmeter

5.6.4 Return to Use

- (a) Ensure that all internal assemblies are correctly fitted and connected (Section 3)
- (b) Refit Top ground/guard assembly (Section 3.4.2)
- (c) Refit Top cover (Section 3.2.2)
- (d) Recalibration is not required after replacing a Power Amp (dc), pcb, but the dc voltage specification may be verified (if desired) in accordance with the User's Handbook, Section 7.

5.7 BUCKING CIRCUIT NULL ADJUSTMENT

After replacing the Power Amplifier (dc), the Power Supply (Outguard) or the Line Transformer, it is necessary to ensure that line-frequency breakthrough on the Lo and Guard terminals is reduced to minimum. In these procedures, R12 on the Out-guard Power Supply Assembly is adjusted to minimise the voltage between Lo and Ground, and R1 on the Power Amplifier (dc) Assembly is adjusted to minimise between Guard and Ground.

5.7.1 Test Equipment required

Oscilloscope (with AC input and sensitivity to 100mV/div.)

5.7.2 Initial Conditions

Power OFF

Top and Bottom ground/guard assemblies fitted and secured (Section 3.4.2 and 3.5.2)
Top cover removed (Section 3.2.1)

5.7.3 Procedure

- (a) Set 4000 Power ON
- (b) Ensure that DC 10V Range selected with Output OFF
- (c) Ensure that Ouput display is 0.000,000V
- (d) Connect oscilloscope AC input between 4000 + (Ground) and Lo Terminals

- Locate R12 on the Out-guard Power Supply pcb through the hole in the Top ground/ guard assembly (refer to Layout Drawing No. 400470)
- (f) Select Output ON +
- (g) Adjust oscilloscope controls to obtain a linefrequency wave-form
- (h) Without touching the Top ground/guard assembly, adjust R12 for minimum waveform amplitude. This should not exceed 1V peak-to-peak
- Select Remote Guard, transfer the oscilloscope AC input connection from Lo to Guard terminal and obtain a line-frequence waveform.
- (k) Locate R1 on the Power Amplifier (dc) pcb through the hole in the Top ground/guard assembly (refer to Layout Drawing No. 400449)
- Without touching the Top ground/guard assembly, adjust R1 for minimum waveform amplitude.
- (m) Select Power OFF
- (n) Disconnect the oscilloscope

5.7.4 Return to Use

- (a) Refit Top cover (Section 3.2.2)
- (b) Recalibration is not required after this adjustment.

	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER		MANUFÄCTURER'S PART No	No. USED Per Assy.
	400438	REAR PANEL ASSY				1
	400440	MOTHER PCB ASSY				
	400441	FRONT PCB ASSY				1
	400454	PA (POS) HEATSINK ASSY				1
	400455	PS/I HEATSINK ASSY				1
	400456	MAINS TRANSFORMER ASSY				1
	400457	MF TRANSFORMER ASSY.				1
	400461	PA (NEG) HEATSINK ASSY.				1
	400462	MAINS SWITCH CABLE ASSY.				1
	400463	DIGITAL PS CABLE ASSY.				1
1	400464	FRONT OP CABLE ASSY.				2
	400469	IN GUARD POWER SUPPLY CAL	LE ASSY			1
	400471	IG WAY RISBON CABLE AS	SY.			2
	450290- 1	GUARD SHEET	19	.		2
	450291 - 1	EARTH SHEET				2
	450292 -	EARTH/GUARD SPACER				8
	450293-	PCB RETAINING BAR				3.
	450265-1	MOULDED CHASSIS	HALLAMS			1
	450270 - 1	PCB GUARD SCREEN	GOULD ADVANCE			7
	450271 -1	FILTER GRILLE	ti II			1
	450272 - 1	TRANSFORMER BOLT PLATE	11 11			4

DESIGNATOR	DATRON		DESCRIPTION		PRINCIPAL			MANUFACT	URER'S	No. USED
	PART No.				MANUFAC	TURER		PART No.		Per Assy.
	45027	7 - 1	50010 51		-	·		2	***************************************	
	45027		FOAM FI					1-1	· · · · · · · · · · · · · · · · · · ·	
	45028			RETAINER						2
				PINOT PINS & B						-
	45030		REAR SP			ADVANCE				2
	45030		EARTH BR		- 11	ţi				1
	45031		R.H. SIDE	EXTRUSION	н	*	<u> </u>			1
	45031		L.H. SIDE	EXTRUSION	**	**	·			1
	45031		HEATSINK	GUARD SCREEN	1 "	**				1
	45031	6-1	POWER SUP	PLY GUARD SCREE	u "	48				11
	SEE TA	BLE	CALIBRATOR	OVERLAY						1
	45032	20-3	FRONT PA	NEL .	GOULD	ADVANCE				
	45032	21-1	GUARD CO	SUARD CONTACT PLATE		ч				1
	45032	3-1	CABLE BE	SIDGE	GOULD	ADVANCE				1
	45036	7-1	POLAROID							2
	52100	6	16/0.2 PVC	INSULATED IKV G	SEEN YELL	OW WIRE,				840 mm
	510999)	7/0.2 "	w	HITE WIRE					410mm
			,							
	59000	6	HEATSHRINK S	SLEEVE \$2.4 INT	R5 of	HELLERMANN	ELECTRIC	399-495	OR LVR 24	120 mm
	59003			SLEEVE \$ 4.8 INT			49		OR LVR 48	15mm
	590013		TY- RAP . CA		PANDUIT	-		PLT I-5L		1
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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	611004	SCREW M3x@mm STEEL PO	T-PAN ZINC PLATED, GKN.		32
	611015	SCREW MAXBum STEEL POZI	CSK. ZINC PLATED. GKN.		2
	611016	SCREW MAXAMM STEEL POZI	PAN. ZINC PLATED. GKN.		11
	611023	SCREW M2-5XIOME STEEL POT	PAN. ZINC PLATED. GKN		2
	611046	SCREW MB X 100mm STEEL H	EK HEAD.		4
	611047	SCREW MSXIZMM STEEL PO	ZI-CSK. ZINC PLATED. GKN	,	8
	611048	SCREW MAXSMM TAPTITE PO	ZI-CSK ZINC PLATED. BLACK GI	KN.	8
	611024	SCREW M5x8mm STEEL POZI	PAN ZINC PLATED. GKN		2
	611012	SCREW M3X 12mm STEEL POZ	THE COK . ZINC PLATED GKN		6
	611038	SCRE W MAX 12mm H.T. STEEL S	SINT HD CSK.		6
	611051	SCREW MB X HOMM STEEL H	EX HEAD.		4
	613005	WASHER M3 INT/SHAKEPROOF S	TEL. GKN DISTRIBUTORS		20
	615009	SOLDER TAG 4BA TINNED BRAS	ss. R.S.		6
	613012	WASHER M2-5 FLAT STEEL .	GKN DISTRIBUTORS.		4
	613014	WASHER M 2-5 INT/SHAKEPROC	STEEL GKN DISTRIBUTORS.		2
	613028	WASHER MS INT SHAKE PROOF	GKN DISTRIBUTORS.		2
	613025.	WASHER M8 FLAT STEEL.	GKN DISTRIBUTORS.		12
	613024	SOLDER TAG M4.	FARNELL .	101-479	1
	613029	WASHER M3 WAYEY	LEWIS SPRING	L5 508/54	25
	6(4008	SPACER 75mm LG x 10-7 00 x 8-5	SID. SPIROL	8-0 x 75 STD - FT	4
	615002	NUT M3 FULL HEX STEEL. ZINC	PLATED		3
	615015	NUT MB FULL HEX STEEL NYLL	ock.		8
	611008	SCREW MIXIOMM STEEL POZI-	CSK ZINC PLATED GKN		4
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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	606005	DIL SOCKET CLIP	CA	CA16 - 200 - DL	2
	613007	WASHER MS PLAT STEEL	GIKN. DISTR	16	7
	G13031	5/16" SPECIAL SOLDER TAG	ROSS COURTNEY	TAG No 201011	1
	630004	P' CLIPS \$ 1/4	RICHCO OR SES	N4 OR CNG	3
	630029	TAPE DOUBLE SIDED 14 X 1/32	3M	4032	204
	630167	FOAM TAPE Good Tx Tom W	TESA	TESAMOLL 761/4763	375 mm
	630168	POLYESTER TAPE SOMM WIDE	Зм	683	200 mm
	630020	CABLE CUP	3 M	708	1
	630003	P'CLIP \$ 3/16"	RICHCO OR SES	NS OR CNS	4
	630162	FOAM TAPE 12mm × 12mm	TESA	TESA MOLL 761/4766	1080mm
	200009	LOCKING COMPOUND	LOCTITE	270	A/R
	220155	TERMINAL COPPER BLACK	DATRON	SEE DES	1
	920173	TERMINAL COPPER RED / BLK	DATRON	SEE DR6	1
	220134	TERMINAL COPPER BEN /BLK	DATRON	SEE DRG	1
	320/35	TERMINAL COPPER BLU/BLK	DATRON	SEE DEG	1
	920136	TERMINAL BRASS WHT/BLK	DATRON	SEE DRG	1
	920137	TERMINAL BRASS GRN/BLK	DATRON	SEE DRG	1
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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	410167-3	PCB			1
	450296-1	540711 0005511			
		EARTH SCREEN			1
ÇI	101103	10AF 25% 250V CER DISC	ITT	CDIO.	1
J3-J8	604033	4 CCT POLARISING WAFER	1,5	22-29-2041 GOLD	12
J1, J?	605002	16 WAY DIL SOCKET	CA	CA- 105 - 1050	2
J27	605086	24 WAY PCB MNT RECEPTACE	E AMPHENOL	57-20240-8	ı
	611004	M3X6 POZIPAN SCREW	C.(.)		
·	612004	M3X4 STANDOFF 1/6 PLB	GKN HAEWIN	ZINC PLATED	2
	800519	M3 XG STANDOFF 1/6 PCA	CAMBION	350-5138-09-07	2
	613029		CAMBIN	390-3136-09-07	2
SI	700046	M3 CRINKLE WASHER SWITCH 6 POSN D.I.L S.P.S.7	AMP OF CONTRAVES	435166-4 OR DSS-6	1
	700047	SWITCH COVER	AMP	435238-3	i
52	700080	SP3P SLIDE P.C.B MNT	ALCO	5L5-131-PC	1
553	700081	SPOT SLIDE P.C.B MNT	ALCO	SLS - 121 -PC	ı
	G14003	STANDOPF 3-3 CLEAR X Gmm BRASS	HARWIN	C5 2117-A	2
	900004	SILICONE RUBBER COMPOUNT	R5.	544-311	A/R
				_	
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DESIGNATOR	DATRON PART No.	DESCR	RIPTIO	V		PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RI	008035				WIREWOUND		W2I	2
RZ	008035	33R			WIREWOUND	WELWYN	MSI	_
R3	000103	IOK	5%	1/4W	CARBON	MULLARD	CR25	38
R4		NOT	USE	D				_
R5		NOT	USE	D				
R6	000103	10k	5%	1/4W	CARBON	MULLARD	CR25	_
R7	000103		11	**	**	11	n	_
R8	000103		-	**	**	n'	.,	_
Re	000103		**	- 11		24	.,	_
Rio		NOT	USE					
Ru	000103	**	**	11	17	"	**	-
R12	000103		10	**	**	14	11	_
R13	000103	••		41	11	**	11	-
RI4	000103	**	**	81	0.0	Pe	**	_
R15	000103		**	11	10	*1	11	-
RIG	000103	**	11	**	**	tr.	19	_
R17	000103	**	11	11			13	_
RI8	000103	41	**	**	**	**	48	_
Ris	000103	#1	**	11	16	**	4.0	_
R20	000103	69	11	11		**	11	_
R21	000103	11	**	11	17	11	11	_
R22	000103	84	11	**	**	11	44	_
R23	000103	**	**	**	**	11	**	_
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DESIGNATOR	DATRON PART No.	DESCRIPT	ION		PRINCIPAL MANUFACTURER	MANUFAC PART No.	TURER'S	No. USED Per Assy.
R24	000103	10k 5%	6 1/4W	CARBON	MULLARD	CR25		
R25	000103	1) 11	11	1/	н	"		_
R26	000103	11 /1	**	tr	п			_
R27	000103	11 /1	n	b	'u	10		-
R28		NOT U	SED					
R29	000103	10K 59	% 1/4W	CARBON	MULLARD	CR25		_
R30	000103	11 11	- 11	H	11	11		_
R31	000103	f* 81	**	н	11	п		_
R32	000103	es to		"	**	**		_
R33	000103	19 11	*1	h				
R34	000103	Pt 15	- 11	н	11	"		_
R35	000103	11 11	- 11	11	n	**		-
R36		NOT U	SED					_
R37		NOT US	ED					_
R38	000103	10k "	н	н	*1	n		
R39		אסז טי	ED					
R40	000103	10k 5%	. 1/4W	CARBON	MULLARD	CR75		_
R41	000473	47k "	••	**		₽ 31		4
R42	000103	IOk "	••	n	14	"		_
R43	000103	lok "		н	п	**		_
R44	000103	lOk "		**	**			-
R45	000103	lok "	**	4	te.	**		_
R46	000103	IOk "	*	**	12	1#		_
NOTES. SEE SHEET 3 FOR L	ATEST ISSUE					2G-MAR 82	datron	
ISS.						CHECKED	4000. M	OTHER PCB
E.C.O. DATE						APPROVED DATE	DRAWING 4004	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R47	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	_
R48	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	-
R49	000473	47k 5% 1/4W CARBON	MULLARD	CR25	-
R50	000473	47k 5% 4W CARBON	MULLARD	CR2S	
RSI	000473	47k 5% 4W CARBON	MULLARD	CR25	_
R52	000104	100k 5% 1/4W CARBON	MULLARD	CR25	
R53	001223	22K5% /ZW CARBON	MULLARD	CR37	2
R54	001223	22K 5% 1/2W CARSON	MULLARD	CR37	-
Fa .					
ANI	090090	47k ×8 2% NETWORK	AB	761-3-47k	6
AN2	090095	47k × 4 2% NETWORK	AB	850-83-47k	3 .
AN3	090090	47k × 8 2% NETWORK	AB	761-3-47k	-
AN4	090095	47k × 4 2% NETWORK	AB	850-83 - 47k	-
AN5	090095	47k × 4 2% NETWORK	AB	850-83 - 47k	
ANG	090090	47k × 8 2% NETWORK	AB	761-3-47k	-
AN7	090090	47k × 8 2% NETWORK	AB	761-3-47k	_
ANS	090090	47k ×8 2% NETWORK	AB	761-3-47k	_
AN9	090090	47k × 8 2% NETWORK	AB	761-3-47k	_
NOTES.			DA	TE Cat	COO
SEE SHEET 3 FOR LA	ATEST ISSUE				ELECTRONICS LTD
ISS.			CH	ECKED TITLE 4000), MOTHER PCB ASSY.
CHKD.			DA	DRAWING	00440 5 SHEET 8

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
CI	140045	JUF 20% IKSV POLYPROP	NORTRONICS (MFD)	NSC 2027	1
22	180036	4700 UF 100V AL. ELECT	MULLARD/ITT	050-1-9472/KS20 472T 100	0 2
C3	180036	4700 pF " " "	n n	f e es	
C4	104032	220pf 10% 2KV CER DISC	LTT	СОДН	ł
LI	370017	COMMON MODE CHOKE	SIGA	SEE DRG	1
	410163-6	PCB			1
	540008	7/-2 PTFE INSUL. (WHITE) WIRE			A/R
	590001	SLEEVE MAX CABLE \$ 3.0	HELLERMANN ELECTRIC	HIS X 20 mm BLACK HELSYN	G
	530000	24/-2 PVC INSUL.WIRE		1.5kVRMS BLACK	350
	530111	24/.2 PVC INSUL WIRE		1.5KV RMS BROWN	240
	530222	24/.2 PYC INSUL WIRE		1.5kV RMS RED	350mm
	530666	24/.2 PVC INSUL. WIRE		1.5kV RMS BLUE	240mm
J19	604042	4WAY -156" PLUG GD PL	MOLEX	09-72-2041	2
NOTES.					
				MAR 82 datron	ELECTRONICS LTD
ISS.	ATEST ISSUE		CHEC	KED AS	MOTHER PCB
DATE			APPR	DRAWING NUMBER 40044	10 6 SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
J28	605071	4WAY -156" HOUSING	MOLEX	90-50-3041	1
JI	605111	24+24 WAY -1"P.CB SOCKET	AMP	2-14 592-4	.3
	605077	CRIMP TERMINAL GD.PL	MOLEX	08-56-0106	4
	(605087-1	24 WAY PCB EDGE CONN.	SEE DRG		10
	605088-	IS WAY PCB EDGE CONN	SEE DRG		8
J2-J16	605089-	12 WAY PCB EDGE CONN.	SEE DRG-		7
	605090-1	6 WAY PCB EDGE CONN.	SEE DRG-		8
	605091-1	GWAY SPECIAL EDGE CONN	SEE DRG-		9
	605092-1	3 WAY PCB EDGE CONN	SEE DRG-		13
	612013	M3 x 8 mm STANDOFF	CAMBION	350- 5182-24-07	1
	613029	M3 CRINKLE WASHER S.S.			5
	611006	M3XIOMM POZI-PAN STEEL	ZNPL		1
	611016	M3x 8 mm POZI-PAN STEEL	ZNPL		5
	611013	M3x35mm POZI-PAN STEEL	ZNPL		4
	612004	STANDOFF M3 ×4mm BRASS	HARWIN	CS2116/B	6
	613005	WASHER MS INT/SHAKEPROO	F ZN/PLTD GKN	1	5
	615002	NUT M3 FULL HEX STEEL			10
NOTES. SEE SHEET 3 FOR LA	ATEST ISSUE			MAR 82 datron	
ISS. E.C.O.			CHECK	4000	MOTHER PCB SY.
DATE CHKD.			DATE	DRAWING 4004	40 7 SHEET

DATE CHKD.

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	617010	NYLATCH PLUNGER	ORDER FROM CJ. FOX SONS	HN3P-32-4-1	20
	617011	NYLATCH GROMMET	ORDER FROM C.J. FOX ISONS	HN36-32-1	20
	620003	SOLDER PIN	HARWIN	H2105A01	2
	620005	CLOVERLEAF P.T.F.E. TERMINAL	SEALECTRO	FTE 15 P59	10
	620006	SOLDER TURRET	HARWIN	H9001-01	47
	630115	CAPACITOR CLIP \$35	RS	543-383	4
	630131	CAPACITOR CLIP \$45mm	RS	543-068	1
				40	
NOTES.		•	DATE	<u> </u>	
SEE SHEET 3 FOR L	ATEST ISSUE				ELECTRONICS LTD
iss.			СНЕСК	4000	O MOTHER PO
E.C.O.			APPRO		
DATE CHKD.		 	DATE	DRAWING NUMBER 400	0440 8 SHEET

DESIGNATOR	DATRON PART No.	DESCRI	PTION			PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RI	000334	330k	5%	14 W	CARBON	MULLARD	CR25	22
R2	000334	- 11	41	et .	N	41	61	
R3	000334		14	ч	44	-1	for .	_
R4	000334	11	Nr.	н			Ou .	_
RS	000334	to to	M	*	N	W	**	-
R6	000334	n	tr .	h	м	**	au .	_
R7	000334	H	4	N	4	"	-	-
RB	000334	N	Ħ			M	n	-
R9	000334	61	4	4	te .	1,	•	-
RIO	000334	- 11	N	4/	N	64	pa .	-
RII	000334	11	4	No.	н	10		-
RI2	000334	- 4	tr.	· ·	4	н	40	
RI3	000334	м	· ·	4	by .	н		-
R14	000334	te	11		н	14		-
RIS	000334	84	н	şê	te .	н .		_
RI6	000334	•		•	e	11	•	-
۲۱7	000334	H	fe .		*	1)	90	_
₹8	000334	N	10	\$q	4	N		-
Rig	000334	N	ч	br		le .	14	_
R20	000334	a a	11	٠,	N	Ar .		_
₹21	000554	N	4	te	W	M	44	_
R22	000334	94	н	4		84		-
रेख	000102	lk	N	м	**	te .	24	11
NOTES. SEE SHEET 2 FOR L		•	8				manual It	GLECTROMICS LYD
ECO - 86	1 2 3 ELEASED 1352 1386	4			-		4	000 It PCB. Assy-

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R24	000102	IK 5% 1/4W CARBO	N MULLARD	CR25	-
R25	000102	lk " " "	ns .		-
R26	000104	look" " "	N	N	3
R27	000102	1k + + + +	10	**	_
R28	000102	lk " " "	nd .	**	_
R29	000102	lk " " "	40	"	
30	000102	lk " " "	N	10	
R31	000102	Ik " "	11	10	_
R32	000102	[k " "	ed	10	_
R33	000102	lk " " "	N	49	_
R34	000102	lk " " "	64	50	_
R35	000103	10k # " "	4,		4
R36	000103	lOk " " "	N	4	_
R37	000103	10k " " "	H	••	
R38		NOT USED			
R39	000472	4k7 " " "		M	6
R40	000688	6R8 " " "		le .	8
R4i	000688	6R8 " " "	**	56	
R42	000688	6R8 " " "		100	
R43	000272	2k7 " " "	••	-	18
R44	000272	2k7 • • •	9	**	-
R45	000472	4k7	èe	to .	_
R46	000272	2k7 " " •		10	_
NOTES. SEE SHEET 2 FOR I	ATEST ISSUE			DRAMM . TITLE 4	COO
E.C.O.				FRON	IT PCB. ASSY.
DATE				DATE DATE	00441 3 SHEET

/ESIGNATOR	PART No.	DESCR	IPTION			PRINCIPAL MANUFACTURER		MANUFACTUR PART No.	ER'S	No. USED Per Assy.
R47	000182	IK8	5%	1/4W	CARBON	MULLARD		CR25		2
R48	000272	2k7	11	11	10	54		*1		_
R49	000272	2k7	11	11	10	11		19		-
Rso	000222	2k2	11	14	44	•4		**		2
RSI	000222	2k2	н	4	16	11		**		_
252	000272	2k7	10	*	Na .	10		γ.		
Rs3	000272	2k7	19	- 14	84	10				_
R54	000472	4k7	44	61		pa .		5 86		_
Rss	000272	2k7	11	и	**	ng .		**		_
Rs6	000272	2k7	+9	12	1 11	to.		"		-
Rs7	000272	2k7	44	14	0.	*				_
RS8	000182	lk8	10	11	**	**		•		
?s9	000272	2K7	19	11	11	100		N		_
R60	000272	2k7	10	16	**	•		84		
R61	000272	2k7	н	10	4,	0g		**		
R62	000 272	2k7		**	84	40		ta .		
R63	000272	2k7	м	н	н	10		**		
R64	000272	2k7		64	44	4		pa		_
R65	000272	2k7	14	**	Pe	De .				_
R66	000272	2k7	94		**			4		_
R67	000688	688	14	14	Ang.	**		**		_
R 68	000688	6RE	la .	44	4	•		*		_
R69	000688	6R8	10	10	10	66		tig .		_
NOTES. SEE SHEET 2 FOR LA						-	DATE 10.	4. 81	datron	ELECYNOMICS LTD
ISS. E.C.O.							CHECKED		4000 FRONT P	CB. ASSY

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R70	000 688	688 5% 1/4W CARBON	MULLARD	CR25	-
R71	000688	6R8 " " "	11 =	"	-
R72	000563	56k " " "	01	*	1
R73, R74, R75	000472	4k7 " " "	43	4	
R76	000103	lok " " "	**	11	-
R77, R78	000104	100k " " "	98	11	
ANT AND	09.0017	100k × 7 2% NETWORK	BECKMAN	L08-1- R100k	2
ANI. ANZ	090017	4k7 × 7 2% NETWORK	BECKMAN	L08-1- R4k7	2
ANS. ANG	090121	look × 8 2% NETWORK	BECKMAN	L09-1- R100k	2
		10 of 20% 16V DIP TANT	UNION CARBIDE	KIOEIG	2
CI	104026	47nF -20 % 50V CER DISC		837449	3
C2 C3	104026	47aF -20 % 50V CER DISC	SIEMENS	837449	-
C4	150001	22 MF 20% 16V DIP TANT	UNION CARBIDE	K22 E16	
Cs	104 026	47aF -20 % 50V CER DISC	SIEMENS	837449	-
C6	10+020	NOT USED	SIEMENO	03/447	
C7		NOT USED			-
C8	110013	100nF 20% 250V POLYESTER	MULLARD	C280AE PIOOk	+
	110013	" " " "	MULLARY	CZBOREPIOO*	19
<u>C9</u>		01 00 00	46	N N	_
Сю	110013	10 10 10 00	"		
C12	110013	11 11 11 11	11	W	
NOTES.	110013				
SEE SHEET 2 FOR LATE	ST ISSUE		DATE 10.4 DRAWN	4.81 datron	
E.C.O.			CHECKE	FRONT PC	B ASSY
DATE CHKD.			DATE	DRAWING 40044	SHEET 5 OF

DESIGNATOR	DATRON PART No.	DESCRI	PTION			PRINCIPAL MANUFACTURER		MANUFACT PART No.	TURER'S	No. USED Per Assy.
CI3	110013	100nF	20%	250	POLYESTER	MULLARD		C2BOAE	Piook	-
C14	110013		81	ч	te .	н		"		-
CIS	110013		11	**	ы	"		"		_
C16	110013		н	R	te.	41		11		_
CIT	110013	м	"	н	11	11		"		-
C18	110013	11	RS.	N		11		"		_
C19	110013	-11	м	4	11			- "		_
C20	110013	46	81	to	W	11		11		_
CZI	110013		le .	41	ы	м		84		_
CZZ	110013	**	н	10	14	н				_
C23	110013	**	ы	64	*1	н		н.		_
C24	110013	**	96	н	н	4		н		_
C25	110013		-	**	**			"		_
C26	110013	••	**		N	74				_
C27	150002	10pF	20%	164	DIP TANT	UNION CARBIDE		KIOEIG		_
CS8	150016	Fسرا	20%	35V	DIP TANT	UNION CARBIDE		KIRO35		ı
Di	200001	75mA	75V 6	iP. Si	DIODE	FAIRCHILD		IN4148		18
02	200001			н м	11	81				_
D3	200001		Pg	N 69	**	**		м		_
D4	200001	-	н		11	n		44	**	_
Ds	200001	- 41	do o	w w	**			"		_
D6	200001	ļ ,,	11 0	1 81	11	11		- I		_
D7	200001	11	., .		11	11		"		_
NOTES							DATE 10	4.81	datron	SUBCYNOMICS LYD
E.C.O							CHECK!	D	4000 FRONT PC	
DATE :		_					BATE		NUMBER 40044	6 OF (1

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
D6	200001	75mA 75v GP, Si. DIODE	FAIRCHILD	IN4148	-
9	200001	ag bd by by	11	•	-
Dio	200001	25 60 FG 60 60	ч	N	_
DII	200001	24 de 16 de ¹⁰²	N	•	_
DIZ .	200001	ec se 16 se 59	•	•	_
Dı3	200001	as on on ag M	De .	04	-
014	200001	60 M 50 00 M	•	Ne .	_
015	200001	69 M 99 80 M	•	4	_
016	200001	gs 64 66 49 59	De .	M	_
D17	213005	75v 1/2W ZENER	MOTOROLA	BZX79C75	1
DIB	200001	75 mA 75V 6P Si DIODE	FAIRCHILD	11448	_
) 9	200001	75 MA 75V GP SI DIODE	FAIRCHILD	IN4148	_
>20	213006	5VI 5W ZENER	UNITRODE	TVS 505	1
			^		
श		NOT USED			
Q2	240009	SI NPN TRANSISTOR	NATIONAL	MPSLOI / TO18	18
Q3	240009	ss 84 94		**	_
24	24 0 009	11 14 19	60	04	_
25	24 0 0 0 9	86 12 0E	to to	11	_
%	24 0009	£0 14 01	04	11	_
Q 7	24 00 09	14 tr - re	11	"	_
26	240009	11 11 11	4	11	_
NOTES.	ATEST ISSUE	9		10.4.81 datror	ELECTRONICS LTD
rès.				CKED 4.0	PCB ASSY
DATE				ROVED DRAWING	PUB ASST

DESIGNATOR	DATRON PART No.	DES	CRIPTIO	N	PRINCIPAL MANUFACTURER		MANUFACT PART No.	URER'S	No. USED Per Assy.
Q9	240009	Si	NPN	TRANSISTOR	NATIONAL		MPSLO	1/1018	_
Qio	250009	Si.	PNP.	TRANSISTOR	NATIONAL		2N540	1/1018	- 11
QII	250009		81		Apr. 1		14		-
Q12	250009	84	14	4			**		_
Фв	250009	14	п	M	14		"1		_
Q14	250009	11	**	84	**				_
Qıs	250009	1t	44	м	**		10		-
Ф к	250009	"	м	***	10		14		-
Q ₁₇	250009	1,0	м	*	11				_
Q _R	.250009	14	14	10			11		_
919	250009	**	м	**	11		1,		-
Q20	250009	11	н	Ag	. 11		.,		_
9 21	240025	Si	NPN	TRANSISTOR	14		MPSAI	3	3
Q22	240025	н	**	ч	19	-	- 11		_
Q23	240025	lu lu	4	16	11		м		_
Q24.		NO	DT USE	ED .					_
Q25	250011	5i	PNP	TRANSISTOR	71		BC 327/1	7018	8
Q26	250011		81	11	14		н		_
Q27	250011	**	11	ų	4		-		-
928	250011	п	н	10	19		"		-
Q29	250011		,11	н	ed .		•		_
930	250011	"	ч	ч	•				-
Q3 ₁	250011	41	н	11	4		++		-
NOTES SEE SHEET 2 FOR L			-			DATE	.4.81	datron	ELECYNOMISE LYP
186. E.C.O.						CHECKE	D	4000 FRONT PC	
CHKD				 		DATE		10044	1 8 of 11

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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
×32	250011	SI PNP TRANSISTOR	NATIONAL	BC327/TO18	_
Q33	240009	SI NPN TRANSISTOR		MPSLOI/TOI8	-
Q34	240009	ed dg M	4	15	_
Q35	240009	16 of pt	W	M	_
<i>Q</i> 36	240009	PB 95 15	N	98	-
Q37	240009	00 Fg FJ	N N	•	_
Q38	240009	10 00 0,	11	W	_
Q39	240009	N N NE		14	-
Q40	240009	as as 45	н		_
Q4 I	240009	00 00 gc	10	**	_
Q42	240009	11 11 11	11	. 16	_
MI	280023	QUAD 2-1/P NOR GATE	MOTOROLA	14C14A01 20P	
M2.	260005	5V IA REGULATOR	MOTOROLA	MC14001 BCP.	
M3	28 0043	4 BIT LATCH 4 To 16 LINE DECODER		MC7805CP MC14-515 BCP	-
M4	280090	DUAL BINARY INFA DECODER		MC 14555 BCP	-
M5	270071	DUAL I of 4 DECODER IS	NATIONAL	DM74LS156N	
M6	280084	PROGRAMMABLE KEYBOARD DIS		8279	-
	230004		MILL	62/7	'
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE			OR ANNU TITLE	electromos LTD
E.C.O				FRONT	PCB. ASSY
DATE				DRAWING MARKET 400	

PART No.				T		7
S1- S27	DESIGNATOR		DESCRIPTION			No. USED Per Assy.
S44-945 700062 KEYBOARD SWITCH GREEN LES SCHADOW SRL-BREEN LED 2	SI- S27	700079	KEYBOARD Y'S SWITCH . BLACK	NSF	KIZ /HALF KEY. BLACK	28
\$40-550, 552-555 \$700061 KEYBOARD \$WITCH . RED LED SCH ADOW \$RL-RED LED - \$556 \$700079 KEYBOARD \$\frac{1}{2}\$ \$\switch . BLACK NSF K12/HALF KEY. BLACK 410144-7 PCB \$1 \$604060 \$24+24 WAY -1\frac{1}{1}^{1} PCB . PLUG GOLD AMP \$605098 \$40 PIN DIL LOW PROFILE \$KT CAMBION \$703-4340-01-06-00 II \$605060/L	534-543	700061	KEYBOARD SWITCH RED LED.	SCHADOW	SRL-RED LED	19
SSG	544-545	700062	KEYBOARD SWITCH GREENLE	SCHADOW	SRL- GREEN LED.	2
SSE 700079 KEYBOARD x 1/2 SWITCH BLACK SLACK SLACK 410144-7 PCB 1	546-350, 552-555	700061	KEYBOARD SWITCH . RED LED	SCHADOW	SRL-RED LED	_
JI 604060 24+24WAY •1" PCB. PLUG GOLD AMP 2-825440-4 3 605098 40 PIN DIL. LOW PROFILE SKT CAMBION 703-4340-01-06-00 1 605060/L 14 WAY DIL. " " CAMBION 703-4324-01-06-00 1 605061/L 16 WAY DIL. " " CAMBION 703-4324-01-06-00 1 612023 STANDOFF M2SX4L6.8RASS KINL CAMBION 350-5181-22-07 2 800017 81/2 DIGIT DISPLAY WITH LEGEND DALE SEE DRG. 2 920096 BUZZER PIEZOELECTRIC TOKO PB 2720 1 620003 SOLDER PCB TERMINAL LUG HARWIN H2105A 2 NOTES. SEE SHEET 2 FOR LATEST ISSUE			KEYBOARD = 12 SWITCH . BLACK	NSF	KIZ/HALF KEY. BLACK	_
605098 40 PIN DIL LOW PROFILE SKT CAMBION 703-4340-0 -06-00 1 605060/L 14 WAY DIL		410144-7	РСВ			1
605098 40 PIN DIL LOW PROFILE SKT CAMBION 703-4340-0 -06-00 1 605060/L 14 WAY DIL	*1	604060	241-24 WAY 1" DCB DUYC COL	AMB	2-925440-4	2
GOSOGO L 14 WAY DIL	01	· · · · · · · · · · · · · · · · · · ·		 		
GOSOGI L 16 WAY DIL				CAMIBION	703-4340-01-06-00	
GOSO97		1,				
SIZO 23 STANDOFF M2.5 X 4 LG. BRASS SIZE CAMBION 350 - 5181 - 22 - 07 2				CAMBION	703-4304 01 06-00	
800017 6½ DIGIT DISPLAY WITH LEGEND DALE \$EE DRG- 2 920096 BUZZER PIEZOELECTRIC TOKO P8 2720 I 620003 SOLDER PCB TERMINAL LUG HARWIN H2IOSA 2 NOTES. SEE SHEET 2 FOR LATEST ISSUE DATE 10.4.81 DATE 10.4.81 DATE 10.4.81 DATE 4000 FRONT PCB. ASSY						2
920096 BUZZER PIEZOELECTRIC TOKO P8 2720 I 620003 SOLDER PCB TERMINAL LUG HARWIN H2105A 2 NOTES. SEE SHEET 2 FOR LATEST ISSUE BY 10.4.81 DOWN 1.81 DOWN		612023	The state of the s	СДАКВІОК	330-3161-22-07	
920096 BUZZER PIEZOELECTRIC TOKO P8 2720 I 620003 SOLDER PCB TERMINAL LUG HARWIN H2IOSA 2 NOTES. SEE SHEET 2 FOR LATEST ISSUE DATE 10.4.8! DATE 10.4.8! TITLE 4000 FRONT PCB. ASSY		800017	8/2 DIGIT DISPLAY WITH LEGENS	DALE	SEE DRG-	2
		. (%)				
NOTES. SEE SHEET 2 FOR LATEST ISSUE DATE 10.4.8! DRAWN TITLE 4000 FRONT PCB. ASSY		720096	BUZZER PIEZOELECTRIC	TOKO	PB 2720	
SEE SHEET 2 FOR LATEST ISSUE SEE SHEET 2 FOR LATEST ISSUE DATE 10.4.8! DRAWN TITLE 4000 FRONT PCB. ASSY		620003	SOLDER PCB TERMINAL LUG	HARWIN	H2IOSA	2
ECO CHECKED 4000 FRONT PCB. ASSY		T ISSUE		1	o.4.81 datron	ELECTRONICS LTD
DATE DATE DATE DATE	106.			CH	AOC FRONT PCE	
	DATE CHKD.			L	TE DPLANING 40044	I 10 of I

.W. 1164

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	611016	M3×8mm POZI PAN STEEL	ZN PL		I
	611054	M2×6mm SLOT CSK STEEL	ZN PL		2
	613005	M3 INT. SHAKEPROOF			1
	613026	M2 WASHER STEEL ZN PL			2
	613027	MZ INT SHAKEPROOF			2
	615002	M3 FULL NUT STEEL ZNPL		11.4	1
	615016	M2 FULL NUT STEEL ZN PL			2
	620007	TEST POINT TERMINAL	MICROVAR	C30	8
	630029	TAPE DOUBLE SIDED 14" x 132"	3M	4032	580 mm
	900004	SILICONE RUBBER COMPOUND	RS	555-588	A/R
- · ·					
NOTES.					
					ELECTRONICS LTD
ISS. E.C.O.	ATEST ISSUE			FRONT	1000 PCB ASSY
DATE			 	APPROVED	0441 SHEET

	DATRON PART No.	DESCRIPT	ION			PRINCIPAL MANUFACTURER	MANUFACT PART No.	URER'S	No. USED Per Assy.
RI	000332	3k3	5%	1/4W	CARBON		 CR25		2
R2	000472	4k7	11	- 11	- 11	11	 11		10
R3	000472	4k7	71	п		11	1.0		
R4	000472	4k7	11	11	11	11	 17		
R5	000472	4k7	11	11	11	11	 *1		_
R6	000103	lOk	11	п	r)	11	 11		5
R7	000104	100k	r.	- 11	le .	11	18		9
R8	000122	lk2	11	11	41	41	 11		2
R9	000104	look	£1	n	- 11	н	44		_
Rio	000104	100k	н	11	"	14	 - 14		_
RII	000103	iok	#1	41	14	te	14		_
R12	000472	4k7	84	*1	61	· ·	tr.		_
213	000472	4k7	н	11	fer	11	tø		_
₹14-	000561	560R	11	11	**	п	**		1
₹15	000104	look	tr	11	11	и	1/	- Ar	_
216	000182	lk8	**	ч	n	14	11		1
217	014751	4k75	1%	/8W 50	bpm M	F HOLCO	H8C		1
R18	000122	1k2	5%	1/40	V CARBO	NMULLARD	CR25		-
219	012491	2k49	1%	1/8W 5	Oþþm M	F HOLCO	H8C		1
₹20	000102	1k	5%			MULLARD	CR25		21
221	000472	4k7	11	11	14	14	 и		_
222	000223	22 k	"		н	11	- 0		1
23	000103	lok	14	tt	4	11	11		_

DESIGNATOR	DATRON PART No.	DESCRI	PTION			PRINCIPAL MANUFACTURER		NUFACTURER'S RT No.	No. USED Per Assy.
R24	000332	3k3	5%	1/4W	CARBON	MULLARD	CF	R25	_
R25	011002	loko	1%	1/8W 50	ppm MF	HOLCO	H	8C :	2
R26	000104	100k	5%		CARBON	MULLARD	CR	225	_
R27	011005	loko	1%	1/8W 50	bom MF	HOLCO	He	SC.	_
R28	0 0 0 4 7 1	470R	5%			MULLARD	CR	25	3
R29	000104	look	11	#1	13	11		1	-
R30	000472	4k7	**	11	+1	11		11	-
R31	000102	lk	11	11	- 0	11		.,	_
R32	000104	look	н	11	U	11		11	-
R33	000102	lk	11	- 11	- 11	11		u	-
R34	000102	lk	11		11	11		11	~
R35	000102	lk	11	**	11	ч		11	-
R36	000102	lk	11	11	11	17		11	-
R37	000102	Ik	11	"	11	11		11	_
R38	000102	ik	11	11	16	11		ч	_
R39	000102	lk	2.0	11	н	11		1	-
R40	000102	lk	61	11	11	al.		HI.	_
R41	000102	lk	11	,,	11	н		,	_
R42	000103	lok	"	11	11	11		T .	-
R43	000102	lk	11	.,	11	**		1	-
R44	000102	1k	11	11	**	11		t	-
R45	000102	IK	11		**	**			_
R46	000102	lk	11	11	**	**		,	
NOTES. SEE SHEET 2 FOR L ISS. E.C.O.	ATEST ISSUE						DATE 18.5.	TITLE 4	D ELECTRONICS LTD 000/4000A ITAL PCB, ASSY
DATE CHKD.							APPROVED DATE	DRAWING 4004	42 SHEET 42A 3 OF 11

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S	No. USED Per Assy.
R47	000102	Ik 5% 1/4W CARBON	MULLARD	PART No.	Per Assy.
R48	000102	lk " " "	"	"	_
R49	000102	lk " " "	41		-
R50	000102	1k " " "	ч	16	-
R51	000102	lk u u u	44	и	_
R52	000472	4k7 " " "	19	11	_
R53	000104	100k " " "	14	11	_
R54	000104	100k " " "	**	44	
RSS	000103	lok " " "	11	11	
R56	000471	470 R " " "	11	11	
R57	000471	470R " "	**	11	_
R58	000102	lk " " "	11	ti .	_
R59	000391	390R " " "	q	4	1 ,
R60	000472	4k7 " " "	н	11	_
ANI	090050	3k3 x 7 2% NETWORK	BECKMAN	764-1- R3k3	1
AN2	090017	100k x 7 2% NETWORK	BETWEEN	764-1- RIOOK	1
AN3	090046	IOK × 7 2% NETWORK	BECKMAN	764 - 1 - RIOK	2
AN4	090046	IOK X7 2% NETWORK	BETWEEN	764-1-Riok	_
AN5	090085	IZK XB 2% NETWORK	AB	761 - 3 - 12k	1
CI	150002	10,0F 20% 16V DIP. TANT.	UNION CARBIDE	KIOEI6	9
C2	150002	10UF 20% 16V DIP TANT.	UNION CARBIDE	KIOE16	
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE	, —	DATE 18. DRAWN CHECKE	5.81 datron	ELECTRONICS LTD DO/4000A AL PCB. ASSY.
DATE CHKD.			APPROV	DRAWING 40044	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
C3	104026	47nF -50% 50V CER DISC	SIEMENS	B37449	14
C4	104 026	47nF -20% 50V CER DISC	SIEMENS	837449	_
C5	104026	47nF +50 % 50V CER DISC	SIEMENS	B37449	-
C6	104026	470F +50 % SOV CER DISC	SIEMENS	B37449	_
C7		NOT USED			
C8	150016	JUF 20% 35V DIP TANT.	UNION CARBIDE	KIR035	3
C9	104026	47 nF -20% 50V CER DISC	SIEMENS	837449	_
CIO	150002	10 UF 20% 16V DIP TANT.	UNION CARBIDE	KIOEI6	_
CII	104026	470F -20% 50V CER DISC	SIEMENS	B37449	-
CI2	150002	IONF 20% IGV DIP TANT.	UNION CARBIDE	KIOEIG	_
CI3	150002	IOUF 20% IGV DIP. TANT.	UNION CARBIDE	KIOEIG	_
CI4	104026	47. F +50 % 50V CER DISC	SIEMENS	B37449	_
C15	150002	IONE 20% IEV DIP. TANT.	UNION CARBIDE	KIO EIG	_
C16	102102	INF 10% 500V CER DISC	ITT	CDIO	1
C17	150002	IONF 20% IGV DIP. TANT	UNION CARBIDE	KIOE16	_
C18	150016	JUF 20% 35V DIP TANT	UNION CARBIDE	KIROSS	_
C19	104026	470F -20% 50V CER DISC	SIEMENS	B37449	_
C20	104026	470F -20% 50V CER DISC	SIEMENS	837449	
C21	150002	100F 20% 16V DIP TANT.	UNION CARBIDE	KIOE 16	
C22	104026	47nF +50% 50V CER DISC	SIEMENS	B37449	_
C23	104026	470F -20% 50V CER DISC	SIEMENS	B37449	_
C24	150002	10 NF 20% IGV DIP TANT	UNION CABBIDE	KIOE IG	_
C25	104026	470F -20% 50V CER DISC	SIEMENS	B37449	_
NOTES. SEE SHEET 2 FOR LI	ATEST ISSUE			DRAWN TITLE	*CO ELECTRONICS LTD 4000/4000/ DIGITAL PCB AS
E.C.O.				APPROVED DRAWING 400	0442 _ SHEET
CHKD.					0442A 5 SHEET

					
DESIGNATOR	DATRON	DESCRIPTION	PRINCIPAL	MANUFACTURER'S	No. USED
	PART No.		MANUFACTURER	PART No.	Per Assy.
C26	101103	10 nF 25% 250V CER DISC	ITT	CDIO	2
C27	104026	47 nF +50 % 50V CER DISC	SIEMENS	B374-49	_
C28	150006	4,07F 20% 16V DIP TANT	UNION CARBIDE	K4R7EIG	1
C29	150016	INF 20% 35V DIP TANT	UNION CARBIDE	KIRO35	_
C30	150024	474F 20% 16V DIP TANT	UNION CARBIDE	K47EI6	1
C31	101103	IONF 25% 250V CER DISC	ITT	CDIO	_
C32	104026	47aF -20 % 50V CER DISC	SIEMENS	B37449	_
1.0					
DI	200001	75mA 75V GPSI DIODE	FAIRCHILD	IN4148 .	5
D2	200001	75 mA 75V GP SI DIODE	FAIRCHILD	IN4148	-
D3	200001	75 MA 75V GP SI DIODE	FAIRCHILD	IN4148	_
D4	200001	75 MA 75V GP SI DIODE	FAIRCHILD	IN4148	_
DS	210047	477 400mW ZENER	MULLARD	BZY88C4V7	1
D6	214012	2V45 3060 ZENER	FERRANTI	ZN458	
D7	220010	SI HOT CARRIER DIODE	H.P.	HSCH1001 / IN6263	1
D8	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	_
NOTES. SEE SHEET 2 FOR LA	TEST ISSUE		DATE 18. DRAWN	5.81 datron	ELECTRONICS LTD
ISS. E.C.O.			CHECKI		TAL PCB ASS
DATE .			APPROV	DRAWING 4004	12 SHEET
CRKU.				4004	+2A 9 of

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
				ă -	
		·			
ત્રા	240001	SI NPN TRANSISTOR	NATIONAL	BC184/TO18	2
Q2	240001	SI NPN TRANSISTOR	NATIONAL	BC 184 / TO18	_
Q3	230031	N-CHAN DUAL JEET	TELEDYNE	SU2656M	1
	-				
NOTES.				DATE & B	
				18.5.81	ELECTRONICS LTD
ISS.	ATEST ISSUE			DRAWN . TITLE	4000/4000A IGITAL PCB ASS
E.C.O.				APPROVED	
DATE				DATE DRAWING A-NUMBER	00442 7 SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION		PRINCIPAL MANUFACTUR	RER	MANUFACT PART No.	'URER'S	No. USED Per Assy.
MI	280024	TRI-STATE HE	X, NON-INV BUFFE			MC145	оз всР	4
M2	280024		(. NON-INV. BUFFER			MC145		
M3	290091-1		M PROGRAMMED		(SEE DRG)		SN (RED)	
M4	270056	8 I/P NAND		NATIONA		DM74.L:		1
M5	270048		P NAND LS	NATIONA		DM74L		4
M6	270050	HEX.INVER		NATIONA		74LS04		2
M7	280008		'NAND' GATE	MOTOROL		MCI40I		2
M8	280011	DUAL D F		MOTOROL		MC 140		Ī
M9	280102		RY COUNTER	MULLAR		HEF 40		
MIO	280091			MOTOROL			23 U B C P	1
MII	220015					FCD 820		2
MI2	280077					MC145		1
MI3	280033		-	MOTOROLA		MC1451	•	i
MI4	280033	QUAD LAT			*	MC 140		2
MIS	280015	QUAD LAT		MOTOROL		MC140		
Mi6	280062	8-BIT STATIO		MOTOROL		MC681		
MI7	270048		NAND GATE	NATIONAL		74 LSO		-
	SEE TABLE		PROGRAMMED	DATRON	book	TMS 25		1
MI8	SEE TABLE		PROGRAMMED			TMS 25		i
MI9			PROGRAMMED					1
M20				-		TMS 253		1
M21	SEE TABLE		PROGRAMMED	DATRON		TMS 2S3		
M22	SEE TABLE		PROGRAMMED	DATRON		TMS 253	2	1
M23		NOT FITTE	1					_
NOTES.	INSTRUMENT	4000	4000A		DAT	_	dateoc	ELECTRONICS LTD
	DIG. ASSY MI8	400442	400442A 290092/A- 11			8.5.81		
	MI9	290093-11	290093/A- 11			ECKED	40	100/4000A TAL PCB. ASSY
	M50	290094- 11	290094/A- 11		APP	PROVED		
	M2I	290095- 11	290095/A- 11		DAT	TE	DRAWING 4004	
	MSS	290098- 11	290095/A- 11		•		1001	,

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
M24	280096	IK X 4 BIT STATIC RAM	FAIRCHILD	2114 LPC	2
M25	280096	IK X4BIT STATIC RAM	FAIRCHILD	2114 LPC	-
M26	280066	256 x 4 BIT STATIC CMOS RAM	SEE DRAWING	1	2
M27	280066	256 X48IT STATIC CMOSRAM	SEE DRAWING		
M28	260043	358 DUAL OP AMP	NATIONAL	LM358N	1
M29	280064	IEEE 488 INTERFACE CHIP	MOTOROLA	MC68488P	1
M30	280005	TRIPLE GATE	MOTOROLA	MC14501 BCP	1
M31	270045	QUAD 2 TO I LINE MUX LS	NATIONAL	DM74 LS157N	1.7
M32	280092	DUAL 4-BIT LATCH	MOTOROLA	MC14508 BCP.	1
M33	270048	QUAD 2 1/P NAND LS	NATIONAL	DM74LSOON	_
M34	280087	MICRO-PROCESSOR CHIP	MOTOROLA	MC6802	1
M35	270057	DUAL J-K FLIP-FLOP LS	NATIONAL	DM74 LS76 N	I
M36	280024	TRI-STATE HEX.NON-INV. BUFFER	MOTOROLA	MC14503 BCP	_
M37	270077	TRI-STATE HEX. BUFFER LS	NATIONAL	DM74LS367	1
M38		NOT USED			
M39	220015	5kV OPTO ISOLATOR	FAIRCHILD	FCD 820 C	
M40	280086	BI-DIRECTIONAL BUS TRANSCE	IVER MOTOROLA	MC3447	2
M41	280059	DUAL BINARY UP COUNTER	MOTOROLA	MC14520 BCP	1
M42	280085	QUAD 2 1/P 'AND' GATE	MOTOROLA	MC 14081 BCP	4
M43	280085	QUAD 21/P 'AND' GATE	MOTOROLA	MC 14081 BCP	_
M44	280008	QUAD 2 I/P 'NAND' GATE	MOTOROLA	MC14011 BCP	_
M45	280085	QUAD 2 1/P 'AND' GATE	MOTOROLA	MC14081BCP	_
M46	280085	QUAD 21/P 'AND' GATE	MOTOROLA	MC14081BCP	_
NOTES. SEE SHEET 2 FOR L. ISS. E.C.O.	ATEST ISSUE		-	DRAWN TITLE 4-0	ELECTRONICS LTD

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
M47	28 0024	TRI-STATE HEX NON-INV BUFFER	MOTOROLA	MC14503 BC	Ρ –
M48	280086	BI-DIRECTIONAL BUS TRANSCE	IVER MOTOROLA	MC3447	_
M49	270048	QUAD 21/P NAND LS	NATIONAL	DM74LSOON	-
M50	270050	HEX. INVERTER	NATIONAL	74 LS 04	_
M51	270058	DUAL 2TO4 LINE DEMUX. LS	NATIONAL	DM74LSISSN	1 2
M52	270058	DUAL 2 TO 4 LINE DE MUX.LS	NATIONAL	DM74 LS155N	_
M53	280068	DUAL PRECISION MONOSTABLE	MOTOROLA	MC14538 60	P 1
	605059	8 WAY DIL SOCKET			2
	410156-5	PCB			1
P's	540002	22 SWG BTC WIRE			A/R
JLI "	604 037	PROGRAMMING CLASS 160 PLUG	AUGAT	8136-475G-8	
	605050	40 WAY DIL LOW PROFILE SKT.			2
	605060	14 WAY DIL SOCKET			15
	605061	IG WAY DIL SOCKET			19
	605062	18 WAY DIL SOCKET		*	2
	605063	22 WAY DIL SOCKET			2
	605064	24 WAY DIL . SOCKET			10
	605066	6 WAY DIL SOCKET			2
	620003	SOLDER PCB. TERMINAL LUG	HARWIN	H2IOSA	1
	630098	COMPONENT CLIP	RICHCO	KKU-8	1
	630112	CIRCUIT BOARD EJECTOR	RICHCO	CBE BLACK	2
31	700065	KEYSWITCH IPIW MOMENT.	LIPA & ISOSTAT	06	1
	620007	TEST POINT TERMINAL	MICROYAR	C30	16

NOTES.

| DATE | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 18.5.81 | | 1

	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	618004	MOUNTING PAD TOIS	JERMYN	TO18-008 D	1
					
			+		
		1			
NOTES.				<u>.</u>	
10123.				DATE	COO
				24. II. 82 UCT	ELECTRONICS LTD 4000/4000A DIGITAL PCB ASS
SEE SHEET 2 FOR LA	TEST ISSUE			DRAWN . TITLE	4000/4000A
ISS.				CHECKED	DIGITAL PCB ASS
E.C.O.				ABBROVED	
DATE			a	DATE DRAWING 40	00442 SHEET 11 OF 1

DESIGNATOR	DATRON	DESCRIPTION	PRINCIPAL	MANUFACTURER'S	No. USED
RI	PART No.	IK 5% YAW CARBON	MANUFACTURER	PART No.	Per Assy.
R2	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	5
R2 R3	000102	NOT USED	MULLARD	CK25	+
R 4		NOT USED	-		+ -
R5	000472	4k7 5% 4W CARBON	MULLARD	CR25	
R6	000 472	4k7 5% 1/4W CARBON	MULLARD	CR25	4
R7	000 474	470k 5% 1/4W CARBON	MULLARD	CR2S	
R8		120k 5% 1/4W CARBON			2
R9	000124	470R 5% 1/4W CARBON	MULLARD MULLARD	CR25	<u> </u>
	000471			CR25	8
RIO	000474	470k 5% 1/4W CARBON	MULLARD	CR25	
RII	012372	23k7 1% 1/8W 50ppm MF	HOLCO	H8C	4
RI2	012372	23k7 1% 1/8W 50 m MF	HoLCO	H8C	
R13	012372	23k7 1% 1/8W 50ppm MF	HOLCO	H8C	
RI4	01237 2	23k7 1% 1/8W 50ppm MF	Holco	H8C	
RIS	000392	3k9 5% 1/4W CARBON	MULLARD	CR25	3
RIG	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	
RI7	000392	3k9 5% 1/4W CARBON	MULLARD	CR25	_
R18	000392	3k9 5% 1/4W CARBON	MULLARD	CR25	_
219	000272	2k7 5% 1/4W CARBON	MULLARD	CR25	1
R20	000471	470R 5% 1/4W CARBON	MULLARD	CR25	_
R21	000471	470R 5% 1/4W CARBON	MULLARD	CR25	_
R22	000471	470R 5% 1/4W CARBON	MULLARD	CR25	_
R23	000471	470R 5% 1/4W CARBON	MULLARD	CR25	_

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R24	000471	470R 5% 1/4W CARBON	MULLARD	CR25	_
R25	000331	330R 5% 1/4W CARBON	MULLARD	CR25	
R26	000471	470R 5% 1/4W CARBON	MULLARD	CR2S	
R27	000102	IK 5% 1/4W CARBON	MULLARD	CR25	_
R28	000102	IK 5% YAW CARBON	MULLARD	CR25	_
R29	000561	560R 5% 1/4W CARBON	MULLARD	CR25	4
R30	000561	SGOR 5% 1/4W CARBON	MULLARD	CR25	_
R31	000561	560R 5% 1/4W CARBON	MULLARD	CR25	_
R32	000561	560R 5% 1/4W CARBON	MULLARD	CR25	_
R33	000471	470R 5% 1/4W CARBON	MULLARD	CR2S	_
R34	000472	4k7 5% 1/4W CARBON	MULLARD	CR25	
f135	000472	4K7 5% 1/4W CARBON	MULLARD	CR25	_
ANI	090079	5k6 × 8 2% NETWORK	AB	850-9I-5k6	2
AN2	090079	5kG × 8 2% NETWORK	АВ	850-91-5k6	_
NOTES.				DATE 19. 6. 81	ELECTRONICS LTD
SEE SHEET 2 FOR L	ATEST ISSUE				0 ANALOG
E.C.O.				CHECKED INTERF	FACE PCB. ASSY.
DATE CHKD.				DO ANNUAL C	00443 3 SHEET

DESIGNATOR	DATRON PART No.		IPTION				PRINCIPAL MANUFACTURER		MANUFACTURE PART No.	:R'S	No. USED Per Assy.
CI	104026	47nF	+50 %	50V	CER-	DISC	SIEMENS		B37449		42
C2	104026	47nF	- 11	11	14	11	**		66		_
C3	104026	47nF	**	11	11	11	"		••		_
C4	104026	47 ₀ F	н	14	11	11	49		84		-
C5	104 026	47nF	- 11	14	n	*1	16		te		_
C6	104026	47nF		49	11	**	"		**		_
C7	104026	47nF	11	.,	11	11	"		••		_
c8	104026	47nF	- 11	11	11	11	14		11		_
C9		NOT	USED								_
CIO	101103	10nF		250V	CER	DISC	ITT		CDIO		1
CII	104026	47nF	+50%	50V	CER	DISC	SIEMENS		B37449		-
CI2	104026	47nF	- 11		11	11	11		20		_
CI3	104026	47nF	**		**	11	91		**		_
C14	104026	47nF	- 11	**	**	н	11		**		_
CIS	104026	47nF	11	- 11	11	и	п				_
C16	104026	47nF	- 11	11	11	н	44		**		_
CI7	104026	47nF		11	11	"	11		*1		_
C18	104026	47nF	н	**	н	11	et e		н		_
C19	104026	47nF	**	**	**	18	**		es .		_
C20	104026	47nF	18		**	**	п		н		_
C21	104026	47nF	н	11	**	н	11		**		_
C22	104026	47aF	11	**	"	**	11	_	**		_
C23	104026	47nF	18	**	14	**	11		**		_
NOTES. SEE SHEET 2 FOR LA	TEST ISSUE							DATE 19	1.6.81	datron	ELECTRONICS LTD
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DATE		-			1	_		DATE	en l	WING 40044	

DESIGNATOR	DATRON PART No.	DESCRIPTION				PRINCIPAL MANUFACTURER		MANUFACT	TURER'S	No. USED Per Assy.
C24	104026	47nF +50%	50V	CER	bisc	SIEMENS		B3744	9	_
C25	104026	44 11	**	н	83	n ii		- 11		_
C26	104026	FF 41	**	11	11	h		11		-
C27	104026	11 11	11	11	11	14		"		_
C28	104026	11 11		11	- 11	14		11		_
C29	150008	470nF 20%	35v	DIP.	TANT	UNION CARBIDE		KR47E3	5	1
C30	104026	47 nF + 50 %	50V	CER	DISC	SIEMENS		B 374 49)	_
C3I	150002	10µF 20%	16V	DIP	TANT	UNION CARBIDE		KIOEI6		1
C32	150012	100nF 20%	35v	DIP	TANT	UNION CARBIDE		KRIOE35		1
C35	104026	47 nF +50 %	50V	CER.	DISC	SIEMENS		B37449		-
C34	104 026		11	**	н	+1	-	"		_
C35	104026	F1 F1	11	11	**	41	_	"		_
C36	104026	11 11	**	**	- 11	11		"		_
C37	104026		- 0	- 11	4	п		.,		_
<i>c3</i> 8	104026	11 10	14	11	u	11		No.		_
C39	102220	22þF 5%	500V	CER	DISC	ITT		CDIO		1
C40	102330	33þF 5%	500V	CER	DISC	ITT		CDIO		ı
C41	104026	47nF +50 %	50V	CER	.DISC	SIEMENS		B37449	·	_
C42	104026	FI 11	74	*1	ti	er		"		_
C43	104026	11 11	11	"	n	11	_	.,		_
C44	104026	14 14	*1	*11	"	**		•,		
C45	104026	11 11	11		*1	11		**		_
C46	104026	11 11	11	- 11	11	**		1,		_
NOTES.			2.					. 6 . 81	datron	ELECTRONICS LTD
SEE SHEET 2 FOR LA	TEST ISSUE			_			DRAWN	/ 	4000. AN	ALOG
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DATE							DATE		DRAWING ACCOUNTS	13 SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
C47	150024	47 JUF 20% IGV DIP TANT	UNION CARBIDE	K47EIG	
C48	104026	470F +50% 50V CER.DISC	SIEMENS	B37449	
C49	104026	47nF +50 % 50V CER DISC	SIEMENS	B37449	
C50	120010	JUSF 10% 160V POLYCARB	ASHCROFT	A28152058	ı
C51	104026	47nF +50 % 50V CER DISC	SIEMENS	B37449	_
DI	220010	SI HOT CARRIER DIODE	HP	HSCHIOOI/ING	263 2
D2	220010	SI HOT CARRIER DIODE	НР	HSCHIOOI/ING	5263 -
Q ।	240007	SI NPN TRANSISTOR	NATIONAL	2N3G46	1
MI	270050	HEX INVERTER LS	NATIONAL	DM74LSO4N	1
M2	28 0008	QUAD 21/P'NAND GATE	MOTOROLA	MC14011BCP	2
М3	280011	DUAL D FLIP-FLOP	MOTOROLA	MCI40I3BCP	2
M4	280059	DUAL BINARY UP COUNTER	MOTOROLA	MC14520BCP	1
M5	280037	HEX BUFFER	MOTOROLA	MC14050BCP	1
M6	270048	QUAD 2 1/P 'NAND' LS	NATIONAL	DM74 LS 00N	2
M7	270072	QUAD 2 1/P 'NOR' LS	NATIONAL	DM74 LS02 N	2
MB	270002	QUAD 2 I/P O/C NAND	NATIONAL	DM740IN	2
M9		NOT USED			-
MIO		NOT USED			_
Mil		NOT USED			-
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE				atron ELECTRONICS LTD
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CHKD.				DATE NUMBER	400443 6 OF

DATE CHKD.

M12 M13 M14 M15 M16 M17	270072 270055 270075 280095 280095	QUAD 2 1/P 'NOR' LS DUAL 4 1/P NAND LS DUAL D FLIP-FLOP LS 4BIT SYNC. BINARY COUNTER	NATIONAL NATIONAL	DM74		
MI4 MI5 MI6 MI7	270075 280095	DUAL D FLIP-FLOP LS		DM74	LS20N	1
MIS MIG MI7	280095		NATIONAL			1
M16 M17		4BIT SYNC, BINARY COUNTER		DM741	LS74N	1
M17	280095	The state of the s	MULLARD	HEF4C	163BP	3
		48IT SYNC. BINARY COUNTER	MULLARD	HEF 40	163BP	_
	280095	4BIT SYNC. BINARY COUNTER	MULLARD	HEF40	1638P	_
MI8	280010	DECADE COUNTER	MOTOROLA	MC1416	SOBCP	1
MI9	280093	QUAD EXCLUSIVE-OR GATE	MOTOROLA	MCI40	70ВСР	6
M20	280093	QUAD EXCLUSIVE -OR GATE	MOTOROLA	MC140	70BCP	-
MSI	280093	QUAD EXCLUSIVE-ORGATE	MOTOROLA	MC1407	70BCP	-
M22	270074	TRIPLE 3 1/P 'NOR' LS	NATIONAL	DM74	LS 27N	3
M23	270074	TRIPLE 3 /P 'NOR' LS	NATIONAL	DM741	S27N	-
M24	270074	TRIPLE 3 I/P 'NOR' LS	NATIONAL	DM741	LS27N	-
M25	280093	QUAD EXCLUSIVE - OR GATE	MOTOROLA	MC140	70BCP	-
M26	280093	QUAD EXCLUSIVE - OR GATE	MOTOROLA	MC140	70 BCP	_
M27	280093	QUAD EXCLUSIVE-ORGATE	MOTOROLA	MC140	70BCP	- /
M28	280008	QUAD 2 1/P 'NAND' GATE	MOTOROLA	MC140	DIIBCP	-
M29	280068	DUAL PRECISION MONOSTABLE	MOTOROLA	MC145	38 BCP	- 1
M30	260029	311 VOLTAGE COMPARATOR	NATIONAL	LM3III	1	1
M3I	280015	QUAD LATCH	MOTOROLA	MC140	76 BCP	7
M32	280015	QUAD LATCH	MOTOROLA	MCI40	76 BCP	_
M33	280015	QUAD LATCH	MOTOROLA	MCIAO	76BCP	_
M34	280015	QUAD LATCH	MOTOROLA	MC140	76BCP	_
NOTES. SEE SHEET 2 FOR LA	TEST ISSUE			DATE 19.6.81	datron	
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E.C.O.			- - - - - - - - - - 	APPROVED DATE	DRAWING NUMBER 40044	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFAC PART No.	TURER'S	No. USED Per Assy.
M35	270073	QUAD 2 1/P O/C 'AND' LS	NATIONAL	DM74L	509N	2
M36	270073	QUAD 21/P O/C 'AND' LS	NATIONAL	DM74-L	509N	_
M37	280015	QUAD LATCH	MOTOROLA	MC140	76 BCP	_
M38	280015	QUAD LATCH	MOTOROLA	MC 1407	6 BCP	_
M39	280015	QUAD LATCH	MOTOROLA	MC140	76 BCP	_
M40	270036	MONOSTABLE	NATIONAL	DM7412	2IN	1
M41	270057	DUAL JK FLIP-FLOP LS	NATIONAL	DM741	\$76N	2
M42	270057	DUAL JK FLIP-FLOP LS	NATIONAL	AL DM74L		_
M43	270048	QUAD 2 1/P NAND LS	NATIONAL	DM74L	SOON	_
M44	280094	SYNC! SERIAL DATA ADAPTOR	MOTOROLA	MC685	2P	1
M45	280024	TRI-STATE HEX, NON-INV. BUFFE	R MOTOROLA	MC145	OS BCP	1
M46	270002	QUAD 2 1/P O/C NAND	NATIONAL	DM740	IN	_
M47	280038	HEX D FLIP-FLOP	MOTOROLA	MC1417	4BCP	4
M48	280038	HEX D FLIP-FLOP	MOTOROLA	MC1417	4 BCP	_
M 4 9	2800 11	DUAL D FLIP-FLOP	MOTOROLA	MC140	3 BCP	_
M50	280105	8 I/P NAND	MOTOROLA	MC140	68 BCP	1
M51	280038	HEX D FLIP-FLOP	MOTOROLA	MC1417	4 BCP	-
M52	280038	HEX D FLIP- FLOP	MOTOROLA	MC1417	4 BCP	
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE		et.	19.6.81 DRAWN 11.	datron	
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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	410155-4	РСВ			1
	605 <i>06</i> 0/A	14 WAY DIL SOCKET			26
	605061/A	16 WAY DIL SOCKET			21
	605064/A	24 WAY DIL SOCKET			1
	630117	CIRCUIT BOARD EJECTOR	RICHCO	CBE BROWN	2
×I	800023	4.096 MHZ CRYSTAL	IQD	A122A	1
	620007	TEST POINT TERMINAL	MICROVAR	C 30	22
	540002	22 SWG TINNED COPPER W	IRE R.S.		A/R
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NOTES.				DATE	,
				19.6.81 data	ELECTRONICS LTD
SEE SHEET 2 FOR LA	ATEST ISSUE			DRAWN 11 TOTAL	
ISS. E.C.O.				CHECKED 400	O. ANALOG CE PCB. ASSY
DATE				DATE DRAWING NUMBER 4.0	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RI	000472	4k7 5% 1/4W CARBON	MULLARD	CR25	5
R2	000561	560R 5% VAW CARBON	MULLARD	CR25	8
R3	000622	6k2 5% 1/4W CARBON	MULLARD	CR25	4
R4	000561	560R 5% 1/4W CARBON	MULLARD	CR25	
RS	000 472	4k7 5% 1/4W CARBON	MULLARD	CR2S	_
R6	000472	4k7 5% 1/4W CARBON	MULLARD	CR25	_
R7	000561	560R 5% 1/4W CARBON	MULL ARD	CR25	
R8	000272	2k7 5% 1/4W CARBON	MULLARD	CR25	2
R9	000561	560R 5% 1/4W CARBON	MULLARD	CR25	_
RIO	000472	4k7 5% 1/4W CARBON	MULLARD	CR25	_
RII	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	7
KIS	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	6
RI3	000622	6k2 5% 1/4W CARBON	MULLARD	CR25	_
RI4	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	~-
RIS	000103	IOK 5% 1/4W CARBON	MULLARD	CR2S	
R16	013161	3k16 1% 1/8W 50pm MF	HOLCO	H8C	4
RI7	000101	100R 5% 1/4W CARBON	MULLARD	CR25	12
RIS	014750	475R 1% 18W 50hm MF	HoLco	H8C	1
RI9	013161	3k16 1% 1/8W 50Hm MF	Holco	H8C	
R20	000101	IOOR 5% 1/4W CARBON	MULLARD	CR25	_
RZI	013161	3k16 1% 1/8W 50bbm MF	HOLCO	H8C	_
R22	000101	IOOR 5% 1/4W CARBON	MULLARD	CR25	-
R23	012261	2k26 1% 1/8W 50ppm MF	HOLCO	H8C	I
E.C.O. RELEASED 1. DATE 7.5.82 1	Z 3 354 1380 1383 14 7.82 24.8.82 11	4 5 139 ±0,1502.151\(\) 2-83 4-7-83.	DRAW! CHECK APPRO	9.81 datron 4000A REI 4000A REI PCB. 1 71TLE 4000 4000A REI 4000A REI 40044 40044 40044	F DIVIDER

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400444 3 SHEET 400444A 3 OF 17

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DESIGNATOR DATRON DESCRIPTION PRINCIPAL MANUFACTURER'S No. USED PART No. MANUFACTURER PART No Per Assy. R24 013161 3k16 1% 1/8W 5000m MF HoLco H8C R25 000101 LOOR 5% 1/4W CARBON MULLARD CR25 R26 5% 1/4W CARBON CR25 000102 MULLARD **R27** 000431 430R 5% 1/4W CARBON MULLARD CR25 2 R28 000101 100R 5% 1/4W CARBON MULLARD CR25 R29 (FSV) 95R3 1% 1/8W 50Hm MF 019538 HOLCO H8C 4 R30 430R 5% 1/4W CARBON 000431 MULLARD CR2S **R31** 000101 100R 5% V4W CARBON MULLARD CR25 **R32** 000102 Ιk 5% 1/4W CARBON MULLARD CR25 **R33** (FSV) 019538 95R3 1% 1/8W 50ppm MF HOLCO H&C R34 5k6 5% 000562 1/4W CARBON MULLARD CR25 4 **R35** 000561 560R 5% 1/4W CARBON MULLARD CR25 R36 000622 6k2 5% 1/4W CARBON MULLARD CR25 **R37** 1/4W CARBON MULLARD 000561 560R 5% CR25 **R38** 000562 5% 1/4W CARBON 5k6 MULLARD CR25 R39 000562 5k6 5% 4W CARBON MULLARD CR25 **R40** 000561 560R 5% 1/4W CARBON MULLARD CR25 R41 000622 5% 1/4W CARBON MULLARD CR25 6k2 R42 CR25 000561 1/4W CARBON MULLARD 560R 5% R43 000562 5k6 5% 1/4W CARBON MULLARD CR25 R44 CR25 2ko 5% 1/4W CARBON MULLARD ſ 000202 5% R45 1/4W CARBON CR25 000222 2k2 MULLARD 1 432 R 1% 1/8W 50 pm MF **R46** 014320 HOLCO H8C 4 NOTES. data ELECTRONICS LTD 21.9.81 SEE SHEET 2 FOR LATEST ISSUE 4000A REF. DIVIDER CHECKED ISS.

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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R47	000101	100R 5% 1/4W CARBON	MULLARD	CR25	_
	SV) 019538	95R3 1% 1/8W 50 pm MF		H8C	_
R49	014320	432R 1% 1/8W 50 pm MF	HOLCO	H8C	_
R50	000101	100R 5% 1/4W CARBON	MULLARD	CR25	_
R51	014320	432R 1% 1/8W 50 pm MF	HOLCO	H8C	_
R52	000101	100R 5% 1/4W CARBON	MULLARD	CR25	_
R53 (1	(50) 019538	95R3 1% 1/8W 50 pm MF	Holco	H8C	_
R54	014320	432R 1% 1/8W50bbm MF	HOLCO	H8C	_
R55	000101	IOOR 5% 1/4W CARBON	MULLARD	CR25	_
R56	000474	470k 5% 14W CARBON	MULLARD	CR25	1
R57	000184	180k 5% 1/4W CARBON	MULLARD	CR25	1
R58	013742	37k4 1% 1/8W 50bpm MF	HoLco	H8C	1
R59	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	_
260	000104	100k 5% 1/4W CARBON	MULLARD	CR25	4
R61	000104	100k 5% 1/4W CARBON	MULLARD	CR25	_
R62	018872	88k7 1% 1/8W 50ppm MF	HOLCO	Н8С	1
263	017872	78k7 1% 1/8W 50ppm MF	HOLCO	нвс	2
R64	070144	36ko .01% 56pm ww		MX125B	1
R65	070142	12ko .01% 5 ppm ww	MANN	MX1258	2
266	017872	78k7 1% 1/8W 50hpm MF	HoLco	HSC	_
267	000912	9k1 5% 1/4W CARBON	MULLARD	CR25	1
368	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	
269		NOT USED			_

R70 R71				PART No.	No. USED Per Assy.
R71		NOT USED			_
		NOT USED			
R72	000682	6k8 5% 1/4W CARBON	MULLARD	CR25	1
R73	000272	2k7 5% 1/4W CARBON	MULLARD	CR25	-
R74	000470	47R 5% 4W CARBON	MULLARD	CR25	2
R7S	011183	118k 1% 1/8W 50ppm MF	HOLCO	HBC	1
R76	011001	1k00 1% 1/8W 50pm MF	HOLCO	HSC	4
R77	011001	1400 1% 1/8W 50 hm MF	HOLCO	HSC	_
R78	012672	26k7 1% 1/8W 50pm MF	HOLCO	H8C	1
R79	080032	78k7 .1% IW 10ppm MF	VISHAY	VS3C5	1
R80	070143	16k0 .01% 5hhm WW	MANN	MX 125B	1
R81	070142	12k0 .01% 5hpm WW	MANN	MX1258	_
R82		NOT USED			
?83		NOT USED			
R84	012212	22k1 1% 1/8W 50ppm MF	HOLCO	HBC	2
R85 (F5V)	015112	51 KI. 1% 1/8 W 50 pm MF	HOLCO	H8C	1
₹86	000102	Ik 5% 4W CARBON	MULLARD	CR25	_
R87	000104	100k 5% 1/4W CARBON	MULLARD	CR25	_
R88		NOT USED			_
R89		NOT USED			_
R 9 0	000104	100k 5% 1/4W CARBON	MULLARD	CR25	_
R9ı	011182	11k8 1% 1/8W 50hm MF	HoLco	HBC	1
R 32	011001	1k00 1% 1/8W 50ppm MF	HOLCO	HBC	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R93	011001	1k00 1% 1/8 w 50 pm MF	HOLCO	HBC	
R94	014532	45k3 1% 1/8W 50ppm MF	HOLCO	HBC	1
R95	011402	14k0 1% 1/8W 50bbm MF	Holco	H8C	i i
R96	019 531	9k53 1% 1/8W 50bbm MF	HOLCO	H8C	
R97	0.755.	NOT USED	710-03		<u> </u>
R98	011002	-1.1	HOLCO	нас	3
R99	070156	555k41 ·01% 5 pm WW	MANN	AXI75B	1
RIOO	070145	475R .01% 5pbm WW	MANN	AX1758	i
RIOI	012212	22k1 1% 1/8W 50pm MF	HOLCO	H8C	
RIO2	000473	47k 5% 1/4W CARBON	MULLARD	CR25	3
RIO3	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	
R104	000103	lok 5% 1/4W CARBON	MULLARD	CR25	_
RIOS	000472	4k7 5% 1/4W CARBON	MULLARD	CR25	_
RIO6	000103	lok 5% 1/4W CARBON	MULLARD	CR25	_
R107	000393	39k 5% 1/4W CARBON	MULLARD .	CR25	2
R108	012001	2k00 1% 1/8W 50hm MF	HOLCO	нас	2
R109	011302	13k0 1% 1/8W 50hm MF	HOLCO	H8C	2
RIIO	012001	2k00 1% 1/8W 50/pm MF	HOLCO	H8C	_
RILI	000393	39k 5% 1/4W CARBON	MULLARD	CR25	-
RIJ2	011302	13k0 1% 1/8W 506 MF	HOLCO	HSC	_
RII3	000101	IOOR 5% 1/4W CARBON	MULLARD	CR25	_
R114	000101	IOOR 5% 1/4W CARBON	MULLARD	CR25	_
RIIS	000470	47R 5% 1/4W CARBON	MULLARD	CR25	_
NOTES.			DA	21.9.81 datron	
ISS.			CHI	4000 AREF	DIVIDER
E.C.O.			API	DRAWING 4.0044	

E.C.O.

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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RIIG	012211	2k21 1% 18W 50 mm MF	HOLCO	HBC	1
RII7	000621	620R 5% 4W CARBON	MULLARD	CR25	1
RII8	006 132	1k30 2% IW MET-OX	ELECTROSIL	FPI	2
RII9	006 132	1k30 2% IW MET-0X	ELECTROSIL	FPI	_
R120	000103	IOK 5% YAW CARBON	MULLARD	CR25	
R121	000473	47k 5% 14W CARBON	MULLARD	CR25	_
R122	000823	82k 5% 1/4W CARBON	MULLARD	CR25	1
R123	000473	47k 5% 1/4W CARBON	MULLARD	CR25	-
R124	000152	IKS 5% YAW CARBON	MULLARD	CR25	J
2125	011002	10KO 1% 18W 50pp m MF	HOLCO	HSC	-
2126	200110	10 KO 1% 1/6W 50ppm MF	Holco	нас	-
Anı	090031	Ik×7 2% NETWORK	BECKMAN	764- - RIK	1
AN2	090096	IM ×8 2% NETWORK	AB	850-91-IM	2
AN3	090096	IM ×8 2% NETWORK	AB	850-91-IM	_
AN4	090085	12k ×8 2% NETWORK	AB	761-3-12k	ı
NOTES.	ATEST ISSUE		4	DRAWN III TITLE	REF DIVIDER
ISS. E.C.O.				APPROVED PC	CB ASSY
DATE CHKD.				DATE DRAWING 40	0444 SHEET 0444A 7 OF I

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
CI		NOT USED			_
C2	104026	47nF +50 % 50V CER DISC	SIEMENS	B37449	23
С3		NOT USED			_
C4		NOT USED			-
C5	104026	47nF -80% 50V CER DISC	SIEMENS	B37449	_
C6	104026	470F 180% SOV CER DISC	SIEMENS	B37449	_
C7	150016	INF 20% 35V DIP TANT	UNION CARBIDE	KIRO E35	2.
C8	104026	470F -20 % SOV CER DISC	SIEMENS	837449	_
C9	104026	470F -20% 50V CER DISC	SIEMENS	B37449	_
C10	104026	47nF -20% 50V CER DISC	SIEMENS	837449	_
CII	104026	47nF +50 % SOV CER DISC	SIEMENS	B37449	_
CI2	104026	47nF +50 % 50V CER DISC	SIEMENS	837449	_
C13	102101	100 F 10% 500V CER DISC	ITT	CDIO	1
C14	104026	47nF - 20 % SOVCER DISC	SIEMENS	B37449	_
CIS	110013	100 AF 20% 250V POLYESTER	MULLARD	C280AE PIOOK	2
C16	110013	100 nF 20% 250V POLYESTE	MULLARD	C280AEPIOOK	_
C17	104026	47nF -20 % SOV CER DISC	SIEMENS	B37449	_
C18	104026	47 nF -20% 50V CER DISC	SIEMENS	837449	_
C19	104026	47nF - 50 % 50V CER DISC	SIEMENS	837449	_
C20	104026	474F -20% 50V CER DISC	SIEMENS	B37449	_
C21	104026	47nF +50% SOV CER DISC	SIEMENS	837449	_
CSS	104026	47nF +50 % 50V CER DISC	SIEMENS	837449	_
C23	140016	470 AF 10% 250V POLYPROP		PHE402 HFK	10
NOTES. SEE SHEET 2 FOR L. ISS. E.C.O.	ATEST ISSUE		DR AWN CHECKE	1000A REF	DIVIDER
DATE CHKD.			APPROV DATE	DRAWING 40044 40044	4 SHEET

E.C.O.

DATE

CHKD.

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFAC PART No.	TURER'S	No. USED Per Assy.
C24	102470	47pF 5% 500V CER DISC	ITT	CDIO		3
C25	104026	47nF -20% 50V CER DISC	SIEMENS	B3744	-9	_
C26	102 470	47pf 5% 500V CER DIS	ITT	CDIO		_
C27	104 026	47nF +50 % 50V CER DISC	SIEMENS	83744	9	_
C28	102102	InF 10% 500 CER DISC		CDIO		2
C29	140016	470nF 10% 250V POLY PRO	RIFA	PHE402	HFK	_
C30	102470	47 F 5% 500V CER DISC	ITT	CDIO		_
C3I	140016	470nF 10% 250V POLYPROF	RIFA	PHE 402	HFK	_
C32	104026	47nF + 50% 50V CER DISC	SIEMENS	83744	9	-
C33	150020	100F 20% 25V DIP. TAN	LUNION CARBIDE	KIO E2	5	5
C34	180015	470 UF 25V AL. ELECT.	MULLARD	017-16	471	1
C35	150020	100F 20% 25V DIP. TANT	1	KIDES	5	_
C36		NOT USED				_
C37		NOT USED				_
C 38	102102	INF 10% 500V CER DISC	ITT	CDIO		_
C39	150020	IOHF 20% 25V DIP TANT	UNION CARBIDE	K10E25		_
C40	102270	27 F 5% 500V CER DISC	ITT	CDIO		2
C41	140016	470 F 10% 250V POLYPROP	RIFA	PHE 402	HFK	_
C42	140016	470 nF 10% 250V POLYPROP	RIFA	PHE 402	HFK	
C43	140016	470nF 10% 250V POLYPROP	RIFA	PHE 402	HFK	
C44	140016	470 NF 10% 250V POLYPROP	RIFA	PHE 402	HFK	_
C45	102270	27 F 5% 500V CER DISC	ITT	CDIO		
C46	140016	470 F 10% 250V POLY PROF		PHE 402	2 HFK	_
NOTES. SEE SHEET 2 FOR LA ISS. E.C.O.	TEST ISSUE			21.9.81 DRAWN JL.	datron	F. DIVIDER
E.C.O.			1 1	APPROVED	۲C5.۸	JJ/.

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
C47	140016	470 nF 10% 250V POLYPROP		PHE 402 HFK	
C48	104026	47nF +50 % 50V CER DISC	SIEMENS	837449	
C49	150020	10,0F 20% 25V DIP TANT		KIOE25	
C50	150020	100F 20% 25V DIP TANT		KIOE 25	_
C51	140051 *	IONE 20% 400V POLYPROP		MKPIO	1
C52	110035	220 AF 20% 63V POLYESTER	4	MKS2	
C53	140016	470 nF 10% 250V POLYPROP	RIFA	PHE 402 HFK	_
C5 4	110042	100nF 20% 63V POLYESTER		MKS2	2
C55	110042	100 nF 20% 63V POLYESTER		MKS2	
C56	110039	470 F 20% 63V POLYESTER		MKS2	2
C57	110039	470 of 20% 63V POLYESTER		MKS2	_
C58	150016	LUF 20% 35V DIP TANT	 	KIROE35	_
259	104026	470f -20 % SOV GER DISC	SIEMENS	837449	_
C60	104026	47 of 150 % SOV CER DISC	SIEMENS	B37449	
C61	104026	470F 150% SOV CER DISC		B37449	_
C62	104026	47aF +50 % 50V CER DISC		B37449	
C63	180021	3,03F 63V AL ELECT	MULLARD	015-18338	2
C64	180021	BUSF GOV AL ELECT	MULLARD	015-18338	_
CG5	102221	2200F 10% 500V CER DISC	ITT	CDIO	1
	102221	ELOST ION DOOF CER DISC			•
NOTES. # ALTERN	LATIVE 140044 STEAT	TITE MKPI841.	[DATE		
				i. s. si datron	ELECTRONICS LTD
SEE SHEET 2 FOR LA	ATEST ISSUE		DRAI	TITLE 4000 RE	
ISS.			CHEC	rub. /	ASSY
E.C.O. DATE				DRAWING 40044	4 SHEET
CHKD.			DATE	400444	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
DI	210027	2V7 400mW ZENER	MULLARD	BZY88C2V7	5
DS	210120	12V 400mW ZENER	MULLARD	BZY88CI2	1 .
D3	210027	2V7 400 mW ZENER	MULLARD	BZY88 C2V7	
D4	210043	4V3 400mW ZENER	MULLARD	82788C4V3	1
D5	210027	2V7 400mW ZENER	MULLARD	BZY88C 2V7	_
DG	210027	2V7 400 mW ZENER	MULLARD	BZY88C2V7	
D7	213009	ISV SW ZENER	UNITRODE	Tvs 515	4
08	213009	15V SW ZENER	UNITRODE	TVS 515	_
D9	213009	ISV SW ZENER	UNITRODE	TVS SIS	_
DIO	200008	200mA 125V LL SI DIODE	FAIRCHILD	IN458A	ı
DII	213009	ISV SW ZENER	UNITRODE	TVS515	_
D12	200002	IA SOV GP SI DIODE	FAIRCHILD	IN400I	1
DI3	210027	2V7 400mW ZENER	MULLARD	BZY88C2V7	_
014	210062	GV2 400mW ZENER	MULLARD	BZY88C6V2	2.
DI5	210062	GV2 400 MW ZENER	MULLARD	BZY88CGV2	
DIG	200001	75 mA 754 GPSI DIODE	FAIRCHILD	IN4148	4
DI7	210150	15V 400mW ZENER	MULLARD	BZŸ88C15	1
D18	200001	75mA 75V GPSI DIODE	FAIRCHILD	IN4148	_
D19	200001	75 A 75V GPSI DIODE	FAIRCHILD	14148	_
080	100005	75mA 75V GP Si DIODE	FAIRCHILD	IN4I48	-
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE	€		44	ELECTRONICS LTD
E.C.O.				APPROVED PC	REF DIVIDE 3 ASSY

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
QI	250004	SI PNP TRANSISTOR	NATIONAL	2N3906/TO18	12
Q2	240006	SI NPN "	NATIONAL	2N3904/TOI8	13
Q3	250004	SI PNP "	NATIONAL	2N3906/TO18	
Q4	240006	SI NPN 11	NATIONAL	2N3904/T018	_
Q5	240006	SI NPN "	NATIONA L	2N3904/TOI8	_
Q6	250004	Si PNP "	NATIONAL	2N3906/T018	_
Q7	240006	SI NPN II	NATIONAL	2N3904/TOI8	
Q8	250004	SI PNP "	NATIONAL	2N3906/TOI8	_
Q9	250004	SI PNP "	NATIONAL	2N3906/TOI8	
QIO	240006	SI NPN "	NATIONAL	2N3904/TOI8	_
QII	250004	SI PNP "	NATIONAL	2N3906/T018	
QI2	240006	SI NPN "	NATIONAL	2N3904/TOI8	_
Q13		NOT USED			
Q14		NOT USED			_
Qıs		NOT USED			_
Q16 ·		NOT USED			_
Q17		NOT USED			_
Q18	(4)	NOT USED			_
Q19	24 0006	SI NPN "	NATIONAL	2N3904/T018	<u> </u>
Q 20	240006	SI NPN "	NATIONAL	2N3904/TOIB	
Q21	250004	SI PNP "	NATIONAL	2N3906/TOI8	_
Q22	240006	SI NPN "	NATIONAL	2N3904/Tol8	_
Q23	250004	SI PNP "	NATIONAL	2N3906/TOI8	
NOTES.				DATE	<u> </u>
SEE SHEET 2 FOR LA	ATEST ISSUE		}-		
rss.				DRAWN IL. TITLE 4000 RE	F DIVIDER

DESIGNATOR	DATRON PART No.	DESCRIPTION	; PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
Q24	240006	SI NPN TRANSISTOR	NATIONAL	2N3904/TO18	_
Q25	240006	SI NPN "	NATIONAL	2N3904 / TOIS	_
Q26	250004	SI PNP	NATIONAL	2N3906/TOI8	_
Q27	240006	SI NPN "	NATIONAL	2N3904/TO18	
Q28	250004	Si PNP "	NATIONAL	2N3906/TOIS	_
Q29	230039	P-CHAN JEET	SILICONIX	J175	2
Q30	230039	P-CHAN JEET	SILICONIX	J175	_
Q3I	230038	N-CHAN JEET	SILICONIX	J112	1
Q32	* 239037-1	N-CHAN JET SEL SET	DATRON (SEE DRG)	J108 (COLOUR)	SET OF 4
Q33	230048	P- CHAN J FET	TELEDYNE	J174	2
Q34	* 239037-1	N-CHAN JET SEL SET	DATRON (SEE DRG)	J108 (coLour)	_
Q3S	± 239037-1	N-CHAN JEET SEL SET	DATRON (SEE DRG)	JIOS (COLOUR)	_
Q36	230048	P- CHAN J FET	TELE DYNE	J174	-
Q37	* 239037-I	N-CHAN JEET SEL SET	DATRON (SEE DRG)	J108 (colouis)	_
Q38		NOT USED			
Q39		NOT USED			
Q40	250004	SI PNP	NATIONAL	2N3906/TOI8	_
Q41	230031	N-CHAN DUAL JEET	TELEDYNE	SU2656M	3
Q42	230031	N-CHAN DUAL JEET	TELEDYNE	SU2656M	_
Q43	250004	Si PNP	NATIONAL	2N 3906 / TOIS	_
Q44	230031	N-CHAN DUAL JEET	TELEDYNE	SU2656M	_
Q45	240006	SI NPN	NATIONAL	2N3904/To18	_
Q46	230042	N-CHAN CURRENT LIM. 3ma		TCR 510	2

OTES. * THESE 4 FETS MUST HAVE THE SAME COLOUR CODING	21.9.81	datron ELECTRONICS LTD
E SHEET 2 FOR LATEST ISSUE	DRAWN .	4000 REF. DIVIDER
SS.	CHECKED	4000A KEF. DIVIDER
co.	APPROVED	PCB . ASSY.
DATE	APPHOVED	DRAWING 400444 SHEET
HKD.	DATE	NUMBER 400444A 13 OF 17
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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
Q47	230042	N-CHAN CURRENT LIM 3ma	TELEDYNE	TCRSIO	_
Q48	250021	SI PNP TRANSISTOR	MOTOROLA	BD140	1 .
Q49	240031	SI NPN TRANSISTOR	MOTOROLA	BD139	į ·
Q50	24 0024	SI NPN TRANSISTOR	NATIONAL	TIP3IA	1
MI	220027	HIGH CMR OPTO ISOL.	НР	HCPL-2601 (5082-4361)	7
M2	220027	HIGH CMR OPTO ISOL.	НР	HCPL- 2601(5082-4361)	
M3	220027	HIGH CMR OPTO ISOL	нР	HCPL- 2601 (5082-4361) _
M4	220017	2k5V DUAL OPTO ISOLATOR	FAIRCHILD	FCD 880	1
Ms	2200.7	NOTUSED	T AIRCONNE		_
M6	220027	HIGH CMR OPTO ISOL.	нр	HCPL-2601/5082-4361) –
M7	220027	HIGH CMR OPTO ISOL.	HP	HCPL- 2601 (5082-4361) –
M8	220027	HIGH CMR OPTO ISOL.	HP	HCPL- 2601 (5082-4361) –
M9	220027	HIGH CMR OPTO ISOL	HP	HCPL- 2601 (5082-436)	
MIO	280068	DUAL PRECISION MONOSTABLE	MOTOROLA	MC 14538 BCP	1
MII	280037	HEX BUFFER	MOTOROLA	MC14050BCP	1
MI2	260025	IOI OP AMP	NATIONAL	LMIOIAH	3
MI3	280011	DUAL-D FLIP.FLOP	MOTOROLA	MCI40I3 BCP	2
M14-	280009	HEX INVERTER / BUFFER	MOTOROL A	MC14049 BCP	1
MIS	280089	8 BIT SHIFT REGISTER	MOTOROLA	MC14094 BCP	6
MI6	260025	IOI OP AMP	NATIONAL	LMIOIAH	_
MI7		NOT USED			
NOTES. SEE SHEET 2 FOR LAT	EST ISSUE			21.9.81 data	ELECTRONICS LTD
E.C.O. DATE CHKD.				APPROVED PCB. A DATE DAWING 40044	SSY.

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MÁNUFAC PART No.	TURER'S	No. USED Per Assy.
MIS	280088	BBIT STATIC SHIFT REGISTER	MOTOROLA	MC140	021BCP	2
MI9	280089	8 BIT STATIC SHIFT REGISTER	MOTOROLA	MC14	094 BCP	_
M20	260025	IOI OP AMP	NATIONAL	LMIO		
M21	260028	1458 DUAL OF AMP	FAIRCHILD	vA145	8 CTC	1
M22	280088	BBIT STATIC SHIFT REGISTER	MOTOROLA	MCI40	21 BCP	_
M23	260027	714 OP AMP	FAIRCHILD	νA 714	.HC	4
M24	280023	QUAD 21/P NOR GATE	MOTOROLA	MCI40	OI BCP	1
M25	280089	BBIT STATIC SHIFT REGISTER	MOTOROLA	MC140	94 BCP	_
M26	260057	5534 OP AMP	SIGNETICS	NE 553	4 N	2
M27	280089	BBIT STATIC SHIFT REGISTER	MOTOROLA	MC140	94 BCP	_
M28	260057	5534 OP AMP	SIGNETICS	NE 553	4N	
M29	290090	7x DARLINGTON DRIVER	SPRAGUE / EXAR	ULN200	02A/×R2202CP	1
M30	280089	8 BIT STATIC SHIFT REGISTER	MOTOROLA	MC140	94 BCP	_
131	280089	BBIT STATIC SHIFT REGISTER	MOTOROLA	MC140	94 BCP	_
432	260027	714 OP AMP	FAIRCHILD	UA714	HC	
M33	260053	7650 OP AMP	INTERSIL	ICL76	SO CPD	1
M34	260027	714 OP AMP	FAIRCHILD	UA 714	HC	
M35	260027	714 OP AMP	FAIRCHILD	4714مر	. HC	
M36	280106	HEX LEVEL SHIFTER	MOTOROLA	MC145	04 BCP	1
M37	280011	DUAL D FLIP FLOP	MOTOROLA	MC140	DI3 BCP	
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE			DATE 21.9.82	datron	ELECTRONICS LTD
ISS.				CHECKED	4000A KI	ASSY.
E.C.O.				APPROVED	DRAWING 40044	

DESIGNATOR	DATRON	DESCRIPTION	PRINCIPAL	MANUFACTURER'S	No. USED
	PART No.		MANUFACTURER	PART No.	Per Assy.
RLI	330018	RELAY 2P2W 7V HOLD-IN	AMF	SEE DRG-	1
RT5	330019	RELAY 4P2W 7V HOLD-IN	AMF	SEE DRG-	1
LI - L7	370001	10.H 0.85 & RF CHOKE	PLESSEY	58/10/0011/10	7
TI-T5	310002	PULSE TX	NEWPORT	76616/4 HV	5
SI	700070	SLIDE SWITCH . EXTRA HI. LEVE	APR	25446A H6	1
	SEE TABLE	REF PCB ASSY			1
	410157-5	РСВ			1
	459112	RELAY BRACKET			2
	540008	7/2 PTFE COVERED WIRE		2	790mm
	540002	225WG BTC WIRE			A/R
	590001	SLEEVE MAX CABLE & 3.0	HELLERMANN ELECTRIC	HISX20mm BLACK HELSYN	15
	602001	FSV TERMINAL	MOLEX	02-04-5114	10
	605059	SWAY DIL . SOCKET			14
	605060	14 WAY DIL. SOCKET			4
	605061	IG WAY DIL. SOCKET			13
	611016	SCREW M3x8mm STEEL POZI-PA	N ZINC PLATED GKN		5
	604053	4 WAY "I" PCB PLUG GD. PL		4030-04 AG (-825"PINS)	2_
	612004		HARWIN	CS2116/B	
NOTES. SEE SHEET 2 FOR LA		INSTRUMENT REF. DIV. ASSY. REF	ASSY. DATE 21.	9.81 datron	
E.C.O. DATE CHKD.			CHECKEE APPROVI	PCB.	

	613 005 613 014 613 029 615 005 615 002 620 003 630 024 63 011 8 62 00 07	WASHER M3 INT/SHAKEPROOF WASHER M2-5 INT/SHAKEPROOF M3 CRINKLE WASHER 55. NUT 3-48UNC FULL HEX-STEEL NUT M3 FULL HEX STEEL SOLDER PCB TERMINAL LUG STANDARD STEATITE INS. BEAD CIRCUIT BOARD EJECTOR TEST POINT TERMINAL	STEEL ZN/PLATED GK ZINC PLATED GK ZINC PLATED GK HARWIN	N N N N N N N N N N N N N N N N N N N	3 2 2 2 3 16 4 2 26
	613029 615005 615002 620003 630024 630118	M3 CRINKLE WASHER 55. NUT 3-48UNC FULL HEX-STEEL NUT M3 FULL HEX STEEL SOLDER PCB TERMINAL LUG- STANDARD STEATITE INS. BEAD CIRCUIT BOARD EJECTOR	ZINC PLATED GK ZINC PLATED GK HARWIN PARK ROYAL PORCELAIN CO	N N H2IOSA TYPE Nº 2 (16 SWG) CBE RED	2 2 3 16 4 2
	615005 615002 620003 630024 630118	NUT 3-48UNC FULL HEX-STEEL NUT M3 FULL HEX STEEL SOLDER PCB TERMINAL LUG- STANDARD STEATITE INS. BEAD CIRCUIT BOARD EJECTOR	ZINC PLATED GK HARWIN PARK ROYAL PORCELAIN CO RICHCO	H2105A TYPE Nº 2 (16 SWG)	2 3 16 4 2
	615002 620003 630024 630118	NUT M3 FULL HEX STEEL SOLDER PCB TERMINAL LUG- STANDARD STEATITE INS. BEAD CIRCUIT BOARD EJECTOR	ZINC PLATED GK HARWIN PARK ROYAL PORCELAIN CO RICHCO	H2105A TYPE Nº 2 (16 SWG)	3 16 4 2
	620003 630024 630118	SOLDER PCB TERMINAL LUG STANDARD STEATITE INS. BEAD CIRCUIT BOARD EJECTOR	HARWIN PARK ROYAL PORCELAIN CO RICHCO	H2105A TYPE Nº 2 (16 SWG)	16 4 2
	630024 630118	STANDARD STEATITE INS. BEAD CIRCUIT BOARD EJECTOR	PARK ROYAL PORCELAIN CO	. TYPE Nº 2 (16 SWG) CBE RED	4 2
	630118	CIRCUIT BOARD EJECTOR	RICHCO	CBE RED	2
					
	620007	TEST POINT TERMINAL	MICROVAR	C 30	26
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ISS. E.C.O.			CHEC	4000A NE	EF DIVIDER ASSY.
DATE			APPF	DRAWING 4004	AA SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RI	000472	4 k7 5% 1/4W CARBON	MULLARD	CR25	1
R2	000103	lok 5% 1/4W CARBON	MULLARD	CR25	8
RB	000105	IM 5% 4W CARBON	MULLARD	CR25	4
R4	000105	IM 5% 1/4W CARBON	MULLARD	CR25	-
R5	000105	IM 5% 1/4W CARBON	MULLARD	CR25	_
R6	000105	IM 5% 1/4W CARBON	MULLARD	CR25	
R7	000153	ISK 5% 1/4W CARBON	MULLARD	CR25	1
R8	041005	10M0 1% 1/2W 100 ppm CF	ALLEN BRADLEY	cc	8
R9	041005	10MO 1% 1/2W 100/pm CF	ALLEN BRADLEY	cc	_
RIO	SEE TABLE	IM MATCHED SET	MANN	SEE DRG	1
RII	019091	9k09 1% 1/8W 50ppm MF	HoLco	HSC	3
Rı2	012372	23k7 1% 1/8W 50bpm MF	HOLCO	H8C	2
RI3	000562	5kg 5% 4W CARBON	MULLARD	CR25	2
RI4	000106	IOM 5% 1/4W CARBON	MULLARD	CR25	3
RIS	000106	IOM 5% 1/4W CARBON	MULLARD	CR2S	
RIG	000682	GK8 5% 4W CARBON	MULLARD	CR2S	1
RIT	019091	9k09 1% 1/8W 50ppm MF	HOLCO	HSC	_
Ris	012372	23k71% 1/8W 50ppm MF	HOLCO	H8C	_
R19	000273	27k 5% 1/4W CARBON	MULLARD	CR25	3
R2o	000273	27k 5% 1/4W CARBON	MULLARD	CR25	_
R21	000222	2k2 5% 1/4W CARBON	MULLARD	CR25	2
R22	013403	340K 1% 18 W 50 ppm MF	HOLCO	нвс	1
R23	000562	5k6 5% 1/4W CARBON	MULLARD	CR25	_
NOTES.	INSTRUMENT 4000	DC. ASSY RIO. 27. 48. 66. 89. 96 400445 090057/B- I	090058/8-1 090059/8-1	3.5.82 datron	ELECTRONICS LTD
E.C.O. RELEASED 13		400445A 090057/A- 5	090058/A-1 090059/A-1 DRAW CHECK APPRO	JACKSON. 4000A DO	
		6, 63 D	DATE		

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R24	000222	2k2 5% 1/4W CARBON	MULLARD	CR25	-
R25	041005	10M0 1% YEW 100 pm CF	ALLEN BRADLEY	CC	
R26	041005	10M0 1% 1/2W 100ppm CF	ALLEN BRADLEY	cc	
R27	SEE TABLE	IM MATCHED SET	MANN	SEE DRG-	_
R28		NOT USED	· · · · · · · · · · · · · · · · · · ·		
R29	050058	18M 1% 1 W 7K5V MF	HOLCO .	HBOIRE	
R30	000103	10k 5% VAW CARBON	MULLARD	CR25	
R3I	000103	lok 5% 1/4W CARBON	MULLARD	CR25	
R32	012378	23R7 1% 1/8W 50ppm MF	Holco	HBC	1
Raa	000272	2k7 5% 1/4W CARBON	MULLARD	CR25	2
R34	000272	2k7 5% '4W CARBON	MULLARD	CR25	
R35	000273	27k 5% 1/4W CARBON	MULLARD	CR25	
R36	012261	2k26 1% 1/8W 50ppm MF	HOLCO	нвс	2
R37	012261	2k26 1% 1/8W 5000 MF	HoLco	H8C	-
R38 .	000102	IK 5% 1/4W CARBON	MULLARD	CR2S	8
R39	000104	100k 5% 1/4W CARBON	MULLARD	CR25	3
R40	000228	2R2 5% 1/4W CARBON	MULLARD	₽ CR25	2
R41	050055	10ko -5% 1/8W 50//m MF	HoLco	Н8	4
R42	050055	10k0 .5% 1/8W 50ppm MF	HOLCO	Н8	_
R43	050055	10k0 -5% /8W 50pm MF	Horco	H8	
R44	050055	10k0 .5% 1/8W 50 m MF	HOLCO	н8	
R45	000101	100R 5% 4W CARBON	MULLARD	CR25	1
R46	041005	10M0 1% 1/2W 100 pm CF	ALLEN BRADLEY	cc	
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE		DR	18. 5.82 Oatro	DC PCB
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DATE				TE DRAWING 4004	45 SHEET 45A 3 OF

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R47	041005	10M0 1% 12W 100ppm CF	ALLEN BRADLEY	CC	_
R48	SEE TABLE	IM MATCHED SET	MANN	SEE DRG-	
R49		NOT USED			
R50		NOT USED			
RSI	000912	Ski 5% 1/4W CARBON	MULLARD	CR2S	1
R52	011502	15ko 1% 1/8W 50 pm MF	HOLCO	HSC	2
Rs3	019091	9k09 1% 1/8W 50 pm MF	HOLCO	HSC	_
R54	070148	90ko · 1% 10 pm ww	MANN	MX125	1
R55	070066	10k -1% 566m WW	MANN	MX125B	
Rs6	012748	27R4 1% 1/8W 50pm MF	HoLco	H8C	2
Rs7	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	
R58	011502	15k0 1% 1/8W 50hm MF	HOLCO	HBC	-
R59	019531	9k53 1% Yaw 5000m MF	HOLCO	HBC	. 1
R60	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	
RGI	000228	2R2 5% 1/4W CARBON	MULLARD	CR25	_
R62	012748	2784 1% Yaw 50pm MF	Holco	H9C	
R63	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	-
R64	041005	10MO 1% 1/2W 100 pm CF	ALLEN BRADLEY	cc	-
R65	041005	10MO 1% 1/2W 100 pm CF	ALLEN BRADLEY	cc	-
R66	SEE TABLE	IM MATCHED SET	MANN	SEE DRG-	_
R67		NOT USED			_
Res		NOT USED			_
R69		NOT USED			_

SEE SHEET 2 FOR LATEST ISSUE

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J.W. 1164 4000A DC PCB ASSY. 400445 | SH 400445A | 4 SHEET 4 OF 16 DATE

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R70		NOT USED			_
R71		NOT USED			_
R72		NOT USED		1	-
R73		NOT USED	,		_
R74	SEE TABLE	90k/10k	MANN	SEE DRG	1
R75 ·	SEE TABLE	IK/IIIRII	MANN	SEE DRG-	ı
R76		NOT USED			_
RTT	000102	Ik 5% VAW CARBON	MULLARD	CR25	_
R78	000473	47k 5% 1/4W CARBON	MULLARD	CR25	4
R79	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	_
R80	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	_
R81	011001	1400 1% 1/8W 500 MF	HOLCO	H8C	ı
R82	000393	39k 5% 1/4W CARBON	MULLARD	CR25	4
R83	011302	13k0 1% 18W 50 m MF	HOLCO	HSC	4
R84	011302	13k0 1% 1/8w 50ppm MF	HoLco	H8C	-
R85	000393	39k 5% 1/4W CARBON	MULLARD	CR25	_
R86	012 001	2k00 1% 1/8W 50ppm MF	MULLARD	CR25	4
R87	012001	2k00 1% 1/8W 50 m MF	MULLARD	CR25	-
R88	008040	20M 5% 2500Y MET-GLAZE	MULLARD	YR37	1
R89	SEE TABLE	IM MATCHED SET	MANN	SEE DRG	_
R90	-	NOT USED			
R9I		NOT USED			
R92	000183	18k 5% 1/4W CARBON	MULLARD	CR25	1
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE			DRAWN . TITLE 4000	A DC PCB
DATE				DRAWING 4004	145 SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R93	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	_
R94	000202	2k 5% 1/4W CARBON	MULLARD	CR25	1
R95	041825	18M2 1% 12W 100ppm CF	ALLEN BRADLEY	cc	1
R96	SEE TABLE	BOOK IOOK MATCHED SET	MANN	SEE DRG-	_
R97	000104	100k 5% 1/4W CARBON	MULLARD	CR25	_
R98	041824	IM82 1% 1/2W 100/pm CF	ALLEN BRADLEY	cc	1
R99		NOT USED			_
R100	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	_
RIOI	011003	100k 1% 1/8W 50hbm MF	HOLCO	нвс	3
R102	011003	100k 1% 1/8W 50ppm MF	HOLCO	H8C	_
R103	011003	100k 1% 1/8W 50ppm MF	HOLCO	H8C	_
R104	000473	47k 5% 1/4W CARBON	MULLARD	CR25	_
Rios	000393	39k 5% 1/4W CARBON	MULLARD	CR25	_
R106	000104	look 5% 1/4W CARBON	MULLARD	CR25	_
R107	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	-
RI08	012001	2k00 1% 1/8W 5066m MF	HOLCO	HSC	_
R109	011302	13k0 1% 18w 50/hm MF	HOLCO	H8C	-
RIIO	011302	13k0 1% 1/8W 506 MF	HOLCO	H8C	
RIII	012001	2k00 1% 18W 50 bbm MF	Holco	HSC	-
RIIZ	000473	47k 5% 1/4W CARBON	MULLARD	CR25	-
RII3	000103	lok 5% 1/4W CARBON	MULLARD	CR25	
RII4	000473	47k 5% 1/4W CARBON	MULLARD	CR25	_
Rns	000393	39k 5% 1/4 CARBON	MULLARD	CR25	_
RII3 RII4 RII5 NOTES. SEE SHEET 2 FOR LAT	000473	47k 5% 1/4W CARBON	MULLARD	CR25 CR25 18.5.82	

DRAWING 400445 NUMBER 400445A

.W. 1164

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RII6	000106	IOM 5% 1/4W CARBON	MULLARD	CR25	-
R117	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	_
RII8	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	_
RII9	000512	5ki 5% 4W CARBON	MULLARD	CR25	2
R120	000512	5kl 5% 4W CARBON	MULLARD	CR25	-
RIZI	000152	IKS 5% YAW CARBON	MULLARD	CR25	2
R122	000152	IK5 5% YAW CARBON	MULLARD	CR25	-
ANI AN2	090096	IM × 8 2% NETWORK	A B	850-9I- IM 850-83- IOOR	1
7		100.11.7 478		1000	
CI	104026	47AF -80% 50V CER DISC	SIEMENS	B37449	15
CZ	104026	470F -20% 50V CER DISC		B37449	_
C3	104 026	470F -20% 50V CER DISC		B37449	_
C4	104026	470F -20% SOV CER DISC		B37449	_
C5	104026	47nF -20% 50V CER DISC	SIEMENS	B37449	_
C 6	180021	3u3F G3V AL. ELECT	MULLARD	015- 18338	2
C7	180021	3 على AL. ELECT	MULLARD	015-18338	_
C8	104026	470F -20 % SON CER DISC	SIEMENS	B37449	_
C9	104026	47.F -20 % 50V CER DISC	SIEMENS	B37449	_
NOTES. SEE SHEET 2 FOR L ISS. E.C.O.	ATEST ISSUE		D	RAWN TITLE 4000 I	C PCB
DATE CHKD.				ATE DRAWING 40044	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
CIO	110007	3,3F 20% 100V POLYESTER	WIMA	MKS	1
CII	150016	JUF 20% 35V DIP TANT	UNION CARBIDE	KIROE35	5
CIZ	150016	INF 20% 35V DIP TANT	UNION CARBIDE	KIROE35	-
CI3	104026	47 of -20% SOV CER DISC	SIEMENS	B37449	_
C14	104026	47nF -20 % 50V CER DISC	SIEMENS	637449	_
C15	104026	47nf -20% 50V CER DISC	SIEMENS	537449	_
C16	110035	220 F 20% 63V POLYESTER	WIMA	MKS2	3
C17	104026	470F -20 % 50V CER DISC	SIEMENS	B37449	-
C18	104026	47nF +50 % 50V CER DISC	SIEMENS	B37449	-
CI9	104026	47nF 150% SOV CER DISC	SIEMENS .	B37449	_
C20	150020	10 UF 20% 25V DIP TANT	UNION CARBIDE	K10E25	2
C21	150020	IONE 20% 25V DIP TANT	UNION CARBIDE	KIOE35	_
C22	150016	اسل 20% 35V DIP TANT	UNION CARBIDE	KIROE35	-
C23	104026	47.F -20 % 50V CER DISC	SIEMENS	B37449	_
C24	104 026	47aF -20 % SOV CER DISC	SIEMENS	837449	
C25	120019	INF 10% 63V POLYCARS	ASHCROFT	A2B1021B	
C26	110041	IONF 20% IOOV POLYESTER	WIMA	FKS2	1
C27	110042	100 AF 20% 65V POLYESTER	WIMA	MKS2	7
C28	150016	JUF 20% 35V DIP TANT	UNION CARBIDE	KIROE35	_
C29	150002	100F 20% IGV DIP TANT	UNION CARBIDE	KIOE 16	2
C30	150002	IONF 20% IN DIP TANT	UNION CARBIDE	KIOEIG	_
C31	110035	220 F 20% 63V POLYESTER	WIMA	MKS2	~
C32	110042	100nF 20% G3V POLYESTER	WIMA	MKS2.	_
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE		DATE 18	s.s.82 datron	
ISS.			CHECKE	1000 ASS	C PCB
DATE CHKD.			APPROVI	DRAWING 40044	5 SHEET
CHKU.				400 44	3/1 2 or 16

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
C33	140003	47.F 10% 400V POLYPRO	WIMA	MKPIO	1
C34	110039	470AF 20% 63V POLYESTER	WIMA	MKS2	4
C35	110039	470 NF 20% 63V POLYESTER	WIMA	MKS	_
C36	110039	470 F 20% 63V POLYESTER	WIMA	MKS2	_
C37	110039	470 AF 20% GBV POLYESTER	WIMA	MKS	_
C38	110040	33nF 20% 63V POLYESTER	WIMA	MKS2	1
C 3 9	110042	100 nF 20% 63V POLYESTER	WIMA	MK52	_
C40	110042	100nF 20% 63V POLYESTER	WIMA	MKS2	_
C41	110042	IOONF 20% GBV POLYESTE	WIMA	MKS2	_
C42	102101	100 F 10% 500V CER DISC	ודד	CDIO	I
C43	150016	JUF 20% 35V DIP TAN	UNION CARBIDE	KIROE35	_
C44	110035	220nF 20% 63V POLYESTER	WIMA	MKS2	
C45	120015	470 F 20% 100V POLYCARE		FKC2MIN	1
c46	104031	202F -20% ZKV CER DIS	CITT	HDI6	2
C47	104 031	202F 140 % 2kV CER DISC	ITT	HDIG	_
C48	104 032	220 F 10% ZKV CER DISC	ITT	HD09	1
C49	110042	100nf 20% G3V POLYESTER	WIMA	MK52	
C50	110042	IOONF 20% G3V POLYESTE	WIMA	MK52	_
C51	105551	220 DF 10% 500V CER DISC	ITT	CDIO	2
C52	102221	220 F 10% 500V CER DIS	ITT	CDIO	_
NOTES.	ATEST ISSUE				ELECTRONICS LTD
ISS.	1000			CHECKED 400	OA DC PCB
E.C.O.				APPROVED	ASSY.
DATE CHKD.				DATE DRAWING 4-0	0445 0445A 9 OF 16

	-			1	1
DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S	No. USED Per Assy.
DI	200002	IA SOV GP SI DIODE	FAIRCHILD	IN400I	9
DS	210027	2V7 400mW ZENER	MULLARD	BZY88C2V7	3
D3	213009	ISV SW ZENER	UNITRODE	TVS 5IS	4
D4	213009	ISV SW ZENER	UNITRODE	TVS5IS	_
D5	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	9
D6	200001	75mA 75V GPSI DIODE	FAIRCHILD	IN4148	_
D7	214012	2V45 30bbm ZENER	FERRANTI	ZN458	3
D8	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	_
D9	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	
Dio	220020	FET DIODE 1006A IR	TELEDYNE	PADIOO/INSULATED CASE	6
DII	214012	2V45 30bm ZENER	FERRANTI	ZN458	-
DI2	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	-
DI3	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	_
D14	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	
Dis	200001	75m A 75V GP Si DIODE	FAIRCHILD	IN4148	_
DIG	220020	FET DIODE 1006A IR	TELEDYNE	PADIOO/INSULATED CASE	-
DI7	213009	ISV SW ZENER	UNITRODE	TVS5IS	_
D18	213009	ISV SW ZENER	UNITRODE	TVS5IS	_
DIS	213006	SV 5W ZENER	UNITRODE	TVs 505	4
D \$ 0	213006	5V 5W ZENER	UNITRODE	TVS 505	_
DSI	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	-
D22	210033	3V3 400mW ZENER	MULLARD	8ZY88C3V3	1
D23	213008	24V 5W ZENER	UNITRODE	TVS 524	4
NOTES. SEE SHEET 2 FOR LA ISS. E.C.O.	TEST ISSUE			18.5.82	C PCB
DATE CHKD.				DRAWING NUMBER 400445	SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACT PART No.	TURER'S	No. USED Per Assy.
D24	213008	24V SW ZENER	UNITRODE	TVS 524	-	_
D25	214012	2V45 30pm ZENER	FERRANTI	ZN458		_
D26	213008	24V SW ZENER	UNITRODE	TVS 524		
D27	213008	24V SW ZENER	UNITRODE	TVS 524		_
D28	210027	2V7 400mW ZENER	MULLARD	8ZY880	2V7	~
D29	210027	2V7 400mW ZENER	MULLARD	8ZY88 C	2V7	_
D3O	200002	IA SOV GP SI DIODE	FAIRCHILD	IN4001		_
D3I	200002	IA SOV GP SI DIODE	FAIRCHILD	1N4001		
D32	213006	5V 5W ZENER	UNITRODE	TVS 505		-
D33	213006	5V SW ZENER	UNITRODE	TVS 505		-
D34	220020	FET DIODE 1006A IR	TELEDYNE	PADIOO/	INSULATED CASE	_
D35	220020	FET DIODE 1000A IR	TELEDYNE	PADIOO/	INSULATED CASE	-
D3G	214014	IVER 1000 ZENER	TELEDYNE	94918	ī	4
D37	214014	1A55 100 Hw	TELEDYNE	949183		-
D38	200002	IA SOV GP SI DIODE	FAIRCHILD	IN400I		-
D39	200002	IA SOV GP SI DIODE	FAIRCHILD	IN4001		_
D40	200002	1A SOV GP SI DIODE	FAIRCHILD	IN4001		-
D41	200002	IA SOV GP SI DIODE	FAIRCHILD	* IN4001		_
D42	200002	IA SOV GP SI DIODE	FAIRCHILD	IN4001		_
D43	200002	IA SOV GP SI DIODE	FAIRCHILD	1N4001		_
D44	210062	GV2 400mW ZENER	MULLARD	BZY88C	6V2	2
D45	210062	GVZ 400 mW ZENER	MULLARD	BZY88C	6V2	-
D46	220020	FET DIODE 1006A IR	TELEDYNE	PADIOO/	INSULATED CASE	~
NOTES. SEE SHEET 2 FOR L.	ATEST ISSUE			18.5.82 DRAWN .	datron	
ISS.	4			CHECKED	4000A D ASSEM	
DATE				APPROVED DATE	DRAWING 40044	S SHEET
CHKD.		1		1	40044	5A 11 OF 1

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
D47	220020	FET DIODE 100 A IR	TELEDYNE	PADIOO/INSULATED CAS	
D48	200008	200mA 125V LL SI DIODE	FAIRCHILD	IN458A	2
D49	200008	200 mA 125V LL SI DIODE	FAIRCHILD	IN458A	_
D50	214014	IV22 100 pm ZENER	TELEDYNE	9491BJ	_
D51	214014	IV22 100 pm ZENER	TELEDYNE	9491 BJ	_
				4	
				**	
QI	250004	SI PNP TRANSISTOR	NATIONAL	2N3906 / TO 92	1
Q2	230036	N-CHAN JEET	SILICONIX	J108	ı
Q3	230042	N-CHAN CURRENT LIM	TELEDYNE	TCR510	1
Q 4	250013	SI PHP TRANSISTOR	NATIONAL	BD136	1
Q5	240021	SI NPN TRANSISTOR	NATIONAL	BD135	1
P6	230031	N-CHAN DUAL JEET	TELEDYNE	SU2656M	2
Q 7	250025	SI PNP TRANSISTOR	MOTOROLA	MJE350	1
ଦଃ	230001	N-CHAN CURRENT LIM.	TELEDYNE	TCR 506	2
ଦ୍ର	230001	N-CHAN CURRENT LIM	TELEDYNE	TCR506	
Qıo	240018	SI NPN TRANSISTOR	MOTOROLA	MJE340	1
QII	230031	N-CHAN DUAL JEET	TELEDYNE	SU2G56M	
NOTES. SEE SHEET 2 FOR LA	TEST ISSUE			DELAWAL #1	DC PCB
E.C.O.				AS:	DC PCB
DATE				DRAWING NUMBER 4004	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
-					
MI	290090	7× DARLINGTON DRIVER	SPRAGUE / EXAR	ULN2002A/xR22020	P 2
M2	290090	7× DARLINGTON DRIVER	SPRAGUE/ EXAR	ULN2002A/XR2202C	
M3	280079	QUAD 2 I/P OR GATE	MOTOROLA	MC 14071 BCP	1
M4	280090	DUAL BINARY TO JOE4 DECOM	MOTOROLA	MC14555BCP	1
M5	280045	TRIPLE 3 I/P NOR GATE	MOTOROLA	MC140258CP	1
M6	280085	QUAD 2 I/P AND GATE	MOTOROLA	MC 14081 BCP	
M7	280009	HEX INVERTER	MOTOROLA	MC14049BCP	1
Ma	260039	324 QUAD OP AMP	NATIONAL	LM324N	1
M9	260050	412 DUAL FET I/P OP AMP	NATIONAL	LF4I2N	2
Mio	260050	412 DUAL FET I/P OP AMP	NATIONAL	LF412N	_
Mii	260057	5534 OP AMP	SIGNETICS	NE 5534N	1
SIM	260042	5532 DUAL OP AMP	SIGNETICS	NE5532N	1
Mis	260069	411 OP AMP	NATIONAL	LF411CH	1
MI4	260043	358 DUAL OP AMP	NATIONAL	LM358N	ı
MI5	260059	OOO2 BUFFER AMP	NATIONAL	LHOOOZCH	1
MI6	260053	7650 OP AMP	INTERSIL	ICL7650 CPD	2
Mı7	260027	714 OP AMP	FAIRCHILD	MA 714 HC	3
MI8	260027	714 OP AMP	FAIRCHILD	иА714 HC	
Mıs	260027	714 OP AMP	FAIRCHILD	μΑ 714 HC	_
M20	260053	7650 OP AMP	INTERSIL	ICL7650 CPD	_
NOTES. SEE SHEET 2 FOR L.	ATEST ISSUE				T ELECTRONICS LTD DC PCB SY
DATE				DRAWING 4004	
СНКО.				DATE NUMBER 4004	

DESIGNATOR	DATRON	DESCRIPTION	PRINCIPAL	MANUFACTURER'S	No. USED
	PART No.		MANUFACTURER	PART No.	Per Assy.
RLI	330018	RELAY 2P2W SV HOLD-IN	AMF	SEE DRG-	9
RLZ	330018	RELAY 2P2W SV HOLD-IN	AMF	SEE DRG-	_
RL3	330019	RELAY 4P2W SV HOLD-IN	AMF	SEE DRG-	6
RL4	330018	RELAY SPZW 5V HOLD - IN	AMF	SEE DRG-	<u> </u>
RL5	330018	RELAY 2PZW SV HOLD-IN	AMF '	SEE DRG-	
RL6	330018	RELAY SPEW 5V HOLD-IN	AMF	SEE DRG	_
RL7	330019	RELAY 4P2W SV HOLD-IN	AMF	SEE DRG	_
RL8	330019	RELAY 4P2W 5V HOLD-IN	AMF	SEE DRG-	-
RL9	330019	RELAY 4PZW SV HOLD-IN	AMF	SEE DRG	_
RLIO	330018	RELAY 2P2W 5V HOLD- IN	AMF	SEE DRG-	-
RLII	330018	RELAY SPZW SV HOLD-IN	AMF	SEE DRG	_
RLIZ	330018	RELAY 2PZW 5V HOLD-IN	AMF	SEE DRG	-
RL13	330019	RELAY 4PZW SV HOLD-IN	AMF	SEE DRG	-
RL14	330019	RELAY 4P2W 5V HOLD-IN	AMF	SEE DRG	_
RLIS	330018	RELAY 2P2W 5V HOLD-IN	AMF	SEE DRG-	-
LI- L6	370001	10/4H 0.85 & RF CHOKE	PLESSEY	58/10/0011/10	6
		,			
			}		
NOTES. SEE SHEET 2 FOR LA	TEST ISSUE		DRAWN	3.5.82 datron	
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DATE CHKD.			APPRO' DATE	DRAWING 40044 NUMBER 40044	5 SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
FI	920120	IA PICOFUSE	LITTLE FUSE	275 001	6
F2	920120	IA PICOFUSE	LITTLE FUSE	275 001	
F3	920120	IA PICOFUSE	LITTLEFUSE	275 001	
F4	920120	IA PICOFUSE	LITTLEFUSE	275 001	_
F5	920120	IA PICOFUSE	LITTLE FUSE	275 001	– ,
F6	920120	IA PICOFUGE	LITTLE FUSE	275 001	_
	410159-6	РСВ		SEE DRG-	ı
	459112- 2	RELAY BRACKET		SEE DRG	15
	540002	22 SWG TINNED CU WIRE			A/R
	590001	SLEEVE MAX CABLE \$ 3.0	HELLERMANN ELECTRIC	HIS Y 20mm BLK. HELSYN	91
	540008	7/0.2 PTFE INSULATED WIRE		IKV ms To BS G210 TYPE C	2770 mm
	590004	SLEEVE - PTFE	HELLERMANN ELECTRIC	FEIO	A/R
	605059/A	8 WAY DIL SOCKET			7
	605060/A	14 WAY DIL SOCKET			6
	605061/A	IG WAY DIL SOCKET		8	4
	611016	SCREW M3×8mm STEEL POZIPA	N ZINC PLATED G-KN		15
	615002	NUT M3 FULL HEX STEEL	ZINC PLATED GKN		15
	613005	WASHER M3 SHAKEPROOF STEE	ZINC PLATED GKN		15
	615005	NUT 3-48 UNC FULL HEX STEE	ZINC PLATED		15
	618004	TRANSISTOR MTG PAD FOR TOIS	JERMYN	TOI8- 008D	5
NOTES.		3		3.5.82 datron	ELECTRONICS LTD
ISS.	ATEST ISSUE		DRAW CHECK	4000 A SS	
E.C.O.			APPRO	DRAWING 4-0044	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	620003	SOLDER PIN TERM! LUG	HARWIN	H2105A	56
	630024	STEATITE BEAD 16 SWG	PARK ROYAL PORCELAIN	Nº 2	34
	630036	STEATITE BEAD 18 SWG	PARK ROYAL PORCELAIN	Nº I	30
	630119	CCT BOARD EJECTOR	RICHCO	CBE ORANGE	2
	630132	POLYAMIDE TAPE	3M	5413	A/R
	620007	TEST POINT TERMINAL	MICROVAR	C 30	12
	613014	WASHER M2-S SHAKEPROOF	STEEL ZN.PLATED GKN		15
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ISS.	ATEST ISSUE		DRAWN	4000 AS	C PCB
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DESIGNATOR	DATRON PART No.		DESC	RIPTION			PRINCIPAL MANUFACTURER		MANUFACT PART No.	URER'S	No. USED Per Assy.
RI	NOT U	SED									
R2	00082	0	82	R 5%	1/4 W	CARBON	MULLARD		CR25		
R3	00082	l	82	DR 5%	1/4 W	CARBON	MULLARD		CR25		1
R4	000827	?	8 K	2 5%	14w	CARBON	MULLARD		CR25		1
R5	008001	2	48	<u> 5%</u>	2/2W	WIRE WOUN	WELWYN		W21		1
RG	000103		101	5%	1/4W	CARBON	MULLARD		CR25		3
R7	000103	•	IOK	5%	44 W	CAR BON	MULLARD		CR25		_
RB	080019	-3	35 6	000	0.1%	M FOIL	VISHAY		SEE DRO	i	1
R9	080020) - 3	500	RO	0.1%	M FOIL	VISHAY		SEE DRO).	1
RIO	080 021	- 3	⊃K(000	0.1%	M FOIL	VISHAY		SEE DRG	l	1
RII	000101		100	R 5%	V4W	CARBON	MULLARD		CR25		8
R12	000101		100	R 5%	14W	CARBON	MULLARD		CR 25		-
RI3	000393	5	39	K 5%	14w	CARBON	MULLARD		CR25	<u> </u>	2
RI4	000473	<u> </u>	47	K 5%	1/4 W	CARBON	MULLARD	<u> </u>	CR25		4
RI5	000473		471	< 5%	14 W	CARBON	MULLARD	··-	CR25		_
RIG	000472	•	471	< 5%	74 W	CARBON	MULLARD		CR25		
RI7	000473)	471	< 5%	14 W	CARBON	MULLARD		CR25		-
RIB	012001		2K	00 1%	1/8 W	50ppm MF	HOLCO		HBC		2
RID	012001		2K	00 1%	YB W	50pm MF	HOLCO		HBC		_
R20	011302	-	13K	0 1%	18 W	50ppm MF	HOLCO		нвс		2
R2I	011 302		13K	0 1%	18 W	50 рен МЕ	HOLCO		нас		-
K25	000 393)	391	< 5%		CARBON	MULLARD		CR25		-
R23	067202		2K	POT 2	OTURN	LERMET	BECKMAN		GBX		1
NOTES. SEE SHEET 2 FOR LA	TEST ISSUE							DATE 3	.5.83	datron	ELECTRONICS LTD
	2 3	4	5	6	7			CHEF	10		SSEMBLY.
DATE \$ 10. \$2. 15. CHKD.	4,36 1450 12-63 17-2-85 0 AO	9.5.83 MD	7.6,83	1529 15.9.83	1537 29.9.8	3		APPRO\	.0,87	DRAWING NUMBER 400448	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R24	000101	100R 5% 1/4W CARBON	MULLARD	CR25	
R25	000101	IDOR 5% YAW CARBON	MULLARD	CR25	_
RZG	011001	1KOO 1% YOW SOPPIN MF	HOLCO	HBC	2
R27	012670	267R 1% YOW 50ppm MF	HOLCO	нвс	1
K28	011001	1KOO 1% 1/8W 50ppm MF	HOLCO	HBC	_
R 25	000101	IOOR 5% 1/4W CARBON	MULLARD	CR25	-
R30	000101	IOOR 5% 1/4W CARBON	MULLARD	CR25	_
RSI	NOT USED				
R32	000472	4K7 5% 1/4W CARBON	MULLARD	CR25	
R33	000103	IOK 5% 1/4W CARBON	MULLARD	CR25	-
R34	000102	IKO 5% 1/4W CARBON	MULLARD	CR25	3
R35	000102	IKO 5% 1/4 W CARBON	MULLARD	CR25	
R36	NOT USED		-		
R37	000101	100R 5% 14 W CARBON	MULLARD	CR25	-
R 38	000101	100R 5% V4W CARBON	MULLARD	CR25	-
R 30	013401	3K40 1% 1/8 W 50pp=MF	HOLCO	нвс	1
R 40	012002	20KO 1% V8 W 50pp an MF	HOLCO	нвс	1
R41	000104	IOOK 5% 1/4 W CARBON	MULLARD	CR75	i
R 42		NOT USED			
R 43	030065 - 2	IOKOOO RESISTOR SET.		SEE DRG.	1 SET
R 44	1	90KOO RESISTOR SET.		SEE DRG.	J
R45	NOT USED				_
R46	NOT USED				
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE			8.5.83 datron	
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DATE CHKD.			DATE	DRAWING	3 4 SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R47	NOT USED				
R48	NOT USED				
R49	000100	IOR 5% 1/4 W CARBON	MULLARD	CR25	2
R50	000100	IOR 5% 1/4 W CARBON	MULLARD	CR25	-
R51	000105	IM 5% YAW CARBON	MULLARD	CR25	1
R52	000153	15K 5% 1/4W CARBON	MULLARD	CR25	1
R53	067201	200R POT 20TURN CERMET	BECKMAN	GBX	1
R54	067 502	5K POT ZOTURN CERMET	BECKMAN	GBX	1
R55	067 503	SOK POT ZOTURN CERMET	BECKMAN	68X	1
R56	067 504	500K POT POTURN CERMET	BECKMAN	GBX	1
R57	067 205	2M POT 20TURN CERMET	BECKMAN	GBX	1
R58	001100	IOR POT ZOTURN CERMET	BECKMAN	G8X	1
R 59	201000	IK 5% 1/4W CARBON	MULLARD	CR25	-
R60	041 585	15MB 1% YZW 100 pp mCF.	ALLEN BRADLEY	cc	1
R61	.011508	15 RO 1% Yaw 500 MF	HOLCO	HBC	1 1
R62	070134 - 3	99K980 50ppm Wille WoonD	MANN	SEE DRG.	. 1
RG3	070133 - 3	IOKOOGO SOPPIN WIREWAUND	MANN	SEE DRG.	l l
R64	070132-3	1K00040 50ggm WIREWOUND		SEE DRG.	1
R65	070131 - 3	100R040 50 as WIREWOUND		SEE DRG.	1
R66	012263	226K 1% 1/8W 50mm MF	HOLCO	нвс	1
R67		NOT USED			
R68	042264	2M26 1% 1/2W 10000 CF	ALLEN BRADLEY	cc	ł
R69	011581	1K58 1% /8W 50ggm MF		HBC	1
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E.C.O.	- '		DATE	DRAWING NUMBER 40044	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R70	012262	22KG 1% 1/8W 50ppm MF	HOLCO	H&C.	1
R71	070129 - 3	IROOOGO SOPE IN WIREWOUND	MANN	SEE DRG.	1
R72	070130 - 3	IOROO4O 50ppm Wire WOUND	MANN	SEE DRG.	
R73	070136 -3	9M9940 50ppm WIREWOUND	MANN	SEE DRG.	1
R74	070135 -3.	999K7D 50pm WIREWOUND	MANN	SEE DRG.	1
R15	014991	4K99 1% 1/8W 50pm MF	HOLCO	HBC.	1
R76	012000	200R 1% 1/8W 50ppm MF	HOLCO	HBC.	1 .
R 77	064201	200R POT ISTURN CERMET		85 P	1
K 78	064202	2K POT ISTURN CERMET	BECKMAN	89 P	1
R 79	060023-3	5R000	VISHAY	SEE DRG	1
R BO	400510	ORIDO SHUNT ASSY	DATRON	SEEDEG	1
R6I	000222	2KZ 5% 4W CARBON	MULLARD	CR 25	1
				b.	
ANI	030036	IM XB 2% NETWORK	A B	850-91-1M	2
AN2	090085	12KXB 2% NETWORK	A B	761 - 3 - 12K	
AN3	050056	IMXB 2% NETWORK	AS	850 - 91 - IM	-
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No. USED DESIGNATOR DATRON DESCRIPTION PRINCIPAL MANUFACTURER'S MANUFACTURER PART No. Per Assy. 47 AF - 10% SOV CER DISC SIEMENS 657449 C24 104026 104026 47 AF - 10% SOV CER DISC 637449 C 25 SIEMENS 150020 IQUE 20% 25V DIP TANT UNION CARBIDE KIOE 26 C 26 104026 47nf 18% 50V CER DISC SIEMENS B37449 C 27 C 28 15 00 20 IONE 20% 25V DIP TANT UNION CARBIDE KIOE 25 242F 20% IGY DIP TANT UNION CARBIDE 2 C 29 150005 K2R2EIG ZHZF 20% IGV DIP TANT KZRZEIG C 30 150005 UNION CARBIDE IDPF 5% 500V CER DISC ITT CD10 2 C 31 102100 C 32 LAF 20% 35V DIP TANT UNION CARBIDE KIROE \$5 150016 47nf -20% SON CER DISC SIEMENS B37445 C 33 104026 47mF 180% SOY CER DISC SIEMENS 637449 C 34 104026 47mF 18% 50V CER DISC SIEMENS 637449 七35 104026 2 224F 20% 25V DIP TANT UNION CARBIDE K22E25 150021 C 36 22MF 20% 25V DIP TANT UNION CARBIDE K22E25 C 37 1500.21 47nF 18% SOV CER DISC SIEMENS 637449 104026 C 38 47nF 150% 50V CER DISC SIEMENS C 39 104026 B57449 C 40 NOT USED 1 nF 20% 400VAC POLY PROP WIMA FKPL 2 C 41 140054 I AF 20% 400V AC POLY PROP FKPI C 42 140054 100 pf 10% 500V CER DISC ITT CDIO ł C 43 101301 10pf 5% 500V CERDISC ITT C 44 102100 CDIO 150022 2µ2F 20% 35V DIP TANT UNION CARBIDE **K2R2E35** ı C45 NOTES datron ELECTRONICS LTD 3.5.83 SEE SHEET 2 FOR LATEST ISSUE DR 4WN 4000 CHECKED

 I/Ω PCB ASSEMBLY.

8 of 15

DRAWING NUMBER 400448

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DATE

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
DI	200002	IA SOV GP SI DIODE	FAIRCHILD	IN 4001	
02	210027	2V7 400mW ZENER	MULLARD	52Y88C2V7	1
03	210056	5VG 400mW ZENER	MULLARD	BZY88C5V6	2
04	210056	546 400mW ZENER	MULLARD	5ZY88C5V6	
D5	213012	2VO 250 W ZENER	MULLARD	5ZY4G - 2YO	1
DG	210033	3V3 400mW ZENER	MULLARD	82Y86C3V3	1
٥7	213009	157 SW ZENER	UNITRODE	TV5 515.	4
84	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4MB	3
09	200001	75MA 75V GP SI DIODE	FAIRCHILD	IN4I48	-
010	200001	75 MA 75V GP SI DIODE	FAIRCHILD	IN4I48	-
DII	213009	154 5W ZENER	UNITRODE	TV5515	-
DIS	213009	15V SW ZENER	UNITRODE	TV55/5	-
013	213009	15V SW ZENER	UNITRODE	TV5515	-
DI4	NOT USED.		•		
DIS	NOT USED.				
DIG	2000 22	3A 400V GP SI DIODE	MOTOROLA	BY252	2
דום	200022	3A 400V GP 51 DIODE	MOTOROLA	BY252	-
DIS	213006	SY SW ZENER	UNITRODE	TV5505	2
NOTES.			DAT	5. 83 datro r	1'
SEE SHEET 2 FOR L	ATEST ISSUE				
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QI (1) (2) (2) (2) (3) (4) (5) (6) (7) (7) (7) (7) (7) (7) (7) (7) (7) (7	250004 230001 250004 230001 240006 230031 250004 230042	SI PNP TRANSISTOR N. CHAN I LIM I. 4 A SI PNP TRANSISTOR N. CHAN I LIM I. 4 A SI NPN TRANSISTOR N. CHAN DUAL J FET SI PNP TRANSISTOR	NATIONAL TELE DYNE NATIONAL TELE DYNE NATIONAL TELE DYNE NATIONAL TELEDYNE NATIONAL	TCR 500 2N350 TCR 500 2N3500 502656	6 / 1092 6 6 / 1092 6 4 / 1092 6 M.	3 3 3 1
Q2 Q3 Q4 Q5 Q6 Q7 Q8 Q9 Q9 Q10	230001 250004 230001 240006 230031 250004 230042	N. CHAN I LIM I. T.MA SI PNP TRANSISTOR N. CHAN I LIM I. T.MA SI NPN TRANSISTOR N. CHAN DUAL J FET SI PNP TRANSISTOR	TELE DYNE NATIONAL TELE DYNE NATIONAL TELEDYNE	TCR 500 2N350 TCR 500 2N3500 502656	6 6 / TO92 6 4 / TO92 6 M.	3 - 3
Q2 Q3 Q4 Q5 Q6 Q7 Q8 Q9 Q9 Q10	230001 250004 230001 240006 230031 250004 230042	N. CHAN I LIM I. T.MA SI PNP TRANSISTOR N. CHAN I LIM I. T.MA SI NPN TRANSISTOR N. CHAN DUAL J FET SI PNP TRANSISTOR	TELE DYNE NATIONAL TELE DYNE NATIONAL TELEDYNE	TCR 500 2N350 TCR 500 2N3500 502656	6 6 / TO92 6 4 / TO92 6 M.	3 - 3
Q? 1 Q3 2 Q4 1 Q5 1 Q6 1 Q7 1 Q8 2 Q9 2 Q1O 2	230001 250004 230001 240006 230031 250004 230042	N. CHAN I LIM I. T.MA SI PNP TRANSISTOR N. CHAN I LIM I. T.MA SI NPN TRANSISTOR N. CHAN DUAL J FET SI PNP TRANSISTOR	TELE DYNE NATIONAL TELE DYNE NATIONAL TELEDYNE	TCR 500 2N350 TCR 500 2N3500 502656	6 6 / TO92 6 4 / TO92 6 M.	3 - 3
Q2 Q3 Q4 Q5 Q6 Q7 Q8 Q9 Q9 Q10	230001 250004 230001 240006 230031 250004 230042	N. CHAN I LIM I. T.MA SI PNP TRANSISTOR N. CHAN I LIM I. T.MA SI NPN TRANSISTOR N. CHAN DUAL J FET SI PNP TRANSISTOR	TELE DYNE NATIONAL TELE DYNE NATIONAL TELEDYNE	TCR 500 2N350 TCR 500 2N3500 502656	6 6 / TO92 6 4 / TO92 6 M.	3 - 3
Q2 Q3 Q4 Q5 Q6 Q7 Q8 Q9 Q9 Q10	230001 250004 230001 240006 230031 250004 230042	N. CHAN I LIM I. T.MA SI PNP TRANSISTOR N. CHAN I LIM I. T.MA SI NPN TRANSISTOR N. CHAN DUAL J FET SI PNP TRANSISTOR	TELE DYNE NATIONAL TELE DYNE NATIONAL TELEDYNE	TCR 500 2N350 TCR 500 2N3500 502656	6 6 / TO92 6 4 / TO92 6 M.	3 - 3
Q2 Q3 Q4 Q5 Q6 Q7 Q8 Q9 Q9 Q10	230001 250004 230001 240006 230031 250004 230042	N. CHAN I LIM I. T.MA SI PNP TRANSISTOR N. CHAN I LIM I. T.MA SI NPN TRANSISTOR N. CHAN DUAL J FET SI PNP TRANSISTOR	TELE DYNE NATIONAL TELE DYNE NATIONAL TELEDYNE	TCR 500 2N350 TCR 500 2N3500 502656	6 6 / TO92 6 4 / TO92 6 M.	3 - 3
Q? Q3 Q4 Q5 Q6 Q6 Q7 Q7 Q8 Q8 Q9	230001 250004 230001 240006 230031 250004 230042	N. CHAN I LIM I. T.MA SI PNP TRANSISTOR N. CHAN I LIM I. T.MA SI NPN TRANSISTOR N. CHAN DUAL J FET SI PNP TRANSISTOR	TELE DYNE NATIONAL TELE DYNE NATIONAL TELEDYNE	TCR 500 2N350 TCR 500 2N3500 502656	6 6 / TO92 6 4 / TO92 6 M.	3 - 3
Q2 Q3 Q4 Q5 Q6 Q7 Q8 Q9 Q9 Q10	230001 250004 230001 240006 230031 250004 230042	N. CHAN I LIM I. T.MA SI PNP TRANSISTOR N. CHAN I LIM I. T.MA SI NPN TRANSISTOR N. CHAN DUAL J FET SI PNP TRANSISTOR	TELE DYNE NATIONAL TELE DYNE NATIONAL TELEDYNE	TCR 500 2N350 TCR 500 2N3500 502656	6 6 / TO92 6 4 / TO92 6 M.	3 - 3
Q3 (2 Q4 (2 Q5 (2 Q6 (2 Q7 (2 Q8 (2 Q9 (2 Q9) (2 Q9	250004 23000 ! 240006 23005 ! 250004 230042	SI PNP TRANSISTOR N'CHAN I LIM I'4 MA SI NPN TRANSISTOR N'CHAN DUAL J FET SI PNP TRANSISTOR	NATIONAL TELE DYNE NATIONAL TELEDYNE	2N3D0 TCR50 2N3D04 5U2G56	6 / TO32 6 4 / TO32 5 M.	3
Q4 7 Q5 7 Q6 7 Q7 7 Q8 8 Q9 8	23000 240006 23003 250004 230042	N-CHAN I LIM 1.4 mA SI NPN TRANSISTOR N-CHAN DUAL J FET SI PNP TRANSISTOR	TELE DYNE NATIONAL TELEDYNE	TCR 500 2N3304 502656	6 4 / 1092 5 M.	3
Q5 (2) (2) (3) (4) (4) (4) (4) (4) (4) (4) (4) (4) (4	240006 230031 250004 230042	SI NPN TRANSISTOR N-CHAN DUAL J FET SI PNP TRANSISTOR	NATIONAL TELEDYNE	2N3504 502656	4 / TO92 M.	3
Q6 7 Q7 2 Q8 2 Q9 2 Q1O 2	250051 250004 230042	N- CHAN DUAL J FET SI PNP TRANSISTOR	TELEDYNE	502656	м.	
Q.7 2 Q.8 2 Q.9 2 Q.IO 2	250004 230042	SI PNP TRANSISTOR	Ť ·			1
GB 2 여연 2 여인 2	230042		NATIONAL		/	i _
Q9 2 Q1O 2			TALLICANE	2N3300	7 1092	
Q10 2		N- CHAN I LIM 3.0 MA	TELEDYNE	TERSIC		ı
	230001	N-CHAN I LIM 1-4-A	TELEDYNE	TCRSO	<u> </u>	_
Olf 2	240006	SI NPN TRANSISTOR	NATIONAL	20390	4 / 1052	_
	240006	SI NPN TRANSISTOR	NATIONAL	213904	4 / TO92	-
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DATE				DATE	DRAWING NUMBER 4004	1 4

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
MI	260027	714 OP AMP	FAIRCHILD	MATIA HC	3
M2	NOT USED				
м3	260053	7650 OP AMP	INTERSIL	ICL7650 CPD	1
PM	260027	7H OP AMP	FAIRCHILD	MATIA HC	_
M5	280023	QUAD 2 VP NOR	MOTOROLA	MCHOO! UBCP	3
мб	280090	DUAL BINARY DECODER	MOTOROLA	MC14555 BCP	- 1
M7	260027	714 OP AMP	FAIRCHILD	MA 714 HC	-
MB	NOT USED				
CM	280023	QUAD 2 I/P NOR	MOTOROLA	MCI4001 UBCP	_
MIO	220017	HEY INVERTER	MOTOROLA	MC HOGO USCP	2
MII	·	NOT USED			_
MIZ	290090	71 DARLINGTON DRIVER	SPRAGUE / EXAR	ULN 2002A / XR 2202CP	4
MI3	230090	7 X DARLINGTON DRIVER	SPRAGUE / EXAR	ULN 2002 A / X R 2 202CP	-
MI4	250050	7 X DARLINGTON DRIVER	SPRAGUE / EXAR	ULN2002A / XR2202CP	_
M15	260039	324 QUAD OF AMP	NATIONAL	LM324 N	1
MIG	280025	QUAD 2 I/P NOR	MOTOROLA	MC 14001 UBCP	_
MI7	2800 17	HEX INVERTER	MOTOROLA	MC 14065 UECP	_
MIS	280035	BCD/DECIMAL DECODER	MOTOROLA	MC 14028 BCP	1
MI9 CIM	280045	TRIPLE 3 1/P NOR	MOTO ROLA	MC14025 BCP	1
M20	290090	7× DARLINGTON DRIVER	SPRAGUE / EXAR	ULN 2002A/XR 2202CP	
NOTES.			DATE		
SEE SHEET 2 FOR LA	ATEST ISSUE		3 DRAWN	5.83	ELECTRONICS LTD
ISS.			CHECKE	I/Ω PCE A	SSEMBLY
E.C.O. DATE			APPROV	VED DRAW(A)C	SHEET
CHKD.			DATE	NUMBER 400448	₩ of

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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RLI	330028	RELAY APOLE LATCHING	NATIONAL	53 -L2-24V	1
RL2	330012	RELAY REED IA GUARDED	HAMLIN	HE 721 A5134	5
RL3	330012	RELAY REED IA GUARDED	HAMLIN	HE721A5134	-
RL4	330012	RELAY REED IA GUARDED	HAMLIN	HE 721A5134	
RL5	330012	RELAY REED IA GUARDED	HAMLIN	HE 721A5134	<u> </u>
RLG	35001 2	RELAY REED IA GUARDED	HAMLIN	HE 72185134	-
RL7	NOT USED				-
RLS	330029	RELAY 2P2W	SDS	DS2E-M-DC24V	2
RLD	330029	RELAY 2PZW	SDS	DS 2E-M- DC 24 V	-
RLIO	3300 30	RELAY 4P N/O	SDS	54-24V	13
RLII	3300 30	RELAY 4P N/O	SDS	54-24 V	-
RL12	330030	RELAY 4P N/O	SDS	S4-24V	-
RL 13	3300 30	RELAY 4P N/O	SDS	54 - 24 V	-
RL14	3300 30	RELAY 4P N/O	SDS	54-24V	_
RL15	3300 27	RELAY IP 2W MINIATURE	TAKAMISAWA	MZ12 HSC	1
RLIG	3300 30	RELAY 4P NO	SDS	S4-24V	-
RL 17	3300.30	RELAY 4P NO	SDS	54-24V	-
RL 18	3300 30	RELAY 4P N/O	SDS	54-24V	_
RL 19	3300 30	RELAY 4P N/O	SDS	54-24V	-
RL20, 23, 24, 25	330030	RELAY 4P N/O	SDS	S4-24V	-
NOTES.	<u> </u>			DATE & L	
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E.C.O.				APPROVED I/Ω PCB	ASSEMBLY
DATE				DATE DRAWING NUMBER 400448	12 SHEET

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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
LI	370001	IOμ H O-85 Ω RF CHOKE	PLESSEY	58/10/0011/10	2
T.5	370001	10μ H 0.85Ω RF CHOKE	PLESSEY	58/10/0011/10	-
		· ·			
	410262-2B	I/A PRINTED CIRCUIT	BOARD		1
	450419 ~ 1	CURRENT HEATSINK			1
_					
	530222	24/0.2 PV.C INS. WIRE	RED ISKV RMS	<u>'</u>	240mm
	530444		YELLOW 1.5KV RMS		240mm
_	530666		BLUE 1.5 KV RMS		240mm
	530999	24/0.2 P.V.C INS. WIRE	WHITE 1.5 KV RMS		240mm
	540002	225WG TINNED COPPER WIRE			A/R
	540008	7/02 WHITE PTE INSULATED	WIRE		A/R
	540006	1/0.4 BLK. PTFE INS! WIRE		TO BSG 210 TYPE A	A/R
	560006	2 CORE PTFE SCREENED 19	0-15 CABLE **	SEE DRG.	310
	530001	SLEEVE MAX.CABLE \$ 3.0	HELLERMANN ELECTRIC.	HIS X POWN BLK. HELSYN	8
	590003		RS OR HELLERMANN ELECTRIC		40
	590004	SLEEVE PTFE	HELLERMANN ELECTRIC	FE IO	A/R
	590002	SLEEVE MAX.CABLE \$6.0		HIS X 25 mm BLK HELSYN	2
NOTES.			DATE	1 1 1 - 1 - 1	
SEE SHEET 2 FOR LA	TEST ISSUE		3	3.5.83 datron	ELECTRONICS LTD
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E.C.O.			APPRO	I/Q PCB	
DATE					SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	602001	FSV TERMINAL	MOLEX	020475114	16
	605060	14 WAY LOW PROFILE DI	L SOCKET		8
	605061	IGWAY LOW PROFILE DI			6
	605072	8 WAY -156" HOUSING	MOLEX	90-50-3081	
	605077	CRIMP TERMINAL GO.PL.	MOLEX	08-56-0106	4
	611006	M3 X IOMM POZI-PAN STE	EL. ZN.PL.		2
	611004	M3 X 6 mm POZI-PAN STE	EL. ZN.PL.		3
	611015	M3 Y 8mm POZI-C.S.K STE	EL. ZN.PL.		2
	613005	M3 INT SHAKEPROOF			2
	613007	M3 WASHER STEEL ZN.P			2
	613029	M3 CRINKLE WASHER SS			5
	615002	M3 FULL NUT STEEL ZN.PL.	,		4
	620001	CLOVERLEAF PTFE INSUL.	SEALECTRO	FTE I2 P 59	18
	620003	SOLDER PIN	HARWIN	H 2105 AOI	15
	620005	CLOVER LEAF PTFE INSUL	. SEALECTRO	FTE 15P59	19
	620007	TEST POINT TERMINAL	MICROVAR	TYPE C30	
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE '	1		DRAWN L. TITLE 400	
E.C.O.				APPROVED I/Ω PCE	ASSEMBLY
DATE				DATE DRAWING NUMBER 4004	48 14 OF 1

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	630003	P' CLIP \$ 4.8 mm	SES	CNB	2
	630024	STEATITE BEAD 16 SWG	PARK ROYAL PORCELAIN	Nº2	18
	630036	STEATITE BEAD 18 SWG	PARK ROYAL PORCELAIN	Nº1	14
	630122	PCB EJECTOR BLUE	RICHCO	CBE	2
	900003	HEAT SINK COMPOUND	RS	554-311	A/R
FI	920124	FUSE 375mA 125V 7mm	LITTLE FOSE	275 • 375	3
F2	220124	FUSE 375 MA 1254 7 mm	LITTLE FUSE	275 • 375	-
F3	920130	FUSE 1 A 125V 7mm	LITTLE FUSE	275 001	1
F4	920124	FUSE 375mA 125V 7mm	LITTLE FUSE	275 • 375	_
F5	920125	FUSE 21/2 A 125V 7mm	LITTLE FOSE	275 02•5	1
	(*)				
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE			3.5.83 datron	,
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E.C.O DATE			APPRO DATE	VED DRAWING NUMBER 40044	SHEET

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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S	No. USED Per Assy.
RI	066205	2M POT % SQ VERT CERMET		72 X W	I CI Assy.
R2	000101	100R 5% 1/4W CARBON	MULLARD	CR25	5
R3	000121	IZOR 5% 1/4W CARBON	MULLARD	CR2S	3
R4	000392	3k9 5% 4w CARBON	MULLARD	CR25	3
R5	000393	39k 5% 1/4W CARBON	MULLARD	CR25	3
R6	000682	GKB 5% 1/4W CARBON	MULLARD	CR25	1
R7	000393	39k 5% 1/4W CARBON	MULLARD	CR25	_
R8	000104	100k 5% 1/4W CARBON	MULLARD	CR25	5
R9	000471	470R 5% 1/4W CARBON	MULLARD	CR25	5
Rio	000183	18k 5% 1/4W CARBON	MULLARD	CR25	8
RII	000183	18k 5% 1/4W CARBON	MULLARD	CR25	_
RI2	000223	22k 5% 1/4W CARBON	MULLARD	CR25	6
R13	000682	6k8 5% 1/4W CARBON	MULLARD	CR25	2
RI4	000104	100k 5% 1/4W CARBON	MULLARD	CR25	
RI5	000682	6k8 5% 1/4W CARBON	MULLARD	CR25	_
RIG	000471	470R 5% 1/4W CARBON	MULLARD	CRS	_
RI7	000472	4k7 5% 1/4W CARBON	MULLARD	CR25	4
R18	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	5
R19	000102	IK 5% 1/4W CARBON	MULLARD	CR2S	_
R20	000472	4k7 5% 1/4W CARBON	MULLARD	CR25	_
R21	000181	180R 5% 1/4W CARBON	MULLARD	CR25	5
R22	000181	180R 5% 1/4W CARBON	MULLARD	CR25	_
R23	008034	ORIS 10% 212W WIREWOUND	WELWYN	W21	4

5 6 7 1458 1516 1529 8-4-83 16-8-83 15-9-83

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DATE 16.4.82

4000 POWER AMP

(DC) PCB ASSY DRAWING NUMBER 400449 2 SHEET 21

SEE SHEET 2 FOR LATEST ISSUE

DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
008034	ORIS 10% 21/2W WIREWOUN	WELWYN	W2I	-
000183	18k 5% YAW CARBON	MULLARD	CR25	-
000183	18k 5% 1/4W CARBON	MULLARD	CR25	_
000123	12k 5% 1/4W CARBON	MULLARD	CR25	2
011962	19k6 1% 18W 50 pm MF	HOLCO	H8C	2
011001	1k00 1% 1/8W 50ppm MF	HOLCO	H8C	2.
000123	12k 5% 1/4W CARBON	MULLARD	CR2S	_
011962	19kg 1% 18W 50pm MF	HOLCO	Н8С	_
011001	1k00 1% Yaw 50pm MF	HOLCO	HSC	-
005103	IOK 2% EW MET-OX	ELECTROSIL	TR5	1
008026	2k7 5% 21/2W WIREWOUND	WELWYN	WSI	1
000472	4k7 5% 1/4W CARBON	MULLARD	CR25	-
008034	ORIS 10% 21/2W WIREWOUND	WELWYN	W21	_
000183	18k 5% 4W CARBON	MULLARD	CR2S	_
000331	330R 5% 1/4W CARBON	MULLARD	CR25	2
000181	180R 5% VAW CARBON	MULLARD	CR25	
000151	ISOR 5% VAW CARBON	MULLARD	CR25	2
000222	2k2 5% 1/4W CARBON	MULLARD	CR25	3
000392	3k9 5% 1/4W CARBON	MULLARD	CR25	-
000183	IBK 5% 14W CARBON	MULLARD	CR25	_
000181	ISOR 5% 1/4W CARBON	MULLARD	CR25	_
000331	330R 5% 4W CARBON	MULLARD	CR25	_
000151	ISOR 5% 1/4W CARBON	MULLARD	CR25	_
TEST ISSUE			CHECKED TITLE 4000	POWER AMP
- 1 1			APPROVED DRAWING	A A O SHEET
	PART No. 008034 000183 000183 000123 011962 011001 000123 011962 011001 005103 008026 000472 008034 000183 000181 000151 000222 000392 000181 000181	PART No. OO8 0 3 4 ORIS 10% 2½ W WIREWOUND OO0 1 8 3 18k 5% 1/4 W CARBON OO0 1 8 3 18k 5% 1/4 W CARBON OO0 1 2 3 12k 5% 1/4 W CARBON O1 1 962 19k6 1% 1/8 W 50 ppm MF OO0 1 2 3 12k 5% 1/4 W CARBON O1 1 0 0 1 1k00 1% 1/8 W 50 ppm MF O1 1 0 0 1 1k00 1% 1/8 W 50 ppm MF O1 1 0 0 1 1k00 1% 1/8 W 50 ppm MF O1 1 0 0 1 1k00 1% 1/8 W 50 ppm MF O05 1 0 3 10k 2% 1/2 W MET OX O08 0 2 6 2k7 5% 2/2 W WIREWOUND O00 4 7 2 4k7 5% 1/4 W CARBON O00 1 8 3 18k 5% 1/4 W CARBON O00 1 8 3 18k 5% 1/4 W CARBON O00 1 8 1 180 R 5% 1/4 W CARBON O00 1 8 1 180 R 5% 1/4 W CARBON O00 1 8 3 18k 5% 1/4 W CARBON O00 1 8 3 18k 5% 1/4 W CARBON O00 1 8 1 180 R 5% 1/4 W CARBON O00 1 8 3 18k 5% 1/4 W CARBON	DOB 0 3 4	PART No.

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R47	000392	3k9 5% 4W CARBON	MULLARD	CR25	
R48	000222	2k2 5% 14W CARBON	MULLARD	CR25	-
R49	008034	ORIS 10% 21/2 W WIREWOUND	WELWYN	W2I	_
R50	000183	18k 5% 14W CARBON	MULLARD	CR25	_
R51	000152	IKS 5% 1/4W CARBON	MULLARD	CR25	3
R52	000152	Iks 5% 1/4W CARBON	MULLARD	CR25	-
R53	000183	18k 5% 1/4W CARBON	MULLARD	CR25	_
R54	000560	56R 5% 1/4W CARBON	MULLARD	CR25	. 5
R55	000560	56R 5% 1/4W CARBON	MULLARD	CR25	_
R56	000228	2R2 5% 1/4W CARBON	MULLARD	CR25	2
R57	000228	2R2 5% VAW CARBON	MULLARD	CR25	_
R58	000102	Ik 5% 1/4W CARBON	MULLARD	CR2S	_
R59	011002	10k0 1% 1/8W 50hm M.F.	Holco	H8C	2
R60	013920	392R 1% 1/8W 50/m M.F.	HOLCO	H8C	1
R61	016810	681R 1% 1/8W 50ppm MF.	HoLco	HSC	1
R62	011002	10k0 1% Vaw 50pm M.F.	HOLCO	H8C	
R63	014751	4k75 1% V8W 50pm M.F.	HoLco	H8C	3
R64	014751	4k75 1% 1/8W 50pm M.F.	HOLCO	H8C	_
R65	064104	100k POT IS TURN CERMET	BECKMAN	89P	1
R66		PART OF Q26 KIT			_
R67	014751	4k75 1% 18W 50pm M.F.	HOLCO	HSC	_
R68	000101	100R 5% VAW CARBON	MULLARD	CR25	_
R69	000471	470R 5% 1/4W CARBON	MULLARD	CR2S	-
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE		L	23.3.82	ELECTRONICS LTD
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DESIGNATOR	DATRON PART No.	DESCRIPTION		PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R70	000822	8k2 5% %	W CARBON	MULLARD	CR25	3
R71	000182	Ik8 5% 1/4	W CARBON	MULLARD	CR2S	3
R72	000104	100k 5% 1/	AW CARBON	MULLARD	CR25	_
R73	000822	8k2 5% 1/	AW CARBON	MULLARD	CR25	_
R74	000182	lk8 5% 1/2	4W CARBON	MULLARD	CR2S	_
R75	000182	1k8 5% 1/2	AW CARBON	MULLARD	CR25	_
R76	000223	22k 5% 1/	4W CARBON	MULLARD	CR25	_
R77	000152	lk5 5% /	4W CARBON	MULLARD	CR25	_
R78	000560	56R 5% 1/	AW CARBON	MULLARD	CR2S	_
R79	000221	220R 5% 1/	4W CARBON	MULLARD	CR25	3
R80	000821	820R 5% 1	4W CARBON	MULLARD	CR25	ı
R81	000103	10k 5% 4	4W CARBON	MULLARD	CR25	7
R82	066501	SOOR POT 1/2	SQ VERT CERME	BECKMAN	72×W	1
R83	000470	47R 5% 4	W CARBON	MULLARD	CR25	3
R84	000560	56R 5% 1/	4W CARBON	MULLARD	CR25	_
R85	000478	4R7 5% 1/4	AW CARBON	MULLARD	CR25	2
R86	000220	22R 5% 1/	4W CARBON	MULLARD	CR25	2
R87	018870	887R 1% 1/8	W 501- M.F.	HOLCO	нвс	2
R88	018870	887R 1% 1/8	W 50 pm M.F.	HOLCO	H8C	_
R89	000393	59k 5% 1/2	W CARBON	MULLARD	CR25	_
R90	000273	27k 5% 1/2	W CARBON	MULLARD	CR25	2
R91	000273	27k 5% 1/2	4W CARBON	MULLARD	CR2S	_
R92	000222	2k2 5% 1/	4W CARBON	MULLARD	CR25	_
NOTES. SEE SHEET 2 FOR L.	ATEST ISSUE				DRAWN . TITLE	D ELECTROMICS LTD POWER AMP
E.C.O.						PCB ASSY
DATE					DRAWING	0449 5 SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION		PRINCIPAL MANUFACTURER		MANUFACTUE PART No.	RER'S	No. USED Per Assy.
R93	000681	680R 5% 1/4W	CARBON	MULLARD		CR25		3
R94	000103	lok 5% 1/4W	CARBON	MULLARD		CR25		_
R95	000681	680R 5% 1/4W	CARBON	MULLARD		CR25		_
R96	012802	28k 1% 19W 5	Ohn M.F.	HOLCO		HSC		1
R97	000104	100k 5% 1/4W	CARBON	MULLARD		CR25		_
R98	000153	15k 5% 1/4W	CARBON	MULLARD		CR25		2
R99	000220	22R 5% 1/4W	CARBON	MULLARD		CR25		_
RIOO	000478	427 5% 1/4W	CARBON	MULLARD		CR25		-
RIOI	000470	47R 5% 1/4W	CARBON	MULLARD		CR25		_
R102	000103	10k 5% 1/4W	CARBON	MULLARD		CR25	,	
R103	000470	47R 5% 1/4W	CARBON	MULLARD		CR25		
R104	000390	39R 5% 1/4W	CARBON	MULLARD		CR25		2
R105	000103	lok 5% 1/4W	CARBON	MULLARD		CR2S		_
R106	000221	220R 5% Y4W	CARBON	MULLARD		CR25		
R107	000471	470R 5% 1/4W	CARBON	MULLARD		CR25		_
R108	000390	39R 5% 1/4W	CARBON	MULLARD		CR25		
R109	000103	lok 5% 1/4W	CARBON	MULLARD		CR25		-
RIIO	000223	22k 5% 1/4W	CARBON	MULLARD		CR25		_
RIII	000471	470R 5% 1/4W	CARBON	MULLARD		CR25		_
RIIZ	000121	120R 5% 1/4W	CARBON	MULLARD		CR25		_
RII3	000121	120R 5% 1/4W	CARBON	MULLARD		CR25		_
RII4	000102	lk 5% 1/4W	CARBON	MULLARD		CR25		
RIIS	008036	383 5% 212W	WIREWOUND	WELWYN		MSI		
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE				DATE 23	. 3.82	tatron	
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DESIGNATOR	DATRON PART No.	DESCRIPTI	ON		PRINCIPAL MANUFACTURER		MANUFACT PART No.	URER'S	No. USED Per Assy.
RIIG	000223	22k 5%	6 1/4W	CARBON	MULLARD		CR25		_
RII7	000102	lk 5%	1/4W	CARBON	MULLARD		CR25		_
RII8	000223	22k 59	6 14W	CARBON	MULLARD		CR25		_
RII9	000103	lok 5%	1/4W	CARBON	MULLARD		CRES		_
R120	000101	100R 5%	4W	CARBON	MULLARD		CR25		_
RIZI	000223	22k 59	6 1/4W	CARBON	MULLARD		CR25		_
R122	000473	47k 5%	. 14w	CARBON	MULLARD		CR2S		3
R123	000472	4k7 5%	/4w	CARBON	MULLARD		CR25		_
RI24	000105	IM 5%	1/4W	CARBON	MULLARD		CR25		3
R125	000105	IM 5%	14w	CARBON	MULLARD		CR25		
R126	000105	IM 5%	14w	CARBON	MULLARD		CR25		_
RI27	000221	220R 5%	1/4W	CARBON	MULLARD		CR25		_
R128	008032	270R 5%	6 2/2w	WIREWOUND	WELWYN		MSI		-
R129	008029	18R 2%	1/zw	MET-GLAZE	NEOHM		RGP OZO	7	2
R130	008029	18R 2%	/zw	MET-GLAZE	NEOHM		RGP 020	7	_
RI3I	000473	47k 5%	1/4W	CARBON	MULLARD		CR25		
R132	000394	390k 5%	1/4W	CARBON	MULLARD		CR25		11
R133	000473	47k 5%	V4W	CARBON	MULLARD		CR2S		_
R134	000363	36k 5%	1/4W	CARBON	MULLARD		CR25		1
R135	000154	150k 5%	1/4W	CARBON	MULLARD		CR25		1
R136	000100	IOR 5%	V4W	CARBON	MULLARD		CR2S		1
R137	000153	15k 5%	1/4W	CARBON	MULLARD		CR25		_
R138	000104	100k 5%	1/4W	CARBON	MULLARD		CR2S		_
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE					DATE 23 DRAWN CHECKE	3.3.82 L	,	WER AMP
E.C.O DATE CHKD.						APPROVI DATE		(DC) PCB DRAWING 40044	ASSY

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R139	000822	8k2 5% 1/4W CARBON	MULLARD	CR25	_
R140	000681	680R 5% 1/4W CARBON	MULLARD	CR25	_
R 4	000181	1808 5% 1/4W CARBON	MULLARD	CR2S	_
R142	000560	SER 5% VAW CARBON	MULLARD	CR25	_
R143	001151	ISOR 5% 12W CARBON	MULLARD	CR37	1.
R144 V	000103	10k 5% 1/4W CARBON	MULLARD	CR25	_
R145	008038	Ik2 5% 21/2W WIREWOUL	B WELWYN	Wal	2
R146	00.8038	Ik2 5% 21/2W WIREWOUN	D WELWYN	W21	_
RI47	000101	IOOR 5% 4W CARBON	MULLARD	CR25	_
R146	000101	1008 5% 4W CARBON	MULLARD	CR25	_
NOTES. SEE SHEET 2 FOR L. ISS. E.C.O. DATE CHKD.	ATEST ISSUE		DATE 2.3 ORAWN CHECKE APPROV DATE	4000. F	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFAC PART No.	TURER'S	No. USED Per Assy.
CI	150021	224F 20% 25V DIP TANT	UNION CARBIDE	K22 E 2	5	3
CS	150021	22 F 20% 25V DIP TANT	UNION CARBIDE	KZZE25		
C3	180039	470 UF 63V AL. ELECT.	STEATITE	EKR O	жJ 34 7J	4
C4		NOT USED				_
C5	104026	474F 150% 50V CER DISC	SIEMENS	B3744	9	11
C6	150016	JAF 20% 35V DIP TANT	UNION CARBIDE	KIROES	35	2
C7	180040	IONE GOV AL. ELECT	STEATITE	EKR O	OCC 210J	2
C8	110013	100nF 20% 250V POLYESTER	MULLARD	C260	AEP IOOK	8
C9		NOT USED				
C10	180039	470vF 63V AL. ELECT.	STEATITE	EKR OO	KJ 347J	_
CII	101103	IOAF 25% 250V CER DISC	ITT	CDIO		2
CI2	101103	IONF 25% 250V CER DISC	ITT.	CDIO		-
CIB	180040	10pf 63V AL. ELECT	STEATITE	EKR O	OCC 210J	_
C14	110013	100 AF 20% 250V POLYESTER	MULLARD	C280	AEP 100K	
C15	180039	470 F 63V AL. ELECT	STEATITE	EKR OC)KJ 347J	
C16	104026	47nf 150% SOV CER DISC	SIEMENS	83744	9	
C17	150016	JUF 20% 35V DIP TANT	UNION CARBIDE	KIROES	5	
C18	110013	100nf 20% 250V POLYESTER	MULLARD	C280 A	EP 100K	
C19	150003	47,4F 20% 6V3 DIP TANT	UNION CARBIDE	K47E6	V3	2
C20	102332	3n3F 20% 500V CER DISC	ITT	CDIO		3
C21	150004	100MF 20% 6V3 DIP TANT	UNION CARBIDE	KIOOE	6V3	3
C22	150004	LOQUE 20% GV3 DIP TANT	UNION CARBIDE	KIOOE	6V3	_
C23	102332	3n3F 20% 500V CER DISC	ITT	CDIO		_
NOTES.				23.3.82		ELECTRONICS LTD
SEE SHEET 2 FOR L	ATEST ISSUE			DRAWN L .	4000 P	OWER AMP
E.C.O.				APPROVED		CB ASSY
DATE CHKD.				DATE	DRAWING NUMBER 4004	1 SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACT PART No.	URER'S	No. USED Per Assy.
C24	150003	47uf 20% GV3 DIP TANT	UNION CARBIDE	K47E6V	3	
C25	180039	47guf GSV AL ELECT	STEATITE	EKR O	OKJ 347J	-
C56	110013	100AF 20% 250V POLYESTER	MULLARD	C280A	EPIOOK	_
C27	110029	InSF 20% 100V POLYESTER	WIMA	FKS2MI	N ·	1
C28	180044	220 JUF 40V AL. ELECT	STEATITE	EKM OO	DE 322G	1
C29	150021	22,4F 20% 25V DIP TANT	UNION CARBIDE	K22 £25	5	_
C3o	102470	47 F 5% 500V CER DISC	ITT	CDIO		2
C31	104026	479 +50% 50V CER DISC	SIEMENS	B37449		_
C32	110005	10nF 20% 250V POLYESTER	MULLARD	C280AE	PIOK	1
Ca3	102470	47pf 5% 500V CER DISC	ITT	CDIO		_
C34	180041	100 JF 40V AL. ELECT	STEATITE	EKM OO	FD 310G	1
C35		NOT USED				_
C36	110035	220 F 20% 63V POLYESTER	WIMA	MKSZ MI	N	1
C57	104026	470F -20% 50V CER DISC	SIEMENS	837449		_
C38	102331	330 F 10% 500V CER DISC	ITT	CDIO		1
C39	102 152	Insf 10% 5000 CER DISC	ITT	CDIO		1
C40	110013	100mF 20% 250V POLYESTER	MULLARD	C280AE	PIOOK	_
C41	120028	4n7F 20% 100V POLYCARB	WIMA	FKC2MI	N	1
C42	102121	1206 10% 500V CER DISC	ITT	CDIO		1
C43	150004	IOOMF 20% 6V3 DIP TANT	UNION CARBIDE	KIOOEGV	/3	_
C44	104026	470F +50% 50V CER DISC	SIEMENS	B37449		_
CA5	102680	68 F 5% 500V CER DISC	ITT	CDIO		1
C46	150015	IONE 20% 35V DIP TANT	UNION CARBIDE	KIOE 35		1

DRAWN | ___ SEE SHEET 2 FOR LATEST ISSUE 4000 POWER AMP (DC) PCB ASSY ISS.
E.C.O.
DATE
CHKD. APPROVED DRAWING NUMBER 400449 10 SHEET 10 OF 21 DATE

J.W. 1164

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFAC PART No.	TURER'S	No. USED Per Assy.
C47	110013	1000F 20% 250V POLYESTER	MULLARD	C260 A	E PIOOK	_
C48	120021	470nf 10% 63V POLYCARB	ASHCROFT	A284	7118	1
C49	150017	100 UF 20% IGV DIP TANT	UNION CARBIDE	KIOOE	16	2
C50	104026	470F 150% 50V CER DISC	SIEMENS	83744	19	-
C5I	104026	47nf + 50% SOV CER DISC	SIEMENS	B374 4	.9	_
C52	104026	47 F + 50% 50V CER DISC	SIEMENS	B3744	9	
C53	180043	470 MF 25V AL ELECT	STEATITE	EKM O	OFE 347E	2
C 54	104026	470F -20% 50V CER DISC	SIEMENS	B3744 9	3	_
C55	104026	47nF -80 % 50V CER DISC	SIEMENS	83744	•	_
C 56	180043	470µF 25V AL ELECT	STEATITE	EKM C	OFE 347E	_
C 5 7	104026	470F -80 % 50V CER DISC	SIEMENS	B3744 9	b	_
C 58	140047	33 NF 10% IKSV POLYPROP	STEATITE	MKPIS	41	3
C59	140047	33 nf 10% IKSV POLYPROP	STEATITE	MKP 18	141	_
C60	110013	100 nf 20% 250V POLYESTER	MULLARD	C280AE	Plook	
C6I	110013	100nF 20% 250V POLYESTER	MULLARD	C280AE	Plook	_
C62	102102	INF 10% 500V CER DISC	ITT	CDIO		1
C63	102221	220 F 10% 500V CER DISC	ITT	CDIO		1
C64	102821	820 F 10% 500V CER DISC	ITT	CDIO		1
C 65	102332	3 n3F 20% 500V CER DISC	ITT	CDIO		_
C66	140048	47nf 10% IKSV POLYPROP	STEATITE	MKP184	H	1
C67	140047	33nF 10% IKSV POLYPROP	STEATITE	MKP184	41	_
C68	150022	2,42F 20% 35V DIP TANT	UNION CARBIDE	K2R2E	35	1
C69		NOT USED				_
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE		12	23.3.82 DRAWN .	datron	
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DATE CHKD.				DATE	DRAWING NUMBER 4004	49 11 OF 2

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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTU PART No.	RER'S	No. USED Per Assy.
C70	150025	3,43F 20% 35V DIP TANT	UNION CARBIDE	K3R3E35		1
C71	150017	100MF 20% IGV DIP TANT	UNION CARBIDE	KIOOEIG)	_
C72	102471	470 F 10% 500V CER DISC		CDIO		2
C73	102471	470 F 10% 500V CER DISC		CDIO		_
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						[
DI	200022	3A 400V GP SI DIODE	MOTOROLA	BY252		4
DS	200022	3A 400V GP SI DIODE	MOTOROLA	BY252		_
D3	210100	IOV 400mW ZENER	MULLARD	BZY88CI)	4
D4	210150	15V 400mW ZENER	MULLARD	BZY88 CIS	5	3
D5	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148		25
D6	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148		_
D7		NOT USED				-
DB		NOT USED				_
D9.	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148		_
NOTES.				DATE		
			:	23. 3. 82.	atron	ELECTRONICS LTD
SEE SHEET 2 FOR LA	ATEST ISSUE			11	4000 PC	WER AME
ISS. E.C.O.				CHECKED	(DC) PCI	
DATE				D	2.4441110	49 12 SHEET 2
CHKD.					4004	12 of 2

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTUF PART No.		No. USED Per Assy.
DIO	200001	75mA 75V GP. SI DIODE	FAIRCHILD	IN4148		-
DII	200001	75m A 75V GP SI DIODE	FAIRCHILD	IN4148		_
DIZ	200022	3A 400V GP SI DIODE	MOTOROLA	BY252		_
DI3	200022	3A 400V GP SI DIODE	MOTOROLA	BY252		
D14	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148		
DIS	214012	2V45 30 pm ZENER	FERRANTI	ZN458		2
DIG	214012	2V45 3000 ZENER	FERRANTI	ZN458		_
D17	200006	IA GOOV GP SI DIODE	FAIRCHILD	IN4005		6
D18	200006	IA GOOV GP SI DIODE	FAIRCHILD	IN4005		_
D19	200006	IA GOOV GP SI DIODE	FAIRCHILD	IN4005		-
D20	200006	IA GOOV GP SI DIODE	FAIRCHILD	IN4005		
DSI	210150	15 V 400mW ZENER	MULLARD	BZY88CI	5	-
D22	200001	75m A 75V GP Si DIODE	FAIRCHILD	IN4148		
D23	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148		_
D24	210150	15V 400mW ZENER	MULLARD	BZY88CI	5	
D25	200001	75mA 75V GP Si DIODE	FAIRCHILD	IN4148		
D26	210056	5VG 400mW ZENER	MULLARD	8ZY88C5	V6	2
D27	200001	75mA 75V GP Si DIODE	FAIRCHILD	IN4148		-
D28	210056	5VG 400mW ZENER	MULLARD	BZY88CS	576	-
D29	200001	75mA 75V GPSI DIODE	FAIRCHILD	IN4148		_
030	213011	IVS 250mW ZENER	MULLARD	BZV46-11	V5	3
D31	213011	IVS 250 mW ZENER	MULLARD	BZV46-11	V5	
D32	200001	75mA 75V GPSI DIODE	FAIRCHILD	IN4148		_
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE		- · · ·	DATE 23. 3. 82	datron .	
iss.				CHECKED	4000 PO	
E.C.O.				APPROVED	(DC) PCB	
DATE CHKD.				DATE DE	RAWING 40044	9 13 OF 2

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
D33	200001	75mA 75v GP Si DIODE	FAIRCHILD	IN4148	
D34	213011	IVS 250mW ZENER	MULLARD	BZV46-1V5	_
D35	213012	2VO 250 MW ZENER	MULLARD	8ZV46-2V0	1
D36 **	214013 BLZ	GVZ ZENER SELECTED	DATRON	SEE DRG-	1
D37	220008	LED RED	PYE-TMC	521-9165	1
D38	200006	IA GOOV GP SI DIODE	FAIRCHILD	IN4005	_
D39	200006	IA GOOV GPSI DIODE	FAIRCHILD	IN4005	
D40	220010	SI HOT CARRIER DIODE	HP	HSCH1001/1N6263	1
D41	200001	75 m A 75V GP SI DIODE	FAIRCHILD	IN4148	_
D42	210033	3V3 400mW ZENER	MULLARD	8ZY88C3V3	1
D43	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	_
D44	210027	2V7 400mW ZENER	MULLARD	BZY88C2V7	1
D45	210240	24V 400 MW ZENER	MULLARD	BZY88C24	1
D46	200001	75 MA 75V GP SI DIODE	FAIRCHILD	IN4148	-
D47	200001	75 mA 75V GP SI DIODE	FAIRCHILD	IN4148	_
D48	200001	75 mA 75V GP Si DIODE	FAIRCHILD	IN4148	_
D49	200001	75mA 75V GP SI DIODE	FAIRCHILD	IN4148	-
D 50	200001	75 mA 75V GP Si DIODE	FAIRCHILD	IN4148	_
DSI	200001	75 mA 75V GP Si DIODE	FAIRCHILD	IN4148	
D52	210100	IOV 400mW ZENER	MULLARD	BZYBBCIO	_
D53	200001	75 m A 75V GP Si DIODE	FAIRCHILD	IN4148	-
D54	200001	75 mA 75V GP Si DIODE	FAIRCHILD	IN4148	
D55	213009	ISV SW ZENER	UNITRODE	TVS SIS	1
NOTES. * FO SEE SHEET 2 FOR LATE ISS.		EE DRG 214013####	DATE 23 DRAWN CHECKEE	.3.82 datron	
E.C.O.	 		CHECKE	(DC) PCB	ASSY

DRAWING NUMBER 400449

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
D56	200020	IA IKSV FR SI DIODE	MOTOROLA	BY339	8
D57	200020	IA IK5V FR SI DIODE	MOTOROLA	BY339	_
DS8	200020	IA IKSV FRSI DIODE	MOTOROLA	BY539	_
D59	200020	IA IKSV FR SI DIODE	MOTOROLA	BY539	_
D60	200020	IA IKSV FR SI DIODE	MOTOROLA	BY339	_
D61	200020	IA IKSV FR SI DIODE	MOTOROLA	5Y339	_
D62	200020	IA IKSV FR SI DIODE	MOTOROLA	8Y339	_
D63	200020	IA IKSY FR SI DIODE	MOTOROLA	BY339	_
D64	200001	75mA 75V QP SI DIODE	FAIRCHILD	IN4148	_
D65	200001	75 mA 75V GP SI DIODE	FAIRCHILD	IN4148	-
D66	210100	IOV 400mW ZENER	MULLARD	BZY88CIO	_
D67	210100	IOV 400 MW ZENER	MULLARD	BZY88CIO	
D68	213006	SV SW ZENER	UNITRODE	TVS 505	2
D69	213006	SV SW ZENER	UNITRODE	TVS 505	_
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NOTES. SEE SHEET 2 FOR LA	ATECT ICCLE		H		ELECTRONICS LTD
ISS.	1300E				POWER AMP
E.C.O.				APPROVED (DC)	PCB ASSY
DATE CHKD.				DRAWING NUMBER A	0449 SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
Qı	240009	SI NPN TRANSISTOR	NATIONAL	MPSLOI / TOIB	7
Q2	250009	SI PHP TRANSISTOR	NATIONAL	2N5401 / TO18	6
Q3	240009	SI NPN TRANSISTOR	NATIONAL	MPSLOI/TOIB	_
Q4	230039	P-CHAN JEET	SILICONIX	J175	1
Qs	230035	N-CHAN JEET	TELEDYNE	U1897 JF	3
ଦ୍ର େ	240009	SI NPN TRANSISTOR	NATIONAL	MPSLOI/TOIS	_
Q 7	240006	SI NPN TRANSISTOR	NATIONAL	2N3904 / TOIS	1
Q8	250009	SI PNP TRANSISTOR	NATIONAL	2N5401 / TOIS	_
Q9	250009	SI PNP TRANSISTOR	NATIONAL	2N5401 / TOIS	_
Qio	240009	SI NPN TRANSISTOR	NATIONAL	MPSLOI/TOIS	_
QII	24 0009	SI NPN TRANSISTOR	NATIONAL	MPSLOI / TOIS	_
Qız	24 0009	SI NPN TRANSISTOR	NATIONAL	MPSLOI/TOIS	_
Qı3	250009	SI PNP TRANSISTOR	NATIONAL	2N5401/TO18	_
Q14	250009	SI PHP TRANSISTOR	NATIONAL	2N5401 / TO18	-
Qıs	250001	SI PHP TRANSISTOR	NATIONAL	BC214 / TO18	2
QIE	240001	SI NPN TRANSISTOR	NATIONAL	BC184/TO18	1
Q17	230042	N-CHAN I LIM 3.0m A	TELEDYNE	TCR510	2
ପାଞ	230042	N-CHAN I LIM 3.0mA	TELEDYNE	TCR510	_
Q19	25 0009	SI PNP TRANSISTOR	NATIONAL	2N5401/TO18	_
Qzo	240009	SI NPN TRANSISTOR	NATIONAL	MPSLOI/TOI8	_
Q2I	240031	SI NPN TRANSISTOR	MOTOROLA	BD139	1 2
Q22	250020	SI PNP TRANSISTOR	MOTOROLA	TIP 32C	2
Q23	240034	SI NPN TRANSISTOR	MOTOROLA	TIP3IC	2
NOTES. SEE SHEET 2 FOR L.	ATEST ISSUE		DATE 23 DHAMM	100V) POW	ELECTRONICS LTD
E.G.O.			APPROV	(NC) PCB	ASSY
DATE CHKD.			DATE	DRAWING NUMBER 40044	9 16 OF 21

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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFAC PART No.	TURER'S	No. USED Per Assy.
Q24	250020	SI PNP TRANSISTOR	MOTOROLA	TIP320		
Q25	240034	SI NPN TRANSISTOR	MOTOROLA	TIPSIC		
Q 26	239051-2	N-CHAN J-FET KIT	DATRON	U1897J	F (COLOUR)+RES	1
Q27	23 0035	N-CHAN J-FET	TELEDYNE	U1897J		_
Qz8	230050	N-CHAN I LIM 2.5mA	TELEDYNE	TCR 50	9	1
Q29	250011	SI PNP TRANSISTOR	NATIONAL	BC327	/TOIS	1
Q30	240014	SI NPN TRANSISTOR	NATIONAL	BC337	TOIS	1
ଠ୍ୟା	240029	SI NPN TRANSISTOR	MOTOROLA	BC 546	/TO18	4
Q32	250018	SI PHP TRANSISTOR	MOTOROLA	BC 556	/TO18	2
Q33	230036	N-CHAN J FET	SILICONIX	J108		1
Q34	230035	N-CHAN J FET	TELEDYNE	U1897 J	F	_
Q35	240029	SI NPN TRANSISTOR	MOTOROLA	BC546	/TOIS	
Q36	240028	SI NPN TRANSISTOR	MOTOROLA	BC 414/	TOI8	2
Q37	240029	SI NPN TRANSISTOR	MOTOROLA	BC 546	1018	_
Q38	240028	SI NPN TRANSISTOR	MOTOROLA	BC414/	TOIS	_
Q39	250018	SI PNP TRANSISTOR	MOTOROLA	BC 556	/TO18	-
240	240029	SI NPN TRANSISTOR	MOTOROLA	BC 546	TOIS	_
241	240030	SI NPN TRANSISTOR	MOTOROLA	80389)	1
Q42	250019	SI PNP TRANSISTOR	MOTOROLA	BD390)	1
Q43	250001	SI PNP TRANSISTOR	NATIONAL	BC214 /	TO18	_
Q44	250008	SI PNP TRANSISTOR	NATIONAL	BC 2140	/T018	1
			<u> </u>			
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE		4	23. 3. 82	atto	ELECTRONICS LTD
ISS.				DRAWN .	4000 PO	
E.C.O.				APPROVED	(DC) PCB	ASSY
DATE CHKD.				DATE	DRAWING 40044	19 17 OF

PART No.						
A2 2600 50 412 DUAL FET I/P OP AMP NATIONAL LF412N 2 A3 2600 57 5534 OP AMP SIGNETICS NE5534 N. 2 A4 2600 57 5534 OP AMP SIGNETICS NE5534 N. — A5 2600 50 412 DUAL FET I/P OP AMP NATIONAL LF412N — A6 2600 27 714 OP AMP FARCHILD AA714 HC I A71 2900 90 7 x DARLINGTON DRIVER SPRAGUE/EXAR ULN2002A/xR2202 CP I B8 280037 HEX BUFFER MOTOROLA MC14050BCP I B10 220015 5kV OPTO ISOLATOR FAIRCHILD FCD820C I A11 220033 INTERFACE OPTO ISOLATOR HP HCPL-3700 I A11 220033 INTERFACE OPTO ISOLATOR HP HCPL-3700 I A12 330020-1 RELAY 2P2W 5A PYE GW 265/24/3 — A13 330005 RELAY 2P2W SAMP P4B RIO-EI-X2-S3-2k (25202) I B10 28 SHEET 2 FOR LATEST ISSUE B11 53 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3 3	DESIGNATOR		DESCRIPTION			
A3	MI	260043	358 DUAL OP AMP	NATIONAL	LM358N	- 1
14	MS	2600 50	412 DUAL FET I/P OP AMP	NATIONAL	LF4I2N	2
15	M3	2600 57	5534 OP AMP	SIGNETICS	NE5534N	2
166	M4	2600 57	5534 OP AMP	SIGNETICS	NE 5534 N.	-
17	Ms .	260050	412 DUAL FET I/P OP AMP	NATIONAL	LF412N	_
18	M6	260027	714 OP AMP	FAIRCHILD	μΑ714 HC	1
19	M7	290090	7 × DARLINGTON DRIVER	SPRAGUE/EXAR	ULN 2002 A / XR2202 CP	1
DUAL D FLIP-FLOP MOTOROLA MC 14-013 BCP MC 14-013 B	M8	280037	HEX BUFFER	MOTOROLA	MC14050BCP	1
AII 220033 INTERFACE OPTO ISOLATOR HP HCPL-3700	M9	22 00 15	5KV OPTO ISOLATOR	FAIRCHILD	FCD820C	1
1	MIO	280011	DUAL D FLIP-FLOP	MOTOROLA	MC 14013 BCP	1
12 330020- RELAY 2P2W 5A PYE GW 265/24/3 -	MII	220033	INTERFACE OPTO ISOLATOR	НР	HCPL- 3700	1
12 330020- RELAY 2P2W 5A PYE GW 265/24/3 -						
12 330020- RELAY 2P2W 5A PYE GW 265/24/3 -	RLI	330020-1	RELAY 2P2W 5A	PYE	GW 265/24/3	2
1.13 330005 RELAY 2P2W SAMP P4B RIO-EI - X2-S3-2k (25209)	RL2	1		 		
EE SHEET 2 FOR LATEST ISSUE 23.3.82	RL3) 1
EE SHEET 2 FOR LATEST ISSUE 23.3.82						
EE SHEET 2 FOR LATEST ISSUE DRAWN	NOTES.			D.	23.3.82 datron	ELECTROMOCATO
APPROVED DRAWING	ISS.	ST ISSUE		1 1	HECKED TITLE 4-000 POL	NER AM
	DATE CHKD.				PPROVED	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
LI	370013	4MH GA RF CHOKE	ERO	F1756-004-601	3
L2	370013	4µH 6A RF CHOKE	ERO	F1756-004-601	-
L3	370013	4 MH GA RF CHOKE	ERO	F1756-004-601	-
L4	370001	IONH 0.850 RF CHOKE	PLESSEY	58/10/0011/10	4
L5	370001	IONH 0.85.2 RF CHOKE	PLESSEY	58/10/0011/10	_
LG	370009	INH 3A RF CHOKE	ERO	F1756-001-301	1
L7	370018	IOMH 1372 RF CHOKE	SIGMA	SC60	1
L8	370007-1	40mH CHOKE	SIGA	SEE DRG	i
L9	370015-1	26m5H CHOKE	SIGA	SEE DRG	1
Lio	370016-1	24mIH CHOKE	SIGA	SEE DRG	1
LII	370001	IONH O.85 & RF CHOKE	PLESSEY	58/10/0011/10	_
LIZ	370001	IONH O.85Ω RF CHOKE	PLESSEY	58/10/0011/10	-
	,				
FI	920128	FUSE 4A 250V 20mm SLO-B	BELLING LEE	L2080A/4	3
FZ	920128	FUSE 4A 250V 20mm SLO-B	BELLING LEE	L2080A/4	_
F3	920128	FUSE 4A 250V 20mm SLO-8	BELLING LEE	L2080A/4	_
SI	700070	SWITCH 2P2W SLIDE	APR	25446H6A	1
	400472	CONSTANT I PCB ASSY.	DATRON		1
NOTES. SEE SHEET 2 FOR L ISS. E.C.O. DATE	ATEST ISSUE			(NC) PCE	OWER AME

DESIGNATOR	DATRON	DESCRIPTION	PRINCIPAL	MANUFACTURER'S	No. USED Per Assy.
	PART No. 410203-4A	DC 8	MANUFACTURER	PART No.	Per Assy.
	410203-4A	rcb			
	459112-2	RELAY BRACKET			1
	590004	SLEEVE - PTFE	HELLERMANN ELECTRIC	FEIO	A/R
	540008	7/-2 PTFE INSULATED (WHITE) WIRE			1260 mm
	540002	22 SWG B.T.C. WIRE			A/R
	590001	SLEEVE . MAX.CABLE \$ 3.0	HELLERMAN ELECTRIC	HIS X 20mm BLK HELSYN	- 11
	590007	LACING CORD (BLACK)	HELLERMANN ELECTRIC	MW/062	A/R
JI- J6	604042	4 WAY .156" PLUG GD/PL	MoLex	09-72-2041	12
4					
	605059/A	8 WAY DIL SOCKET			6
	605060/A	14 WAY DIL SOCKET		\$e!	1
	605061/A	IG WAY DIL SOCKET			2
	605066/A	G WAY DIL SOCKET			1
	613014	M2-5 INT SHAKEPROOF			1
	611016	M3×8mm POZIPAN STEEL	ZN PL		7
	613005	M3 INT SHAKEPROOF			7
	613007	M3 WASHER STEEL ZN PL			4
	615002	M3 FULL NUT STEEL ZN PL			7
	615005	3-48 UNC FULL NUT STEEL	ZNPL		1
	618004	MOUNTING PAD TOIS	JERMYN	T018-008D	2 -
NOTES.			DATE 2	3.3.82 datron	ELECTRONICS LTD
SEE SHEET 2 FOR LA	TEST ISSUE		DRAW CHECK	4000 PO (DC) PCB	WER AMP
DATE CHKD.			APPRO DATE	DRAWING	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTUR PART No.	RER'S	No. USED Per Assy.
	620003	SOLDER PIN	HARWIN	H2 los Ac	H	15
	630024	STEATITE BEAD 16 SWG	PARK ROYAL PORCELAIN	Nes		10
	630036	STEATITE BEAD 18 SWG	PARK ROYAL PORCELAIN	Nº I		5
	630123	PCB EJECTOR VIOLET	RICHCO	CBE		2
	620007	TEST POINT TERMINAL	MICROVAR	C 30		30
	920091-1	HEATSINK TO-220	SEE DRG			4
	920126	FUSE HOLDER 20mm PCB	BELLING LEE	L1426		3
	920105-1	HEATSINK TO-202	SEE DRG			2
	900003	HEATSINK COMPOUND	RS	554-311		A/R
						_
				1		
NOTES.			DATE	23.3.82	datron	ELECTRONICS LTD
SEE SHEET 2 FOR L	ATEST ISSUE		ORAM CHECI	KED	4000 PC (DC) PCB	
DATE DATE			APPRO	OVED	RAWING 40044	SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RI	000102	Ik 5% 1/4W CARBON	MULLARD	CR25	2
R2	011502	15k 1% 1/8W 50 m M.F.	HOLCO	H8C	1
R3	000338	3R3 5% 1/4W CARBON	MULLARD	CR25	1
R4	000682	6k8 5% 1/4W CARBON	MULLARD	CR25	1
R5	011101	1K10 1% 1/8W 50ppm M.F.	Holco	нвс	1
R6	000102	Ik 5% 1/4W CARBON	MULLARD	CR2S	_
R7	000272	2k7 5% 1/4W CARBON	MULLARD	CR25	2
R8	000272	2k7 5% 1/4W CARBON	MULLARD	CR25	-
vi .					
CI	180042	3300NF 25V AL. ELECT.	STEATITE	EG 00MG 433E	2
C2	180042	3300PF 25V AL. ELECT.	STEATITE	EG OOMG 433 E	_
C3	180025	1000 PF 35V AL. ELECT.	WIMA	PRINTILYT 1	3
C4	180025	1000 uf 35V AL. ELECT.	WIMA	PRINTILYT I	_
C5	104026	47aF -20% SOV CER DISC	SIEMENS	B37449	5
C6	150021	22/F 20% 25V DIP TANT	UNION CARBIDE	K22E25	4
C7	150021	22/F 20% 25V DIP TANT	UNION CARBIDE	K22E25	
<i>C</i> 8	150001	22 UF 20% 16V DIP TANT	UNION CARBIDE	K22E16	4
C9	150001	22 MF 20% 16V DIP TANT	UNION CARBIDE	K22 E16	
CIO	104026	47nF -20% 50V CER DISC	SIEMENS	B37449	
CII	150021	22 MF 20% 25V DIP TANT	UNION CARBIDE	K22E25	
CI2	104 026	47nF +50% SOV CER DISC	SIEMENS	B37449	
NOTES. SEE SHEET 2 FOR LA				DRAWN . TITLE	T ELECTRONICS LTD
ISS.	2 3			CHECKED PIST	PLY PCB. ASS'
DATE 9. 3.82 13 CHKD. M.D.	326 1529 3.5.62 15.9.83			DATE 9.3.82.	

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFAC PART No.		No. USED Per Assy.
CI3	150021	22 MF 20% 25V DIP TANT	UNION CARBIDE	K22E3	2.5	_
C14	180024	IOUF GSV AL. ELECT.	MULLARD	016 18	109	1
CI5	102102	INF 10% 500V CERDISC	IŢT	CDIO		1
C16	150016	LUF 20% 35V DIP TANT	UNION CARBIDE	KIROE	35	1
CI7	104026	470F -20 SOV CER DISC	SIEMENS	83744	9	_
CI8	150001	22,F 20% 16V DIP TANT	UNION CARBIDE	K22E16	5	_
C19	150001	22, F 20% 16V DIP TANT	UNION CARBIDE	K22EI	6	_
C20	104026	47nF -50 % SOV CER DISC	SIEMENS	B37449)	_
C21	180038	1000pf 63V AL. ELECT	STEATITE	EG 00 1	MG 410J	1
C22	180025	1000 F 35V AL ELECT	WIMA	PRINTI	LYT I	_
C23	180005	10000F 25V AL. ELECT	WIMA	PRINTI	LYT I	2
C24	180005	1000 F 25V AL. ELECT	WIMA	PRINTIL	YT I	-
	,					
DI	200022	3A 400V GP Si DIODE	MOTOROLA	BY25	2	4
DZ	200022	3A 400V GP Si DIODE	MOTOROLA	BY25	2	_
03	200022	3A 400V GP Si DIODE	MOTOROLA	BY25	2	_
D4	200022	3A 400V GP Si DIODE	MOTOROLA	BY25	2	
05	210150	15V 400mW ZENER	MULLARD	BZY88	C15	1
NOTES. SEE SHEET 2 FOR LA	ATEST ISSUE	,	n .	19.11.81 DRAWN	datron	
E.C.O.				CHECKED	POWER SUPPI	
DATE				DATE	DRAWING 4004	51 3 OF 5

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFAC PART No.	TURER'S	No. USED Per Assy.
DG	211150	15V 1-3W ZENER	MOTOROLA	BZXGI	C15	1
D7	214012	2V45 30pm ZENER	FERRANTI	ZN458	3	1
WI - W4	209003	IAS 100V BRIDGE RECTIFIER	MICRO-ELECTRONICS	WOOI		4
Qı	240009	SI NPN TRANSISTOR	NATIONAL	MPSLO	/TOI8	1
Qs	240014	SI NPN TRANSISTOR	NATIONAL	BC337	/ TOIS	1
Q3	230047	N-CHAN CURRENT LIM	TELEDYNE	TCR 51	3	1
Q4-	240024	SI NPN TRANSISTOR	NATIONAL	TIPSIA		ı
MI	260051	-15V IA REGULATOR	MOTOROLA	MC791	5CT	2
M2	260006	ISV IA REGULATOR	MOTOROLA	MC781	SCP	1
M3	260045	-8V 1/2A REGULATOR	MOTOROLA	MC791	108CT	2
M4	260044	8V 1/2A REGULATOR	MOTOROLA	MC78 N	A OBCT	2
M5	260026	212 OP AMP	NATIONAL	LM 212	2H	i
M6	260005	5V IA REGULATOR	MOTOROLA	MC78	OSCP .	1
M7	260051	-ISV IA REGULATOR	MOTOROLA	MC791	SCT	-
M8	260045	-8V 1/2A REGULATOR	MOTOROLA	MC791	MOSCT	~
M9	260044	8V 1/2A REGULATOR	MOTOROLA	MC78 A	108 CT	_
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE			19.11.81 DRAWN	datron	
E.C.O.				CHECKED	4000. IN POWER SUPP	LY PCB. ASSY
СНКО.				DATE	NUMBER 40045	4 of 5

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER		MANUFACTURER'S PART No.	No. USED Per Assy.
LI- L3	370013	4 H GA RF CHOKE	ERO		F1756-004-601	3
4-L9	370014	BUH 3A RF CHOKE	ERO		F1756-008-301	6
.10	370019-1	P.S. COMMON MODE CHOKE	SIGA		SEE DRG.	1
	410160-6A	РСВ				1
	540002	22 SWG- B.T.C. WIRE	RS.			A/R
JI- J3	604042	4-WAY PLUG WITH LOCKING RA	MP MOLEX		09-72-2041	5
	611016	SCREW M3×8mm POZIPANSTEEL		KN		12
	613005	WASHER M3 SHAKEPROOF	ZN/PLATED C	KN		12
	620007	TEST POINT TERMINAL	MICROVAR		C30	6
	615002	NUT M3 HEX FULL STEEL	ZN/PLATED C	KN		12
	900004	SILICONE RUBBER COMPOUN	R5		555-588	A/R
	920089-1	HEATSINK TOREO	SEE DRG.		· -	4
	920090-1	HEATSINK 2x TO220	SEE DRG.			3
F1. F2	920128	FUSE 4 A SLO - BLOW	BELLING LEE		L2080A/4	2
	920126	FUSE HOLDER	BELLING LEE		L1426	4
F3, F4	920127	FUSE 2 A SLO-BLOW	BELLING LEE		L2080A/2	2
	900003	HEATSINK COMPOUND	RS		554-311	A/R
NOTES.	ATCCT ISSUE	<u> </u>		DATE 19.	.II.81 datro	ELECTRONICS LTD
ISS.	ATEST ISSUE			CHECKED	4000.	IN-GUARD DPPLY PCB. ASS
DATE				DATE	DRAWING NUMBER 400	451 5 SHEET

	PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RI	090014-2	50K .02/R ZppmR W.W.	MANN	AXI75B	3
R2	050014-2	9K995 .02/R ZpmR W.W	MANN	AXI75B) 1 SE1
R5		PART OF KIT DI-4 D6-9	MANN	AXI75B	-
R4		PART OF KIT DI-4 DG-9	MANN	AXI75B	-
R5	018251	BK25 1% /BW 50ppm MF	HOLCO	HSC	1
R6	000470	47R 5% YAW CARBON	MULLARD	CRES	5
R7	070152	68R .1% 10ppm W.W	MANN	MX125	2
RS	070152	GBR 1% 10ppm W.W	MANN	MX125	_
R9	070153	34R . 1% 10ppm W.W.	MANN	MX125	2
Rio	070153	34R . 1% 1000m W.W.	MANN	MXI25	_
RII	011698	16 R9 1% 1/8 W 50ppm MF	HOLCO	нас	2
RIZ	011698	16 R9 1% /8W 50ppm MF	HOLCO	H&C	-
RIB	050056	IOR .25% /8W 50pm MF	HOLCO	нас	2
RIA	050056	IOR .25% /8W 50ppm MF	Halco	нвс	-
RIS	000438	4R3 5% YAW CARBON	MULLARD	CR25	2
RIG	000438	483 5% 4W CARBON	MULLARD	CR 25	- parts
RI7	018459	BR45 1% 1/8W 50ppm MF	HOLCO	HSC	2
RIS	018459	8845 1% 1/8W 50ppm MF	HOLCO	HBC	-
RIS	090081	2K NTC THERMISTOR	RHOPOINT	MSB 202K	1
R20	006751	750R 2% IW MET-0X	ELECTROSIL.	FPI	1
R21	000470	47R 5% YAW CARBON	MULLARD	CR25	
R22	000555	2K2 5% YAW CARBON	MULLARD	CR25	1
R23	015231	5K23 1% 1/8W 50ppm MF	HOLCO	нас	2

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTUREF PART No.	No. USED Per Assy.
R 24	090099-3	25 K))
R25	090099-3	IOK ATTEN SET	MANN	SEE DRG	A4 }1 SET
R26	030039-3	IOK			
R27	000125	IM2 5% YAW CARBON	MULLARD	CR25	
R28	012263	226K 1% /8W 50ppmMF	HOLCO	HBC	2
R29	063104	IOOK POT 3/8 SO CERMET	BECKMAN	72 <i>P</i>	
R30	012003	200K 1% 1/8W 50ppm MF	7	HBC	
R3I	015231	5K 23 1% 18W 50ppm MF	HOLCO	HBC	
R32	012263	226K 1% 1/8W 50ppm MF	HOLCO	HBC	_
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			<u> </u>		
NOTES.					datron ELECTRONICS LTD
SEE SHEET 2 FOR LA	ATEST ISSUE			B. JACKSON TITLE	4000/4000A
E.C.O.					FERENCE PCB ASSY
DATE				DATE DRAWII	NG 400452 R 400452A 3 OF 5

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTU PART No.	RER'S	No. USED Per Assy.
	17411 140.		WATER FROM THE STATE OF THE STA	17411 110.		
····						
		17 - 48 - 4				
CI	102470	47 F 5% SOOV CERDISC	ITT	CDIO		
C2	105551	220pf 10% SOON CER DISC	ITT	CDIO		
C3	104026	470F + 50% 500V CER DISC	SIEMENS	837449		1
				-		
10346789	210015	6V2 X 8 ZENER+RESISTOR X 2	DATRON	* INDODAYO	+ AX1755 X 2.	1 KIT
01,2,3,4,6,7,8,9.	219015-2			INASA	TAXI/DBX 2.	1
05	200008	200mA 125V LL SI DIDE	FAIRCHILD	AOCFNI		,
Q.I	240006	SI NPN TRANSISTOR	NATIONAL	2N3904	/ тогв	2
Q2	240006	SI NPN TRANSISTOR	NATIONAL	2N3904	TOIS	_
MI	260025	IOI OP AMP	NATIONAL	LM IOI AH		1
M2	260027	714 OP AMP	FAIRCHILD	MATIAHC		1.
NOTES.	<u> </u>			DATE	1.1	
				18 MAR 82	datron	ELECTRONICS LTD
SEE SHEET 2 FOR LATE	ST ISSUE			B.JACKSON	4000	D/4000A
E.C.O.					REFERENCE PO	CB ASSY.
DATE			- + - +	APPROVED	DRAWING 40045 40045	2 SHEET 4 OF 5

СНКD. J.W. 1164

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
P 1-4	604056	4 WAY -I" PCB PLUG GD PL	MOLEX	22-10-2041	1
	•				
<u> </u>	605085	4 WAY PCB SOCKET	MOLEX	22-17-2042	2
12	605085	4 WAY PCB SOCKET	MOLEX	22-17-2042	_
	410162-6	PRINTED CIRCUIT BOARD			
	450372-3	HEATSINK BLOCK			
	450373-2	HEATSINK PLATE			
	540002	22 SWG TINNED COPPER WIRE			A/R
	611004	M3XGwm POZIPAN STEEL	ZN PL		2
	G11007	M3KGmm POZI-CSK STEEL	ZN PL		2
	613029	M3 CRINKLE WASHER SS			2
	200003	HEATSINK COMPOUND	R5	554-311	A/R
NOTES.	ATEST ISSUE	1			ELECTRONICS LTD
ISS.				CHECKED 4C	00/4000A
E.C.O				APPROVED REFERENCE DRAWING 400	PCB ASSY

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RI	008021	OR47 2 2 w 5% W/W	WELWYN	W 21	3
R2	008021	OR47 2 2 4 5% W/W	ы		_
R3	090096	TS 485 THERMAL SENSOR	MICROTHERM	T5485	1
R4	008021	OR47 2 12 W 5% W/W	WELWYN	W21	-
					ļ
				,	
Q١	240027	SI NPN TRANSISTOR	MOTOROLA	MJ15001	3
Q2	240027	SI NPN TRANSISTOR	14	MJ 15001	_
Q 3	240027	SI NPN TRANSISTOR	**	MJ15001	-
Q4	NOT USED.				
Q 5	240014	SI NPN TRANSISTOR	NATIONAL	BC 337/ TO 18	ı
					. /-
	590004	SLEEVE PTFE	HELLERMANN ELECTRIC	FEID	A/R
	530001 920087-1	SLEEVE MAX CABLE \$ 3-0	HELLERMANN ELECTRIC	HIS X 20mm BLACK HELSYN	4
		TRANSISTOR HEATSINK	SEE DEG.		1
	410166-4	HEATSINK P.C.B			1
	450279-	HEATSINK			l
NOTES.			DATE	datasa	
SEE SHEET 2 FOR LAT	FST ISSUE			r-2-81 datron	ELECTRONICS LTD
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E.C.O BELE			APPRO	POSITIVE HEAT	SINK ASSY
			1 1 1	DRAWING	SHEET

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	540002	22 SWG TINNED CU WIRE			A/R
	530000	24/-2 WIRE BLACK		Ī	170mm
	530222	" RED			150mm
	530444	" YELLOW			170mm
	530555	" GREEN			195 mm
	900005	HEATSINK COMPOUND	R5	554-311	AIR
	530777	24/0.2 WIRE VIOLET			195mm
	530889	" GREY			195 mm
	530999	" WHITE			330mm
	605101	13 WAY CRIMP TERMINAL	HOUSING + LOCKING RAMP	09-91-1301	- 1
	605077	GOLD CRIMP	MOLEX	2478 GL	8
	611017	M3 X 16 POZIPAN SCREW	GKN	ZINC PLATED	5
	611027	M3 X 20 POZIPAN SCREW	at a	gd go	2
	612004	M3 X 4 STANDOFF	HARWIN	C5 2116 / B	6
	612022	M3 X 3 STANDOFF	SEE DRG.		2
	6/3005	M3 INT SHAKEPROOF ST	GKN DISTRIBUTORS	ZINC PLATED	8
	613007	M3 FLAT STEEL WASHER	30 80	D	10
	615002	MS HEX NUT STEEL	pr 54	Ď0	3
	618008	INSULATING BUSH	ASSMANN / MULLARD	105 358 / 56201 6	2
	611006	MSX 10mm POZI-PAN SCREW	GKN	ZINC PLATED	1
-	620003	SOLDER PIN	HARWIN	H2105A	8
	630126	CABLE CLIPS 7-9 DIA	RICHCO	N5	1
IOTES. EE SHEET 2 FOR LA	ATEST ISSUE				ELECTRONICS LTD
ISS.			CHECK	4000 POWE	R AMPLIFIER ATSINK ASSY
DATE			AFTH	DRAWING NUMBER 4004	54 3 OF 3

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
RI	000101	IOOR 5% 14 W CARBON	MULLARD	CR25	2
R2	008037	ORIB 10% 212W WIREWOUND	WELWYN	WEI	2
R3	008037	OR18 " " "		te .	-
R4	000101	IOOR 5% 1/4W CARBON	MULLARD	CR25	-
K 5	090098	NTC THERMISTOR (85°C)	MICRO THERM	T5 485	
RG	000102	IKO 5% WW CARBON	MULLARD	CR25	1
R 7	000220	22R 11 44 11	60	**	1
CI	104025	100 nf +80% 50V CER DISC	ITT	552	1
CZ	180045	47 MF GOV AL ELECT.	MULLARD	031-38479	1
C3	104026	47 nF + 50 % 50V CER DISC	SIEMENS	637445	5
C4	104026	47nF " " "	96	**	_
Q1	240036	SI NPN DARL TRANSISTOR	MOTOROLA	W11000	
Q2	250024	SI PNP DARL TRANSISTOR	18	W1300	1
Q3	240035	SI NPN DARL TRANSISTOR	et	W111010	1
Q4	250023	SI PNP DARL TRANSISTOR	u	M 111015	1
Q 5	240001	SI NPN TRANSISTOR	NATIONAL	BCIB4/TOIB	2
Q6	250001	SI PHP TRANSISTOR	NATIONAL	6C214/TO18	1
Q7	240001	SI NPN TRANSISTOR	NATIONAL	BCI84/TDI8	-
NOTES. SEE SHEET 2 FOR L	ATEST ISSUE		Di	BJACKSON TITLE	ELECTRONICS LTD
E.C.O R.	BLEASED 0-482		^	PPROVED 3 MAN DRAWING ATE 23.4.82 NUMBER 40045	SINK ASSY

DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	530000	24/2 WIRE BLACK			355 mm
	530111	" BROWN	J	i i	865 mm
	530222	" RED			860mm
	530333	" ORANG	E		305mm
	530444	" YELLO	w		375 mm
	530555	" GREEN			170 mm
	530666	" BLUE			125 mm
	530777	" VIOLET			170 mm
	530666	" GREY			170mm
	530999	" WHITE			290 mm
	605099	5 WAY 0-156 CRIMP	TERMINAL HOUSINGT RA	MP 09 91 050) i
	605100	3 WAY 0-156 CRIMP	TERMINAL HOUSING + RA	MP 09 91 090	2
	605077	GOLD GRIMP	MOLEX	2478-GL	16
	612022	M3X3 STANDOFF	SEE DRG.		6
	611017	M3 X 16 POZ IPAN SCI	REW GKN DISTRIBUTORS	ZINC PLATED	. 4
	611027	M3X 20 POZIPAN	11 11 11	41 1/	4
	613005	M3 INT SHAKEPROO	F ST GKN DISTRIBUTORS	ZINC PLATE	ED 8
	613007	M3 FLAT STEEL	м		10
	615002	M3 HEX NUT STEEL	a r	4 11	4
	618008	INSULATING BUSH	ASSMANN/ MULLARD	105 358 / 5	620IC 8
	616009	TO3 SIL PAD	WARTH INTERNATIONAL.	3225 -07 FR -	06 4
	620003	SOLDER PIN	HARWIN	H2105A	16
	630126	CABLE CLIP 7.9	DIA RICHCO	N5	2
IOTES. EE SHEET 2 FOR LA	ATEST ISSUE	•		DRAWN TITLE	latron ELECTRONICS LTD
ISS.				CHECKED	O POWER SUPPLY / RENT HEATSINK ASSY

Per Assy. 1 500 mm HELS YN 8 1
500mm
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DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
R1, R2	008021	OR47 2 w 5% W/W	WELWYN	W 21	3
R3	090098	TS 485 THERMAL SENSOR	MICROTHERM	T5485	1
R4	008021	0R47 2½w 5% W/W	WELWYN	W21	-
QI	250017	SI PNP TRANSISTOR	MOTOROLA	MJ 15002	3
92	250017	SI PNP TRANSISTOR	MOTOROLA	MJ 15002	_
Q3	250017	SI PNP TRANSISTOR	MOTOROLA	MJ 15002	-
					
	19%				
	410166-4	HEATSINK P.C.B			1
	450279-1	HEATSINK			1
	530000	24/-2 WIRE BLACK			170 mm
	530222	" RED			150 MM
NOTES.					RELECTRONICS LTD
ISS. C I			C	HECKED 750 NEGATIVE H	R AMPLIFIER JEATSINK ASSY
DATE 5-8-81 19-4-	-62			DRAWING NUMBER 4004	2 SHEET

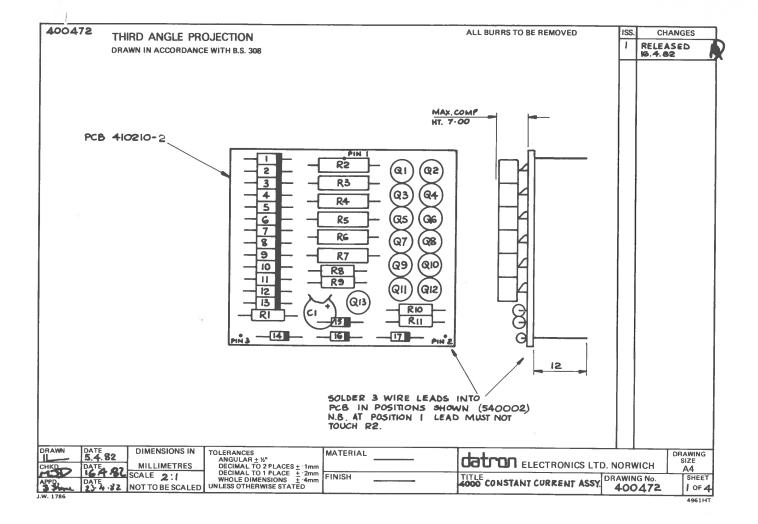
DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACT PART No.	TURER'S	No. USED Per Assy.
	530444	24/-2 WIRE YELLOW				170 mm
				i		
	530999	24/-2 WIRE WHITE				330mm
	605100	9 WAY 0-156 CRIMP TERM	NAL HOUSING + RAMP	09 - 9	1-0901	f
	605077	GOLD CRIMP	MOLEX	2476	÷L	5
	611017	M3XI6 POZIPAN SCREW	GKN	ZINC	PLATED	6
	611027	M3 X 20 POZIPAN SCREW	60	••	44	1
	612004	M3X4 STANDOFF 1/6" PCB	HARWIN	C52116	/ B	6
	612022	M3 X 3 STANDOFF 1/6" PCB	SEE DRG.			2
	613005	M3 INT SHAKEPROOF ST	GKN DISTRIBUTORS	ZINC PL	ATED	8
	613007	M3 FLAT STEEL WASHER	0.0	3+		10
<u> </u>	618008	INSULATING BUSH	ASSMANN / MULLARD	105 358	/56201C	2
	611006	M3XIONN POZIPAN SCREW	GKN	ZINE P	LATED	1
	620003	SOLDER PIN	HARWIN	H2105 A		5
	630004	CABLE CLIP 6-4 DIA	RICHCO	N4		1
	540002	225WG TINNED CU WIRE				A/R
	61500 2	NUT MS FULL HEX STEEL		ZINC P	LATED.	2
	530001	SLEEVE MAK CABLE & 3-0	HELLERMAN ELECTRIC	HI5 X 20	mm BUK HELSYN	3
	590004	SLEEVE - PTFE	11 11	FEIO		A/R
	300003	HEATSINK COMPOUND	R5	554-31)		A/R
NOTES.				DATE 14-7-61	datron	FLECTROMICS LTD
SEE SHEET 2 FOR L	ATEST ISSUE			DRAWN K	4000 POWER	AMPLIFIER
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CHKD.	+ +	 		DATE	NUMBER 400461	3 OF 5

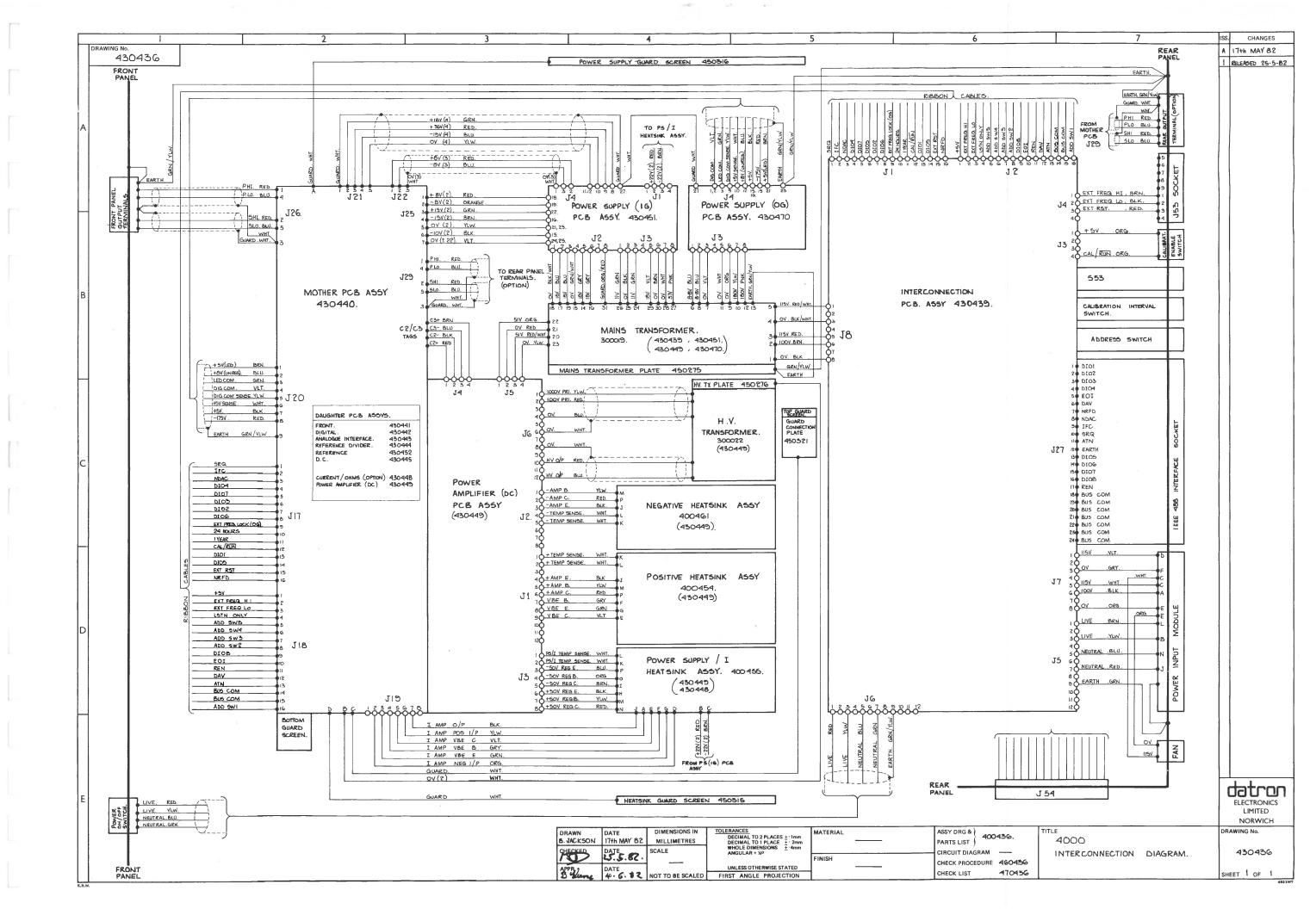
DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACT	TURER'S	No. USED Per Assy.
RI	008024	0R27 10% 212W WW	WELWYN	WZI		1
R2	000330	33R 5% 4W CARBON	MULLARD	CR25		1
R3	000102	IKO 5% 4W CARBON	MULLARD	CR25		3
R4	000182	IK8 5% 4W CARBON	MULLARD	CR25	· · · · · · · · · · · · · · · · · · ·	i
R5	013922	39K21% % W 50 ppm MF	HOLGO	HSC		1
R6	013742	37K41% % W 50 PPM MF	HOLCO	H#C		1
R7	100000	PTC THERMISTOR	MULLARD	V A8 65	0	ı
Rô	000470	47R 5% 4 W CARBON	MULLARD	CR25		2
R9	000470	47R 5% 4 W CARBON	MULLARD	CR25		-
RIO	011003	100k 1% 18 w 50 ppm MF	HOLCO	HAC		2
RII	011003	100k 1% 18 W 50ppm MF	HOLCO	HEC		_
R 12	066205	2M POT % SQ VERT CERM	ET BECKMAN	72×W		1
R 13	001184	IBOK 5% ZW CARBON	MULLARD	CR 37		1
R 14	000102	IKO 5% 4W CARBON	MULLARD.	CR25		-
R15	000102	IKO 5% 4w CARBON	MULLARD	CR25		
R 16	000221	2208 5% 4 W CARBON	MULLARD	CR25		1
R17	008022	OR 27 10% 2W MF	RS	147-525	5	2
RIS	008022	OR 27 10% 12 W MF	RS	147-525	5	-
R19	000104	100K 5% 4W CARBON	MULLARD	CR25		ı
R20	000221	22085% 4W CARBON	MULLARD	CR25		1
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	2 3 4 14.1324 1447 1468/1476			DRAWN & CHECKED APPROVED	datron 4000 out POWER SUP	GUARD
	.5.62 14-3-63 8-4-83 12	AD A0		DATE 97. 3.62	DRAWING NUMBER 40047	2 SHEET

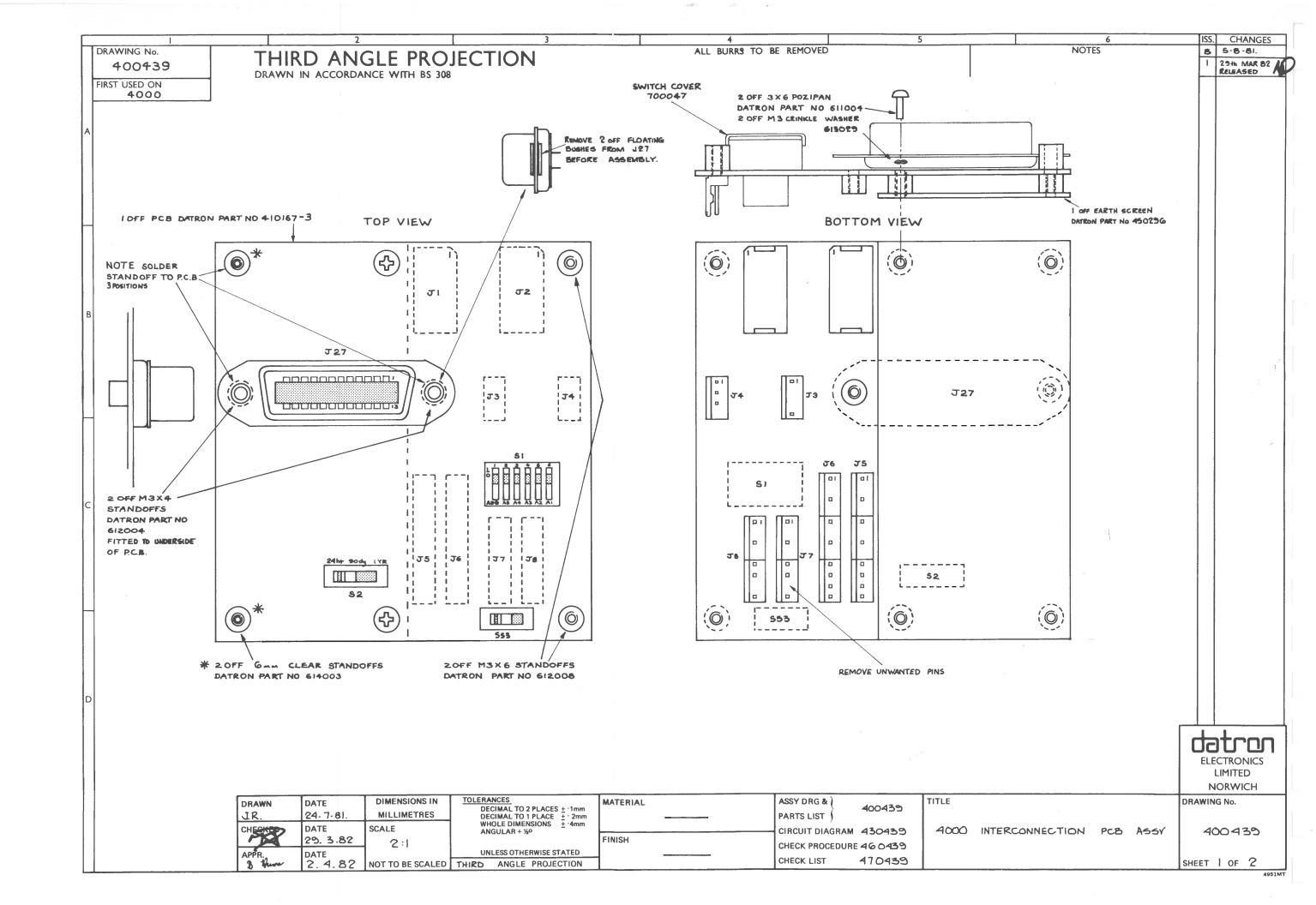
DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTI PART No.	URER'S	No. USED Per Assy.
CI		NOT USED				
C2	150016	INF 20% 35V DIP TANT	UNION CARBIDE	KIROES	5	1
СЗ		NOT USED		1		
C4	150017	100 pf 20% 16 V DIP TANT	UNION CARBIDE	KIOOEI	6	ı
C5	180004	4700pF 16 V AL. ELECT.	WIMA	PRINTIL	-YTI	5
C 6	101103	10nf 25% 250v CER DISC	ITT	CDIO		ı
C7	180026	10pf 350v ALELECT.	ITT	EN12.12	10/350	1
CB	104030	100 F 10%4KV CERDISC	ITT	HDIE		1
ငၶ	120032	100 AF 10% IGOV POLYCARE	ASHCROFT	A28 3321	8	1
C10	110004	47nf 20%250v POLYESTI	R MULLARD	C280A	EP47K	1
) I	200022	3A 400V GP SI DIODE	MOTOROLA	BY252		2
02	200 0 2 2	3A400V GP SI DIODE	MOTOROLA	BY252		~
3	210027	2v7 400 MW ZENER	MULLARD	BZY88C	2V7	l.
04	214012	2V45 30ppm ZENER	FERRANTI	ZN458		1
5	213006	5v 5w ZENER	UNITRODE	TV8 50 5	5	1
)6	210068	646400MW ZENER	MULLARD	5ZY860	26V8	1
D7	213004	180V ZW ZENER	MOTOROLA	IN5279	В	1
IOTES.	12			DATE		
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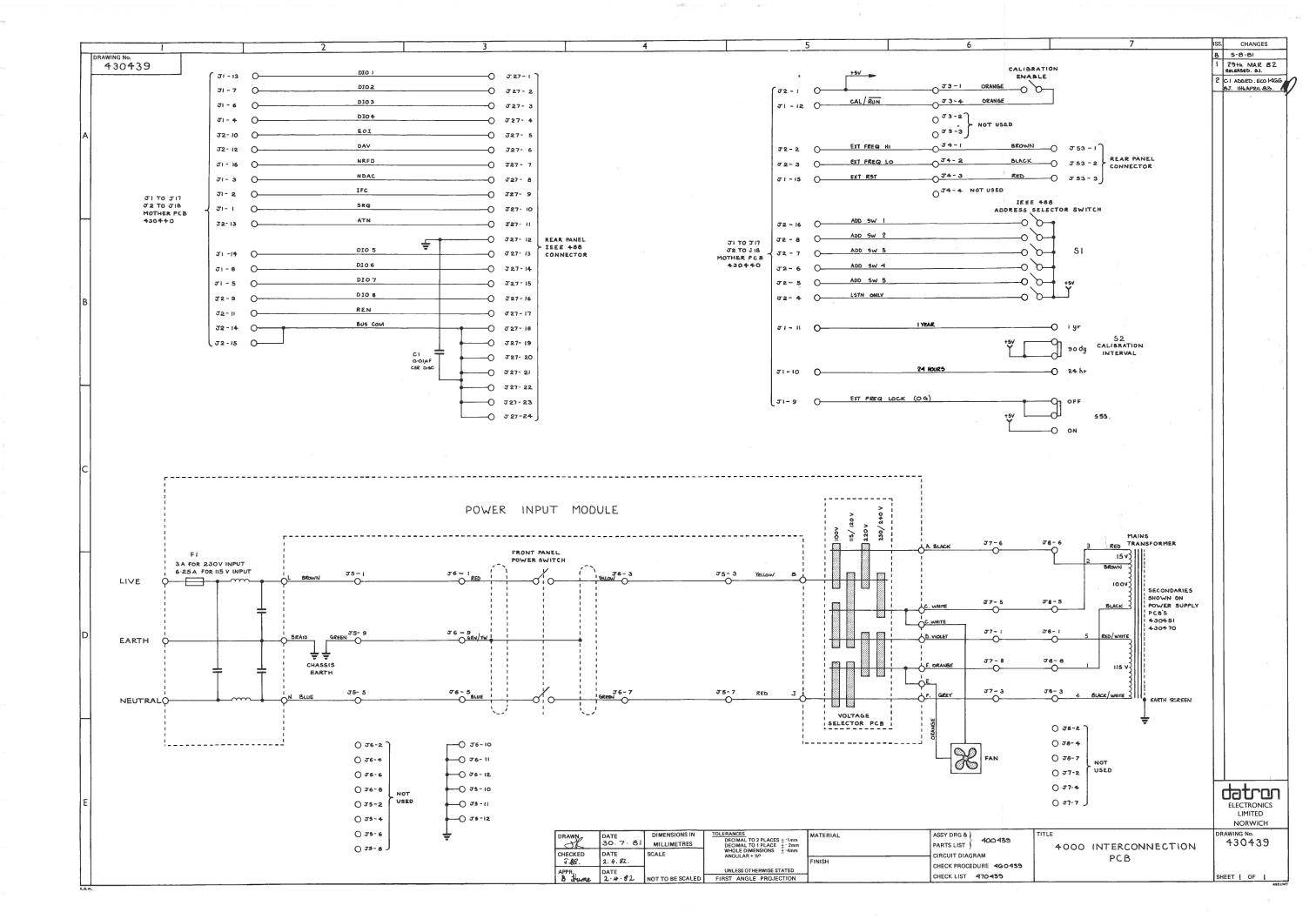
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DEDION (TOT	DATEON				
DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
QI	250011	SI PNP TRANSISTOR	NATIONAL	BC 327/TO18	ł
Q2	240024	SI NPN TRANSISTOR	NATIONAL	TIPSIA	ſ
QЗ	240018	SI NPN TRANSISTOR	MOTOROLA	MJE340	2
Q 4	240018	SINPN TRANSISTOR	MOTOROLA	MJE340	_
Q5	250016	SI PNP TRANSISTOR	MOTOROLA	MJ2955	2
Q6	250016	SI PNP TRANSISTOR	MOTOROLA	MJ2955	-
МІ	260061	3140 OP AMP	RCA	CA3140E	1
V.				· · · · · · · · · · · · · · · · · · ·	
WI	209013	IAS 600V BRIDGE RECT	MICRO-ELECTRONICS	W006	. 1
FI	920128	4A FUSE 20mm SLO-B	BELLING LEE	L2080A/4	1
	410179-3A	P.C.B			
			<i>E</i> .		1 10
	540002	22 SWG TINNED CU WII		100 70 0000	A/R 2
	604042		RAMP GOLD MOLEX	09-12-2041	
	605059	6 WAY DIL SOCKET			1
	611006	M3X10mm POZIPAN SCR			6
	611004	M3 X 6 mm POZIPAN SCR	EW GKN		3
NOTES.			DATE	-11-01 datron	ELECTRONICS LTD
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1		·		POWER SUP	DIV ACEV
E.C.O.			APPI	DRAWING NUMBER 40047	

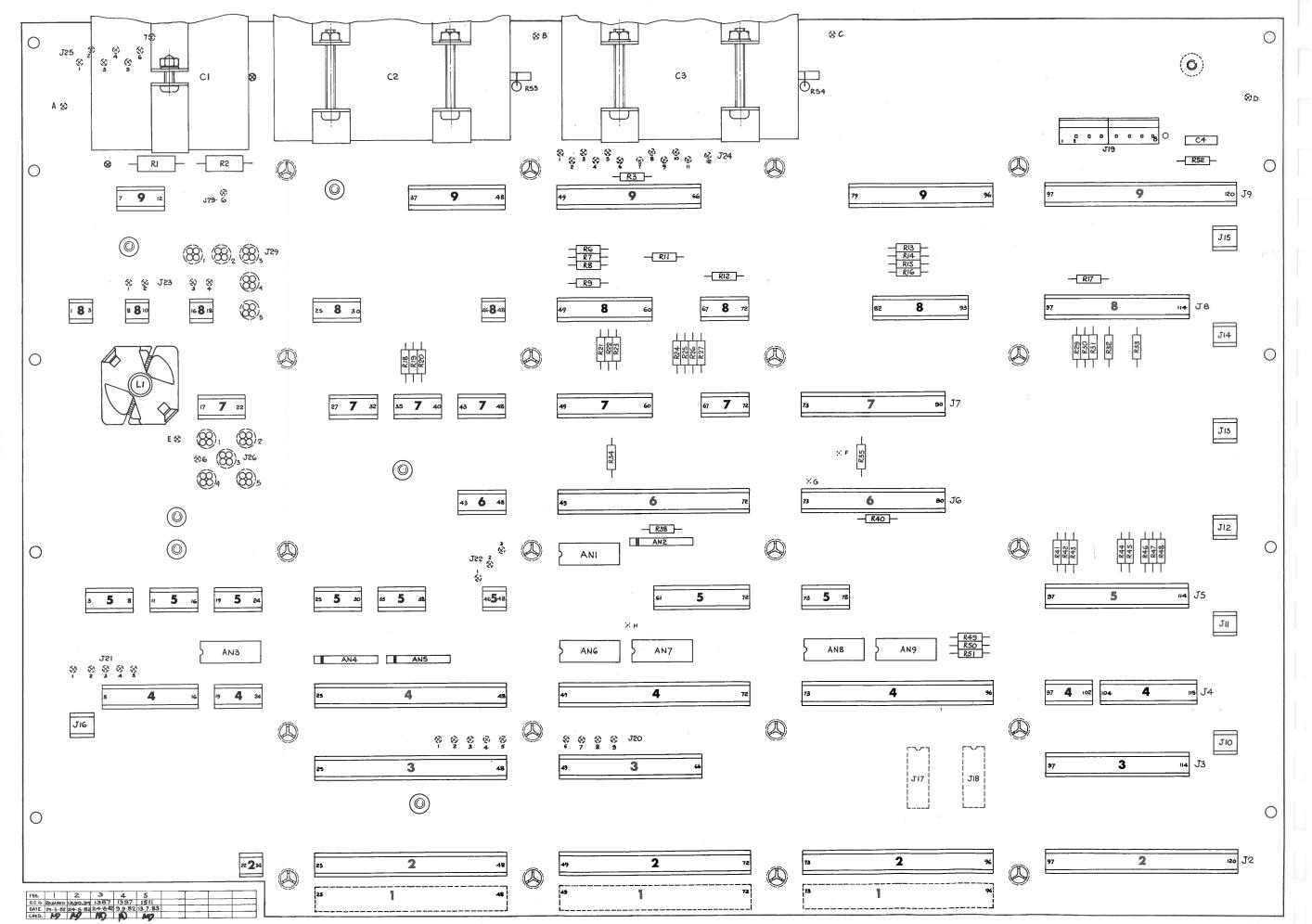
DESIGNATOR	DATRON PART No.	DESCRIPTION	PRINCIPAL MANUFACTURER	MANUFACTURER'S PART No.	No. USED Per Assy.
	613005	M 3 SHAKEPROOF WASHE	R GKN		9
,	613007	M3 FLAT STEEL WASHER	GKN		3
	615002	M3 STEEL HEX NUT	GKN	1	9
	630024	STEATITE BEAD 165WG	PARK ROYAL PORCELAIN	Nos	6
	900003	HEAT SINK COMPOUND	RS	554-311	A/R
	920088-1	TO-3 HEATSINK	SEE DRG		2
	1-060026	2X TO 220 HEATSINK	SEE DRG		2
,	920126	FUSE HOLDER PCB MT	BELLING LEE	L1426	- 1
	900004	SILICONE RUBBER COM	POUND RS	555-588	A/R
	590004	PTFE SLEEVE	HELLERMANN ELECTRIC	-	A/R
	620007	TEST POINT TERMINAL	MICROVAR	C30	7
		-			
		-			-
					-
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10123 .			DATE 16	-11-81 datron	ELECTRONICS LTD
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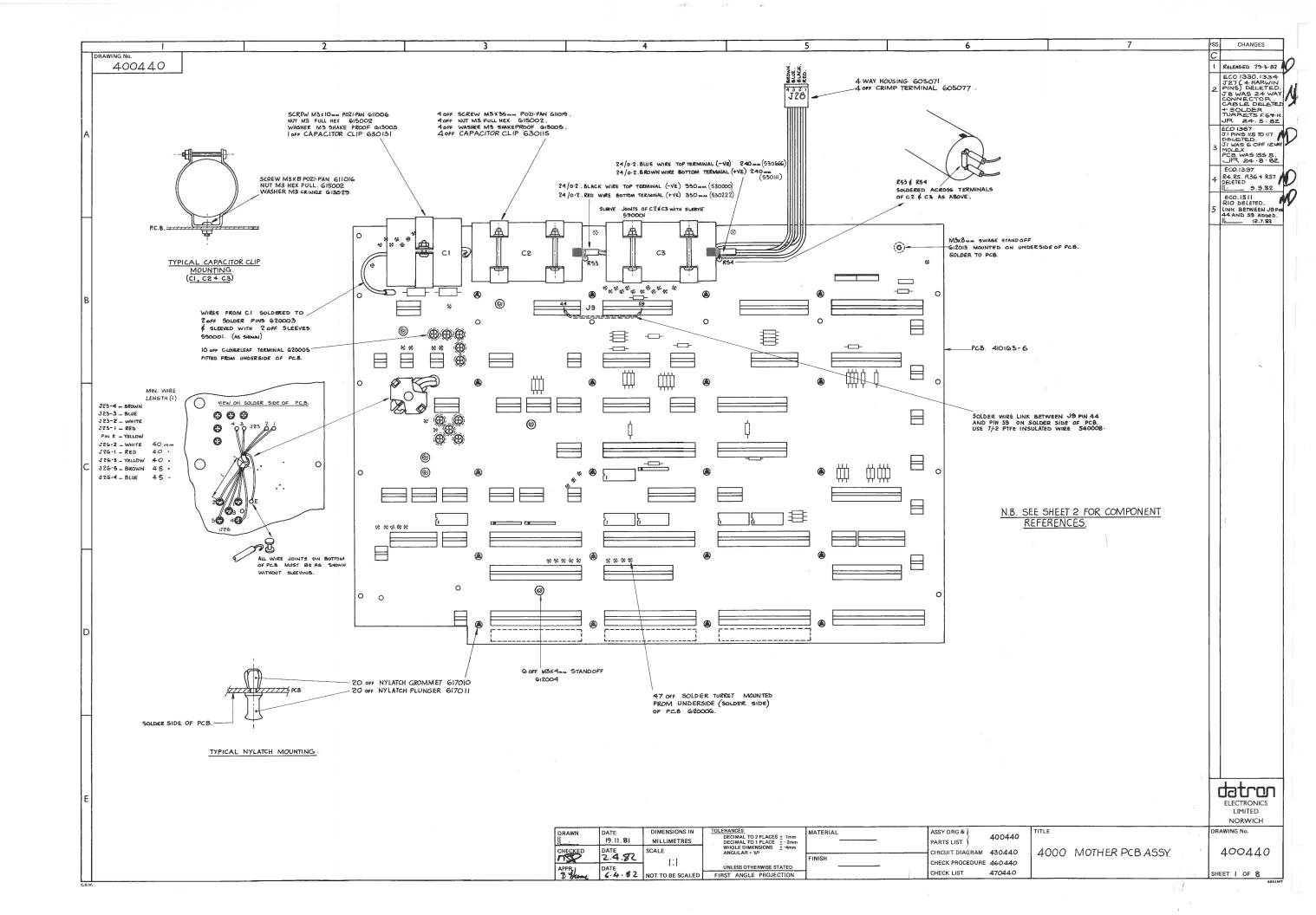


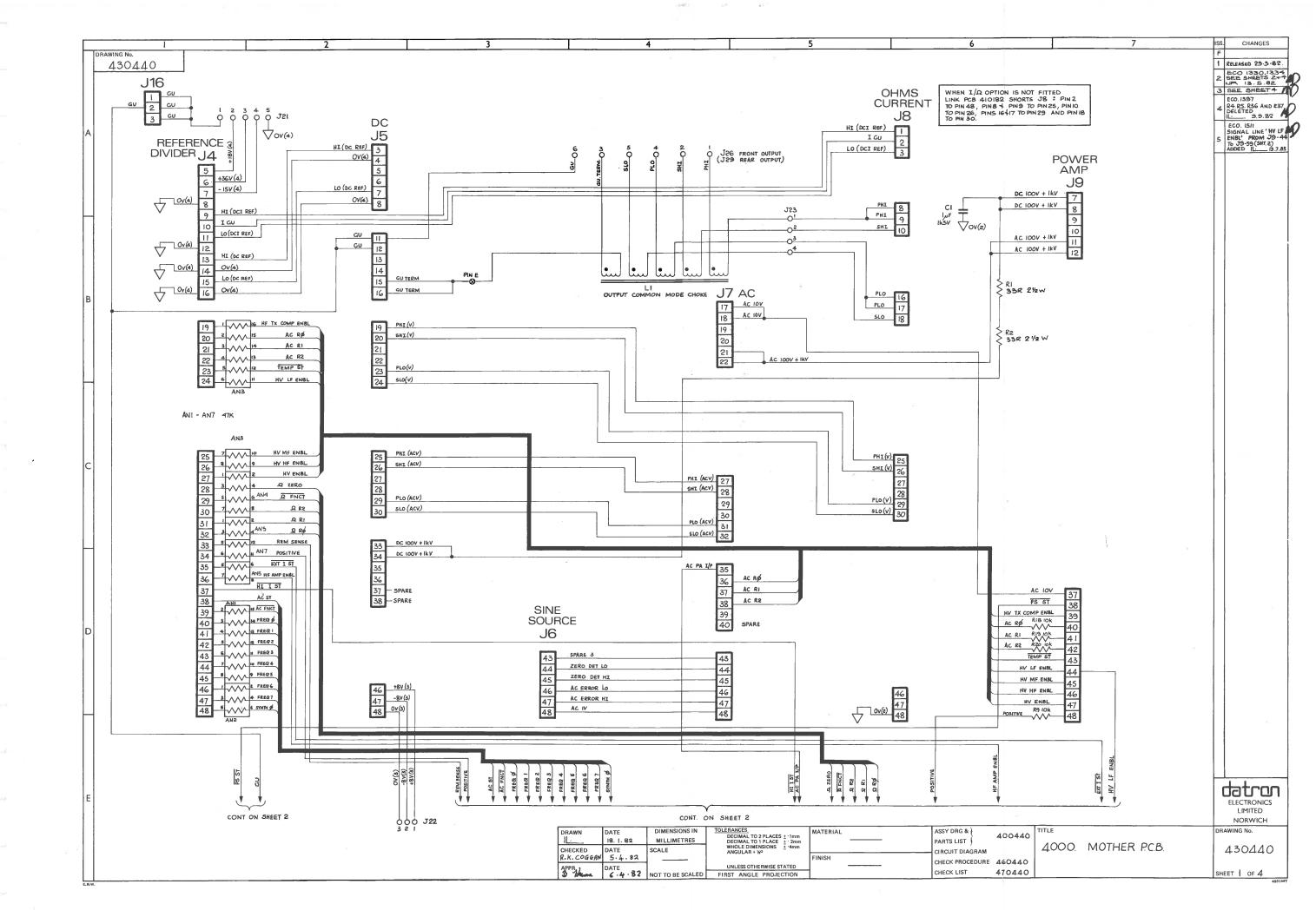


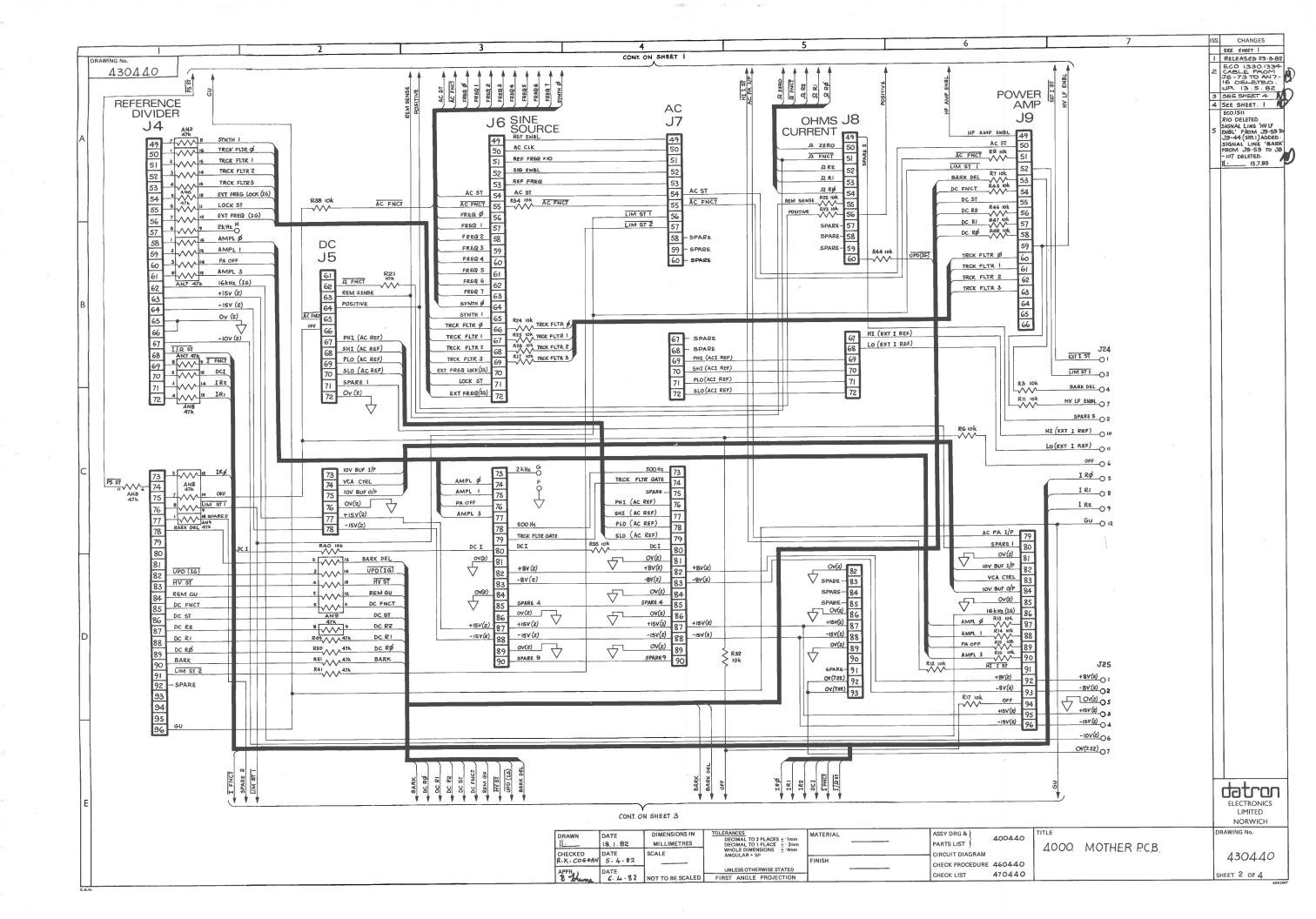


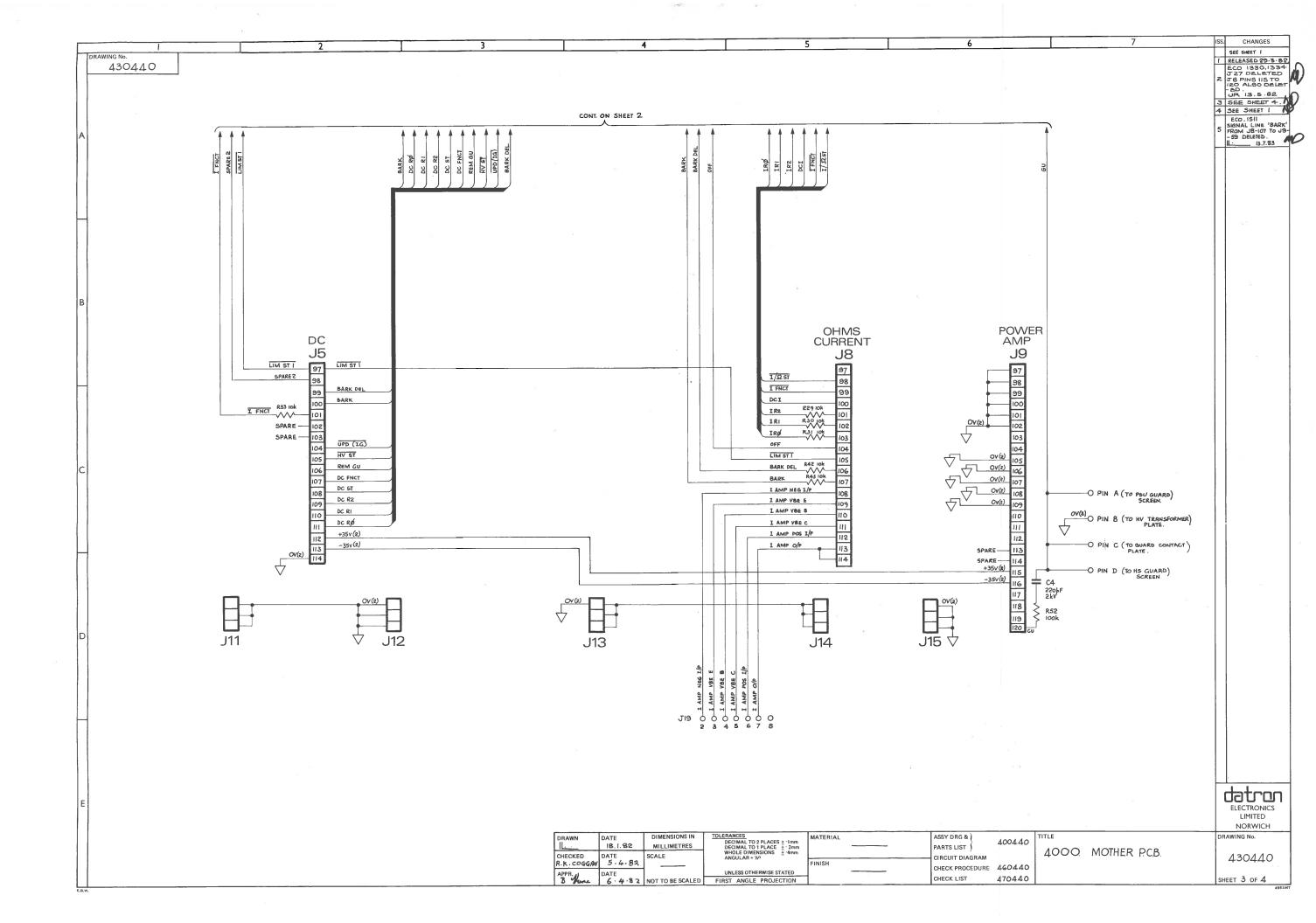


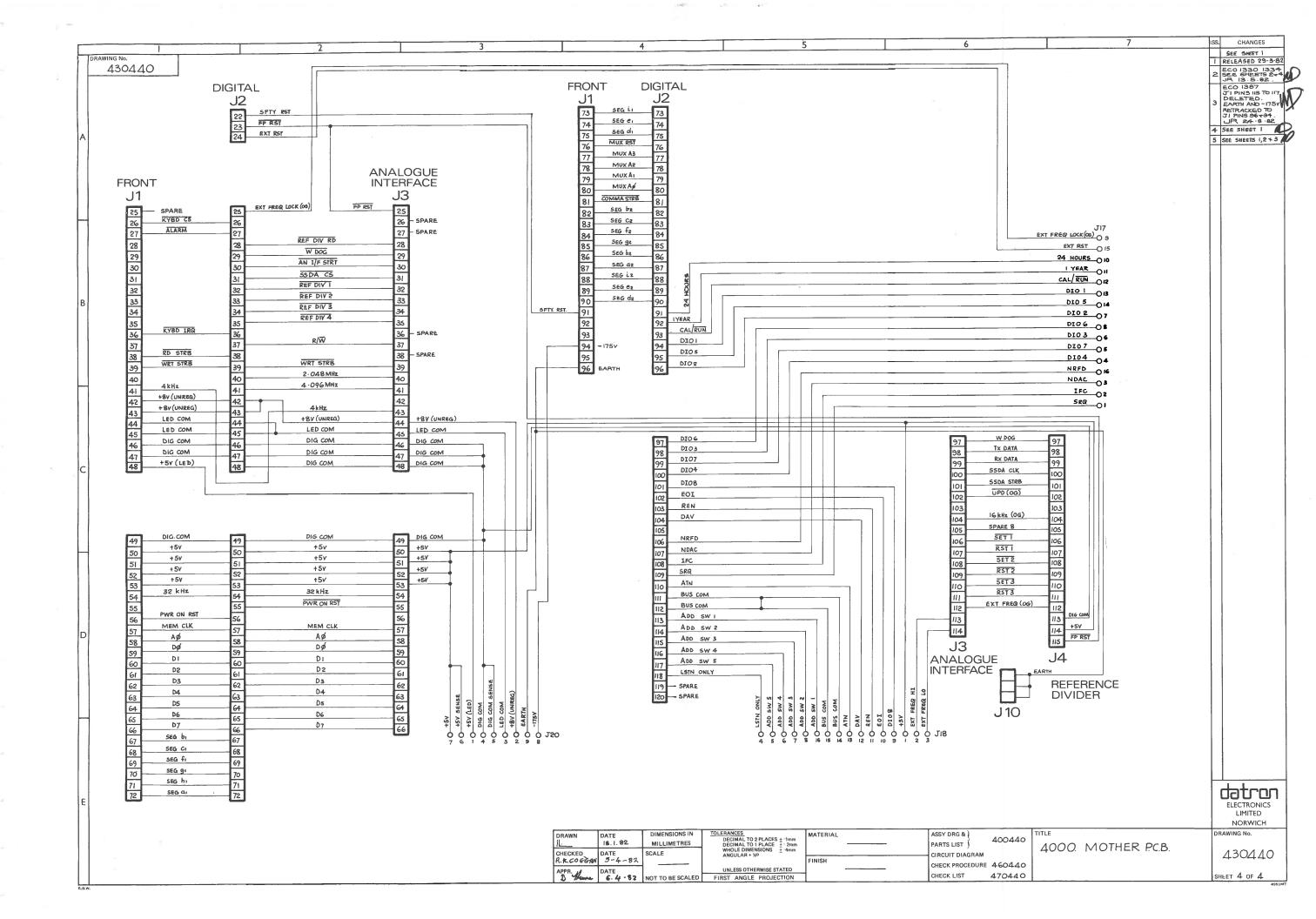


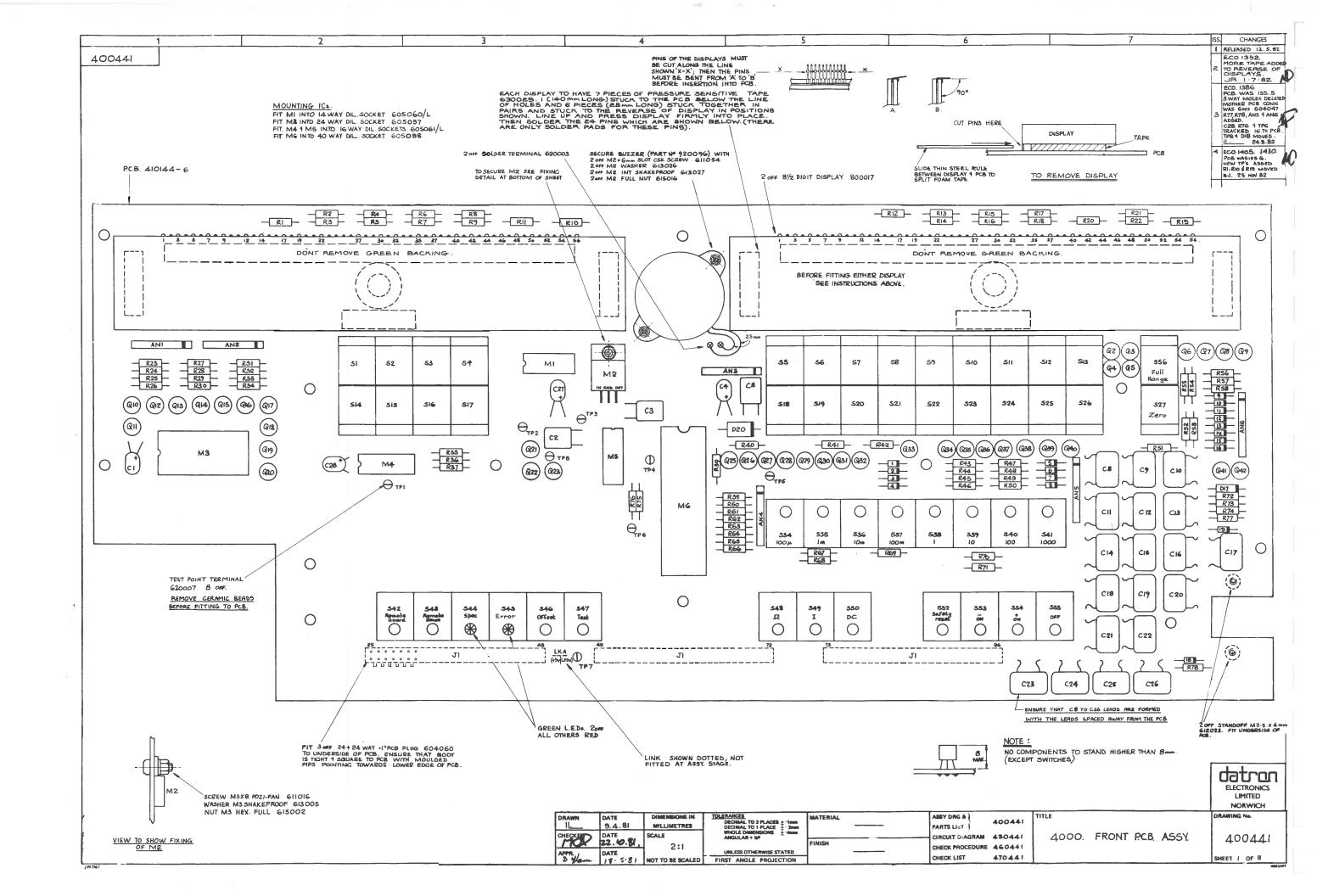


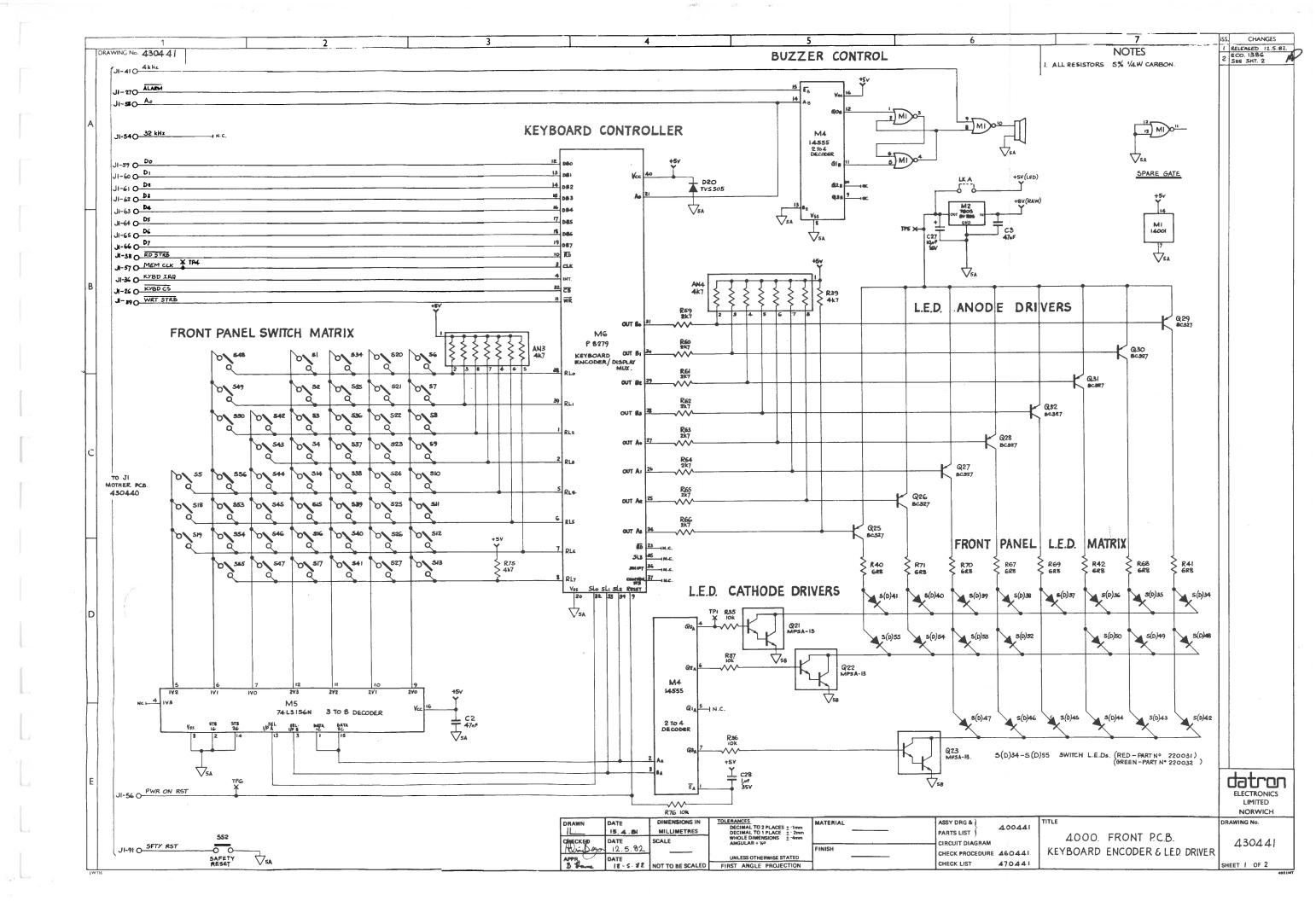


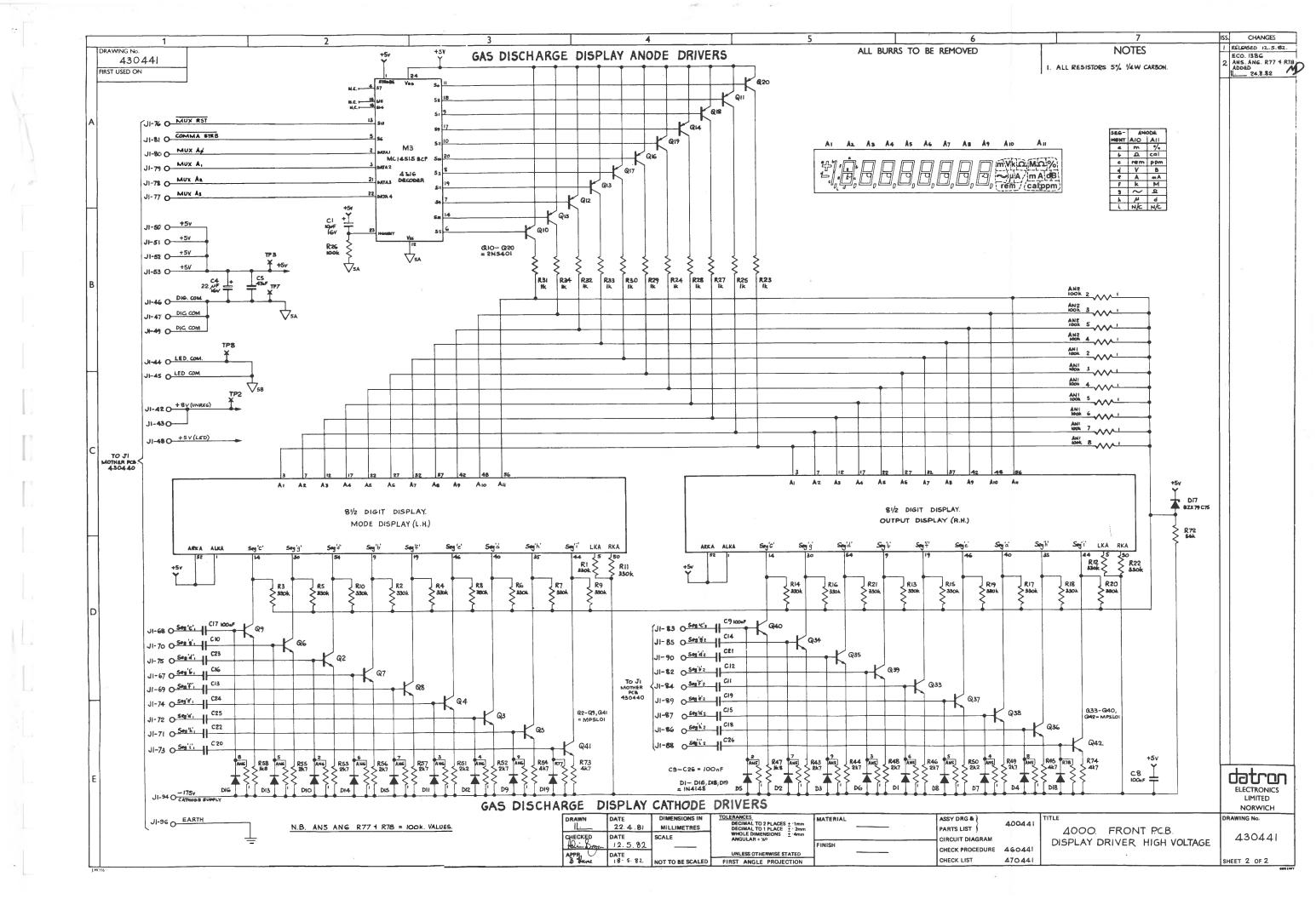


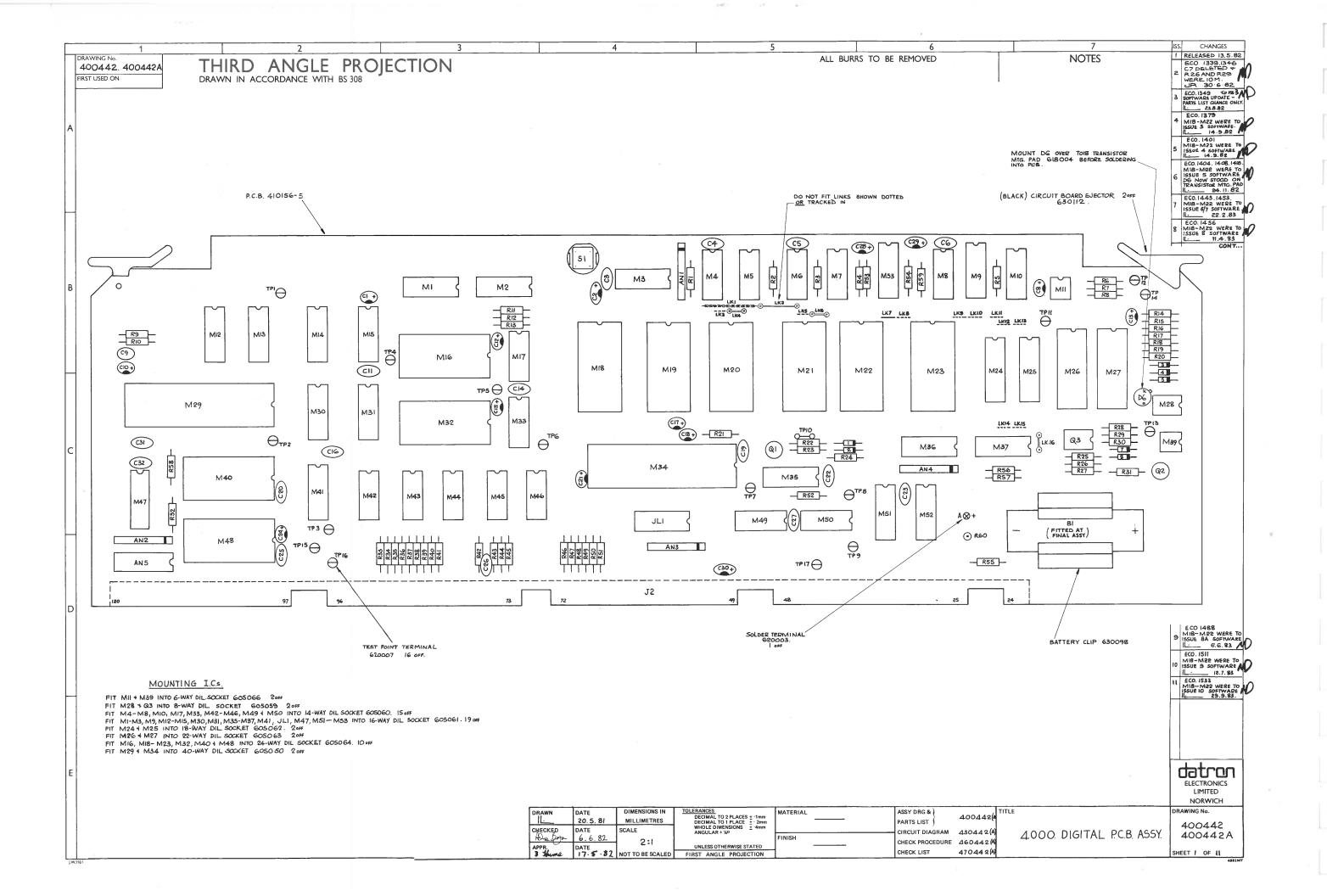


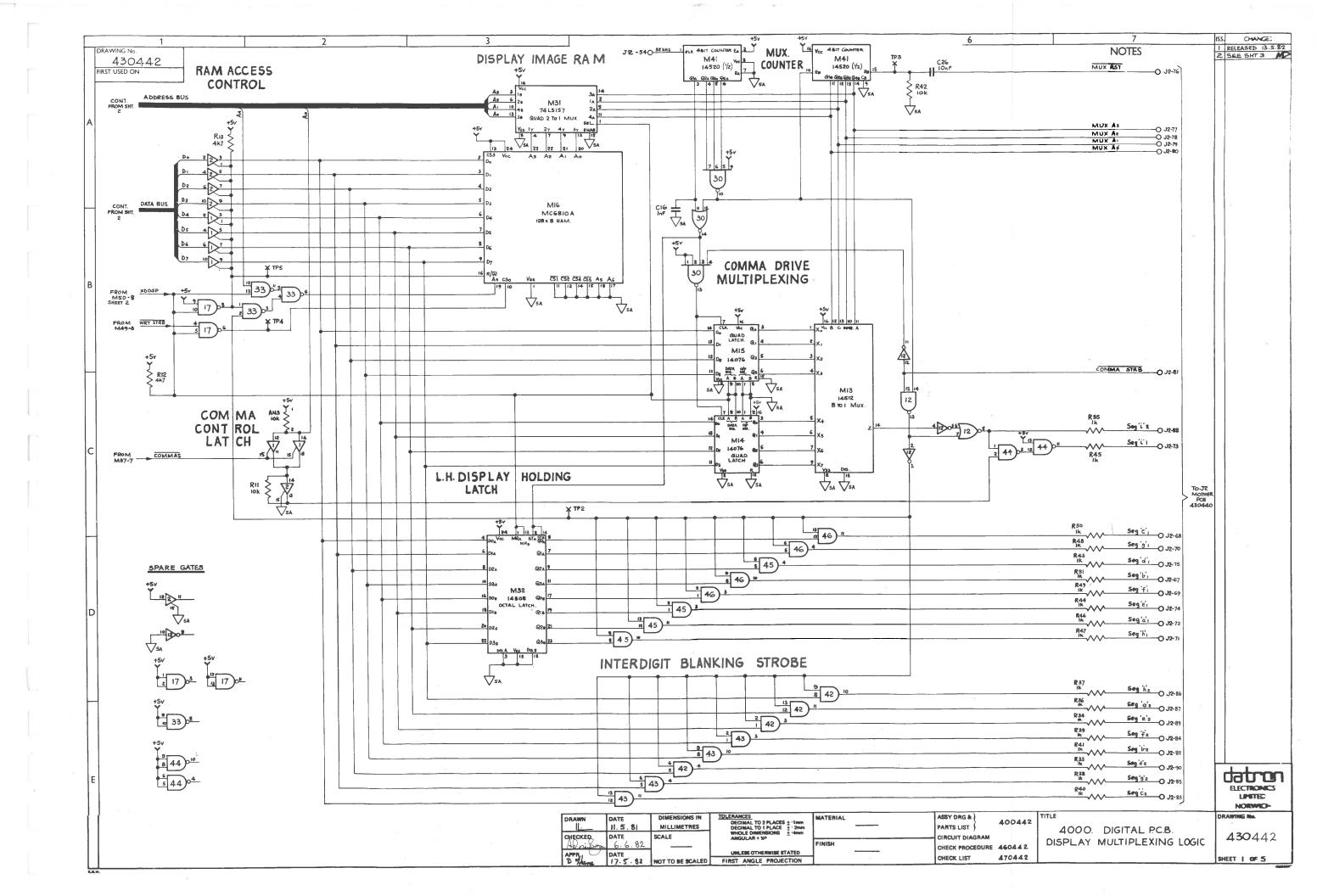


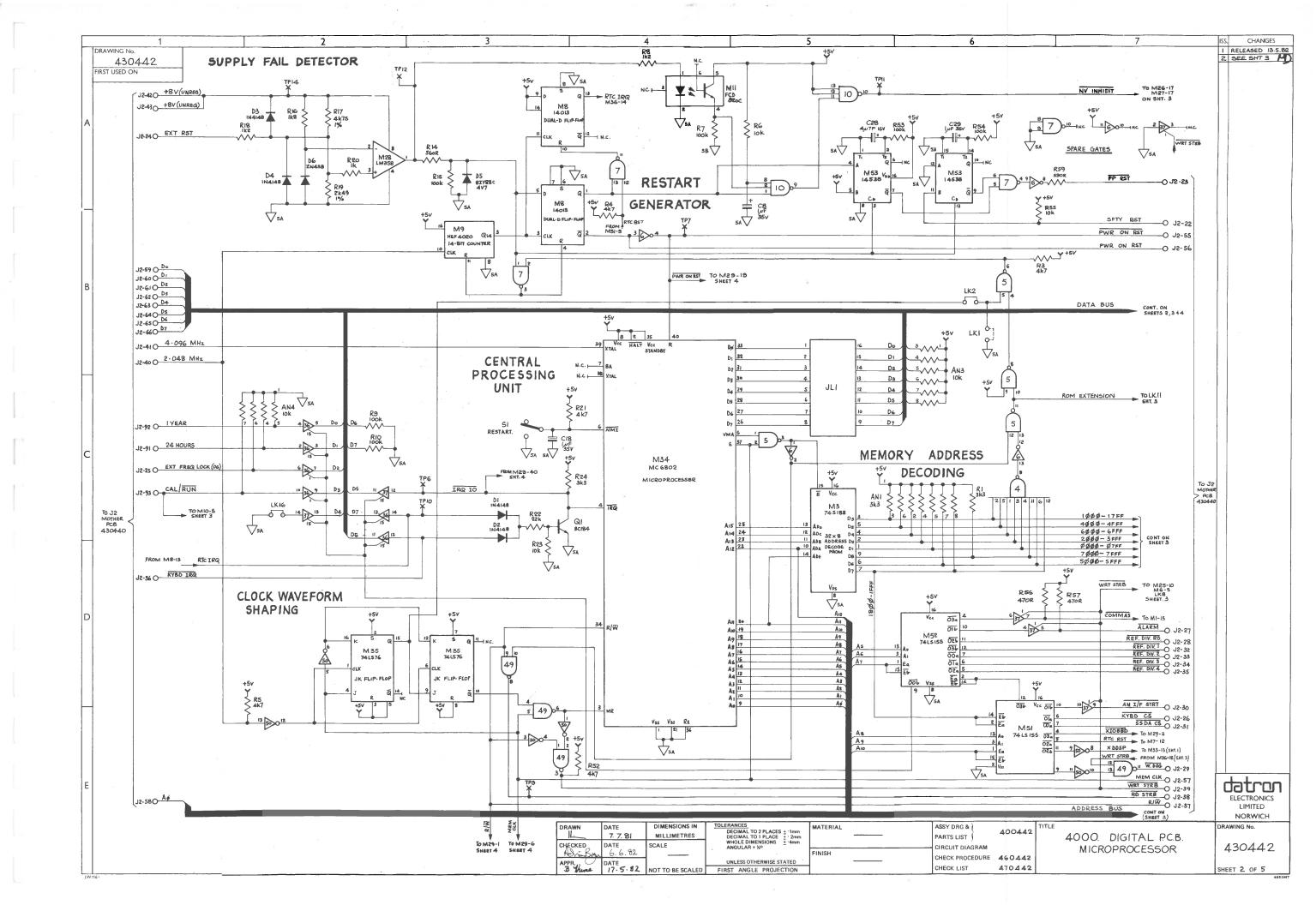


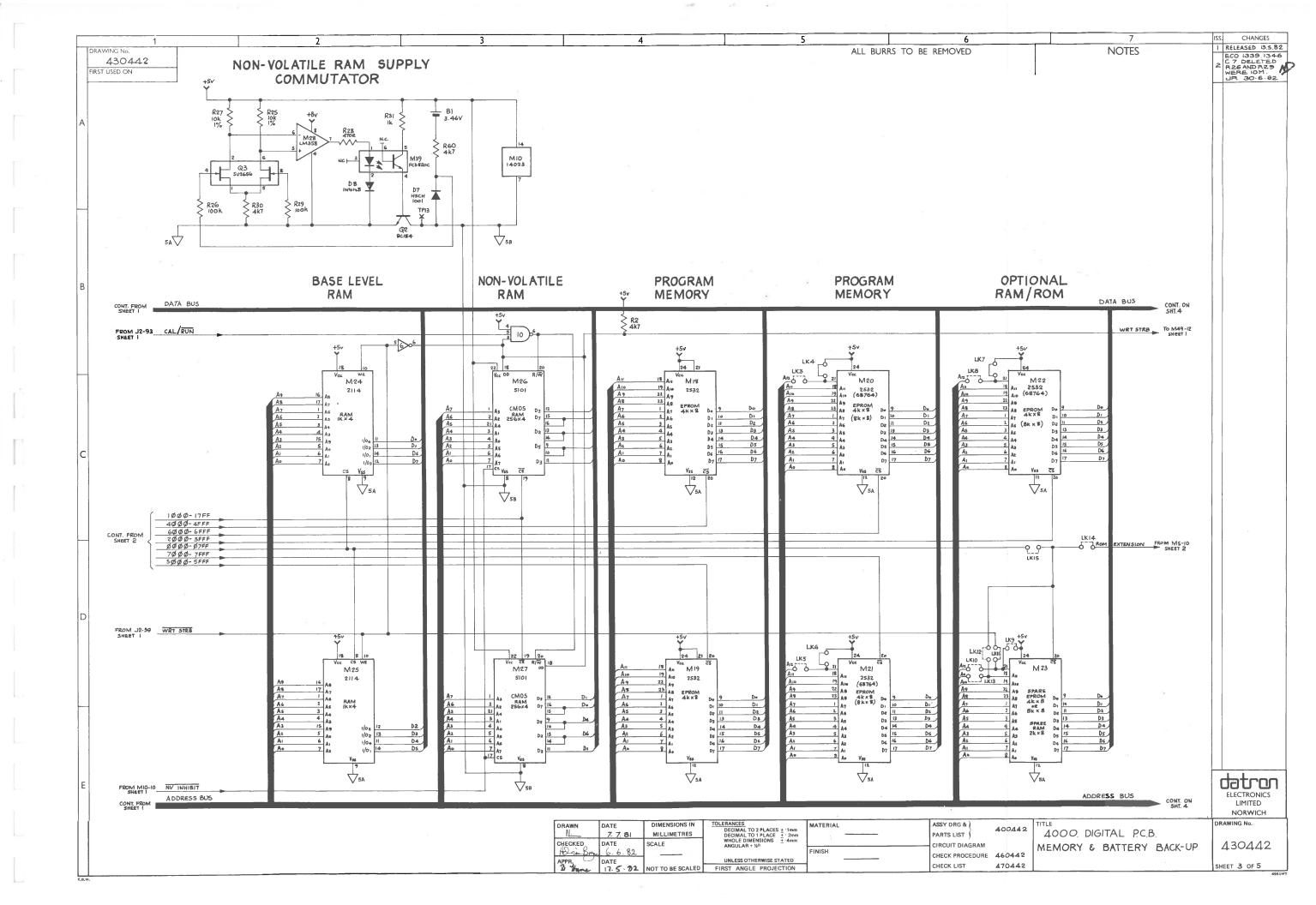


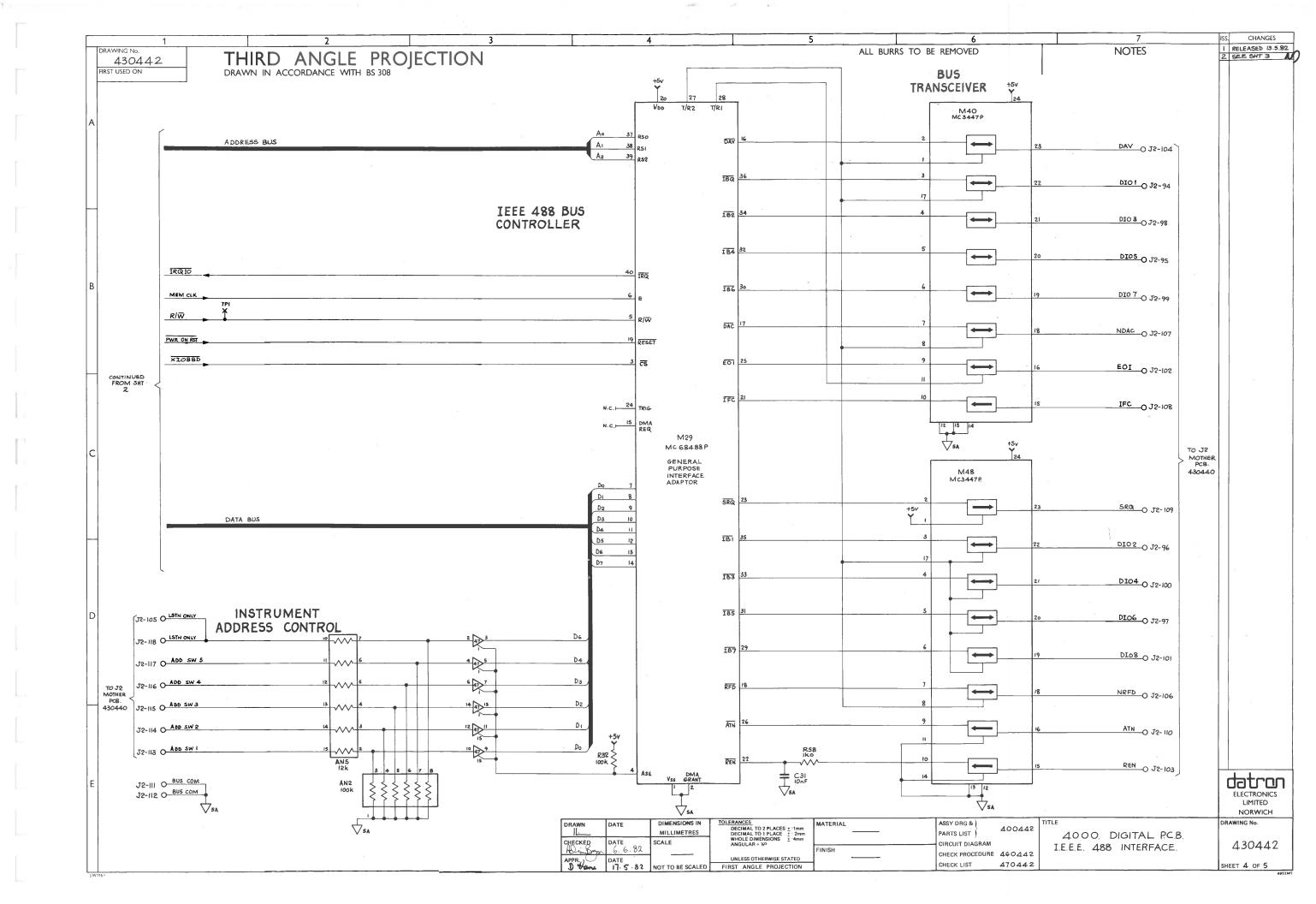


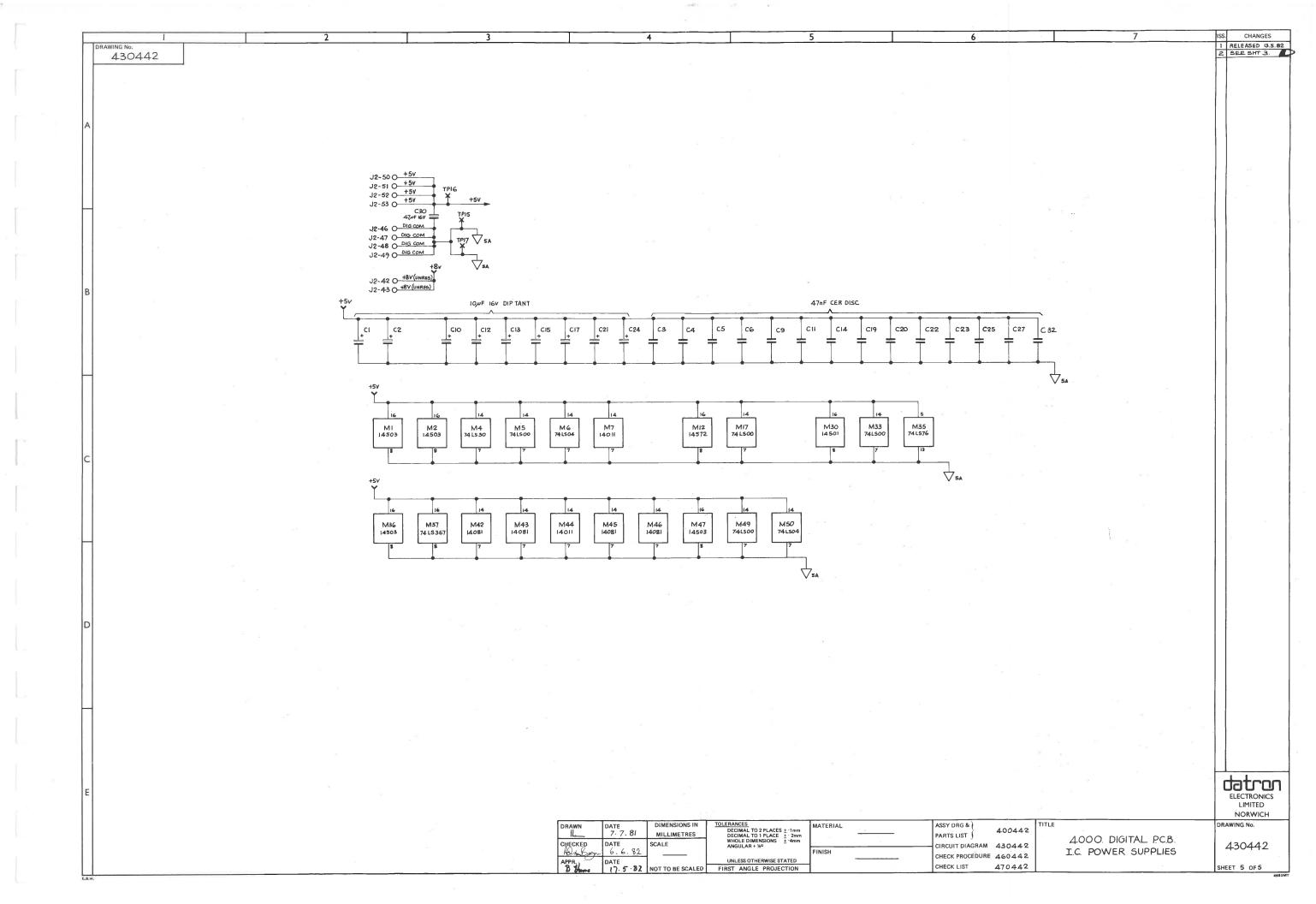


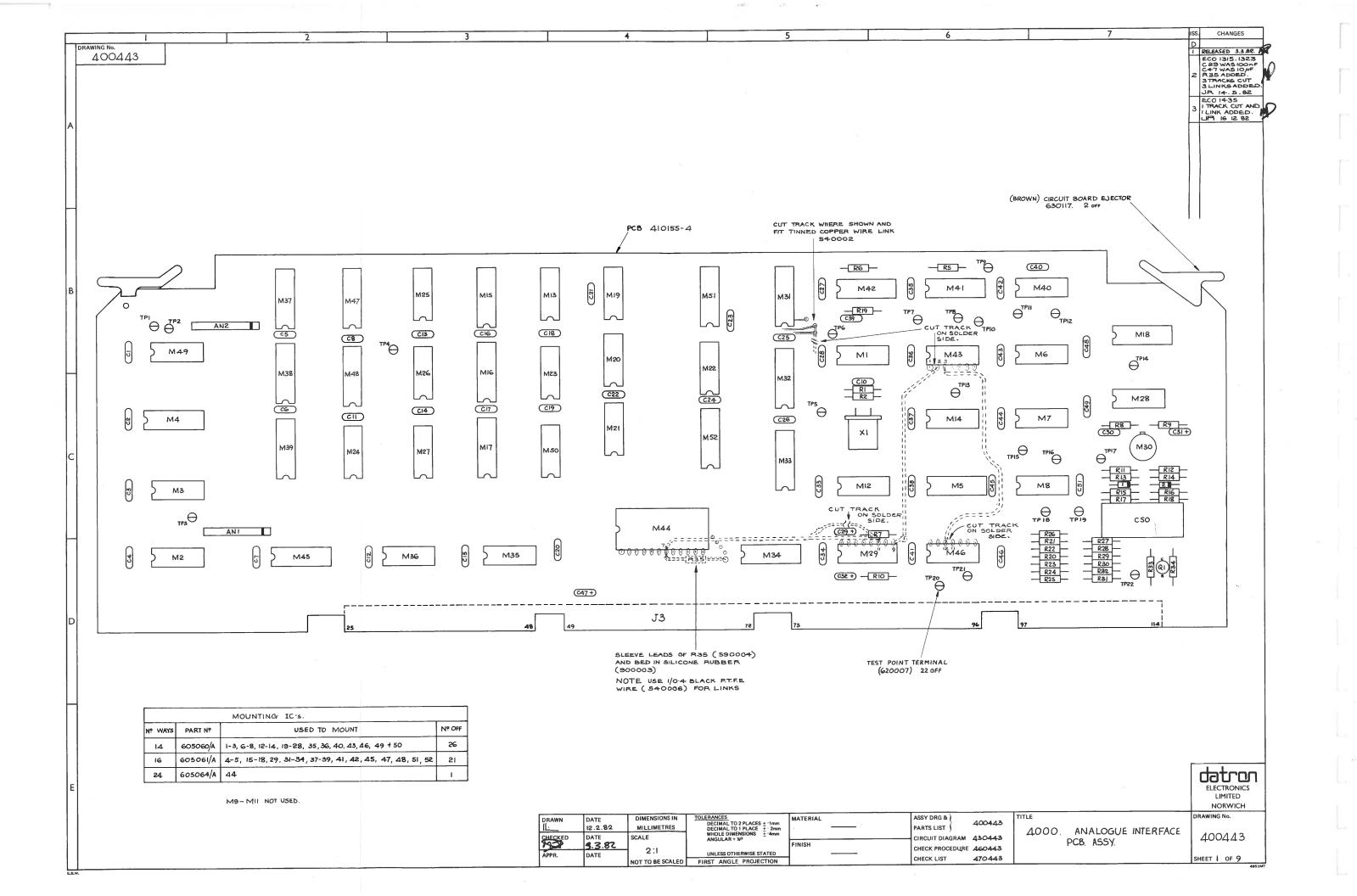


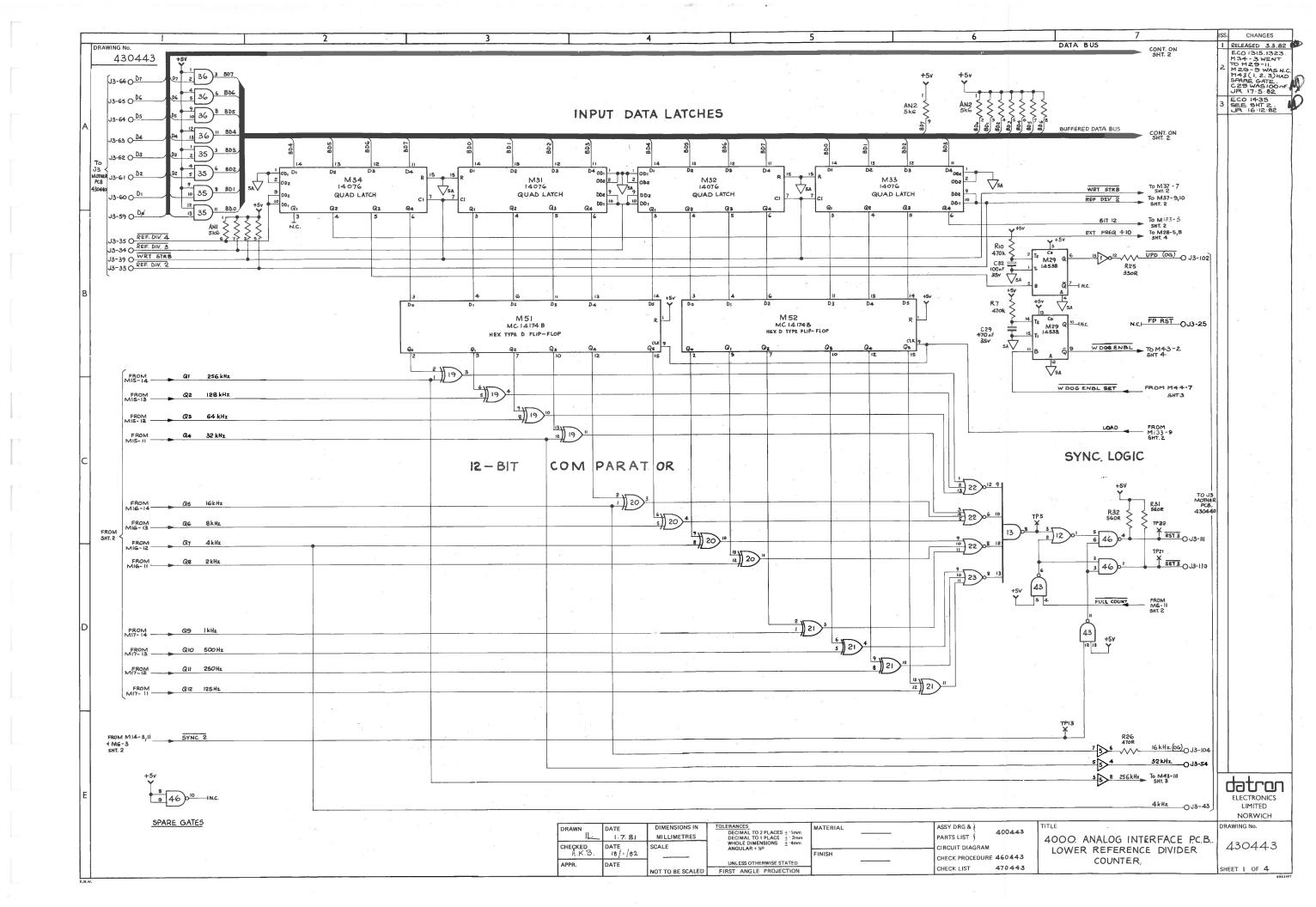


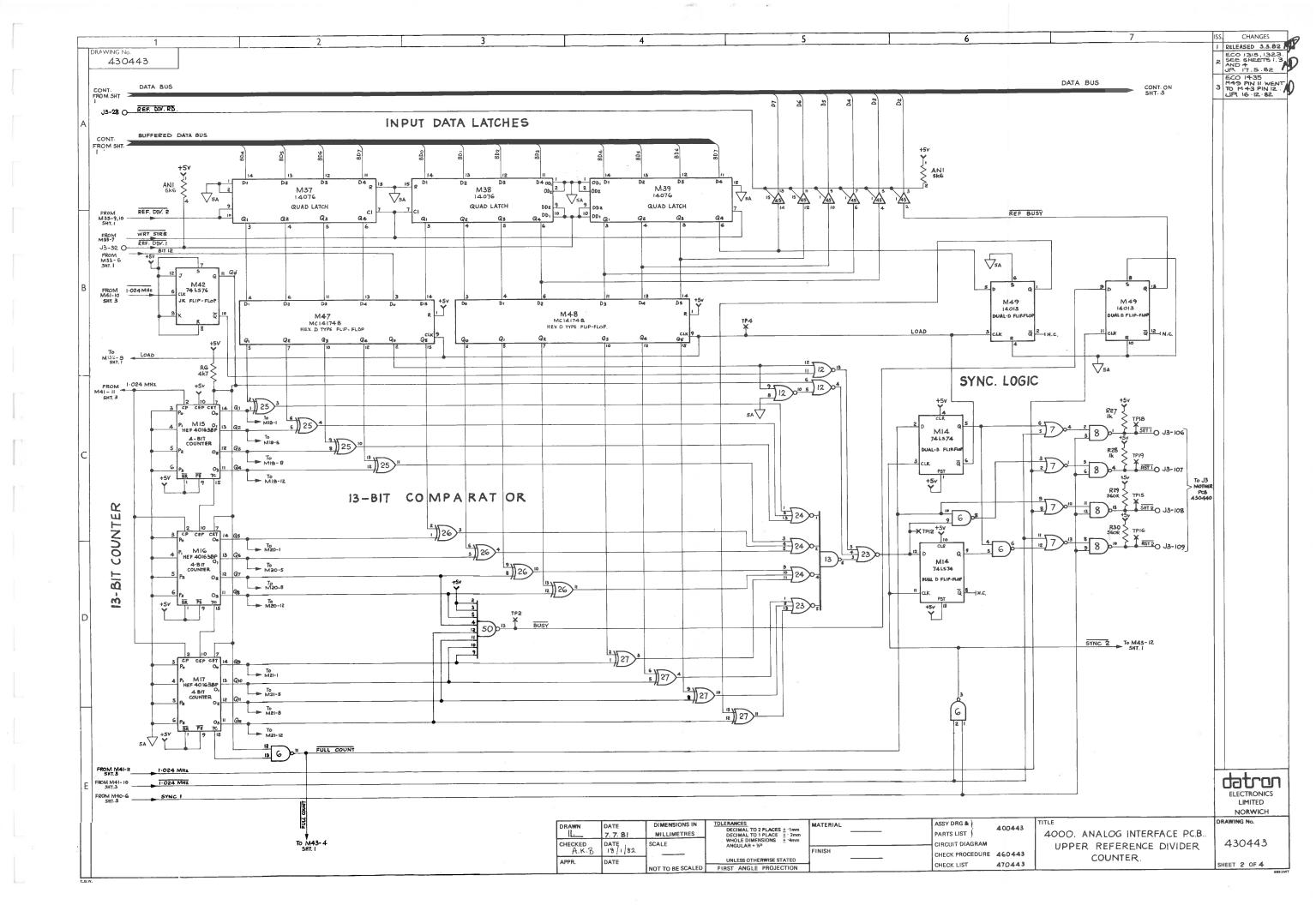


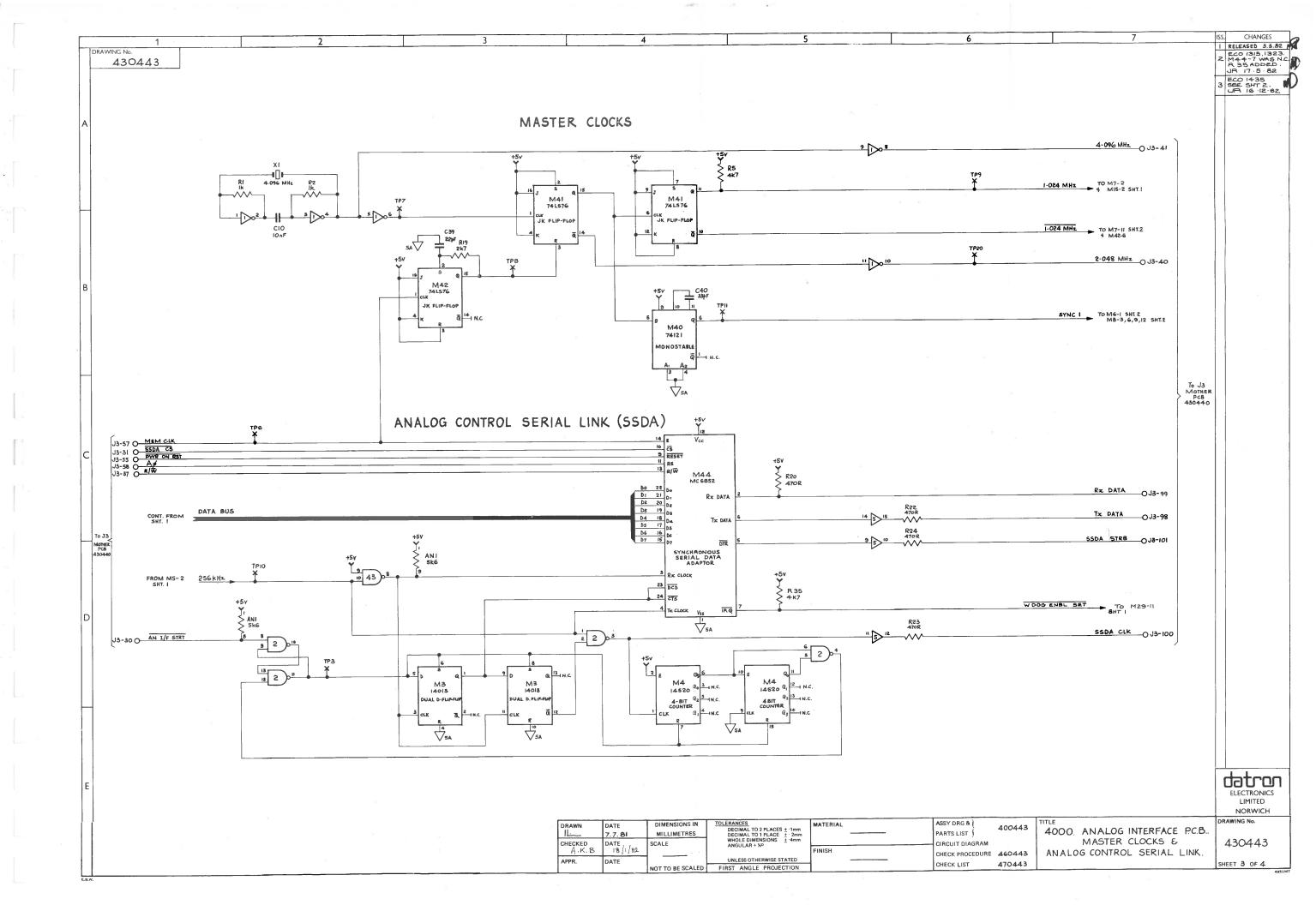


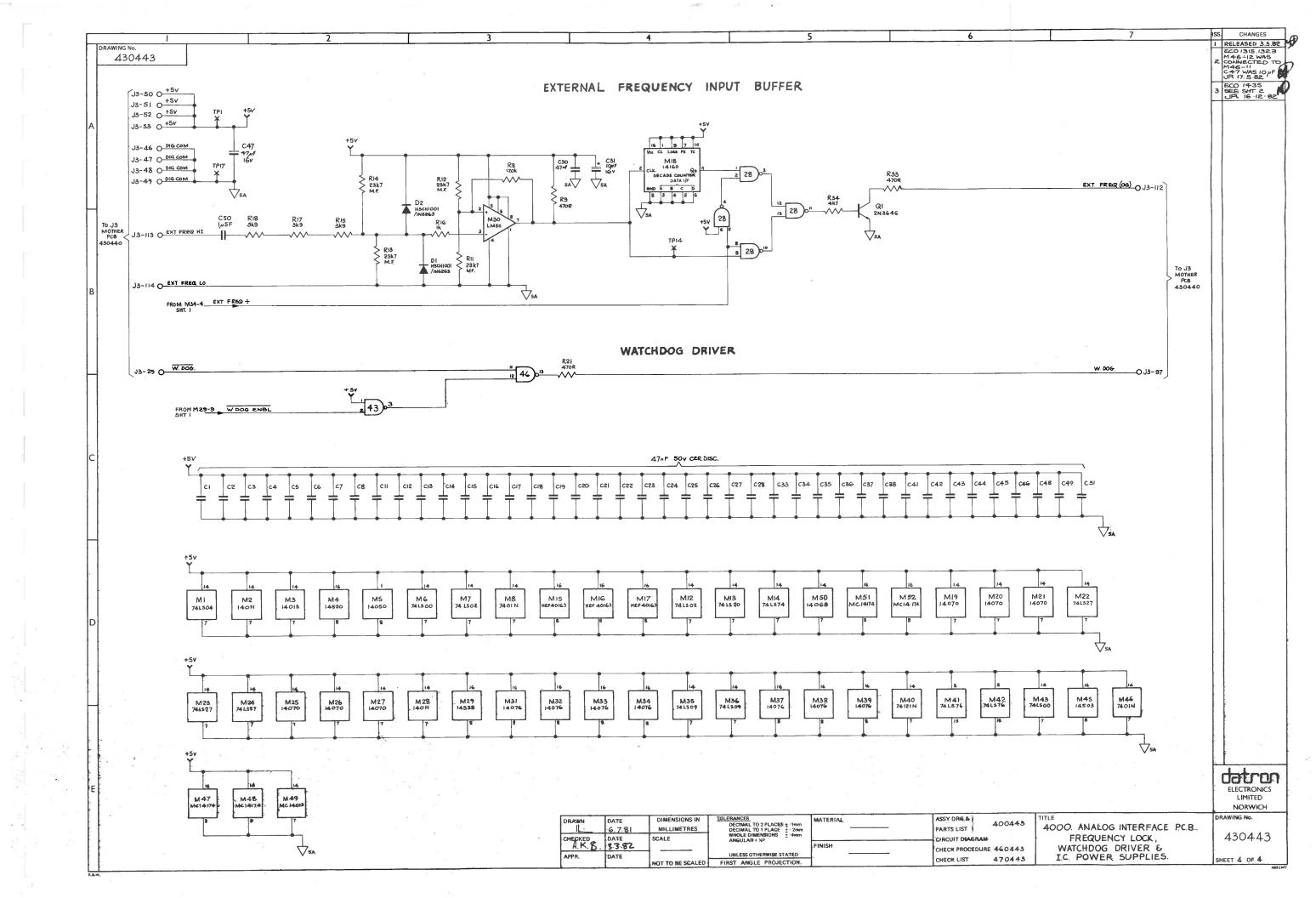


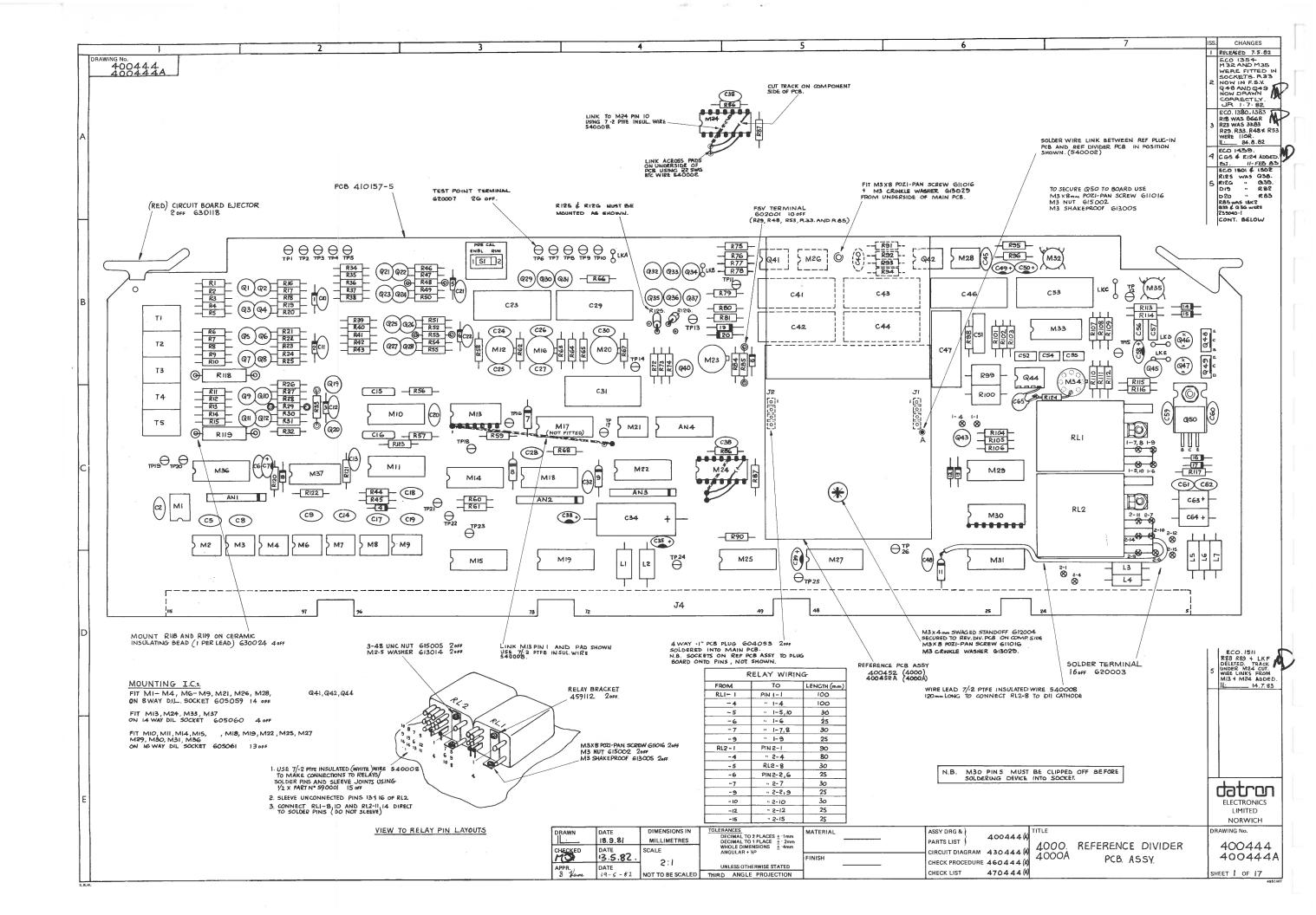


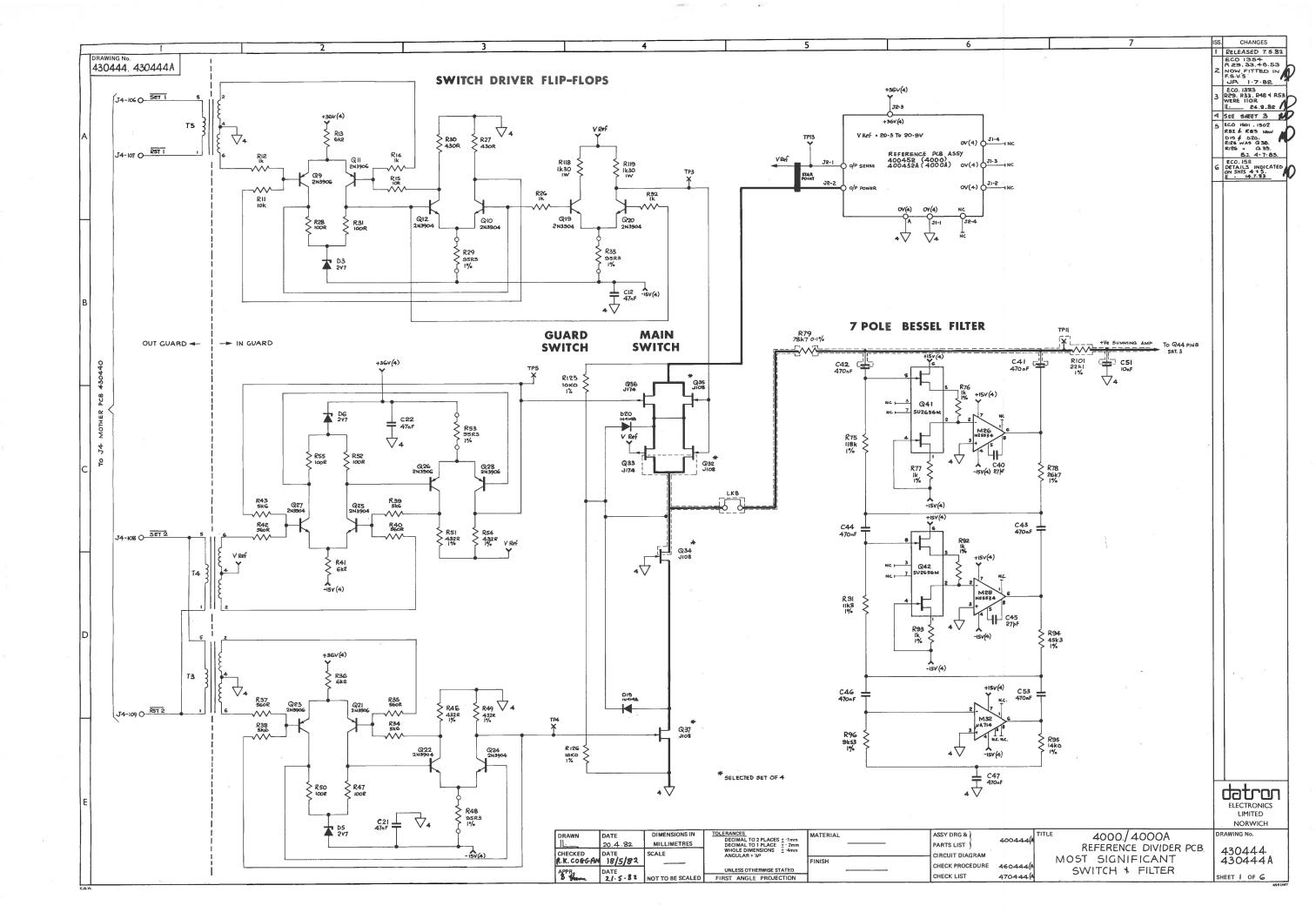


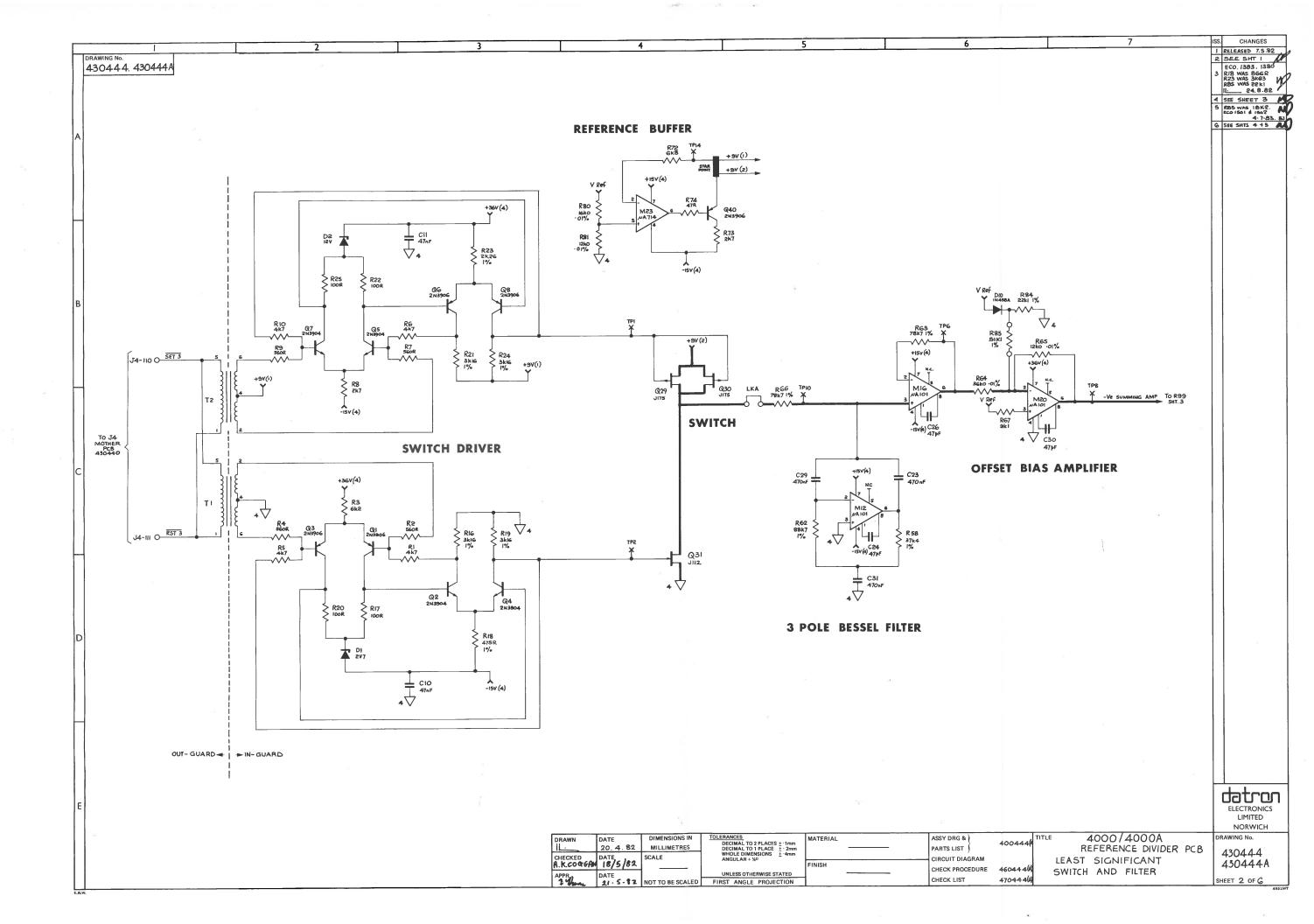


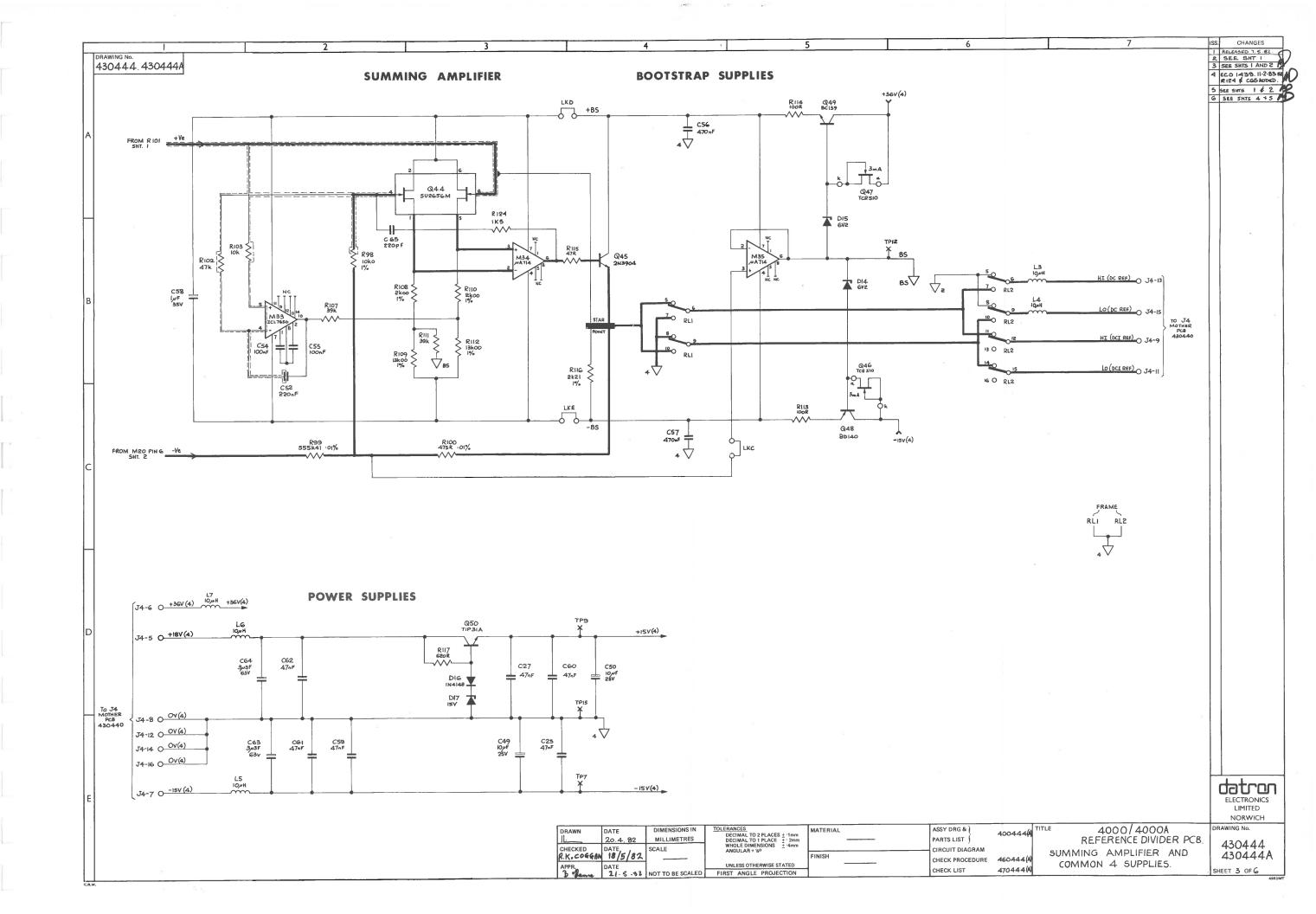


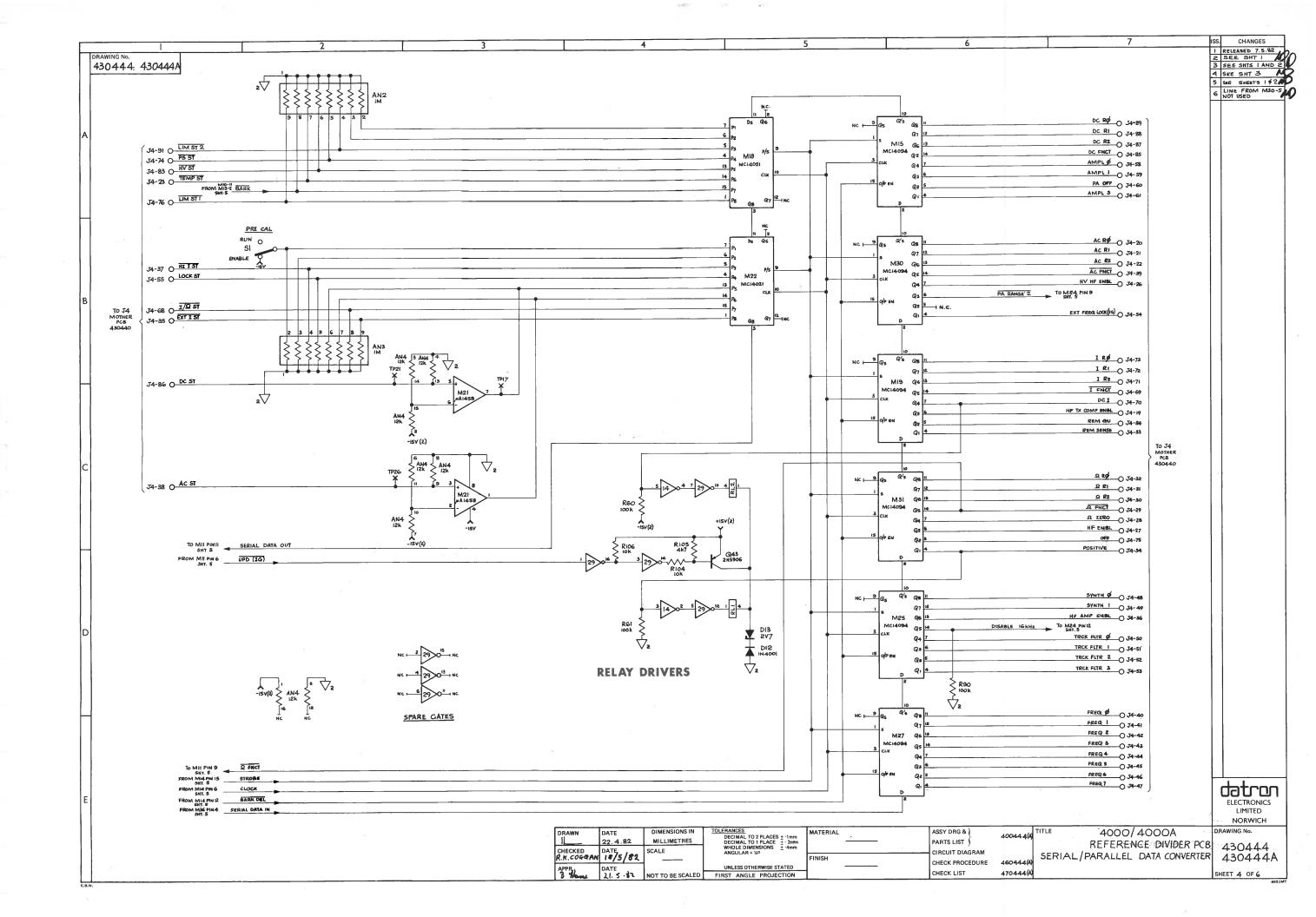


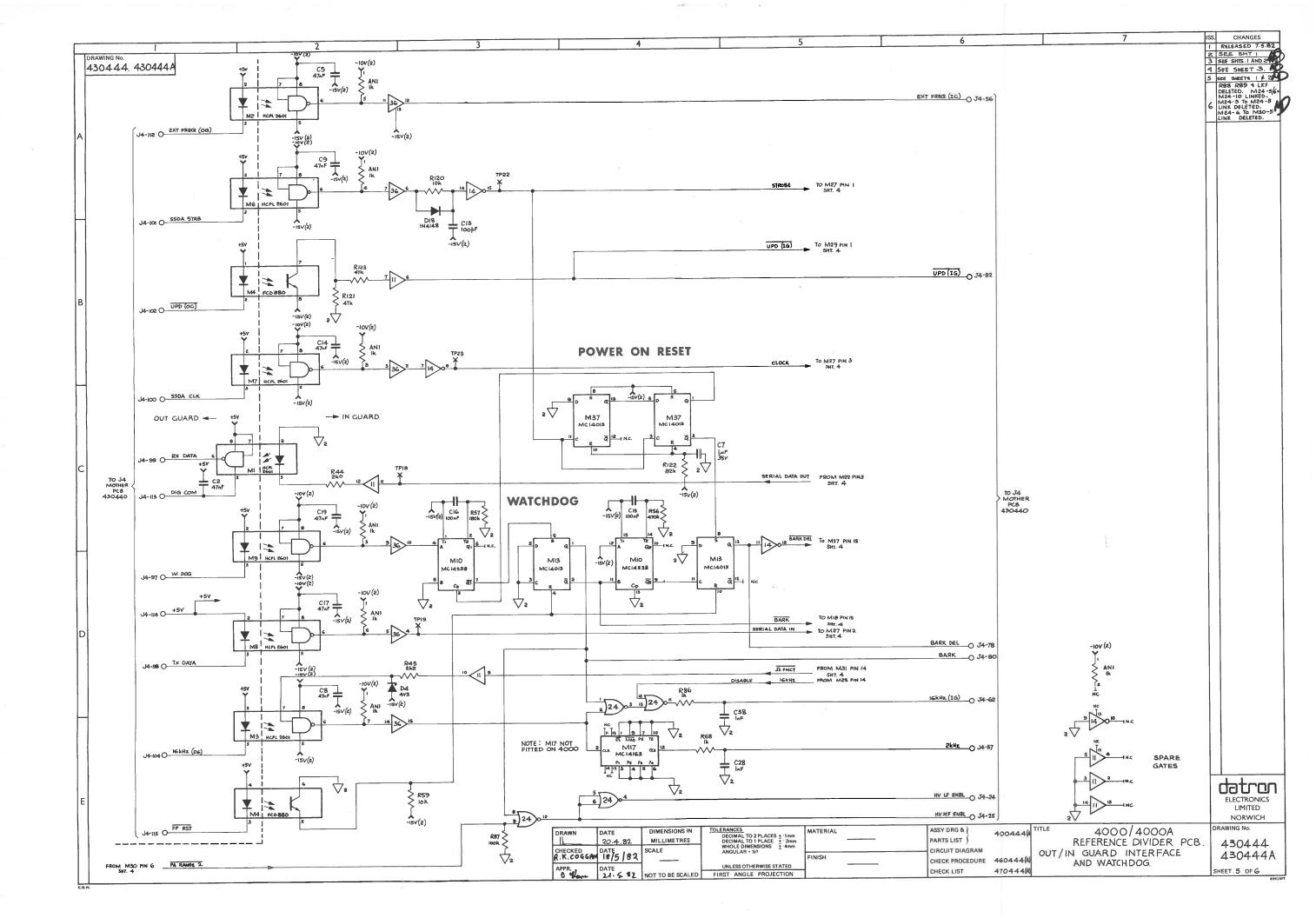


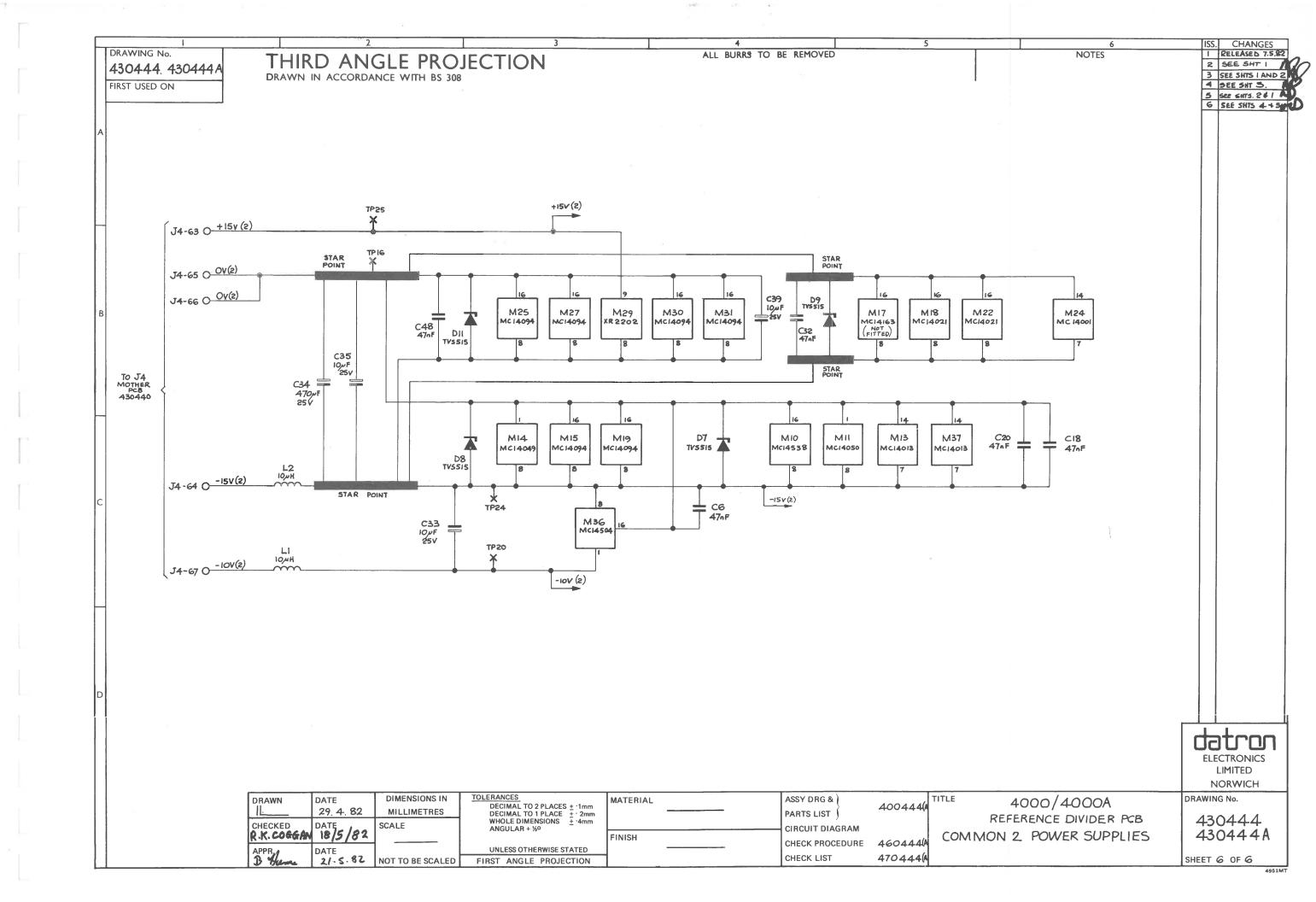


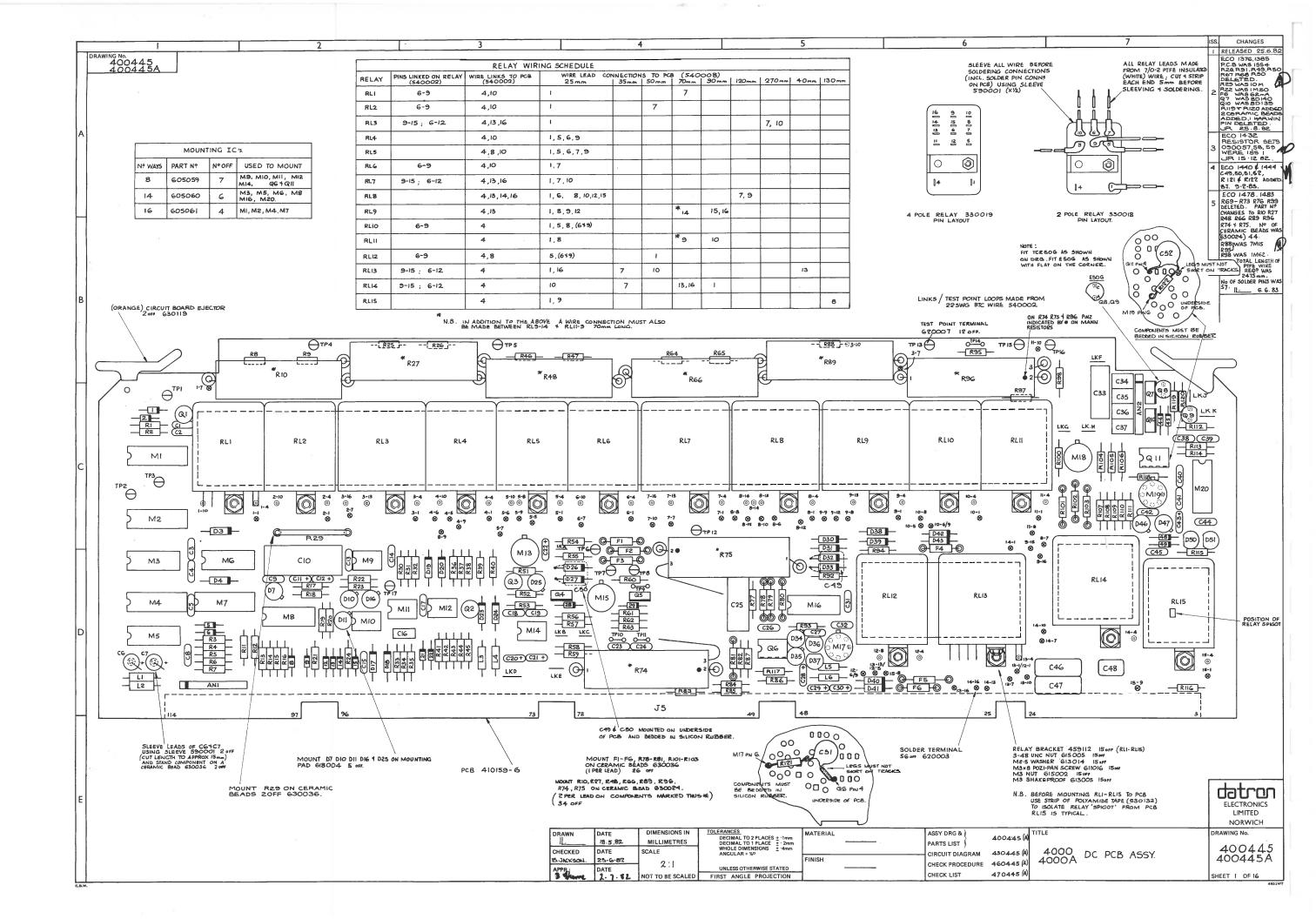


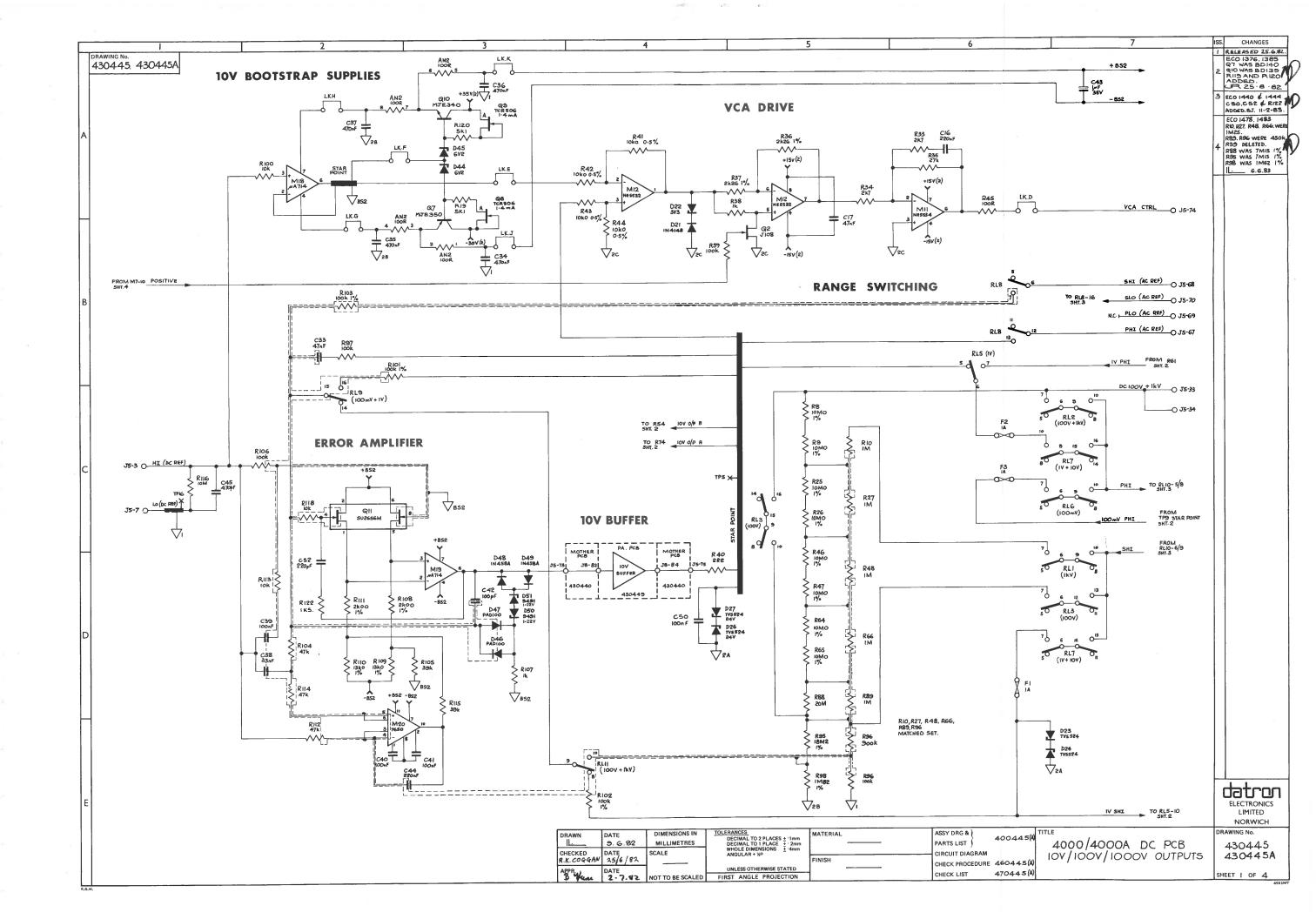


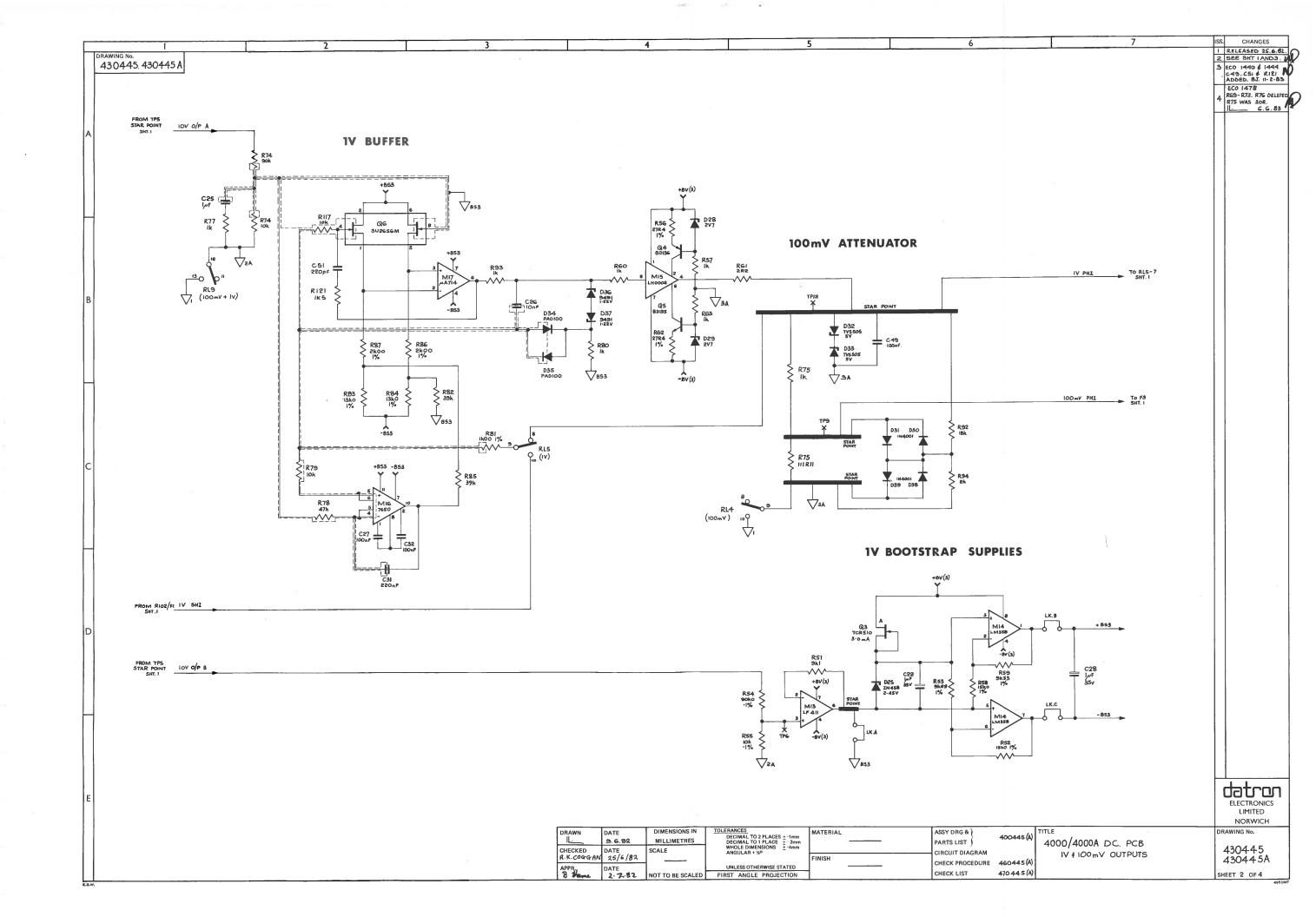


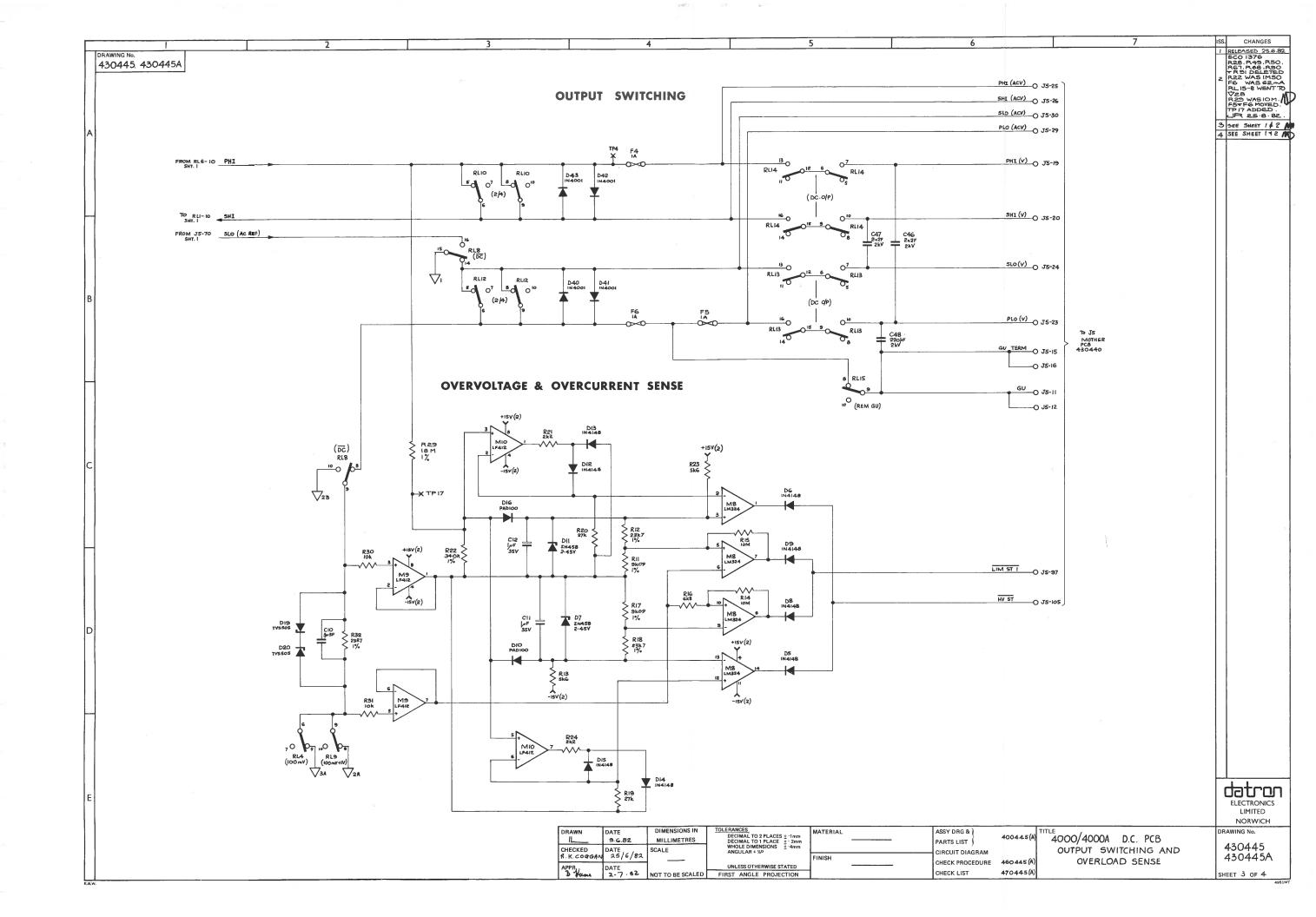


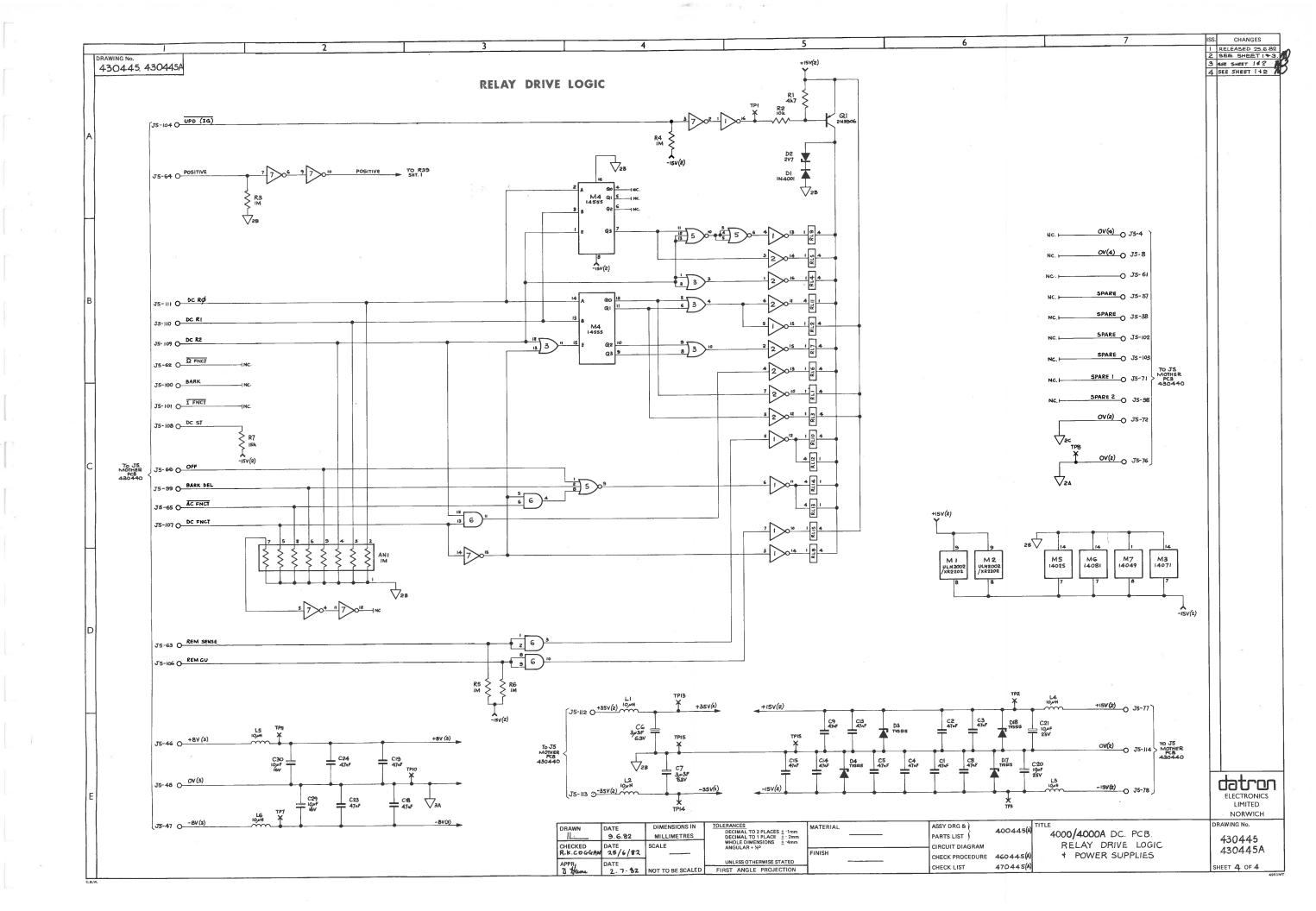


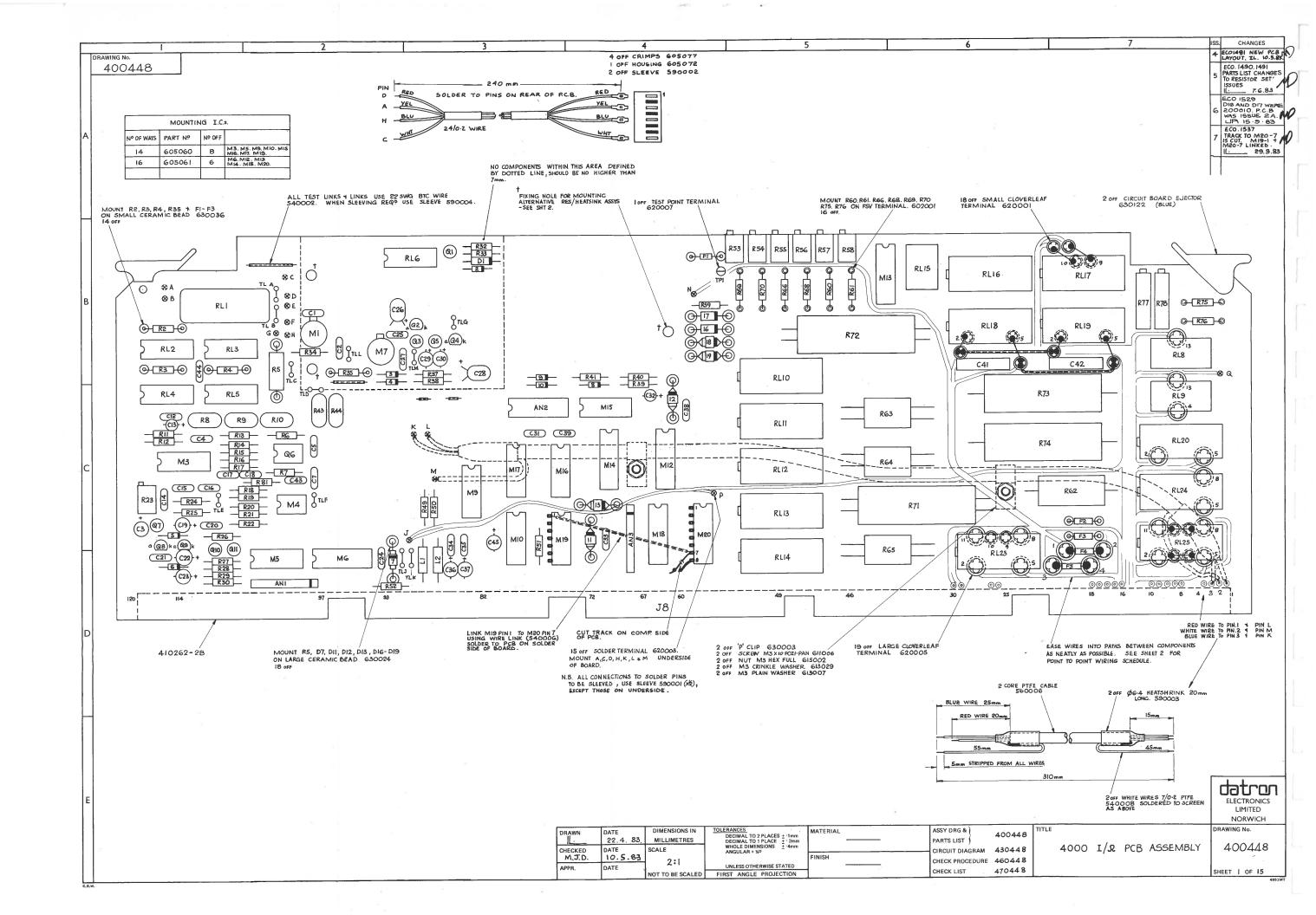


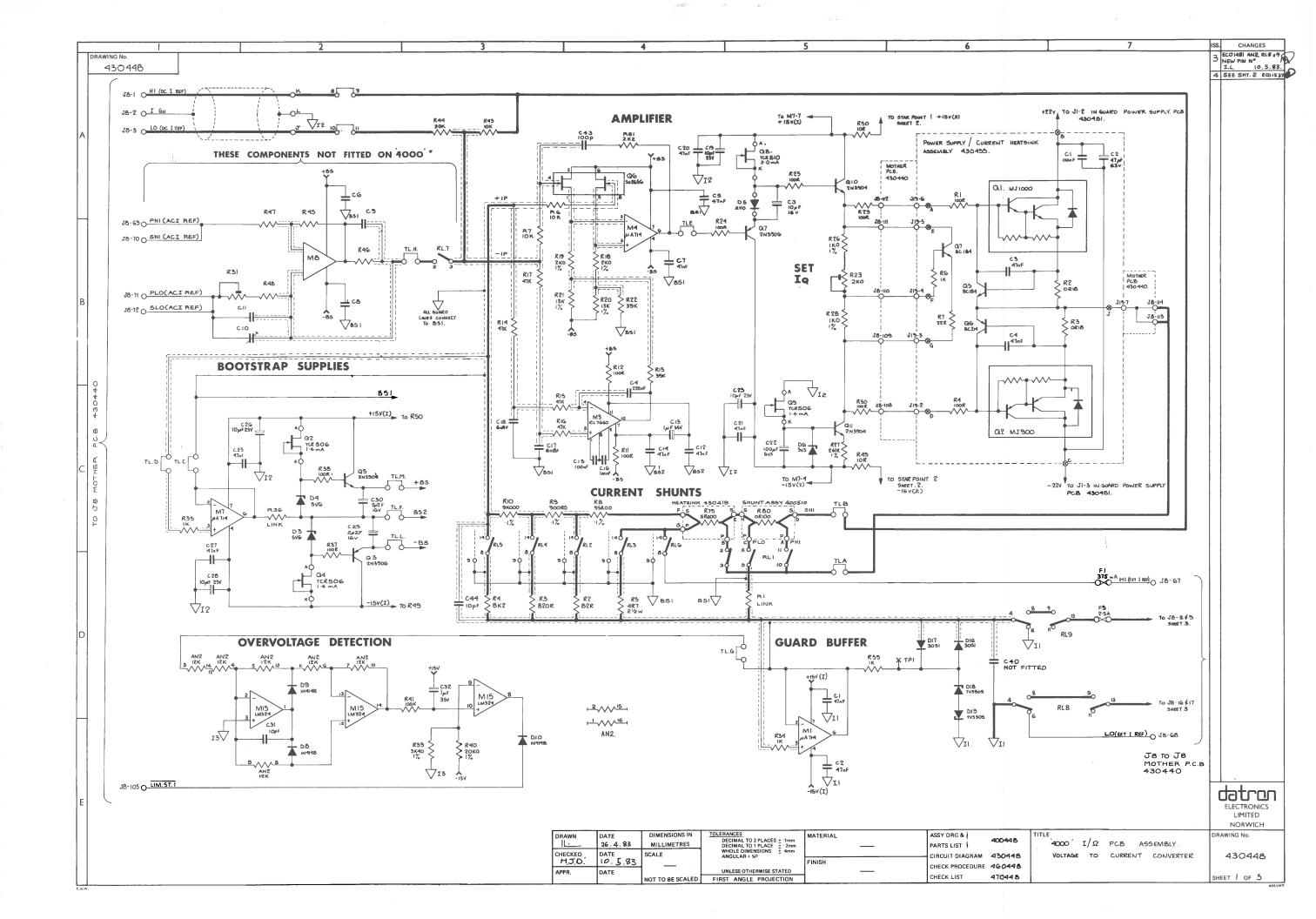


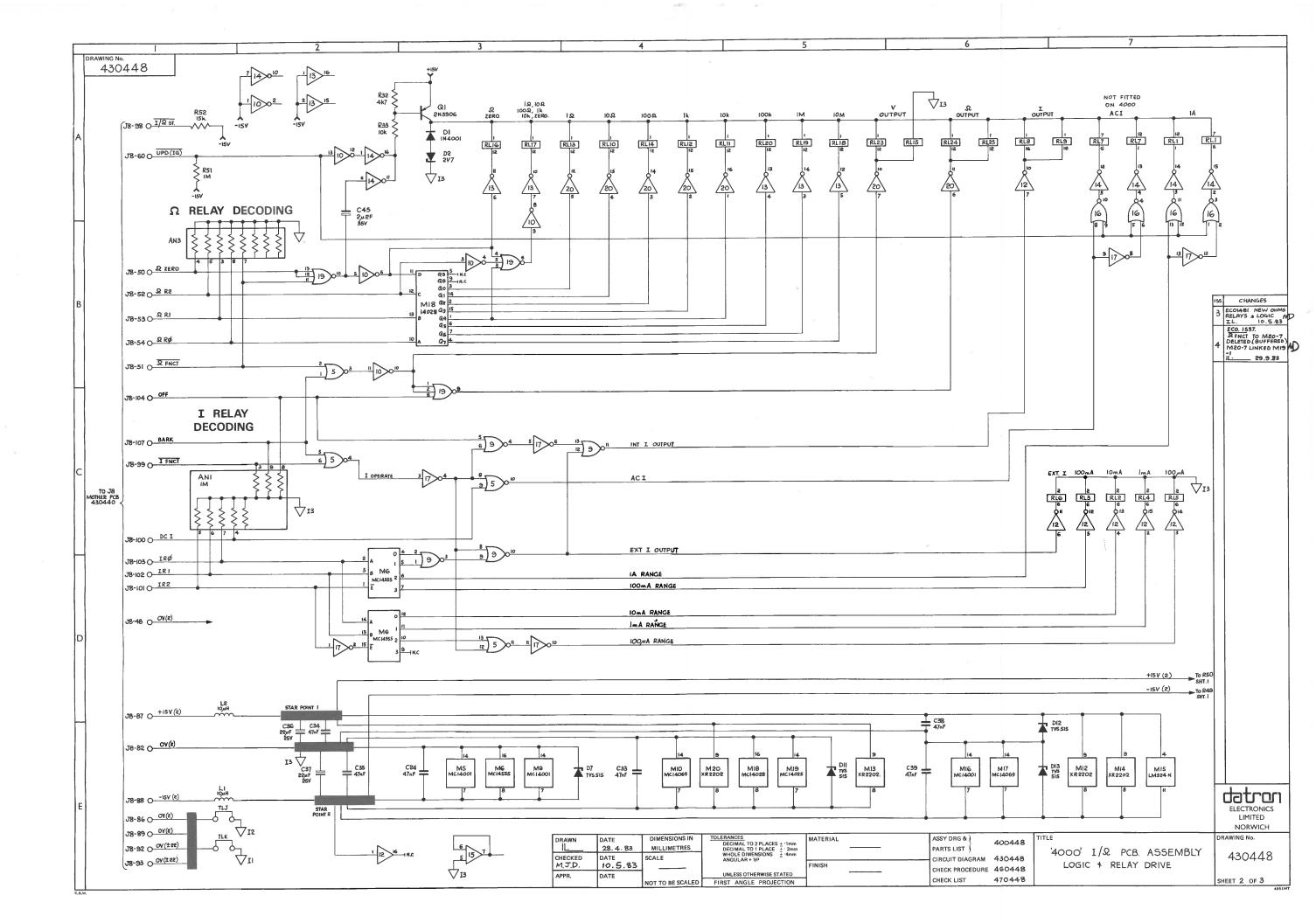


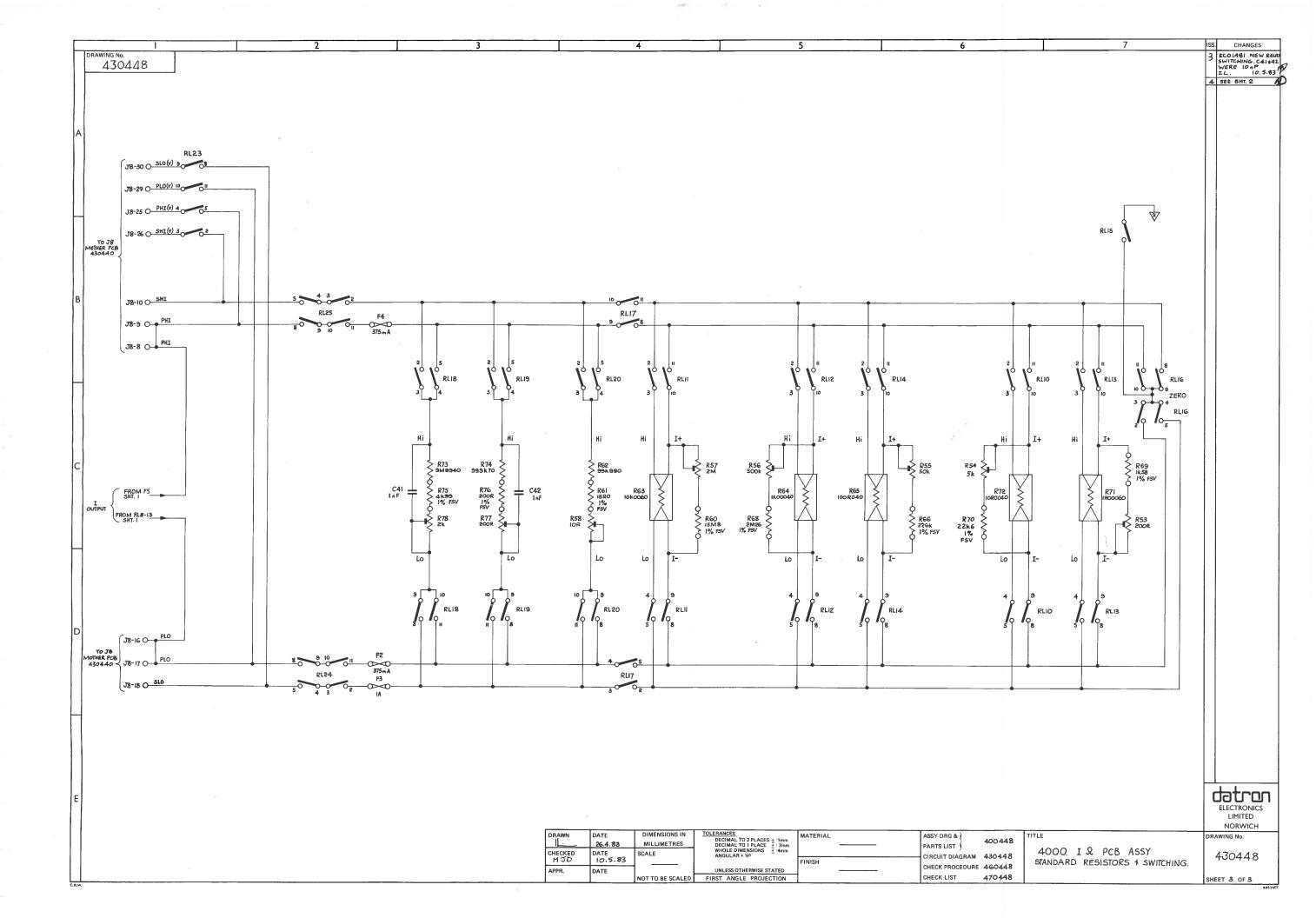


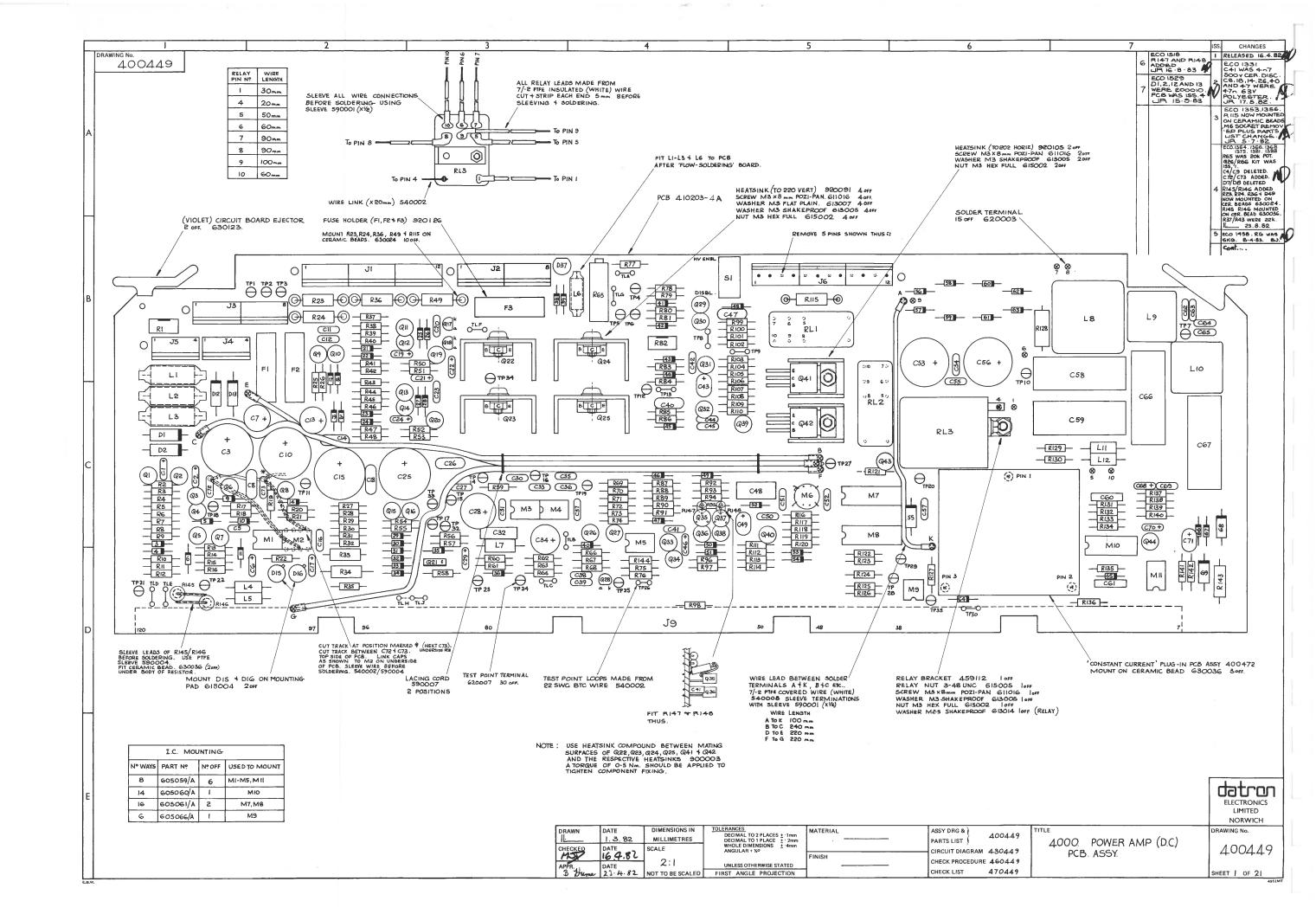


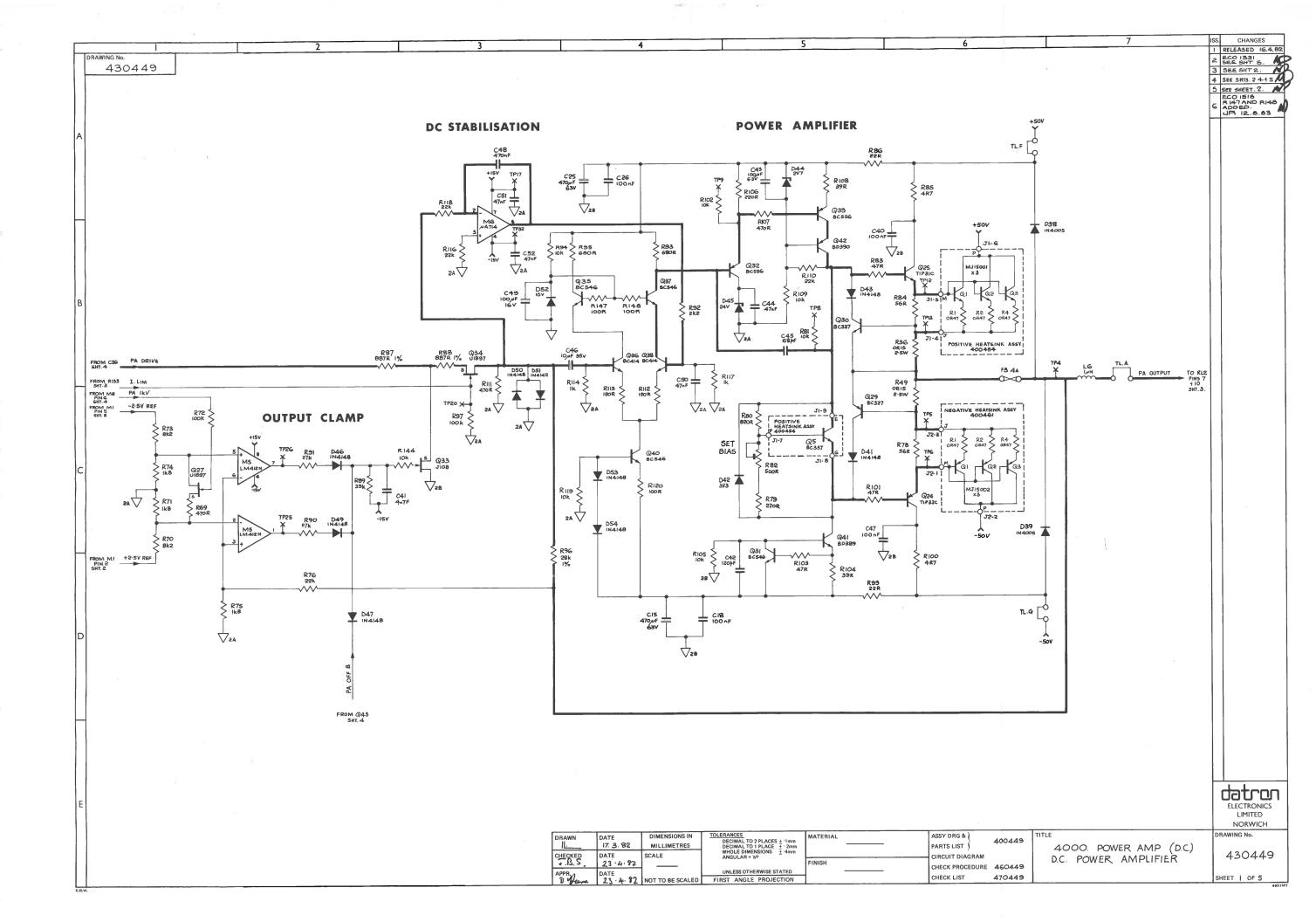


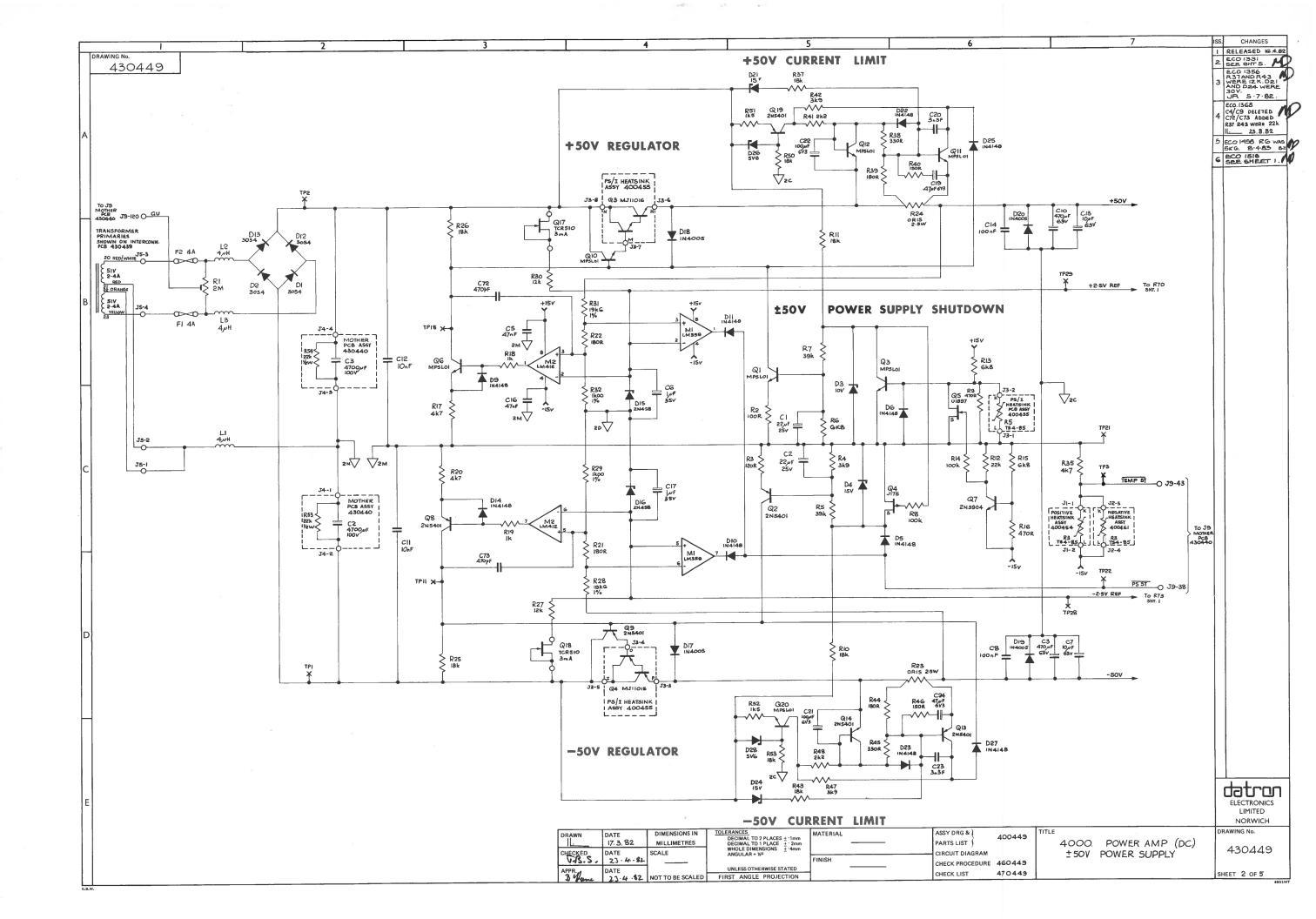


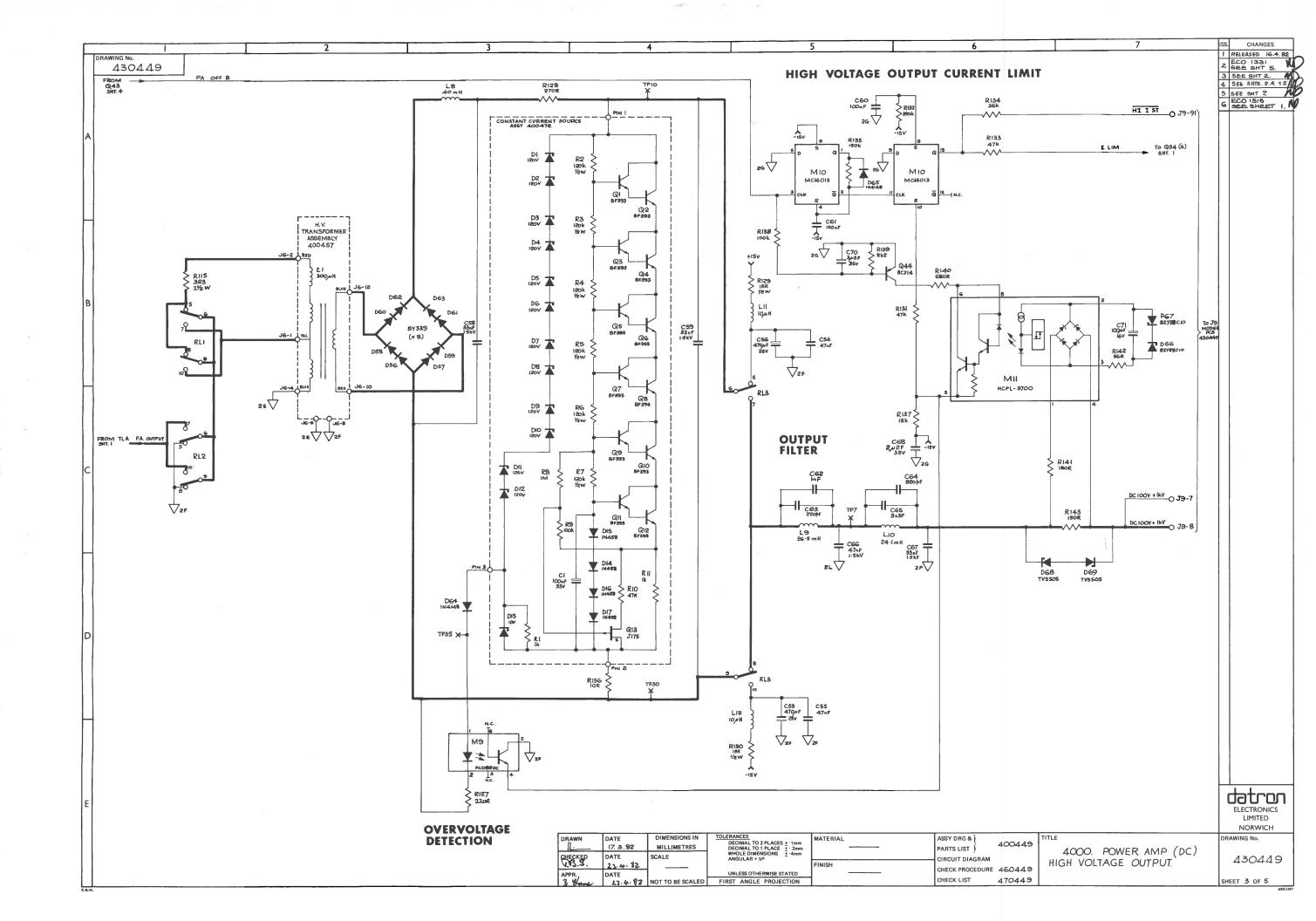


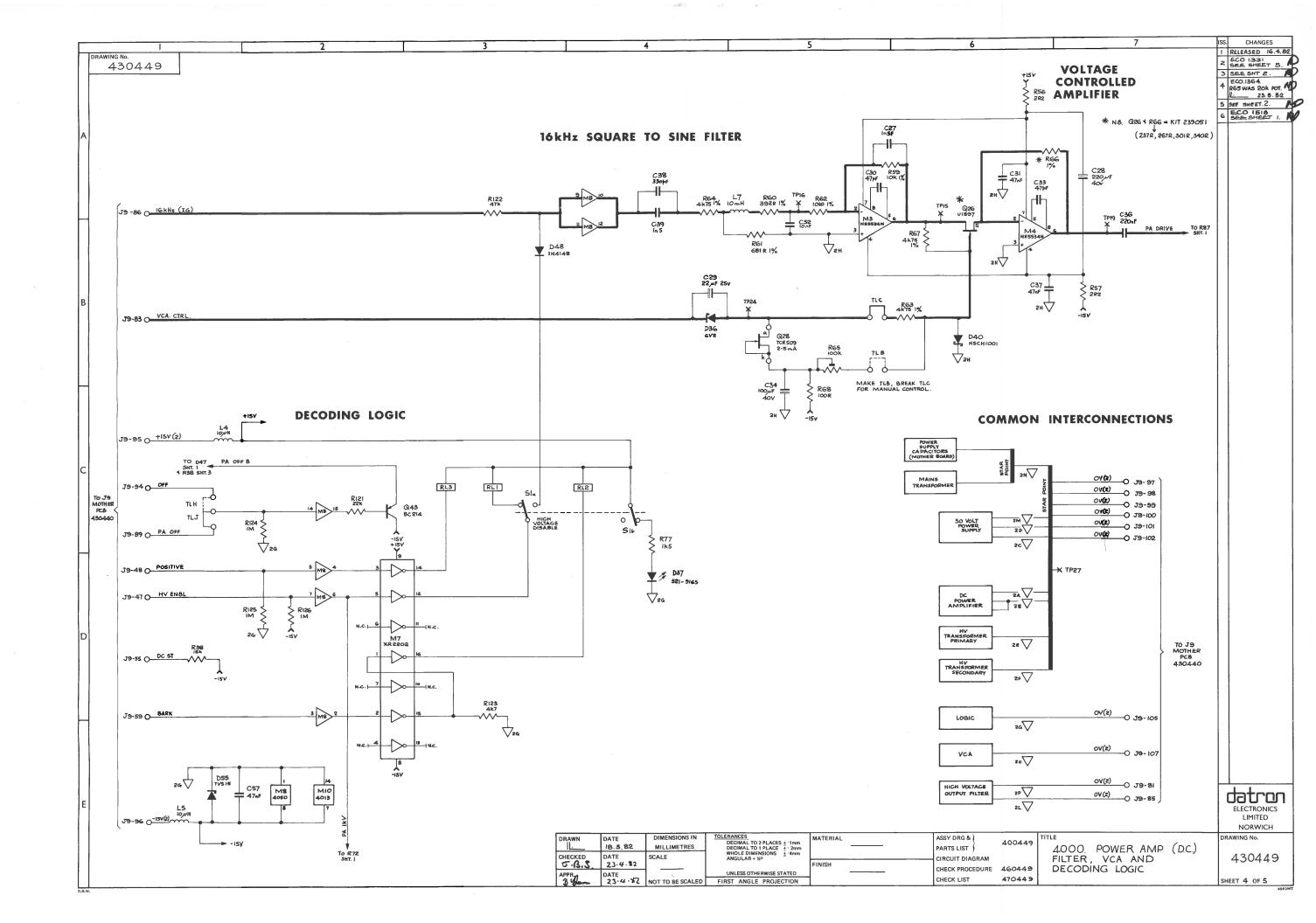


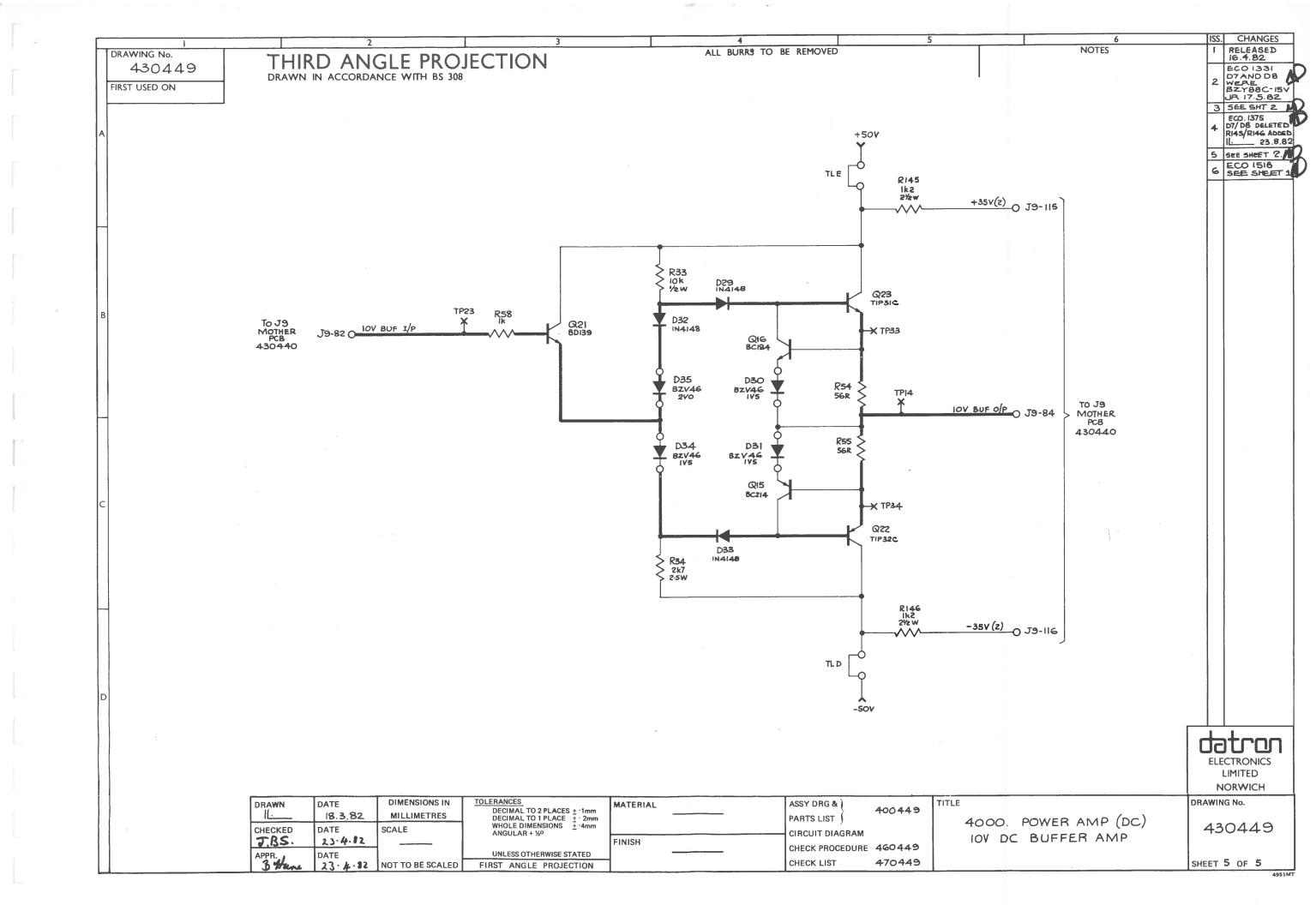


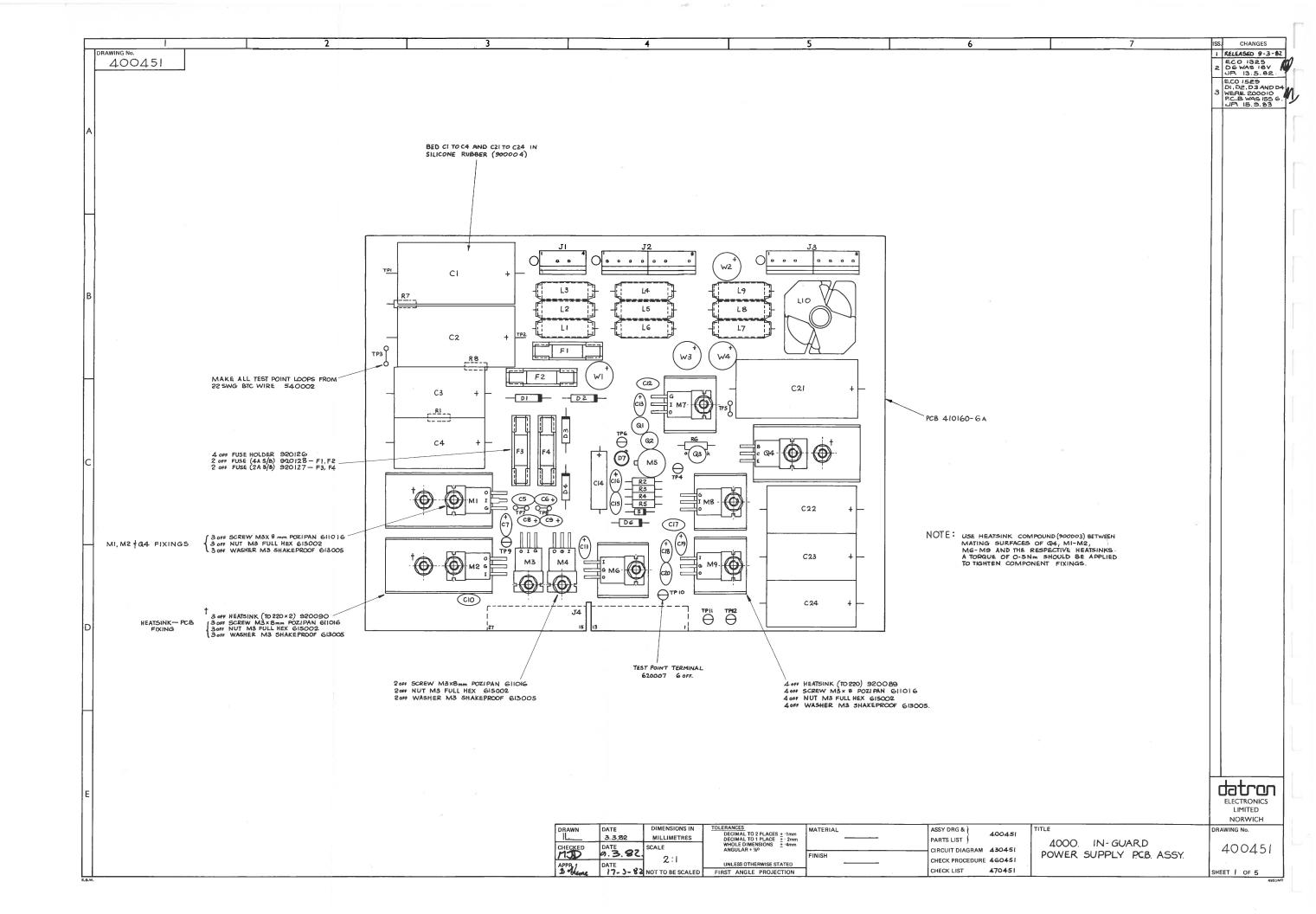


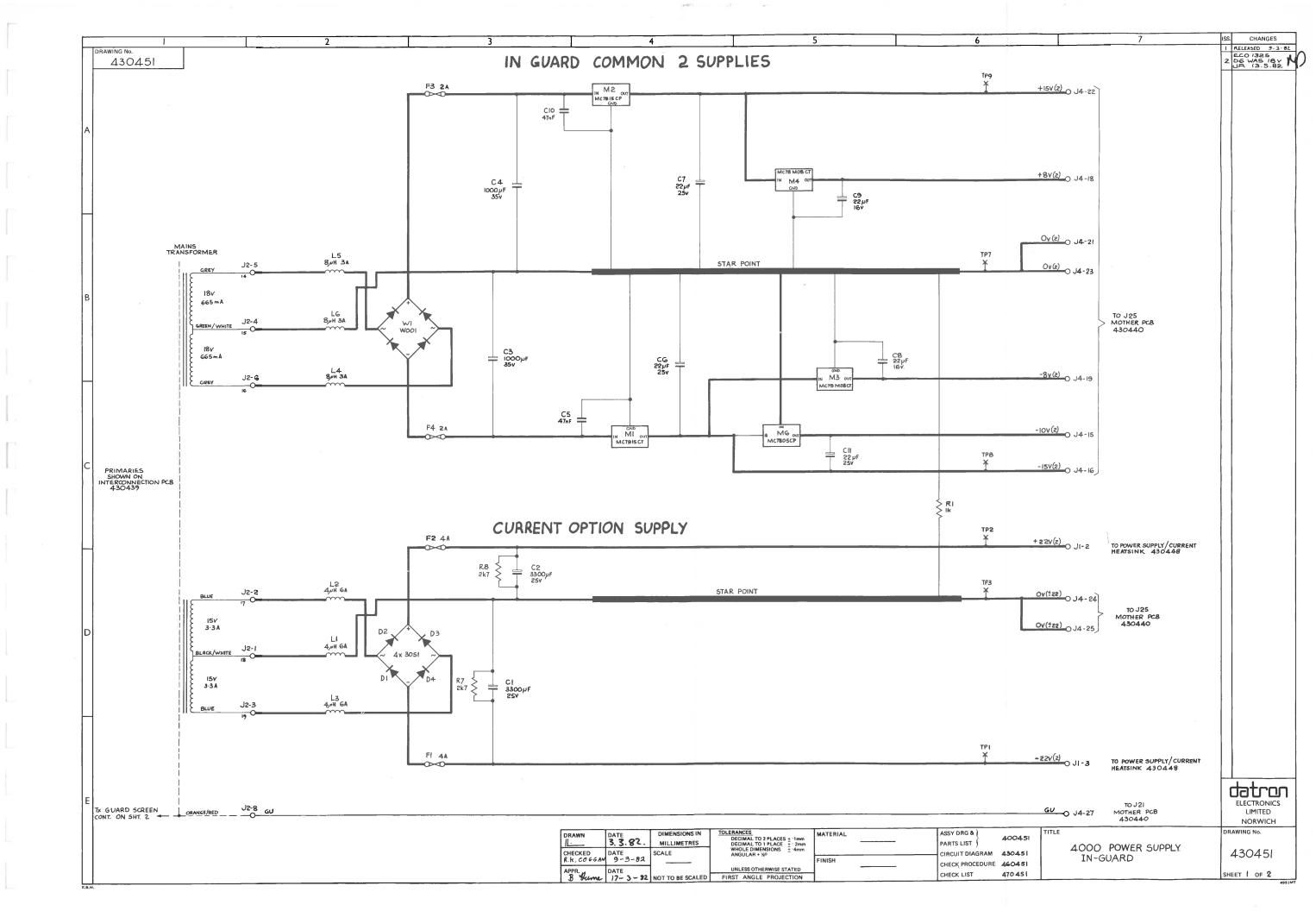


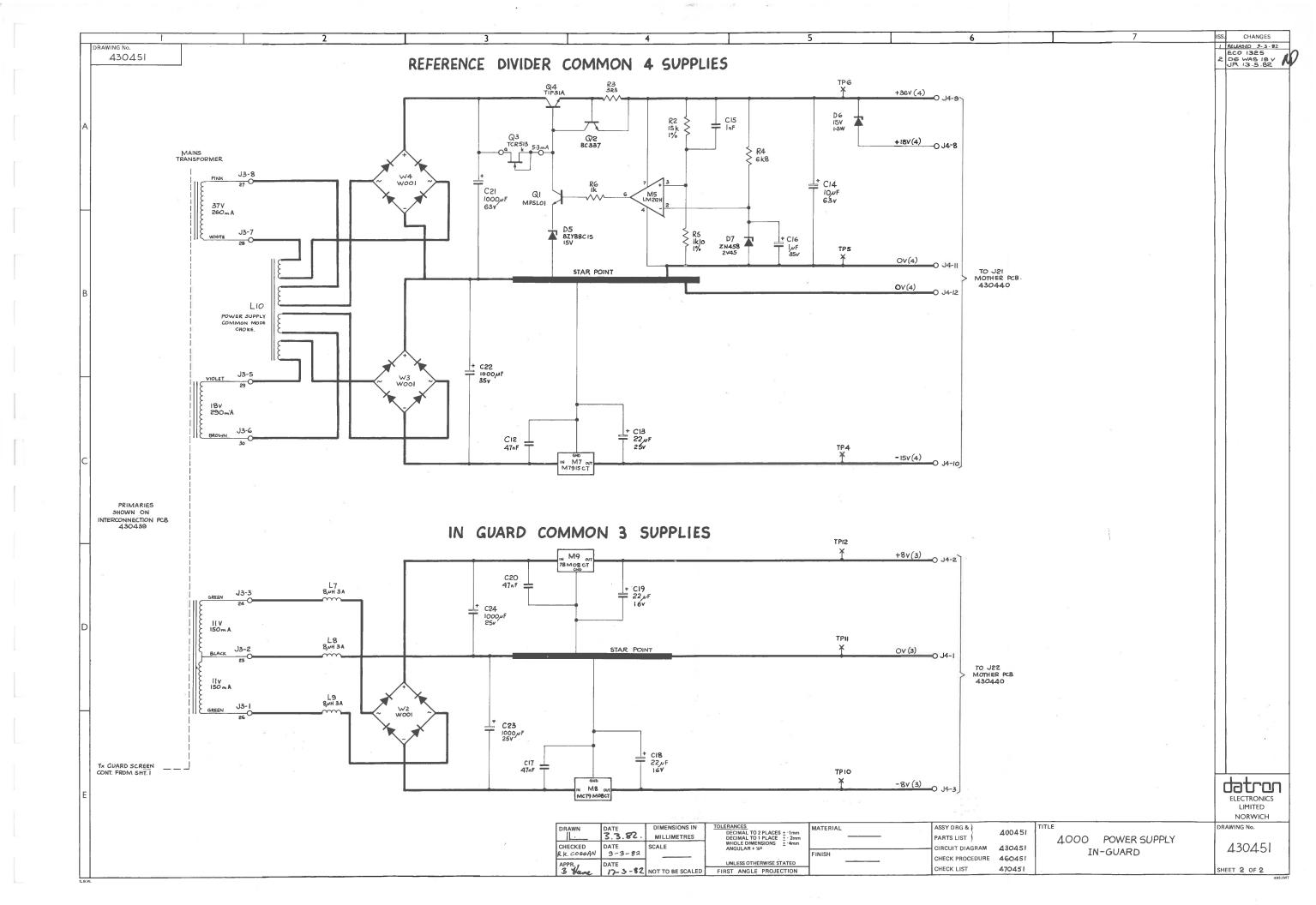


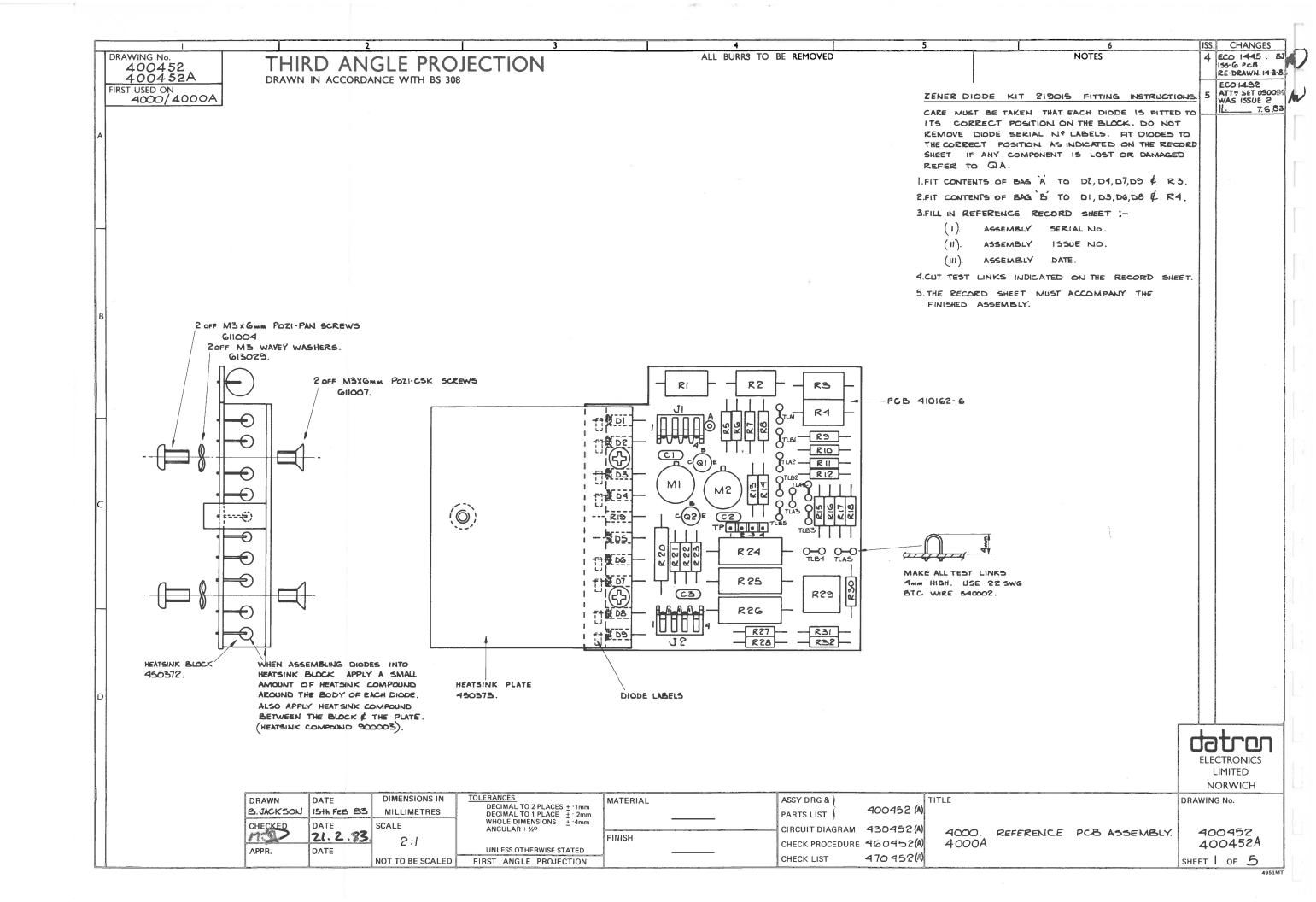


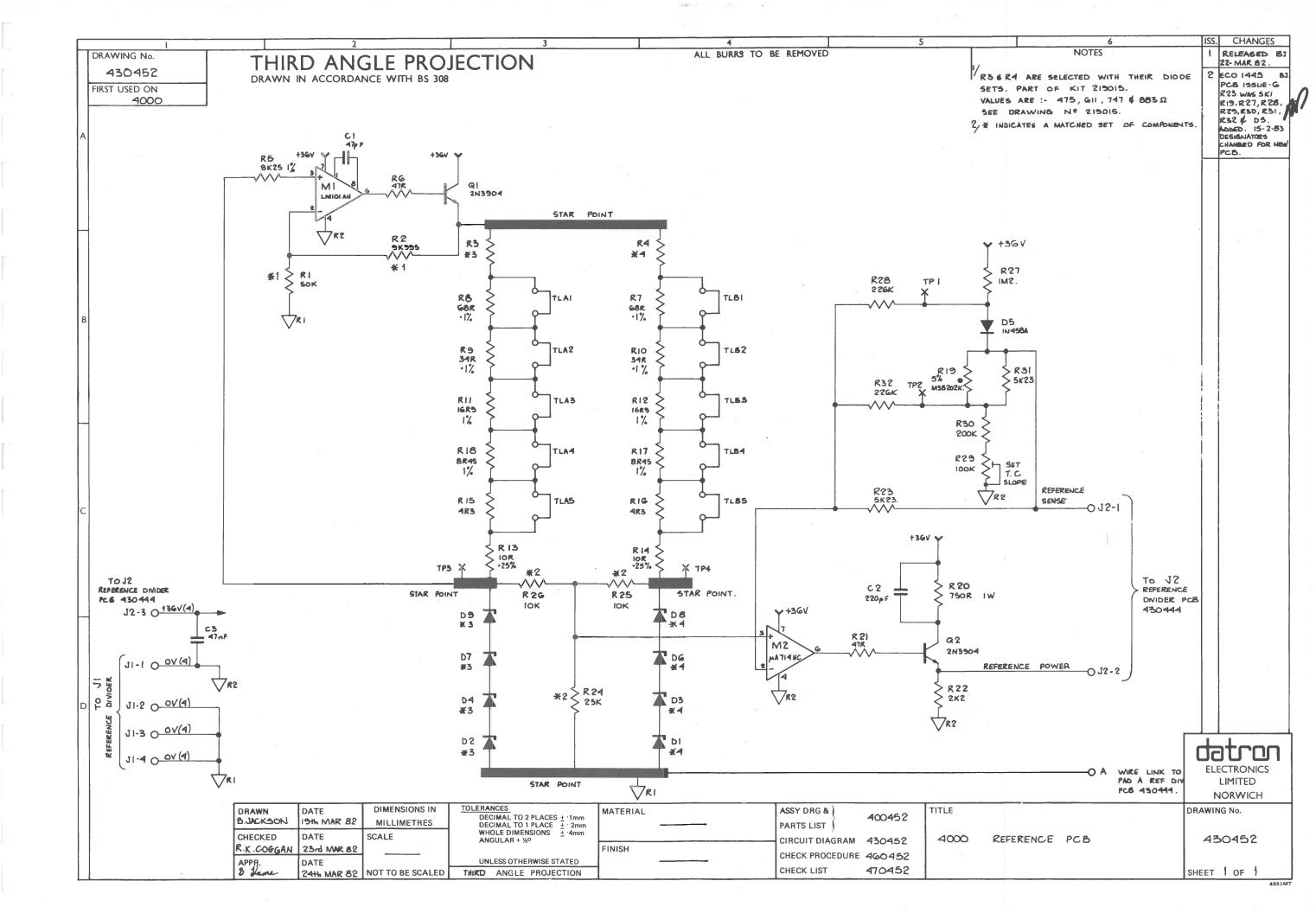


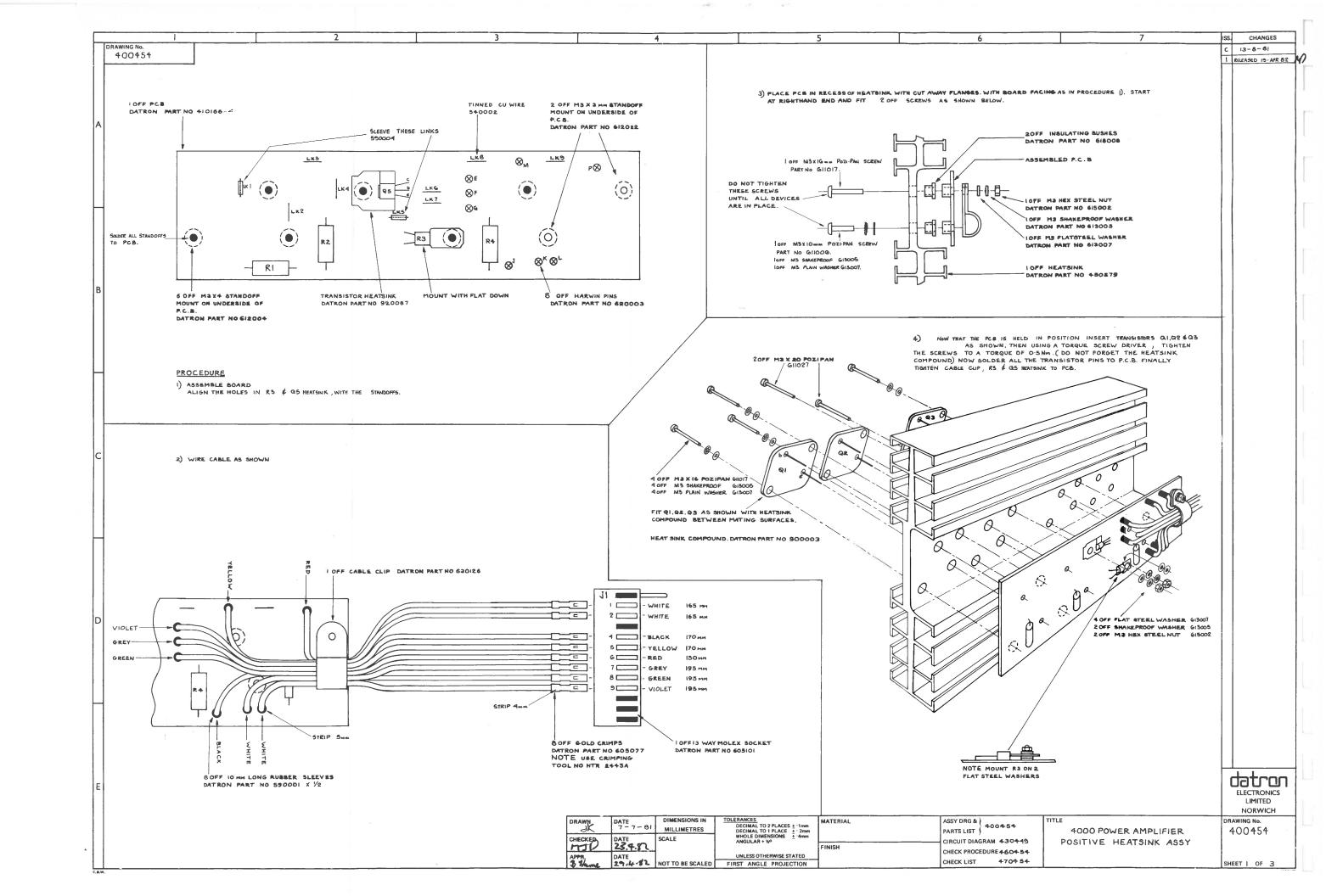


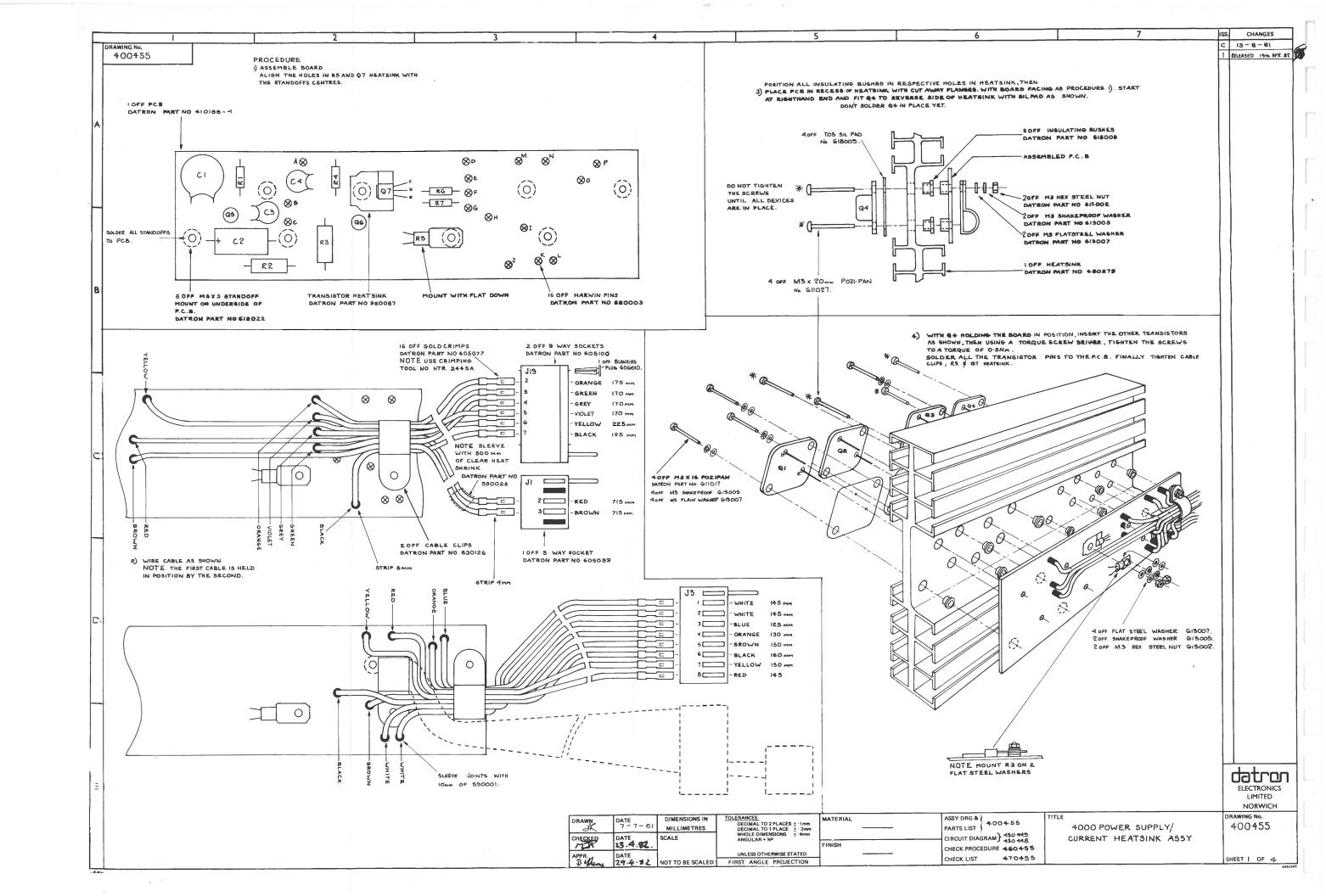


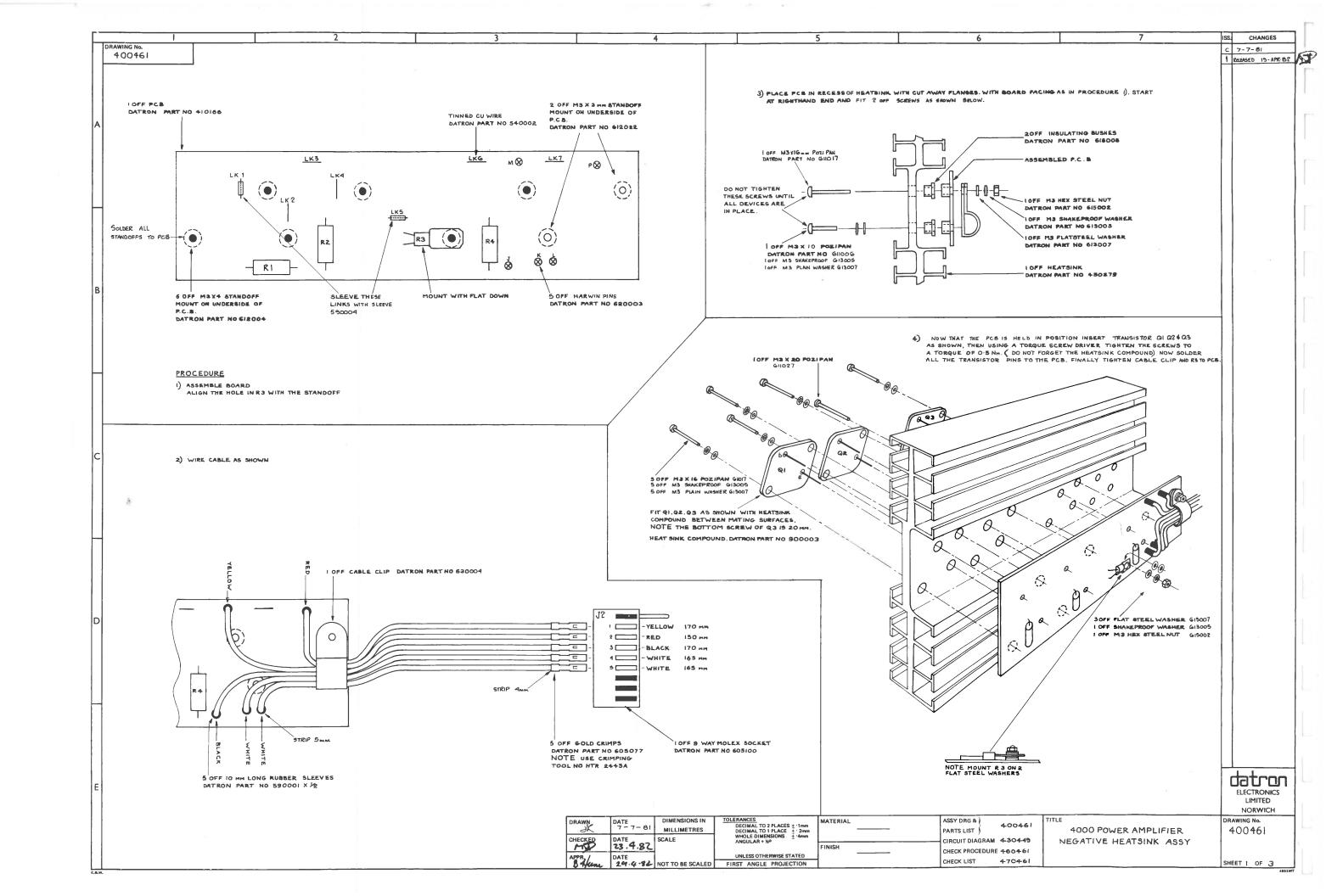


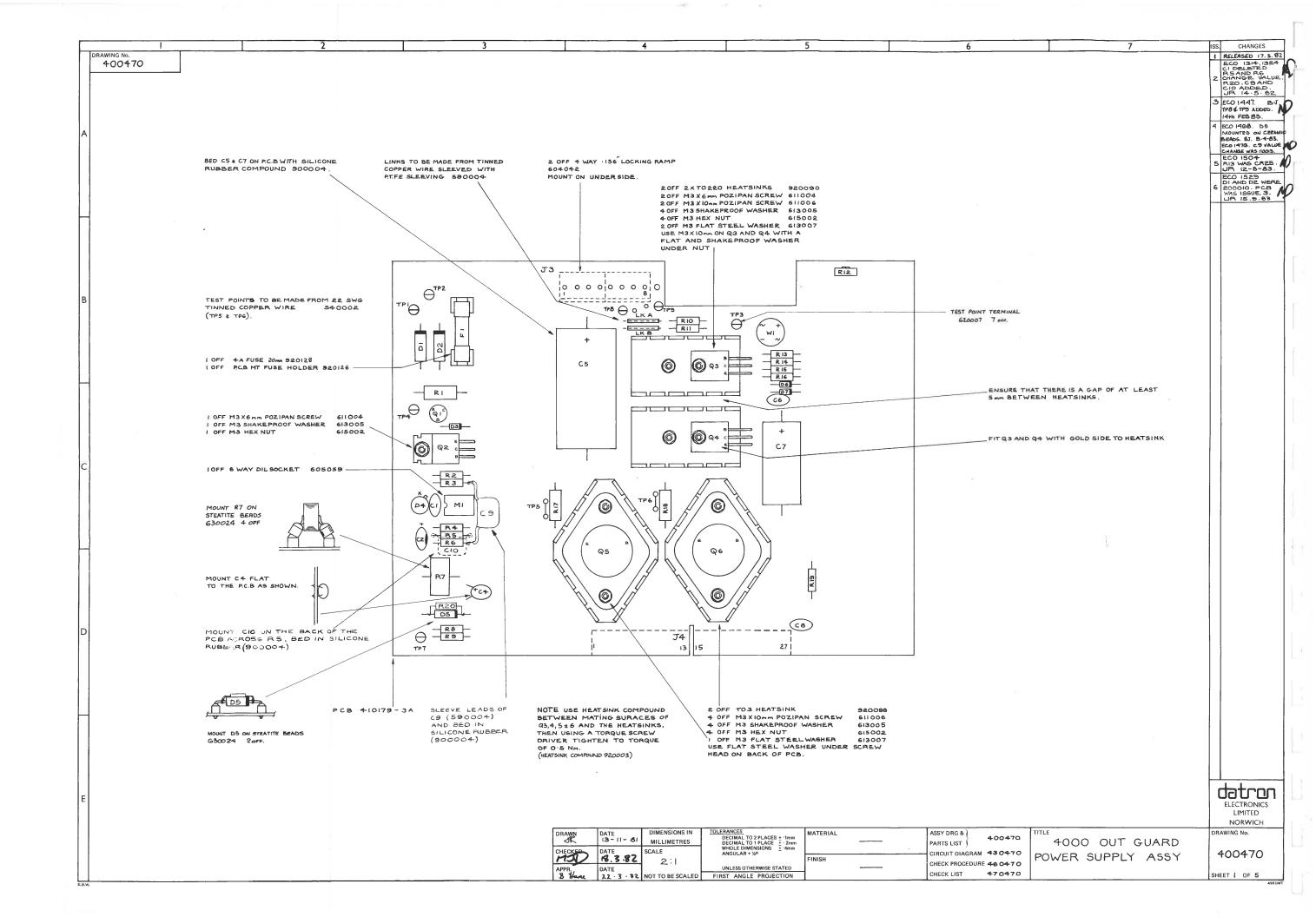


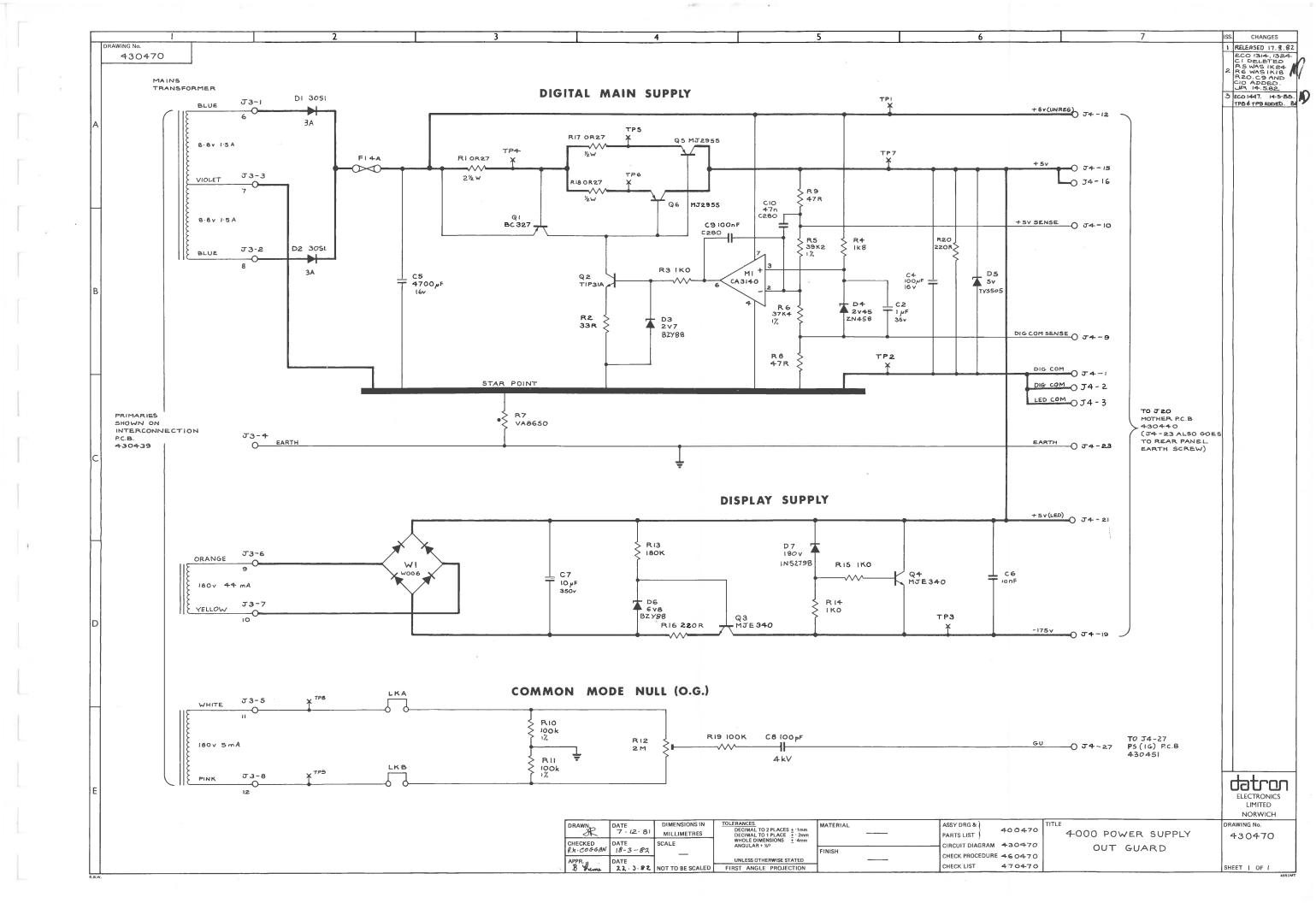












DATRON INSTRUMENT FAILURE REPORT

(This form must accompany all warranty claims.)

	Date
Submitted by (Name)	
Name of Company	
Address	
	:
Datron Instrument Model No.	
Datron Instrument Serial No.	
Date of purchase (if known)	
Customer Order Number	
Datron Sales/Service Center	
Symptoms of Failure	,
Please describe the symptoms of failure, including any relevan if necessary).	t diagrams (use a separate shee

TERMS AND CONDITIONS OF SALE

1 GENERAL

The acceptance of a quotation, of any goods supplied, advice given or service rendered includes the acceptance of the following terms and conditions and no variation of or addition to the same shall be binding upon us unless expressly agreed in writing by us. Any order shall be subject to our written acceptance.

2. QUOTATION

Unless previously withdrawn our quotation is open to acceptance in writing within the period stated or where no period is stated within thirty (30) days after its date. We reserve the right to correct any errors or omissions in our quotation. Unless otherwise stated all quotations are firm and fixed. The prices quoted are based on manufacture of the quantity and type ordered and are subject to revision when interruptions, engineering changes or changes in quantity are caused or requested by the customer.

3. LIABILITY FOR DELAY

Any delivery times quoted are from the date of our written acceptance of any order and on receipt of all information and drawings to enable us to put the work in hand. Where delivery is to take place by instalments each such instalment shall constitute a separate contract. We will use our best endeavours to complete delivery of the goods or services in the period stated but accept no liability in damages or otherwise for failure to do so for any cause whatsoever. In all cases of delay the delivery time shall be extended by reasonable period having regard to the cause of delay.

4. PAYMENT

Payment shall be made net cash within thirty (30) days of delivery or in accordance with the payment terms set out in the quotation. Unless specifically stated to the contrary payment shall be in pounds sterling. In the event of any payment to us being overdue we may without prejudice to any other right suspend delivery to you or terminate the contract and/or charge you simple interest on overdue amounts at the rate of 2.5% above the ruling Bank of England Minimum Lending Rate. No payment to us shall in any circumstance be offset against any sum owing by us to you whether in respect of the present transaction or otherwise.

5. INSPECTION & TEST

All goods are fully inspected at our works and where practicable subjected to our standard tests before despatch. If tests are required to be witnessed by your representative notice of this must be given at the time of placing the order and notice of readiness will then be given to you seven (7) days in advance of such tests being carried out. In the event of of any delay on your part in attending such tests or in carrying out inspection by you after seven (7) days notice of readiness the tests will proceed in your absence and shall be deemed to have been made in your presence and the inspection deemed to have benn made by you. In any event you shall be required promptly after witnessing a test or receiving test results of witnessed or unwitnessed tests to notify us in writing of any claimed defects in the goods or of any respect in which it is claimed that the goods do not conform with the contract. Before you become entitled to reject any goods we are to be given reasonable time and opportunity to rectify them. You assume the responsibility that the goods stipulated by you are sufficient and suitable for your purpose and take all steps to ensure that the goods will be safe and without risk to health when properly used. Any additional certification demanded may incur extra cost for which a special quotation will be issued.

6. DELIVERY AND PACKING

All shipments are, unless otherwise specifically provided, Ex-works which is the address given on the invoice. An additional charge will be made for carriage and insurance as necessary with the provision that all shipments shall be insured and this insurance expense shall be paid by the purchaser. Where special domestic or export packing is specified a charge will be made to cover the extra expense involved.

7. DAMAGE IN TRANSIT

Claims for damage in transit or loss in delivery of the goods will only be considered if the carriers and ourselves receive notice of such damage within seven (7) days of delivery or in the event of loss of goods in transit within fourteen (14) days of consignment.

8. TRANSFER OF PROPERTY & RISK

Title and property of the goods shall pass when full payment has been received of all sums due to us whether in respect of the present transaction or not. The risk in the goods shall be deemed to have passed on delivery.

9. WARRANTY

We agree to correct, either by repair, or at our election, by replacement, any defects of material or workmanship which develop within the warranty period specified in the sales literature or quotation after delivery to the original purchaser. All items claimed defective must be promptly returned to us carriage paid unless otherwise arranged and will be returned to you free of charge. Unless otherwise agreed no warranty is made concerning components or accessories not manufactured by us. We will be released from all obligations under warranty in the event of repairs or modifications made by persons other than our own authorised service personnel unless such repairs are made with our prior written consent.

10. PATENTS

We will indemnify you against any claim of infringement of Letters Patent, Registered Design, Trade Mark or Copyright (published at the date of the contract) by the use or sale of any goods supplied or service rendered by us to you and against all costs and damages which you may incur and for which you may become liable in any action for such infringement. Provided always that this indemnity shall not apply to any infringement which is due to our having followed a design or instruction furnished or given by you or to the use of such goods or service in association or combination with any other article, material or service no supplied by us. This indemnity is conditional on your giving to us the earliest possible notice in writing of any claim being made or action threatened or brought against you and on your permitting us at our own expense to conduct litigation that may ensue and all negotiations for a settlement of the claim or action. You on your part warrant that any design or instruction furnished or given by you shall not cause us toinfringe any Letter Patent, Registered Design, Trade Mark or Copyright in the execution of your order.

11. DOCUMENTATION

All drawings, plans, designs, software specifications, manuals and technical documents and information supplied by us for your use or information shall remain at all times our exclusive property and must not be copied, reproduced, transmitted or communicated to a third party without our prior written consent.

12. FRUSTRATION

If any contract or any part of it shall become impossible of performance or otherwise frustrated we shall be entitled to a fair and reasonable proportion of the price in respect of the work done up to the date thereof. For this purpose any monies previously paid by you shall be retained against the sum due to us under this provision. We may dispose of the goods as we think fit due allowance being made to you for the net proceeds thereof.

13. BANKRUPTCY

If the purchaser shall become bancrupt or insolvent, or being a Limited Company commence to be wound up or suffer a Receiver to be appointed, we shall be at liberty to treat the contract as terminated and be relieved of further obligations. This shall be without prejudice to our right to claim for damages for breach of contract.

14. LEGAL INTERPRETATION

Any contract will be deemed to be made in England and shall be governed and construed for all purposes and in all respects in accordance with English Law and only the Courts of England shall have jurisdiction.

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SALES AND SERVICE REPRESENTATIVES WORLDWIDE

COUNTRY AND F	Telephone	Telex	
AUSTRALIA	Scientific Devices (Australia) Pty. Ltd., 2 Jacks Road, South Oakleigh, Victoria 3167	(579)3622	32742
AUSTRIA	Kontron GmbH & Co, Electronics Department Eisgrubengasse 2, A-2334 Voesendorf B. Wien	(222)692531	131699
BELGIUM	Air-Parts International B.V. Avenue Huart-Hamoir 1-Box 19, 1030 Brussels	0103222416460	25146
BRAZIL	Comercial Goncalves Rua Deocleciana, 77, Ponte Pequena Sao Paulo SP, Cep 01106	(11)2294044	22104
CHINA	Tianjin First Radio Factory No. 5 Zhao Jia Chang Street, Hong Qiao Section, Tianjin	Tianjin 251941	-
DENMARK	Instrutek A/S, Head Office: Christiansholmsgade DK-8700 Horsens	(5)611100	61656
EASTERN EUROPE	Amtest Associates Ltd., Amtest Hse, 75-79 Guilford St, Chertsey, Surrey KT16 9AS, England	0932568355	928855
EGYPT & MIDDLE EAST	EPIC 20 Ashmoun St, PO Box 2682, Horria, Heliopolis	(2)661767	23315
FINLAND	T.B.A.	, -	9 -
FRANCE	JOD Instrumentation 37-41 rue des Artisans, 78760 Jouans Pontchartrain, Paris	(1)34891174	698485
GERMANY	Wavetek Electronics GmbH Hans-Pinsel Strasse 9-10, 8013 Haar b. Munchen, W.Germany	(89)461090	5212996
GREECE	American Technical Enterprises PO Box 156, 48 Patission Street, Athens 147	(1)8219470	216046
HONG KONG	Eurotherm (Far East) Ltd., 21/F Kai Tak Commercial Building, 317-321 Des Voeux Road, Central, Hong Kong	(5)411268	72449
INDIA	Technical Trade Links 42, Navketan Estate, Mahakali Caves Road, Andheri (East), Post Box No. 9447, Bombay 400 093	(22)4133341	1171071
INDONESIA	PT & PD Bah Bolon Trading Co., D1/Arena Pekan Raya Jakarta. P. O. Box 2157, Jakarta 10000	(21)377008	46164
IRELAND	Euro Instruments & Electronics Euro House, Swords Road, Santry, Dublin 9	01-425-000	318121
ISRAEL	Racom Electronics Co. Ltd., 7 Kehilat Saloniki St., P. O. Box 21120, Tel-Aviv 61210	(3)491922	33808

COUNTRY AND	REPRESENTATIVE	Telephone	Telex
ITALY(1)	Telav International Via Salaria 1313, 00138 Roma	(6)691-9312/ 9376/7058	614381
ITALY(2)	Telav International SRL Viale Leonardo da Vinci 43, 20090 Trezzano sul Naviglio, Milano	(2)4455741	312827
JAPAN	G & G Japan Inc., No. 406, 12-14, 4-Chome, Hongoh, Bunkyo-ku, Tokyo	(3)8130971	2722884
KOREA	Sama Trading Corporation CPO Box 2447, Seoul	(2)733 8336	26375
MALAYSIA	TME Systems Pte Ltd., 21 Moonstone Lane, No. 06-01, Poh Leng Building, Singapore 1232	(286)4608	37545
NETHERLANDS	Air Parts International BV PO Box 255, 12 Kalkovenweg, 2400 AG Alphen a.d. Rijn	(72)43221	39564
NEW ZEALAND	G.T.S. Engineering Ltd., 52 Broadway, Newmarket, AUCKLAND Box 9613	(9)546 745	60430
NORWAY	Norsk Marconi A/S Ryensvingen 5, PO Box 50, Manglerud, N-0612, Oslo 6	(2)680480	77140
PAKISTAN	CMC 22 Fareed Chambers, Abdullah Haroon Road, Karachi-3	(21)516134	24791
PORTUGAL	Omnitecnica SARL Estrada de Alfragide, 2700 Amadora	(19)905517	13433
SINGAPORE	Mecomb Singapore Ltd., Sime Darby Centre, 896 Dunearn Road, 04-2 Singapore 2158	(469)8833	23178
SPAIN	Essa (Equipos y Systemas SA) C/Apolonio Morales 13-B, Madrid 16	010344580150	831 42856
SOUTH AFRICA	Altech Instruments (PTY) Ltd PO Box 41062, Craighall 2024	010271179	422033
SWEDEN	Ferner Electronics AB Snormakarvagen 35, Box 125, 16126 BROMMA	(8)802540	10312
SWITZERLAND	Kontron Electronic AG Bemerstrasse-Sued 169, 8048 Zurich	0104114354111	822195
TAIWAN	Evergo Corporation Room A, 9Fl., 305 Section, 3 Nan King East Road, P. O. Box 94-546, Taipei	(2)7150283	27027
UNITED KINGDOM	Datron Instruments Hurricane Way, Norwich, Norfolk, England	(0603)404824	975173
UNITED STATES & CANADA	Wavetek Indiana Inc., 5808 Churchman, Box190, Beech Grove, IN 46107	(317)787-3332	TWX8103413226

For customers in countries not listed please contact DATRON INSTRUMENTS in the United Kingdom

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